

ProASIC3L Low-Power Flash FPGAs with Flash*Freeze Technology



Features and Benefits

Low Power

- Dramatic Reduction in Dynamic and Static Power Savings
- 1.2 V to 1.5 V Core and I/O Voltage Support for Low Power
- Low Power Consumption in Flash*Freeze Mode Allows for Instantaneous Entry to / Exit from Low-Power Flash*Freeze Mode
- Supports Single-Voltage System Operation
- Low-Impedance Switches

High Capacity

- 250 k to 3 M System Gates
- Up to 504 kbits of True Dual-Port SRAM
- Up to 620 User I/Os

Reprogrammable Flash Technology

- 130-nm, 7-Layer Metal (6 Copper), Flash-Based CMOS Process
- Live-at-Power-Up (LAPU) Level 0 Support
- Single-Chip Solution
- Retains Programmed Design when Powered Off

High Performance

- 350 MHz (1.5 V systems) and 250 MHz (1.2 V systems) System Performance
- 3.3 V, 66 MHz, 66-Bit PCI (1.5 V systems) and 66 MHz, 32-Bit PCI (1.2 V systems)

In-System Programming (ISP) and Security

- Secure ISP Using On-Chip 128-Bit Advanced Encryption Standard (AES) Decryption via JTAG (IEEE 1532-compliant)
- FlashLock[®] to Secure FPGA Contents

High-Performance Routing Hierarchy

- Segmented, Hierarchical Routing and Clock Structure
- High-Performance, Low-Skew Global Network
- Architecture Supports Ultra-High Utilization

Advanced and Pro (Professional) I/Os

- 700 Mbps DDR, LVDS-Capable I/Os
- 1.2 V, 1.5 V, 1.8 V, 2.5 V, and 3.3 V Mixed-Voltage Operation
- Bank-Selectable I/O Voltages—up to 8 Banks per Chip

- Single-Ended I/O Standards: LVTTTL, LVCMOS 3.3 V / 2.5 V / 1.8 V / 1.5 V / 1.2 V, 3.3 V PCI / 3.3 V PCI-X, and LVCMOS 2.5 V / 5.0 V Input
- Differential I/O Standards: LVPECL, LVDS, B-LVDS, and M-LVDS
- Voltage-Referenced I/O Standards: GTL+ 2.5 V / 3.3 V, GTL 2.5 V / 3.3 V, HSTL Class I and II, SSTL2 Class I and II, SSTL3 Class I and II (A3PE3000L only)
- Wide Range Power Supply Voltage Support per JESD8-B, Allowing I/Os to Operate from 2.7 V to 3.6 V
- Wide Range Power Supply Voltage Support per JESD8-12, Allowing I/Os to Operate from 1.14 V to 1.575 V
- I/O Registers on Input, Output, and Enable Paths
- Hot-Swappable and Cold-Sparing I/Os Programmable Output Slew Rate and Drive Strength
- Programmable Input Delay (A3PE3000L only)
- Schmitt Trigger Option on Single-Ended Inputs (A3PE3000L)
- Weak Pull-Up/-Down
- IEEE 1149.1 (JTAG) Boundary Scan Test
- Pin-Compatible Packages across the ProASIC[®]3L Family (except PQ208)

Clock Conditioning Circuit (CCC) and PLL

- Six CCC Blocks, One with Integrated PLL (ProASIC3L) and All with Integrated PLL (ProASIC3EL)
- Configurable Phase Shift, Multiply/Divide, Delay Capabilities, and External Feedback
- Wide Input Frequency Range 1.5 MHz to 250 MHz (1.2 V systems) and 350 MHz (1.5 V systems)

SRAMs and FIFOs

- Variable-Aspect-Ratio 4,608-Bit RAM Blocks (x1, x2, x4, x9, and x18 organizations available)
- True Dual-Port SRAM (except x18)
- 24 SRAM and FIFO Configurations with Synchronous Operation:
 - 250 MHz: For 1.2 V systems
 - 350 MHz: For 1.5 V systems

ARM[®] Processor Support in ProASIC3L FPGAs

- ARM Cortex[™]-M1 Soft Processor Available with or without Debug

Table 1 • ProASIC3 Low-Power Product Family

ProASIC3L Devices	A3P250L	A3P600L	A3P1000L	A3PE3000L
ARM Cortex-M1 Devices ¹		M1A3P600L	M1A3P1000L	M1A3PE3000L
System Gates	250 k	600 k	1 M	3 M
VersaTiles (D-flip-flops)	6,144	13,824	24,576	75,264
RAM kbits (1,024 bits)	36	108	144	504
4,608-Bit Blocks	8	24	32	112
FlashROM Bits	1 k	1 k	1 k	1 k
Secure (AES) ISP ²	Yes	Yes	Yes	Yes
Integrated PLL in CCCs ³	1	1	1	6
VersaNet Globals	18	18	18	18
I/O Banks	4	4	4	8
Maximum User I/Os	157	235	300	620
Package Pins				
VQFP	VQ100			
PQFP	PQ208	PQ208	PQ208	PQ208 ³
FBGA	FG144, FG256	FG144, FG256, FG484	FG144, FG256, FG484	FG324, FG484, FG896

Notes:

1. Refer to the [Cortex-M1 product brief](#) for more information.
2. AES is not available for ARM-enabled ProASIC3L devices.
3. For the A3PE3000L, the PQ208 package has six CCCs and two PLLs.

I/Os Per Package ¹

ProASIC3L Low-Power Devices	A3P250L ²		A3P600L		A3P1000L		A3PE3000L	
ARM Cortex-M1 Devices			M1A3P600L		M1A3P1000L		M1A3PE3000L ³	
Package	I/O Type							
	Single- Ended I/O ⁴	Differential I/O Pairs	Single- Ended I/O ⁴	Differential I/O Pairs	Single- Ended I/O ⁴	Differential I/O Pairs	Single- Ended I/O ⁴	Differential I/O Pairs
VQ100	68	13		–	–	–	–	–
PQ208	151	34	154	35	154	35	147	65
FG144	97	24	97	25	97	25		
FG256	157	38	177	43	177	44	–	–
FG324	–	–	–	–	–	–	221	110
FG484	–	–	235	60	300	74	341	168
FG896	–	–	–	–	–	–	620	310

Notes:

- When considering migrating your design to a lower- or higher-density device, refer to the packaging section of the datasheet to ensure you are complying with design and board migration requirements.
- For A3P250L devices, the maximum number of LVPECL pairs in east and west banks cannot exceed 15.
- ARM Cortex-M1 support is TBD on this device.
- Each used differential I/O pair reduces the number of single-ended I/Os available by two.
- FG256 and FG484 are footprint-compatible packages.
- "G" indicates RoHS-compliant packages. Refer to "ProASIC3L Ordering Information" on page III for the location of the "G" in the part number.
- For A3PE3000L devices, the usage of certain I/O standards is limited as follows:
 - SSTL3(I) and (II): up to 40 I/Os per north or south bank
 - LVPECL / GTL+ 3.3 V / GTL 3.3 V: up to 48 I/Os per north or south bank
 - SSTL2(I) and (II) / GTL+ 2.5 V / GTL 2.5 V: up to 72 I/Os per north or south bank
- When the Flash*Freeze pin is used to directly enable Flash*Freeze mode and not as a regular I/O, the number of single-ended user I/Os available is reduced by one.

Table 2 • ProASIC3L FPGAs Package Sizes Dimensions

Package	VQ100	PQ208	FG144	FG256	FG324	FG484	FG896
Length × Width (mm\mm)	14 × 14	28 × 28	13 × 13	17 × 17	19 × 19	23 × 23	31 × 31
Nominal Area (mm ²)	196	784	169	289	361	529	961
Pitch (mm)	0.5	0.5	1.0	1.0	1.0	1.0	1.0
Height (mm)	1.00	3.40	1.45	1.60	1.63	2.23	2.23

A3P1000L – **1** **FG** **G** **144** **I**

Part Number

Speed Grade
Blank = Standard
1 = 15% Faster than Standard

Package Type
VQ = Very Thin Quad Flat Pack (0.5 mm pitch)
PQ = Plastic Quad Flat Pack (0.5 mm pitch)
FG = Fine Pitch Ball Grid Array (1.0 mm pitch)

Lead-Free Packaging
Blank = Standard Packaging
G = RoHS-Compliant (Green) Packaging

Package Lead Count

Application (Temperature Range)
Blank = Commercial (0°C to +70°C Ambient Temperature)
I = Industrial (–40°C to +85°C Ambient Temperature)

A3P250L = 250,000 System Gates
A3P600L = 600,000 System Gates
A3P1000L = 1,000,000 System Gates
A3PE3000L = 3,000,000 System Gates

M1A3P600L = 600,000 System Gates
M1A3P1000L = 1,000,000 System Gates
M1A3PE3000L = 3,000,000 System Gates

Temperature Grade Offerings

Package	A3P250L	A3P600L	A3P1000L	A3PE3000L
ARM Cortex-M1 Devices		M1A3P600L	M1A3P1000L	M1A3PE3000L
VQ100	C, I	–	–	
PQ208	C, I	C, I	C, I	C, I
FG144	C, I	C, I	C, I	
FG256	C, I	C, I	C, I	
FG324	–	–	–	C, I
FG484	–	C, I	C, I	C, I
FG896	–	–	–	C, I

Notes:

1. C = Commercial temperature range: 0°C to 70°C ambient temperature.
2. I = Industrial temperature range: –40°C to 85°C ambient temperature.

Speed Grade and Temperature Grade Matrix

Temperature Grade	Std.	–1
C ¹	✓	✓
I ²	✓	✓

Notes:

1. C = Commercial temperature range: 0°C to 70°C ambient temperature.
2. I = Industrial temperature range: –40°C to 85°C ambient temperature.

Contact your local Actel representative for device availability:
<http://www.actel.com/contact/default.aspx>.

1 – ProASIC3L Device Family Overview

General Description

The ProASIC3L family of Actel flash FPGAs dramatically reduces dynamic power consumption by 40% and static power by 50%. These power savings are coupled with performance, density, true single-chip, 1.2 V to 1.5 V core and I/O operation as low as 1.2 V, reprogrammability, and advanced features.

Using Actel's proven Flash*Freeze technology enables users to shut off dynamic power instantaneously and switch the device to static mode without the need to switch off clocks or power supplies while retaining internal states of the device. This greatly simplifies power management on a board done through I/Os and clocks. In addition, optimized software tools using power-driven layout provide instant push-button power reduction.

Nonvolatile flash technology gives ProASIC3L devices the advantage of being a secure, low-power, single-chip solution that is live at power-up (LAPU). ProASIC3L offers dramatic dynamic power savings giving the FPGA users flexibility to combine low power with high performance.

These features enable designers to create high-density systems using existing ASIC or FPGA design flows and tools.

ProASIC3L devices offer 1 kbit of on-chip, reprogrammable, nonvolatile FlashROM storage as well as clock conditioning circuitry (CCC) based on an integrated phase-locked loop (PLL). ProASIC3L devices support devices from 250 k system gates to 3 million system gates with up to 504 kbits of true dual-port SRAM and 620 user I/Os.

M1 ProASIC3L devices support the high-performance, 32-bit Cortex-M1 processor developed by ARM for implementation in FPGAs. ARM Cortex-M1 is a soft processor that is fully implemented in the FPGA fabric. It has a three-stage pipeline that offers a good balance between low-power consumption and speed when implemented in an M1 ProASIC3L device. The processor runs the ARMv6-M instruction set, has a configurable nested interrupt controller, and can be implemented with or without the debug block. ARM Cortex-M1 is available for free from Actel for use in M1 ProASIC3L FPGAs.

The ARM-enabled devices have Actel ordering numbers that begin with M1 and do not support AES decryption.

Flash*Freeze Technology

The ProASIC3L devices offer Actel's proven Flash*Freeze technology, which allows instantaneous switching from an active state to a static state. ProASIC3L devices do not need additional components to turn off I/Os or clocks while retaining the design information, SRAM content, and registers. Flash*Freeze technology is combined with in-system programmability, which enables users to quickly and easily upgrade and update their designs in the final stages of manufacturing or in the field. The ability of ProASIC3L devices to support a wide range core voltage (1.2 V to 1.5 V) allows for an even greater reduction in power consumption, which enables low total system power.

When the ProASIC3L device enters Flash*Freeze mode, the device automatically shuts off the clocks and inputs to the FPGA core; when the device exits Flash*Freeze mode, all activity resumes and data is retained.

The availability of low-power modes, combined with a reprogrammable, single-chip, single-voltage solution, make ProASIC3L devices suitable for low-power data transfer and manipulation in portable media, secure communications, radio applications as well as high performance portable, industrial, test, scientific, and medical applications.

Flash Advantages

Low Power

The ProASIC3L family of Actel flash-based FPGAs provide a low-power advantage, and when coupled with high performance, enables designers to make power-smart choices using a single-chip, reprogrammable, and live-at-power-up device.

ProASIC3L devices offer 40% dynamic power and 50% static power savings by reducing the core operating voltage to 1.2 V. In addition, the Power Driven Layout (PDL) feature in Libero® Integrated Design Environment (IDE) offers up to 30% additional power reduction. With Flash*Freeze technology, ProASIC3L is able to retain device SRAM and logic while dynamic power is reduced to a minimum, without the need to stop clock or power supplies. Combining these features provides a low-power, feature-rich and high-performance solution.

Security

Nonvolatile, flash-based ProASIC3L devices do not require a boot PROM, so there is no vulnerable external bitstream that can be easily copied. ProASIC3L devices incorporate FlashLock, which provides a unique combination of reprogrammability and design security without external overhead, advantages that only an FPGA with nonvolatile flash programming can offer.

ProASIC3L devices utilize a 128-bit flash-based lock and a separate AES key to secure programmed intellectual property and configuration data. In addition, all FlashROM data in ProASIC3L devices can be encrypted prior to loading, using the industry-leading AES-128 (FIPS192) bit block cipher encryption standard. AES was adopted by the National Institute of Standards and Technology (NIST) in 2000 and replaces the 1977 DES standard. ProASIC3L devices have a built-in AES decryption engine and a flash-based AES key that make them the most comprehensive programmable logic device security solution available today. ProASIC3L devices with AES-based security allow for secure, remote field updates over public networks such as the Internet, and ensure that valuable IP remains out of the hands of system overbuilders, system cloners, and IP thieves. The contents of a programmed device cannot be read back, although secure design verification is possible.

Security, built into the FPGA fabric, is an inherent component of the ProASIC3L family. The flash cells are located beneath seven metal layers, and many device design and layout techniques have been used to make invasive attacks extremely difficult. The ProASIC3L family, with FlashLock and AES security, is unique in being highly resistant to both invasive and noninvasive attacks. Your valuable IP is protected and secure, making remote ISP possible. A ProASIC3L device provides the most impenetrable security for programmable logic designs.

Single Chip

Flash-based FPGAs store their configuration information in on-chip flash cells. Once programmed, the configuration data is an inherent part of the FPGA structure, and no external configuration data needs to be loaded at system power-up (unlike SRAM-based FPGAs). Therefore, flash-based ProASIC3L FPGAs do not require system configuration components such as EEPROMs or microcontrollers to load device configuration data. This reduces bill-of-materials costs and PCB area, and increases security and system reliability.

Live at Power-Up

The Actel flash-based ProASIC3L devices support Level 0 of the LAPU classification standard. This feature helps in system component initialization, execution of critical tasks before the processor wakes up, setup and configuration of memory blocks, clock generation, and bus activity management. The LAPU feature of flash-based ProASIC3L devices greatly simplifies total system design and reduces total system cost, often eliminating the need for CPLDs and clock generation PLLs. In addition, glitches and brownouts in system power will not corrupt the ProASIC3L device's flash configuration, and unlike SRAM-based FPGAs, the device will not have to be reloaded when system power is restored. This enables the reduction or complete removal of the configuration PROM, expensive voltage monitor, brownout detection, and clock generator devices from the PCB design. Flash-based ProASIC3L devices simplify total system design and reduce cost and design risk while increasing system reliability and improving system initialization time.

Reduced Cost of Ownership

Advantages to the designer extend beyond low unit cost, performance, and ease of use. Unlike SRAM-based FPGAs, flash-based ProASIC3L devices allow all functionality to be live at power-up; no external boot PROM is required. On-board security mechanisms prevent access to all the programming information and enable secure remote updates of the FPGA logic. Designers can perform secure remote in-system reprogramming to support future design iterations and field upgrades with confidence that valuable intellectual property cannot be compromised or copied. Secure ISP can be performed using the industry-standard AES algorithm. The ProASIC3L family device architecture mitigates the need for ASIC migration at higher user volumes. This makes the ProASIC3L family a cost-effective ASIC replacement solution, manipulation in portable media and secure communications, radio applications as well as high performance portable Industrial, test, scientific and medical applications.

Firm-Error Immunity

Firm errors occur most commonly when high-energy neutrons, generated in the upper atmosphere, strike a configuration cell of an SRAM FPGA. The energy of the collision can change the state of the configuration cell and thus change the logic, routing, or I/O behavior in an unpredictable way. These errors are impossible to prevent in SRAM FPGAs. The consequence of this type of error can be a complete system failure. Firm errors do not exist in the configuration memory of ProASIC3L flash-based FPGAs. Once it is programmed, the flash cell configuration element of ProASIC3L FPGAs cannot be altered by high-energy neutrons and is therefore immune to them. Recoverable (or soft) errors occur in the user data SRAM of all FPGA devices. These can easily be mitigated by using error detection and correction (EDAC) circuitry built into the FPGA fabric.

Advanced Flash Technology

The ProASIC3L family offers many benefits, including nonvolatility and reprogrammability, through an advanced flash-based, 130-nm LVC MOS process with 7 layers of metal. Standard CMOS design techniques are used to implement logic and control functions. The combination of fine granularity, enhanced flexible routing resources, and abundant flash switches allows for very high logic utilization without compromising device routability or performance. Logic functions within the device are interconnected through a four-level routing hierarchy.

Advanced Architecture

The proprietary ProASIC3L architecture provides granularity comparable to standard-cell ASICs. The ProASIC3L device consists of five distinct and programmable architectural features ([Figure 1-1 on page 1-4](#) and [Figure 1-2 on page 1-4](#)):

- FPGA VersaTiles
- Dedicated FlashROM
- Dedicated SRAM/FIFO memory
- Extensive CCCs and PLLs
- I/O structure

The FPGA core consists of a sea of VersaTiles. Each VersaTile can be configured as a three-input logic function, a D-flip-flop (with or without enable), or a latch by programming the appropriate flash switch interconnections. The versatility of the ProASIC3L core tile, as either a three-input lookup table (LUT) equivalent or a D-flip-flop/latch with enable, allows for efficient use of the FPGA fabric. The VersaTile capability is unique to the Actel ProASIC family of third-generation-architecture flash FPGAs. VersaTiles are connected with any of the four levels of routing hierarchy. Flash switches are distributed throughout the device to provide nonvolatile, reconfigurable interconnect programming. Maximum core utilization is possible for virtually any design.

In addition, extensive on-chip programming circuitry allows for rapid, single-voltage (3.3 V) programming of ProASIC3L devices via an IEEE 1532 JTAG interface.

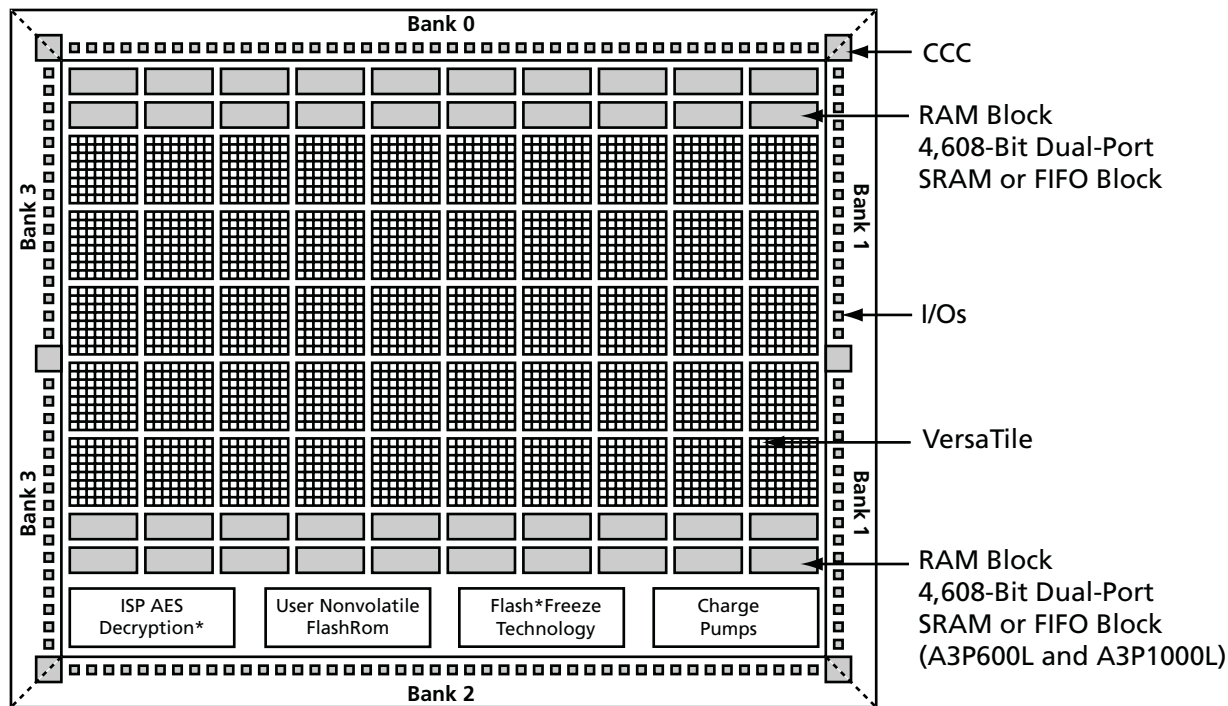


Figure 1-1 • ProASIC3L Device Architecture Overview with Four I/O Banks (A3P250L, A3P600L, and A3P1000L)

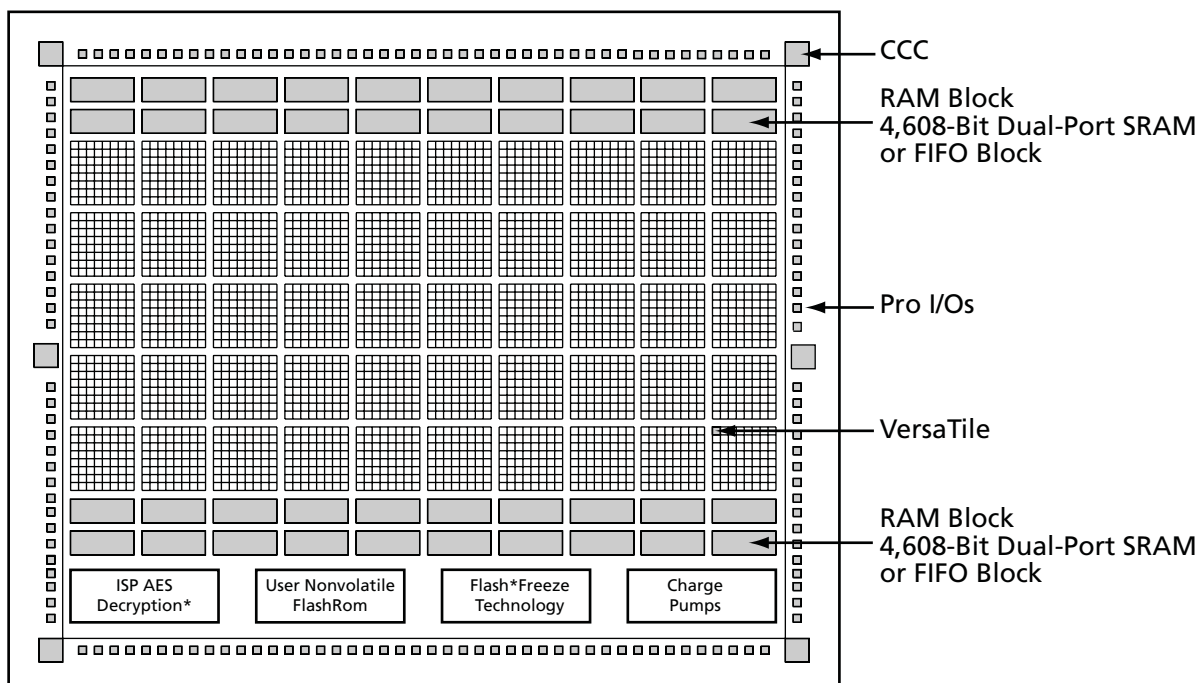


Figure 1-2 • ProASIC3EL Device Architecture Overview

Flash*Freeze Technology

The ProASIC3L devices offer Actel's proven Flash*Freeze technology, which enables designers to instantaneously shut off dynamic power consumption while retaining all SRAM and register information. Flash*Freeze technology enables the user to quickly (within 1 μ s) enter and exit Flash*Freeze mode by activating the Flash*Freeze (FF) pin while all power supplies are kept at their original values. In addition, I/Os and global I/Os can still be driven and can be toggling without impact on power consumption; clocks can still be driven or can be toggling without impact on power consumption; and the device retains all core registers, SRAM information, and states. I/O states are tristated during Flash*Freeze mode or can be set to a certain state using weak pull-up or pull-down I/O attribute configuration. No power is consumed by the I/O banks, clocks, JTAG pins, or PLL. Flash*Freeze technology allows the user to switch to active mode on demand, thus simplifying the power management of the device.

The FF pin (active low) can be routed internally to the core to allow the user's logic to decide when it is safe to transition to this mode. It is also possible to use the FF pin as a regular I/O if Flash*Freeze mode usage is not planned, which is advantageous because of the inherent low-power static and dynamic capabilities of the ProASIC3L device. Refer to [Figure 1-3](#) for an illustration of entering/exiting Flash*Freeze mode.

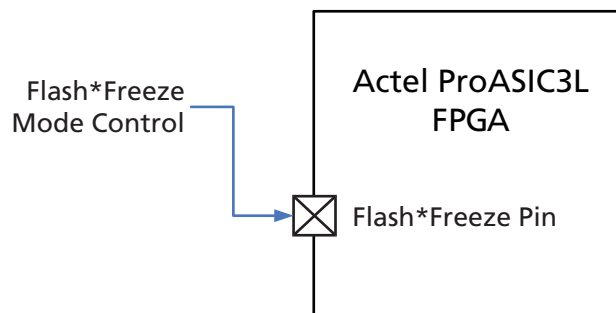


Figure 1-3 • ProASIC3L Flash*Freeze Mode

VersaTiles

The ProASIC3L core consists of VersaTiles, which have been enhanced beyond the ProASIC^{PLUS}® core tiles. The ProASIC3L VersaTile supports the following:

- All 3-input logic functions—LUT-3 equivalent
- Latch with clear or set
- D-flip-flop with clear or set
- Enable D-flip-flop with clear or set

Refer to [Figure 1-4](#) for VersaTile configurations.

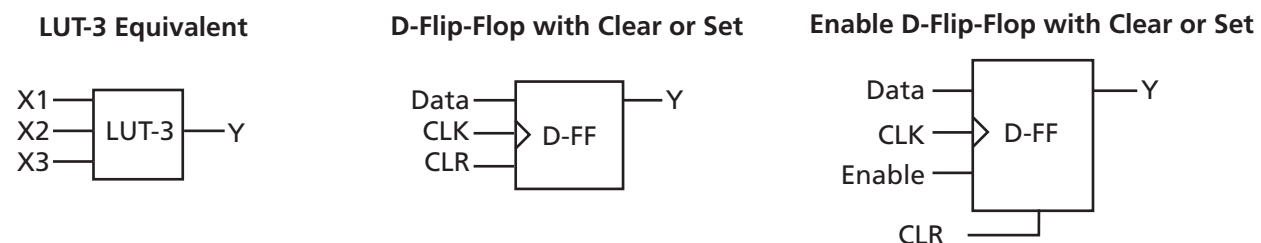


Figure 1-4 • VersaTile Configurations

User Nonvolatile FlashROM

Actel ProASIC3L devices have 1 kbit of on-chip, user-accessible, nonvolatile FlashROM. The FlashROM can be used in diverse system applications:

- Internet Protocol addressing (wireless or fixed)
- System calibration settings
- Device serialization and/or inventory control
- Subscription-based business models (for example, set-top boxes)
- Secure key storage for secure communications algorithms
- Asset management/tracking
- Date stamping
- Version management

The FlashROM is written using the standard ProASIC3L IEEE 1532 JTAG programming interface. The core can be individually programmed (erased and written), and on-chip AES decryption can be used selectively to securely load data over public networks, as in security keys stored in the FlashROM for a user design.

The FlashROM can be programmed via the JTAG programming interface, and its contents can be read back either through the JTAG programming interface or via direct FPGA core addressing. Note that the FlashROM can only be programmed from the JTAG interface and cannot be programmed from the internal logic array.

The FlashROM is programmed as 8 banks of 128 bits; however, reading is performed on a byte-by-byte basis using a synchronous interface. A 7-bit address from the FPGA core defines which of the 8 banks and which of the 16 bytes within that bank are being read. The three most significant bits (MSBs) of the FlashROM address determine the bank, and the four least significant bits (LSBs) of the FlashROM address define the byte.

The Actel ProASIC3L development software solutions, Libero IDE and Designer, have extensive support for the FlashROM. One such feature is auto-generation of sequential programming files for applications requiring a unique serial number in each part. Another feature allows the inclusion of static data for system version control. Data for the FlashROM can be generated quickly and easily using Actel Libero IDE and Designer software tools. Comprehensive programming file support is also included to allow for easy programming of large numbers of parts with differing FlashROM contents.

SRAM and FIFO

ProASIC3L devices have embedded SRAM blocks along their north and south sides. Each variable-aspect-ratio SRAM block is 4,608 bits in size. Available memory configurations are 256×18, 512×9, 1k×4, 2k×2, and 4k×1 bits. The individual blocks have independent read and write ports that can be configured with different bit widths on each port. For example, data can be sent through a 4-bit port and read as a single bitstream. The embedded SRAM blocks can be initialized via the device JTAG port (ROM emulation mode) using the UJTAG macro.

In addition, every SRAM block has an embedded FIFO control unit. The control unit allows the SRAM block to be configured as a synchronous FIFO without using additional core VersaTiles. The FIFO width and depth are programmable. The FIFO also features programmable Almost Empty (AEMPTY) and Almost Full (AFULL) flags in addition to the normal Empty and Full flags. The embedded FIFO control unit contains the counters necessary for generation of the read and write address pointers. The embedded SRAM/FIFO blocks can be cascaded to create larger configurations.

PLL and CCC

ProASIC3L devices provide designers with flexible clock conditioning circuit (CCC) capabilities. Each member of the ProASIC3L family contains six CCCs. One CCC (center west side) has a PLL.

The six CCC blocks are located at the four corners and the centers of the east and west sides. One CCC (center west side) has a PLL.

All six CCC blocks are usable; the four corner CCCs and the east CCC allow simple clock delay operations as well as clock spine access.

The inputs of the six CCC blocks are accessible from the FPGA core or from one of several inputs located near the CCC that have dedicated connections to the CCC block.

The CCC block has these key features:

- Wide input frequency range (f_{IN_CCC}) = 1.5 MHz up to 250 MHz
- Output frequency range (f_{OUT_CCC}) = 0.75 MHz up to 250 MHz
- 2 programmable delay types for clock skew minimization
- Clock frequency synthesis

Additional CCC specifications:

- Internal phase shift = 0°, 90°, 180°, and 270°. Output phase shift depends on the output divider configuration.
- Output duty cycle = 50% $\pm$ 1.5% or better
- Low output jitter: worst case < 2.5% $\times$ clock period peak-to-peak period jitter when single global network used
- Maximum acquisition time is 300 μ s
- Exceptional tolerance to input period jitter— allowable input jitter is up to 1.5 ns
- Four precise phases; maximum misalignment between adjacent phases of 40 ps $\times$ 250 MHz / f_{OUT_CCC}

Global Clocking

ProASIC3L devices have extensive support for multiple clocking domains. In addition to the CCC and PLL support described above, there is a comprehensive global clock distribution network.

Each VersaTile input and output port has access to nine VersaNets: six chip (main) and three quadrant global networks. The VersaNets can be driven by the CCC or directly accessed from the core via multiplexers (MUXes). The VersaNets can be used to distribute low-skew clock signals or for rapid distribution of high-fanout nets.

I/Os with Advanced I/O Standards

The ProASIC3L family of FPGAs features a flexible I/O structure, supporting a range of voltages (1.2 V, 1.5 V, 1.8 V, 2.5 V, 3.0 V wide range, and 3.3 V). ProASIC3L FPGAs support different I/O standards, including single-ended, differential, and voltage-referenced (ProASIC3EL only). The I/Os are organized into banks, with two, four, or eight (ProASIC3EL only) banks per device. The configuration of these banks determines the I/O standards supported. For ProASIC3EL, each I/O bank is subdivided into V_{REF} minibanks, which are used by voltage-referenced I/Os. V_{REF} minibanks contain 8 to 18 I/Os. All the I/Os in a given minibank share a common V_{REF} line. Therefore, if any I/O in a given V_{REF} minibank is configured as a V_{REF} pin, the remaining I/Os in that minibank will be able to use that reference voltage.

Each I/O module contains several input, output, and enable registers. These registers allow the implementation of the following:

- Single-data-rate applications (e.g., PCI 66 MHz, bidirectional SSTL 2 and 3, Class I and II)
- Double-data-Rate applications (e.g., DDR LVDS, B-LVDS, and M-LVDS I/Os for point-to-point communications, and DDR 200 MHz SRAM using bidirectional HSTL Class II).

ProASIC3L banks support LVPECL, LVDS, B-LVDS, and M-LVDS. B-LVDS and M-LVDS can support up to 20 loads.

Wide Range I/O Support

Actel ProASIC3L devices support JEDEC-defined wide range I/O operation. ProASIC3L devices support both the JESD8-B specification, covering 3 V and 3.3 V supplies, for an effective operating range of 2.7 V to 3.6 V, and JESD8-12 with its 1.2 V nominal, supporting an effective operating range of 1.14 V to 1.575 V.

Wider I/O range means designers can eliminate power supplies or power conditioning components from the board or move to less costly components with greater tolerances. Wide range eases I/O bank management and provides enhanced protection from system voltage spikes, while providing the flexibility to easily run custom voltage applications.

Part Number and Revision Date

Part Number 51700100-001-4

Revised February 2009

List of Changes

The following table lists critical changes that were made in the current version of the document.

Previous Version	Changes in Current Version (v1.3)	Page
v1.2 (February 2009)	The "I/Os Per Package ¹ " table was revised to change the number of differential I/O pairs for A3PE3000L from 300 to 310.	II
	Table 2 · ProASIC3L FPGAs Package Sizes Dimensions is new.	II
v1.1 (July 2008)	The "Advanced and Pro (Professional) I/Os" section was revised to add two bullets regarding wide range power supply voltage support.	I
	3.0 V wide range was added to the list of supported voltages in the "I/Os with Advanced I/O Standards" section. The "Wide Range I/O Support" section is new.	1-7
v1.0 (April 2008)	As a result of the Libero IDE v8.4 release, Actel now offers a wide range of core voltage support. The document was updated to change 1.2 V / 1.5 V to 1.2 V to 1.5 V.	N/A
51700100-001-1 (April 2008)	This document was divided into two sections and given a version number, starting at v1.0. The first section of the document includes features, benefits, ordering information, and temperature and speed grade offerings. The second section is a device family overview.	N/A
51700100-001-0 (January 2008)	Reference to M1A3P250L was removed from Table 1 · ProASIC3 Low-Power Product Family, the "I/Os Per Package ¹ " table, the "ProASIC3L Ordering Information" section, and the "Temperature Grade Offerings" table. The table note regarding M1A3P250L was removed from the "I/Os Per Package ¹ " table.	I, II, III, IV

Datasheet Categories

Categories

In order to provide the latest information to designers, some datasheets are published before data has been fully characterized. Datasheets are designated as "Product Brief," "Advance," "Preliminary," and "Production." The definitions of these categories are as follows:

Product Brief

The product brief is a summarized version of a datasheet (advance or production) and contains general product information. This document gives an overview of specific device and family information.

Advance

This version contains initial estimated information based on simulation, other products, devices, or speed grades. This information can be used as estimates, but not for production. This label only applies to the DC and Switching Characteristics chapter of the datasheet and will only be used when the data has not been fully characterized.

Preliminary

The datasheet contains information based on simulation and/or initial characterization. The information is believed to be correct, but changes are possible.

Unmarked (production)

This version contains information that is considered to be final.

Export Administration Regulations (EAR)

The products described in this document are subject to the Export Administration Regulations (EAR). They could require an approved export license prior to export from the United States. An export includes release of product or disclosure of technology to a foreign national inside or outside the United States.

Actel Safety Critical, Life Support, and High-Reliability Applications Policy

The Actel products described in this advance status document may not have completed Actel's qualification process. Actel may amend or enhance products during the product introduction and qualification process, resulting in changes in device functionality or performance. It is the responsibility of each customer to ensure the fitness of any Actel product (but especially a new product) for a particular purpose, including appropriateness for safety-critical, life-support, and other high-reliability applications. Consult Actel's Terms and Conditions for specific liability exclusions relating to life-support applications. A reliability report covering all of Actel's products is available on the Actel website at http://www.actel.com/documents/ORT_Report.pdf. Actel also offers a variety of enhanced qualification and lot acceptance screening procedures. Contact your local Actel sales office for additional reliability information.

2 – ProASIC3L DC and Switching Characteristics

General Specifications

Operating Conditions

Stresses beyond those listed in [Table 2-1](#) may cause permanent damage to the device.

Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Absolute Maximum Ratings are stress ratings only; functional operation of the device at these or any other conditions beyond those listed under the Recommended Operating Conditions specified in [Table 2-2 on page 2-2](#) is not implied.

Table 2-1 • Absolute Maximum Ratings

Symbol	Parameter	Limits	Units
V_{CC}	DC core supply voltage	–0.3 to 1.65	V
V_{JTAG}	JTAG DC voltage	–0.3 to 3.75	V
V_{PUMP}	Programming voltage	–0.3 to 3.75	V
V_{CCPLL}	Analog power supply (PLL)	–0.3 to 1.65	V
V_{CCI} and VMV^3	DC I/O buffer supply voltage	–0.3 to 3.75	V
V_I	I/O input voltage	–0.3 V to 3.6 V (when I/O hot insertion mode is enabled) –0.3 V to ($V_{CCI} + 1$ V) or 3.6 V, whichever voltage is lower (when I/O hot-insertion mode is disabled)	V
T_{STG}^2	Storage temperature	–65 to +150	°C
T_J^2	Junction temperature	+125	°C

Notes:

1. The device should be operated within the limits specified by the datasheet. During transitions, the input signal may undershoot or overshoot according to the limits shown in [Table 2-4 on page 2-3](#).
2. For flash programming and retention maximum limits, refer to [Table 2-3 on page 2-2](#), and for recommended operating limits, refer to [Table 2-2 on page 2-2](#).
3. VMV pins must be connected to the corresponding V_{CCI} pins. See [Pin Descriptions](#) for further information.

Table 2-2 • Recommended Operating Conditions ¹

Symbol	Parameter		Commercial	Industrial	Units
T _A	Ambient temperature		0 to +70	–40 to +85	°C
T _J	Junction Temperature		0 to + 85	–40 to +100	°C
V _{CC} ²	1.2 V–1.5 V wide range core voltage		1.14 to 1.575	1.14 to 1.575	V
V _{JTAG}	JTAG DC voltage		1.4 to 3.6	1.4 to 3.6	V
V _{PUMP} ³	Programming voltage	Programming Mode	3.15 to 3.45	3.15 to 3.45	V
		Operation ³	0 to 3.45	0 to 3.45	V
V _{CCPLL} ⁶	Analog power supply (PLL)	1.2 V–1.5 V wide range core voltage	1.14 to 1.575	1.14 to 1.575	V
V _{CCI} and VMV ⁵	1.2 V DC supply voltage ⁴		1.14 to 1.26	1.14 to 1.26	V
	1.5 V DC supply voltage		1.425 to 1.575	1.425 to 1.575	V
	1.8 V DC supply voltage		1.7 to 1.9	1.7 to 1.9	V
	2.5 V DC supply voltage		2.3 to 2.7	2.3 to 2.7	V
	3.3 V wide range DC supply voltage ⁷		2.7 to 3.6	2.7 to 3.6	V
	3.3 V DC supply voltage		3.0 to 3.6	3.0 to 3.6	V
	LVDS differential I/O		2.375 to 2.625	2.375 to 2.625	V
	LVPECL differential I/O		3.0 to 3.6	3.0 to 3.6	V

Notes:

1. All parameters representing voltages are measured with respect to GND unless otherwise specified.
2. The ranges given here are for power supplies only. The recommended input voltage ranges specific to each I/O standard are given in [Table 2-13 on page 2-10](#). V_{CCI} should be at the same voltage within a given I/O bank.
3. V_{PUMP} can be left floating during normal operation (not programming mode).
4. For ProASIC[®]3L devices, V_{CCI} ≥ V_{CC}.
5. VMV pins must be connected to the corresponding V_{CCI} pins. See [Pin Descriptions](#) for further information.
6. V_{CCPLL} pins should be tied to V_{CC} pins. See [Pin Descriptions](#) for further information.
7. 3.3 V wide range is compliant to the JEDEC8a specification and supports 3.0 V V_{CCI} operation.

Table 2-3 • Flash Programming Limits – Retention, Storage, and Operating Temperature ¹

Product Grade	Programming Cycles	Program Retention (biased/unbiased)	Maximum Storage Temperature T _{STG} (°C) ²	Maximum Operating Junction Temperature T _J (°C) ²
Commercial	500	20 years	110	100
Industrial	500	20 years	110	100

Notes:

1. This is a stress rating only; functional operation at any condition other than those indicated is not implied.
2. These limits apply for program/data retention only. Refer to [Table 2-1 on page 2-1](#) and [Table 2-2](#) for device operating conditions and absolute limits.

Table 2-4 • Overshoot and Undershoot Limits ¹

V_{CCI}	Average V_{CCI} -GND Overshoot or Undershoot Duration as a Percentage of Clock Cycle ²	Maximum Overshoot/Undershoot ²
2.7 V or less	10%	1.4 V
	5%	1.49 V
3 V	10%	1.1 V
	5%	1.19 V
3.3 V	10%	0.79 V
	5%	0.88 V
3.6 V	10%	0.45 V
	5%	0.54 V

Notes:

1. Based on reliability requirements at junction temperature at 85°C.
2. The duration is allowed at one out of six clock cycles. If the overshoot/undershoot occurs at one out of two cycles, the maximum overshoot/undershoot has to be reduced by 0.15 V.
3. This table does not provide PCI overshoot/undershoot limits.

I/O Power-Up and Supply Voltage Thresholds for Power-On Reset (Commercial and Industrial)

Sophisticated power-up management circuitry is designed into every ProASIC3 device. These circuits ensure easy transition from the powered-off state to the powered-up state of the device. The many different supplies can power up in any sequence with minimized current spikes or surges. In addition, the I/O will be in a known state through the power-up sequence. The basic principle is shown in [Figure 2-1 on page 2-4](#) and [Figure 2-2 on page 2-5](#).

There are five regions to consider during power-up.

ProASIC3 I/Os are activated only if ALL of the following three conditions are met:

1. V_{CC} and V_{CCI} are above the minimum specified trip points ([Figure 2-1 on page 2-4](#) and [Figure 2-2 on page 2-5](#)).
2. $V_{CCI} > V_{CC} - 0.75$ V (typical)
3. Chip is in the operating mode.

 V_{CCI} Trip Point:

Ramping up: $0.6 \text{ V} < \text{trip_point_up} < 1.2 \text{ V}$

Ramping down: $0.5 \text{ V} < \text{trip_point_down} < 1.1 \text{ V}$

 V_{CC} Trip Point:

Ramping up: $0.6 \text{ V} < \text{trip_point_up} < 1.1 \text{ V}$

Ramping down: $0.5 \text{ V} < \text{trip_point_down} < 1 \text{ V}$

V_{CC} and V_{CCI} ramp-up trip points are about 100 mV higher than ramp-down trip points. This specifically built-in hysteresis prevents undesirable power-up oscillations and current surges. Note the following:

- During programming, I/Os become tristated and weakly pulled up to V_{CCI} .
- JTAG supply, PLL power supplies, and charge pump V_{PUMP} supply have no influence on I/O behavior.

PLL Behavior at Brownout Condition

Actel recommends using monotonic power supplies or voltage regulators to ensure proper powerup behavior. Power ramp-up should be monotonic at least until V_{CC} and V_{CCPLX} exceed brownout activation levels. The V_{CC} activation level is specified as 1.1 V worst-case (see Figure 2-1 and Figure 2-2 on page 2-5 for more details).

When PLL power supply voltage and/or V_{CC} levels drop below the V_{CC} brownout levels ($0.75\text{ V} \pm 0.25\text{ V}$), the PLL output lock signal goes low and/or the output clock is lost. Refer to the [Power-Up/Down Behavior of Low-Power Flash Devices](#) chapter of the handbook for information on clock and lock recovery.

Internal Power-Up Activation Sequence

1. Core
2. Input buffers

Output buffers, after 200 ns delay from input buffer activation.

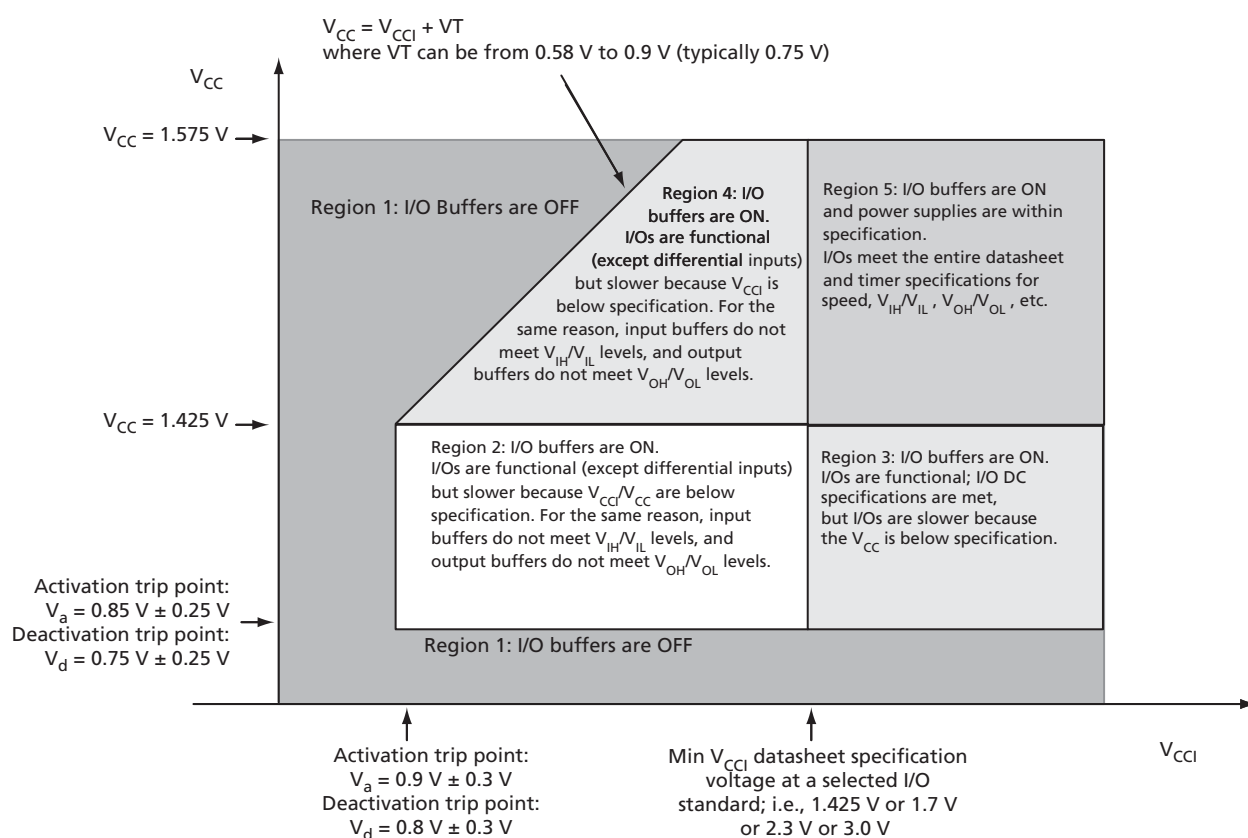


Figure 2-1 • V5 Devices – I/O State as a Function of V_{CCI} and V_{CC} Voltage Levels

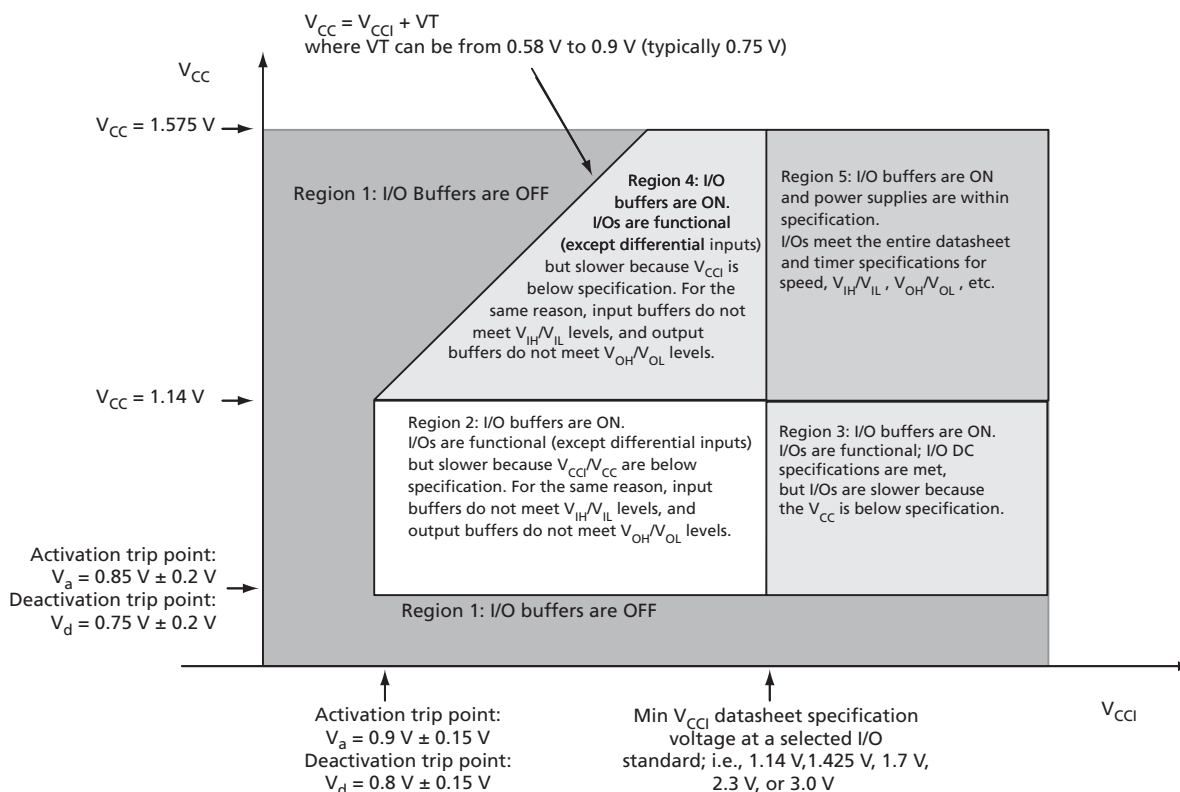


Figure 2-2 • V2 Devices – I/O State as a Function of V_{CCI} and V_{CC} Voltage Levels

Thermal Characteristics

Introduction

The temperature variable in the Actel Designer software refers to the junction temperature, not the ambient temperature. This is an important distinction because dynamic and static power consumption cause the chip junction temperature to be higher than the ambient temperature.

EQ 2-1 can be used to calculate junction temperature.

$$T_J = \text{Junction Temperature} = \Delta T + T_A$$

EQ 2-1

where:

T_A = Ambient Temperature

ΔT = Temperature gradient between junction (silicon) and ambient $\Delta T = \theta_{ja} * P$

θ_{ja} = Junction-to-ambient of the package. θ_{ja} numbers are located in Table 2-5.

P = Power dissipation

Package Thermal Characteristics

The device junction-to-case thermal resistivity is θ_{jc} and the junction-to-ambient air thermal resistivity is θ_{ja} . The thermal characteristics for θ_{ja} are shown for two air flow rates. The absolute maximum junction temperature is 100°C. EQ 2-2 shows a sample calculation of the absolute maximum power dissipation allowed for a 484-pin FBGA package at commercial temperature and in still air.

$$\text{Maximum Power Allowed} = \frac{\text{Max. junction temp. (°C)} - \text{Max. ambient temp. (°C)}}{\theta_{ja}(\text{°C/W})} = \frac{100^\circ\text{C} - 70^\circ\text{C}}{20.5^\circ\text{C/W}} = 1.463 \text{ W}$$

EQ 2-2

Table 2-5 • Package Thermal Resistivities

Package Type	Device	Pin Count	θ_{jc}	θ_{ja}			Units
				Still Air	200 ft./min.	500 ft./min.	
Very Thin Quad Flat Pack (VQFP)	All devices	100	10.0	35.3	29.4	27.1	C/W
Plastic Quad Flat Pack (PQFP)	All devices	208	8.0	26.1	22.5	20.8	C/W
PQFP with embedded heatspreader	All devices	208	3.8	16.2	13.3	11.9	C/W
Fine Pitch Ball Grid Array (FBGA)	A3P250L	144	12.2	43.8	37.7	35.8	C/W
	A3P600L	144	8.3	35.8	30.2	28.3	C/W
	A3P1000L	144	6.3	31.6	26.2	24.2	C/W
	A3P250L	256	12.0	38.6	34.7	33.0	C/W
	A3P600L	256	8.5	32.0	27.5	25.8	C/W
	A3P1000L	256	6.6	28.1	24.4	22.7	C/W
	AGLE3000	324	TBD	TBD	TBD	TBD	C/W
	A3P600L	484	9.5	27.5	21.9	20.2	C/W
	A3P1000L	484	8.0	23.3	19.0	16.7	C/W
	A3PE3000L	484	4.7	20.6	15.7	14.0	C/W
	A3PE3000L	896	2.4	13.6	10.4	9.4	C/W

Temperature and Voltage Derating Factors

Table 2-6 • Temperature and Voltage Derating Factors for Timing Delays
(normalized to $T_J = 70^\circ\text{C}$, $V_{CC} = 1.14\text{ V}$)

Array Voltage V_{CC} (V)	Junction Temperature ($^\circ\text{C}$)					
	-40°C	0°C	25°C	70°C	85°C	110°C
1.14	0.90	0.94	0.96	1.00	1.01	1.03
1.2	0.87	0.90	0.92	0.96	0.97	0.99
1.26	0.83	0.86	0.88	0.92	0.93	0.85
1.3	0.81	0.84	0.86	0.90	0.91	0.93
1.35	0.78	0.81	0.83	0.87	0.88	0.89
1.4	0.75	0.78	0.80	0.83	0.84	0.86
1.425	0.74	0.77	0.78	0.82	0.83	0.85
1.5	0.70	0.72	0.74	0.77	0.79	0.80
1.575	0.67	0.70	0.72	0.75	0.76	0.77

Calculating Power Dissipation

Quiescent Supply Current

Table 2-7 • Quiescent Supply Current (I_{DD}) Characteristics, ProASIC3L Flash*Freeze Mode*

	Core Voltage	A3P250L	A3P600L	A3P1000L	A3PE3000L	Units
Typical (25°C)	1.2 V	0.33	0.55	0.88	2.75	mA
	1.5 V					mA

* I_{DD} includes V_{CC} , V_{PUMP} , V_{CCI} , V_{JTAG} , and V_{CCPLL} currents. Values do not include I/O static contribution (P_{DC6} and P_{DC7}).

Table 2-8 • Quiescent Supply Current (I_{DD}) Characteristics, ProASIC3L Sleep Mode ($V_{CC} = 0\text{ V}$)*

	Core Voltage	A3P250L	A3P600L	A3P1000L	A3PE3000L	Units
$V_{CCI} / V_{JTAG} = 1.2\text{ V}$ (per bank) Typical (25°C)	1.2 V / 1.5 V	1.7	1.7	1.7	1.7	μA
$V_{CCI} / V_{JTAG} = 1.5\text{ V}$ (per bank) Typical (25°C)	1.2 V / 1.5 V	1.8	1.8	1.8	1.8	μA
$V_{CCI} / V_{JTAG} = 1.8\text{ V}$ (per bank) Typical (25°C)	1.2 V / 1.5 V	1.9	1.9	1.9	1.9	μA
$V_{CCI} / V_{JTAG} = 2.5\text{ V}$ (per bank) Typical (25°C)	1.2 V / 1.5 V	2.2	2.2	2.2	2.2	μA
$V_{CCI} / V_{JTAG} = 3.3\text{ V}$ (per bank) Typical (25°C)	1.2 V / 1.5 V	2.5	2.5	2.5	2.5	μA

* I_{DD} includes V_{CC} , V_{PUMP} , and V_{CCPLL} currents. Values do not include I/O static contribution (P_{DC6} and P_{DC7}).

Table 2-9 • Quiescent Supply Current (I_{DD}) Characteristics, Shutdown Mode (V_{CC} , $V_{CCI} = 0\text{ V}$)

	Core Voltage	A3PE3000L	Units
Typical (25°C)	1.2 V / 1.5 V	0	μA

* I_{DD} includes V_{CC} , V_{PUMP} , V_{CCI} , V_{JTAG} , and V_{CCPLL} currents. Values do not include I/O static contribution (P_{DC6} and P_{DC7}).

Table 2-10 • Quiescent Supply Current (I_{DD}), No ProASIC3L Flash*Freeze Mode¹

	Core Voltage	A3P250L	A3P600L	A3P1000L	A3PE3000L	Units
I_{CCA} Current²						
Typical (25°C)	1.2 V	0.33	0.55	0.88	2.75	mA
	1.5 V					mA
I_{CCI} or I_{JTAG} Current^{3, 4}						
$V_{CCI} / V_{JTAG} = 1.2$ V (per bank) Typical (25°C)	1.2 V / 1.5 V	1.7	1.7	1.7	1.7	μA
$V_{CCI} / V_{JTAG} = 1.5$ V (per bank) Typical (25°C)	1.2 V / 1.5 V	1.8	1.8	1.8	1.8	μA
$V_{CCI} / V_{JTAG} = 1.8$ V (per bank) Typical (25°C)	1.2 V / 1.5 V	1.9	1.9	1.9	1.9	μA
$V_{CCI} / V_{JTAG} = 2.5$ V (per bank) Typical (25°C)	1.2 V / 1.5 V	2.2	2.2	2.2	2.2	μA
$V_{CCI} / V_{JTAG} = 3.3$ V (per bank) Typical (25°C)	1.2 V / 1.5 V	2.5	2.5	2.5	2.5	μA

Notes:

1. To calculate total device I_{DD} , multiply the number of banks used by I_{CCI} and add I_{CCA} contribution.
2. Includes V_{CC} , V_{CCPLL} , and V_{PUMP} currents.
3. Per V_{CCI} or V_{JTAG} bank.
4. Values do not include I/O static contribution (P_{DC6} and P_{DC7}).

Power per I/O Pin

Table 2-11 • Summary of I/O Input Buffer Power (per pin) – Default I/O Software Settings
Applicable to Pro I/O Banks

	V_{CCI} (V)	Static Power P_{DC6} (mW) ¹	Dynamic Power P_{AC9} (μW/MHz) ²
Single-Ended			
3.3 V LVTTTL/LVCMOS	3.3	–	16.34
3.3 V LVTTTL/LVCMOS – Schmitt trigger	3.3	–	24.49
2.5 V LVCMOS	2.5	–	4.71
2.5 V LVCMOS – Schmitt trigger	2.5	–	6.13
1.8 V LVCMOS	1.8	–	1.66
1.8 V LVCMOS – Schmitt trigger	1.8	–	1.78
1.5 V LVCMOS (JESD8-11)	1.5	–	1.01
1.5 V LVCMOS (JESD8-11) – Schmitt trigger	1.5	–	0.97
1.2 V LVCMOS	1.2	–	0.60
1.2 V LVCMOS – Schmitt trigger	1.2	–	0.53
3.3 V PCI	3.3	–	17.76
3.3 V PCI – Schmitt trigger	3.3	–	19.10
3.3 V PCI-X	3.3	–	17.76
3.3 V PCI-X – Schmitt trigger	3.3	–	19.10
Voltage-Referenced			
3.3 V GTL	3.3	2.90	7.07
2.5 V GTL	2.5	2.13	3.62
3.3 V GTL+	3.3	2.81	2.97
2.5 V GTL+	2.5	2.57	2.55
HSTL (I)	1.5	0.17	0.85
HSTL (II)	1.5	0.17	0.85
SSTL2 (I)	2.5	1.38	3.30
SSTL2 (II)	2.5	1.38	3.30
SSTL3 (I)	3.3	3.21	8.08
SSTL3 (II)	3.3	3.21	8.08
Differential			
LVDS	2.5	2.26	0.95
LVPECL	3.3	5.71	1.62

Notes:

1. P_{DC6} is the static power (where applicable) measured on V_{CCI} .
2. P_{AC9} is the total dynamic power measured on V_{CCI} .

Table 2-12 • Summary of I/O Input Buffer Power (per pin) – Default I/O Software Settings¹
Applicable to Advanced I/O Banks

	V _{CCI} (V)	Static Power P _{DC6} (mW) ²	Dynamic Power P _{AC10} (μW/MHz) ³
Single-Ended			
3.3 V LVTTTL / 3.3 V LVCMOS	3.3	–	16.22
2.5 V LVCMOS	2.5	–	4.65
1.8 V LVCMOS	1.8	–	1.65
1.5 V LVCMOS (JESD8-11)	1.5	–	0.98
1.2 V LVCMOS	1.2	–	0.61
3.3 V PCI	3.3	–	17.64
3.3 V PCI-X	3.3	–	17.64
Differential			
LVDS	2.5	2.26	0.95
LVPECL	3.3	5.72	1.63

Notes:

1. Dynamic power consumption is given for standard load and software default drive strength and output slew.
2. P_{DC6} is the static power (where applicable) measured on V_{CCI}.
3. P_{AC10} is the total dynamic power measured on V_{CCI}.

Table 2-13 • Summary of I/O Input Buffer Power (per pin) – Default I/O Software Settings
Applicable to Standard Plus I/O Banks

	V _{CCI} (V)	Static Power P _{DC6} (mW) ¹	Dynamic Power P _{AC9} (μW/MHz) ²
Single-Ended			
3.3 V LVTTTL / 3.3 V LVCMOS	3.3	–	16.23
2.5 V LVCMOS	2.5	–	4.66
1.8 V LVCMOS	1.8	–	1.64
1.5 V LVCMOS (JESD8-11)	1.5	–	0.99
1.2 V LVCMOS	1.2	–	0.58
3.3 V PCI	3.3	–	17.64
3.3 V PCI-X	3.3	–	17.64

Notes:

1. P_{DC6} is the static power (where applicable) measured on V_{CCI}.
2. P_{AC9} is the total dynamic power measured on V_{CCI}.

Table 2-14 • Summary of I/O Output Buffer Power (per pin) – Default I/O Software Settings ¹
Applicable to Pro I/Os

	C_{LOAD} (pF)	V_{CCI} (V)	Static Power P_{DC7} (mW) ²	Dynamic Power P_{AC10} (μW/MHz) ³
Single-Ended				
3.3 V LVTTTL/LVCMOS	5	3.3	–	148.00
2.5 V LVCMOS	5	2.5	–	83.23
1.8 V LVCMOS	5	1.8	–	54.58
1.5 V LVCMOS (JESD8-11)	5	1.5	–	37.05
1.2 V LVCMOS	5	1.2	–	17.94
3.3 V PCI	10	3.3	–	204.61
3.3 V PCI-X	10	3.3	–	204.61
Voltage-Referenced				
3.3 V GTL	10	3.3	–	24.08
2.5 V GTL	10	2.5	–	13.52
3.3 V GTL+	10	3.3	–	24.10
2.5 V GTL+	10	2.5	–	13.54
HSTL (I)	20	1.5	7.08	26.22
HSTL (II)	20	1.5	13.88	27.22
SSTL2 (I)	30	2.5	16.69	105.56
SSTL2 (II)	30	2.5	25.91	116.60
SSTL3 (I)	30	3.3	26.02	114.87
SSTL3 (II)	30	3.3	42.21	131.76
Differential				
LVDS	–	2.5	7.70	89.62
LVPECL	–	3.3	19.42	168.02

Notes:

1. Dynamic power consumption is given for standard load and software default drive strength and output slew.
2. P_{DC7} is the static power (where applicable) measured on V_{CCI} .
3. P_{AC10} is the total dynamic power measured on V_{CCI} .

Table 2-15 • Summary of I/O Output Buffer Power (per pin) – Default I/O Software Settings¹
Applicable to Advanced I/O Banks

	C_{LOAD} (pF)	V_{CCI} (V)	Static Power P_{DC7} (mW) ²	Dynamic Power P_{AC10} (μW/MHz) ³
Single-Ended				
3.3 V LVTTTL / 3.3 V LVCMOS	5	3.3	–	141.97
2.5 V LVCMOS	5	2.5	–	79.98
1.8 V LVCMOS	5	1.8	–	52.26
1.5 V LVCMOS (JESD8-11)	5	1.5	–	35.62
1.2 V LVCMOS	5	1.2	–	21.29
3.3 V PCI	10	3.3	–	201.02
3.3 V PCI-X	10	3.3	–	201.02
Differential				
LVDS	–	2.5	7.74	89.71
LVPECL	–	3.3	19.54	167.54

Notes:

1. Dynamic power consumption is given for standard load and software default drive strength and output slew.
2. P_{DC7} is the static power (where applicable) measured on V_{CCI} .
3. P_{AC10} is the total dynamic power measured on V_{CCI} .

Table 2-16 • Summary of I/O Output Buffer Power (per pin) – Default I/O Software Settings¹
Applicable to Standard Plus I/O Banks

	C_{LOAD} (pF)	V_{CCI} (V)	Static Power P_{DC7} (mW) ²	Dynamic Power P_{AC10} (μW/MHz) ³
Single-Ended				
3.3 V LVTTTL / 3.3 V LVCMOS	5	3.3	–	125.97
2.5 V LVCMOS	5	2.5	–	70.82
1.8 V LVCMOS	5	1.8	–	36.39
1.5 V LVCMOS (JESD8-11)	5	1.5	–	25.34
1.2 V LVCMOS	5	1.2	–	16.24
3.3 V PCI	10	3.3	–	184.92
3.3 V PCI-X	10	3.3	–	184.92

Notes:

1. Dynamic power consumption is given for standard load and software default drive strength and output slew.
2. P_{DC7} is the static power (where applicable) measured on V_{CCI} .
3. P_{AC10} is the total dynamic power measured on V_{CCI} .

Power Consumption of Various Internal Resources

Table 2-17 • Different Components Contributing to Dynamic Power Consumption in ProASIC3L Devices at 1.2 V V_{CC}

Parameter	Definition	Device Specific Dynamic Power (μW/MHz)			
		A3PE3000L	A3P1000L	A3P600L	A3P250L
P _{AC1}	Clock contribution of a Global Rib	12.61	9.28	8.19	7.07
P _{AC2}	Clock contribution of a Global Spine	2.66	1.59	1.19	1.01
P _{AC3}	Clock contribution of a VersaTile row	0.56	0.52		
P _{AC4}	Clock contribution of a VersaTile used as a sequential module	0.07			
P _{AC5}	First contribution of a VersaTile used as a sequential module	0.05			
P _{AC6}	Second contribution of a VersaTile used as a sequential module	0.19			
P _{AC7}	Contribution of a VersaTile used as a combinatorial Module	0.11			
P _{AC8}	Average contribution of a routing net	0.45			
P _{AC9}	Contribution of an I/O input pin (standard-dependent)	See Table 2-11 on page 2-9. through Table 2-13 on page 2-10.			
P _{AC10}	Contribution of an I/O output pin (standard-dependent)	See Table 2-14 on page 2-11 through Table 2-16 on page 2-12.			
P _{AC11}	Average contribution of a RAM block during a read operation	25.00			
P _{AC12}	Average contribution of a RAM block during a write operation	30.00			
P _{AC13}	Dynamic contribution for PLL	1.74			

* For a different output load, drive strength, or slew rate, Actel recommends using the Actel power spreadsheet calculator or SmartPower tool in Libero IDE.

Table 2-18 • Different Components Contributing to Dynamic Power Consumption in ProASIC3L Devices at 1.5 V V_{CC}

Parameter	Definition	Device Specific Dynamic Power (μW/MHz)			
		A3PE3000L	A3P1000L	A3P600L	A3P250L
P _{AC1}	Clock contribution of a Global Rib	19.7	14.50	12.80	11.00
P _{AC2}	Clock contribution of a Global Spine	4.16	2.48	1.85	1.58
P _{AC3}	Clock contribution of a VersaTile row	0.88	0.81		
P _{AC4}	Clock contribution of a VersaTile used as a sequential module	0.12			
P _{AC5}	First contribution of a VersaTile used as a sequential module	0.07			
P _{AC6}	Second contribution of a VersaTile used as a sequential module	0.29			
P _{AC7}	Contribution of a VersaTile used as a combinatorial Module	0.29			
P _{AC8}	Average contribution of a routing net	0.70			
P _{AC9}	Contribution of an I/O input pin (standard-dependent)	See Table 2-11 on page 2-9. through Table 2-13 on page 2-10.			
P _{AC10}	Contribution of an I/O output pin (standard-dependent)	See Table 2-14 on page 2-11 through Table 2-16 on page 2-12.			
P _{AC11}	Average contribution of a RAM block during a read operation	25.00			
P _{AC12}	Average contribution of a RAM block during a write operation	30.00			
P _{AC13}	Dynamic contribution for PLL	2.60			

* For a different output load, drive strength, or slew rate, Actel recommends using the Actel power spreadsheet calculator or SmartPower tool in Libero IDE.

Table 2-19 • Different Components Contributing to the Static Power Consumption in ProASIC3L Devices

Parameter	Definition	Device Specific Dynamic Power (μW)			
		A3PE3000L	A3P1000L	A3P600L	A3P250L
P _{DC1}	Array static power in Active mode	See Table 2-10 on page 2-8.			
P _{DC2}	Array static power in Static (Idle) mode	See Table 2-8 on page 2-7.			
P _{DC3}	Array static power in Flash*Freeze mode	See Table 2-7 on page 2-7.			
P _{DC4}	Static PLL contribution at 1.2 V core (operating mode only)	1.42 mW			
	Static PLL contribution at 1.5 V core (operating mode only)	2.55 mW			
P _{DC5}	Bank quiescent power (V _{CCI} -dependent)	See Table 2-7 on page 2-7, Table 2-8 on page 2-7, Table 2-10 on page 2-8.			
P _{DC6}	I/O input pin static power (standard-dependent)	See Table 2-11 on page 2-9 through Table 2-13 on page 2-10.			
P _{DC7}	I/O output pin static power (standard-dependent)	See Table 2-14 on page 2-11 through Table 2-16 on page 2-12.			

* For a different output load, drive strength, or slew rate, Actel recommends using the Actel power spreadsheet calculator or SmartPower tool in Libero IDE.

Power Calculation Methodology

This section describes a simplified method to estimate power consumption of an application. For more accurate and detailed power estimations, use the SmartPower tool in Actel Libero IDE software.

The power calculation methodology described below uses the following variables:

- The number of PLLs as well as the number and the frequency of each output clock generated
- The number of combinatorial and sequential cells used in the design
- The internal clock frequencies
- The number and the standard of I/O pins used in the design
- The number of RAM blocks used in the design
- Toggle rates of I/O pins as well as VersaTiles—guidelines are provided in [Table 2-20 on page 2-17](#).
- Enable rates of output buffers—guidelines are provided for typical applications in [Table 2-21 on page 2-17](#).
- Read rate and write rate to the memory—guidelines are provided for typical applications in [Table 2-21 on page 2-17](#). The calculation should be repeated for each clock domain defined in the design.

Methodology

Total Power Consumption— P_{TOTAL}

$$P_{TOTAL} = P_{STAT} + P_{DYN}$$

P_{STAT} is the total static power consumption.

P_{DYN} is the total dynamic power consumption.

Total Static Power Consumption— P_{STAT}

$$P_{STAT} = (P_{DC1} \text{ or } P_{DC2} \text{ or } P_{DC3}) + N_{BANKS} * P_{DC5} + N_{INPUTS} * P_{DC6} + N_{OUTPUTS} * P_{DC7}$$

N_{INPUTS} is the number of I/O input buffers used in the design.

$N_{OUTPUTS}$ is the number of I/O output buffers used in the design.

N_{BANKS} is the number of I/O banks powered in the design.

Total Dynamic Power Consumption— P_{DYN}

$$P_{DYN} = P_{CLOCK} + P_{S-CELL} + P_{C-CELL} + P_{NET} + P_{INPUTS} + P_{OUTPUTS} + P_{MEMORY} + P_{PLL}$$

Global Clock Contribution— P_{CLOCK}

$$P_{CLOCK} = (P_{AC1} + N_{SPINE} * P_{AC2} + N_{ROW} * P_{AC3} + N_{S-CELL} * P_{AC4}) * F_{CLK}$$

N_{SPINE} is the number of global spines used in the user design—guidelines are provided in [Table 2-20 on page 2-17](#).

N_{ROW} is the number of VersaTile rows used in the design—guidelines are provided in [Table 2-20 on page 2-17](#).

F_{CLK} is the global clock signal frequency.

N_{S-CELL} is the number of VersaTiles used as sequential modules in the design.

P_{AC1} , P_{AC2} , P_{AC3} , and P_{AC4} are device-dependent.

Sequential Cells Contribution— P_{S-CELL}

$$P_{S-CELL} = N_{S-CELL} * (P_{AC5} + \alpha_1 / 2 * P_{AC6}) * F_{CLK}$$

N_{S-CELL} is the number of VersaTiles used as sequential modules in the design. When a multi-tile sequential cell is used, it should be accounted for as 1.

α_1 is the toggle rate of VersaTile outputs—guidelines are provided in [Table 2-20 on page 2-17](#).

F_{CLK} is the global clock signal frequency.

Combinatorial Cells Contribution— P_{C-CELL}

$$P_{C-CELL} = N_{C-CELL} * \alpha_1 / 2 * P_{AC7} * F_{CLK}$$

N_{C-CELL} is the number of VersaTiles used as combinatorial modules in the design.

α_1 is the toggle rate of VersaTile outputs—guidelines are provided in [Table 2-20 on page 2-17](#).

F_{CLK} is the global clock signal frequency.

Routing Net Contribution— P_{NET}

$$P_{NET} = (N_{S-CELL} + N_{C-CELL}) * \alpha_1 / 2 * P_{AC8} * F_{CLK}$$

N_{S-CELL} is the number of VersaTiles used as sequential modules in the design.

N_{C-CELL} is the number of VersaTiles used as combinatorial modules in the design.

α_1 is the toggle rate of VersaTile outputs—guidelines are provided in [Table 2-20 on page 2-17](#).

F_{CLK} is the global clock signal frequency.

I/O Input Buffer Contribution— P_{INPUTS}

$$P_{INPUTS} = N_{INPUTS} * \alpha_2 / 2 * P_{AC9} * F_{CLK}$$

N_{INPUTS} is the number of I/O input buffers used in the design.

α_2 is the I/O buffer toggle rate—guidelines are provided in [Table 2-20 on page 2-17](#).

F_{CLK} is the global clock signal frequency.

I/O Output Buffer Contribution— $P_{OUTPUTS}$

$$P_{OUTPUTS} = N_{OUTPUTS} * \alpha_2 / 2 * \beta_1 * P_{AC10} * F_{CLK}$$

$N_{OUTPUTS}$ is the number of I/O output buffers used in the design.

α_2 is the I/O buffer toggle rate—guidelines are provided in [Table 2-20 on page 2-17](#).

β_1 is the I/O buffer enable rate—guidelines are provided in [Table 2-21 on page 2-17](#).

F_{CLK} is the global clock signal frequency.

RAM Contribution— P_{MEMORY}

$$P_{MEMORY} = P_{AC11} * N_{BLOCKS} * F_{READ-CLOCK} * \beta_2 + P_{AC12} * N_{BLOCK} * F_{WRITE-CLOCK} * \beta_3$$

N_{BLOCKS} is the number of RAM blocks used in the design.

$F_{READ-CLOCK}$ is the memory read clock frequency.

β_2 is the RAM enable rate for read operations.

$F_{WRITE-CLOCK}$ is the memory write clock frequency.

β_3 is the RAM enable rate for write operations—guidelines are provided in [Table 2-21 on page 2-17](#).

PLL Contribution— P_{PLL}

$$P_{PLL} = P_{DC4} + P_{AC13} * F_{CLKOUT}$$

F_{CLKOUT} is the output clock frequency.¹

1. If a PLL is used to generate more than one output clock, include each output clock in the formula by adding its corresponding contribution ($P_{AC13} * F_{CLKOUT}$ product) to the total PLL contribution.

Guidelines

Toggle Rate Definition

A toggle rate defines the frequency of a net or logic element relative to a clock. It is a percentage. If the toggle rate of a net is 100%, this means that this net switches at half the clock frequency. Below are some examples:

- The average toggle rate of a shift register is 100% because all flip-flop outputs toggle at half of the clock frequency.
- The average toggle rate of an 8-bit counter is 25%:
 - Bit 0 (LSB) = 100%
 - Bit 1 = 50%
 - Bit 2 = 25%
 - ...
 - Bit 7 (MSB) = 0.78125%
 - Average toggle rate = $(100\% + 50\% + 25\% + 12.5\% + \dots + 0.78125\%) / 8$

Enable Rate Definition

Output enable rate is the average percentage of time during which tristate outputs are enabled. When nontristate output buffers are used, the enable rate should be 100%.

Table 2-20 • Toggle Rate Guidelines Recommended for Power Calculation

Component	Definition	Guideline
α_1	Toggle rate of VersaTile outputs	10%
α_2	I/O buffer toggle rate	10%

Table 2-21 • Enable Rate Guidelines Recommended for Power Calculation

Component	Definition	Guideline
β_1	I/O output buffer enable rate	100%
β_2	RAM enable rate for read operations	12.5%
β_3	RAM enable rate for write operations	12.5%

Timing Model

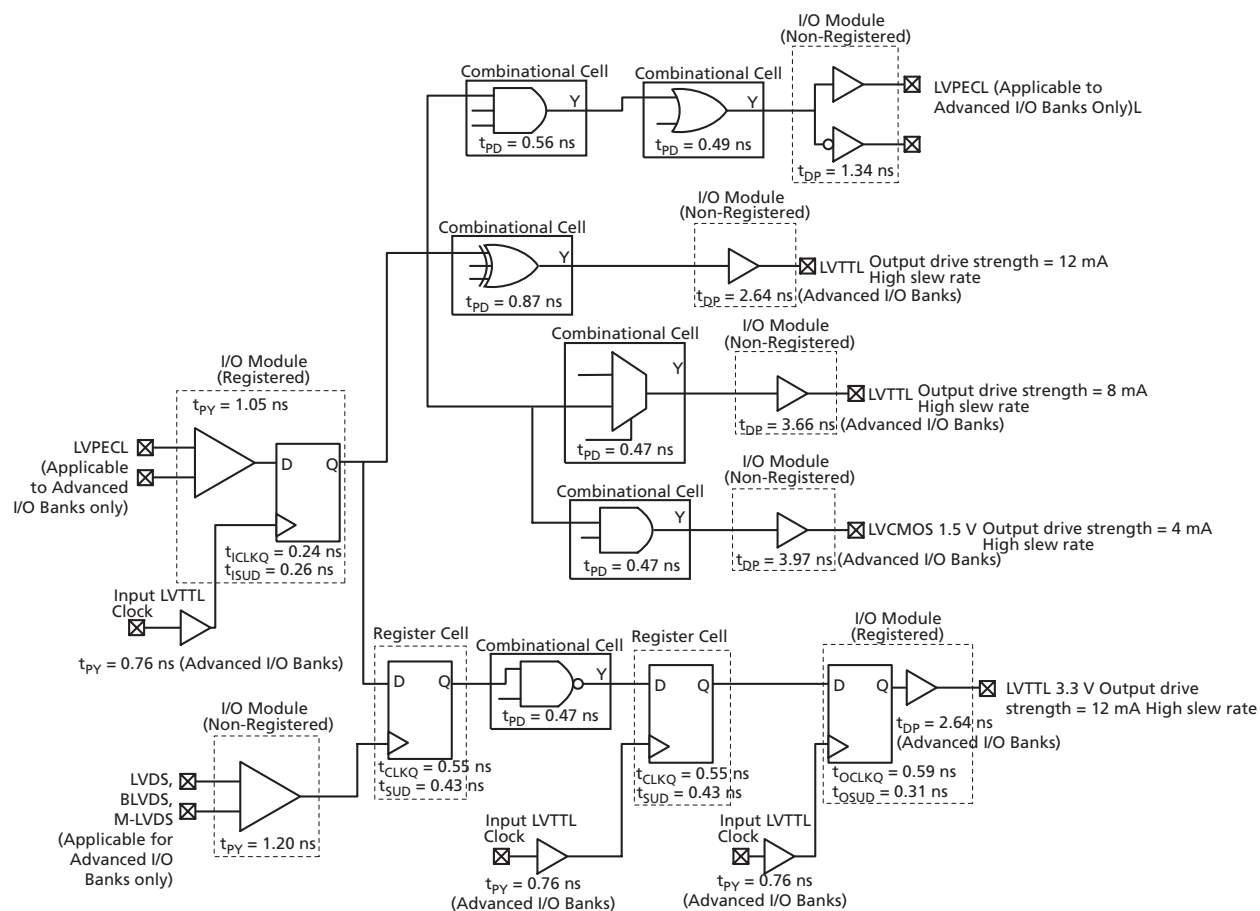


Figure 2-3 • Timing Model
Operating Conditions: –1 Speed, Commercial Temperature Range (T_J = 70°C), Worst-Case
V_{CC} = 1.14 V

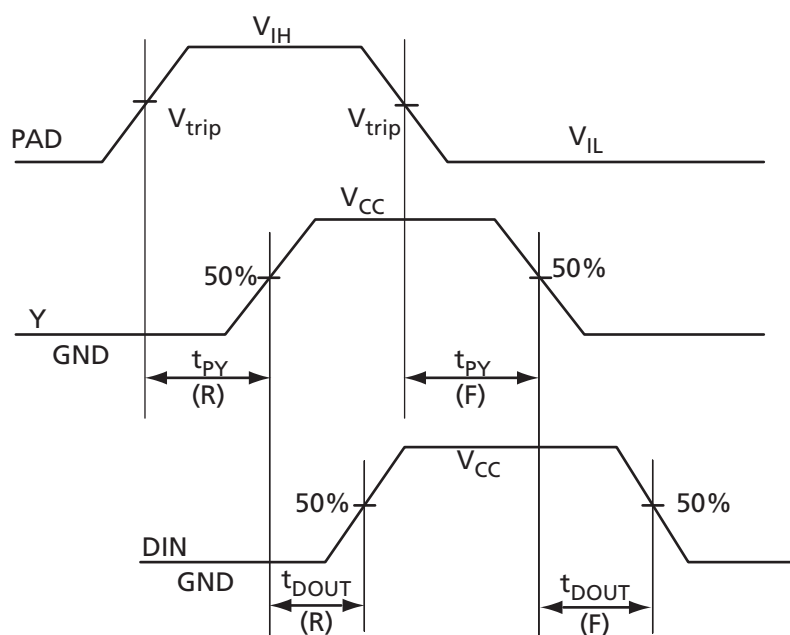
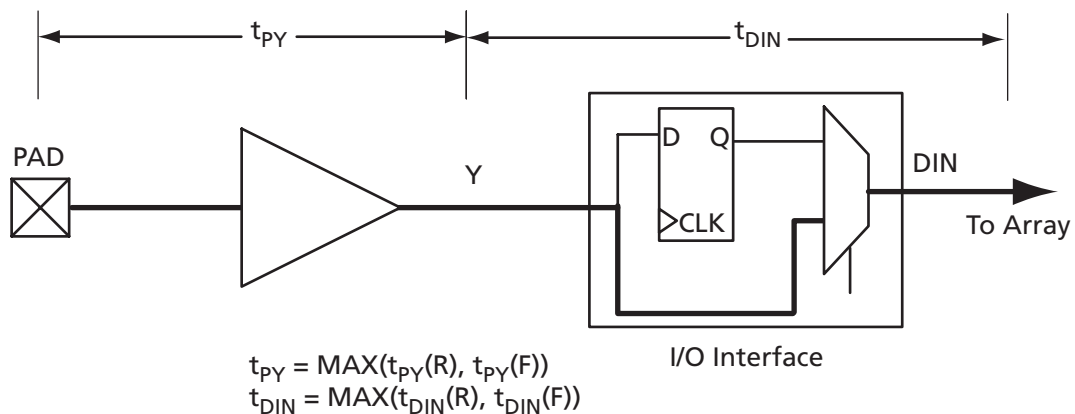


Figure 2-4 • Input Buffer Timing Model and Delays (example)

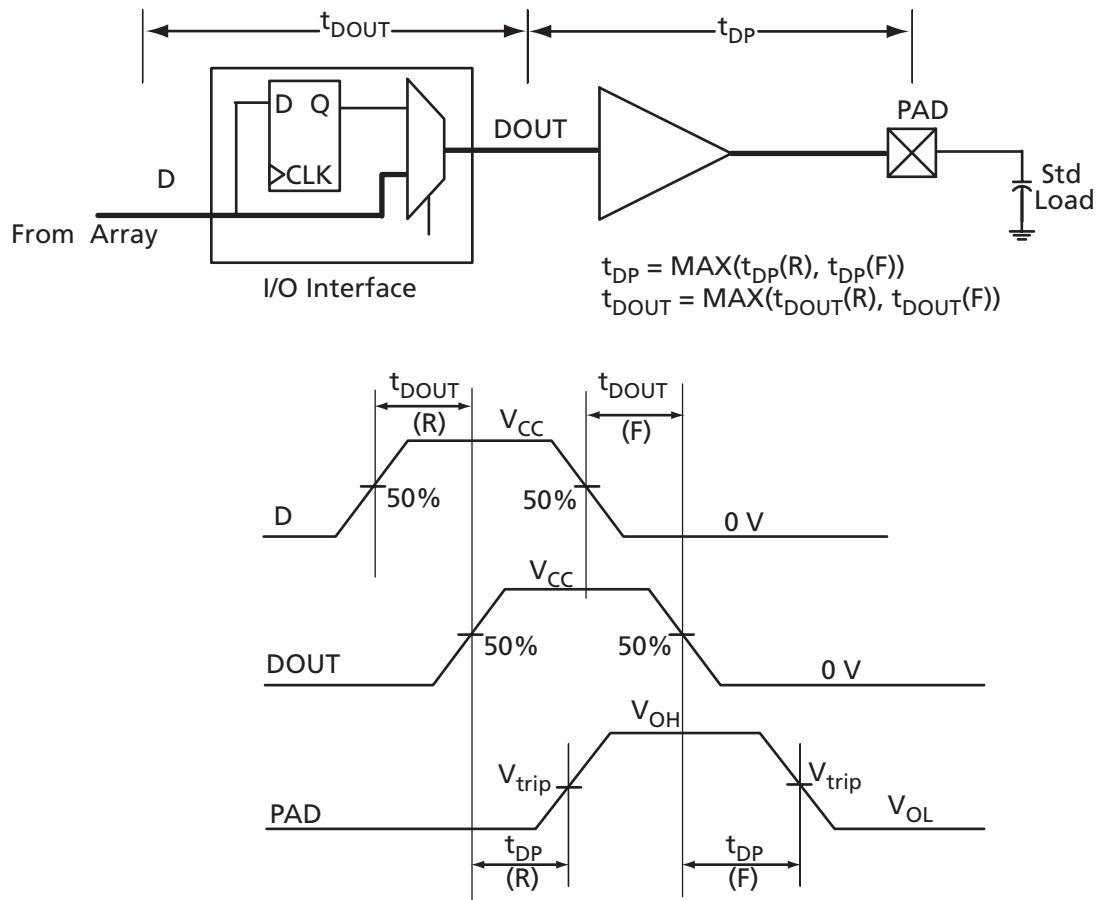


Figure 2-5 • Output Buffer Model and Delays (example)

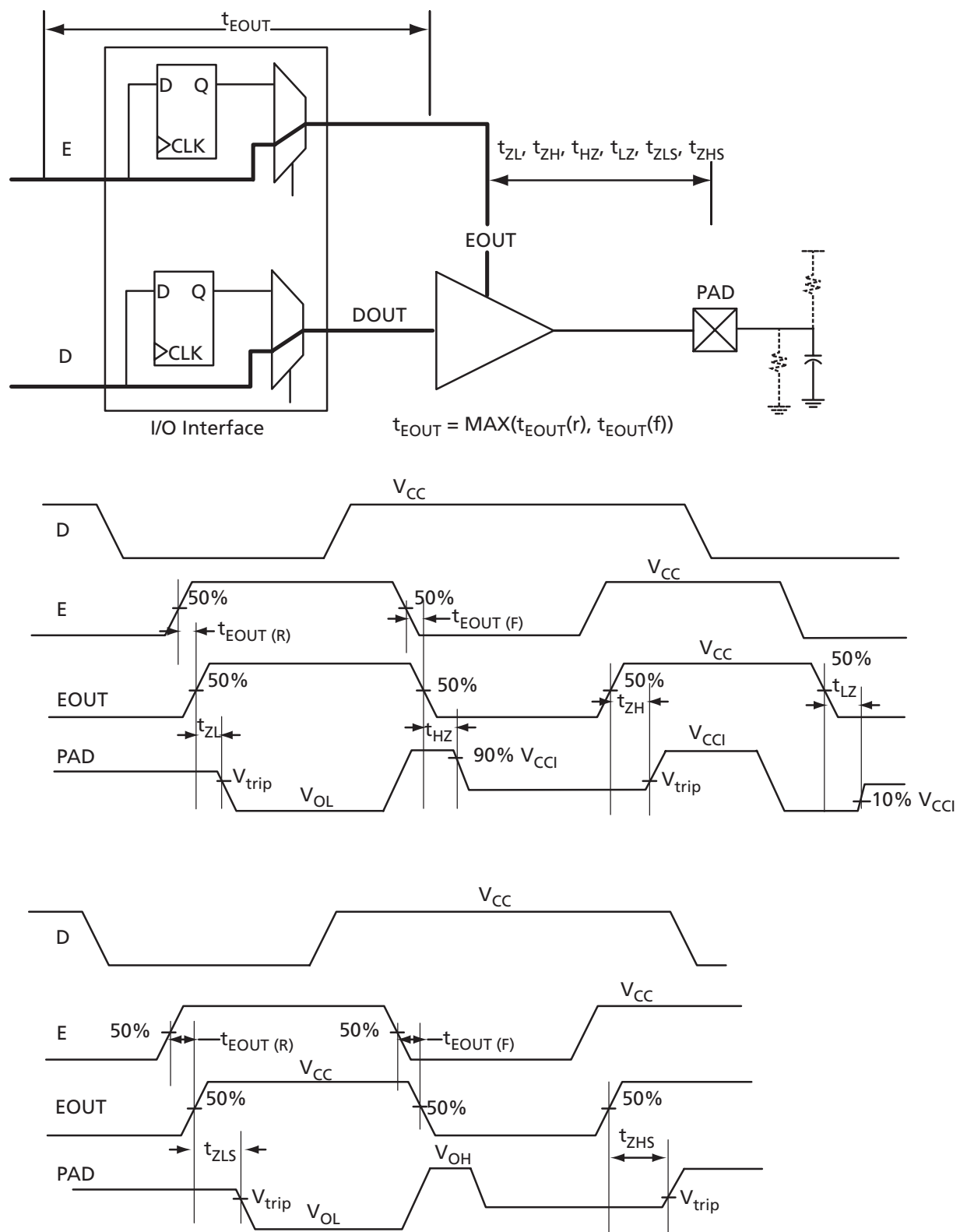


Figure 2-6 • Tristate Output Buffer Timing Model and Delays (example)

Overview of I/O Performance

Summary of I/O DC Input and Output Levels – Default I/O Software Settings

Table 2-22 • Summary of Maximum and Minimum DC Input and Output Levels Applicable to Commercial and Industrial Conditions—Software Default Settings
Applicable to Pro I/O

I/O Standard	Drive Strength	Slew Rate	V_{IL}		V_{IH}		V_{OL}	V_{OH}	I_{OL}^1	I_{OH}^1
			Min, V	Max, V	Min, V	Max, V	Max, V	Min, V	mA	mA
3.3 V LVTTTL / 3.3 V LVCMOS	12 mA	High	−0.3	0.8	2	3.6	0.4	2.4	12	12
3.3 V LVCMOS Wide Range	Any ²	High	−0.3	0.8	2	3.6	0.2	$V_{CCI} - 0.2$	0.1	0.1
2.5 V LVCMOS	12 mA	High	−0.3	0.7	1.7	2.7	0.7	1.7	12	12
1.8 V LVCMOS	12 mA	High	−0.3	$0.35 * V_{CCI}$	$0.65 * V_{CCI}$	1.9	0.45	$V_{CCI} - 0.45$	12	12
1.5 V LVCMOS	12 mA	High	−0.3	$0.35 * V_{CCI}$	$0.65 * V_{CCI}$	1.575	$0.25 * V_{CCI}$	$0.75 * V_{CCI}$	12	12
1.2 V LVCMOS	2 mA	High	−0.3	$0.35 * V_{CCI}$	$0.65 * V_{CCI}$	1.26	$0.25 * V_{CCI}$	$0.75 * V_{CCI}$	2	2
3.3 V PCI	Per PCI Specification									
3.3 V PCI-X	Per PCI-X Specification									
3.3 V GTL	25 mA ³	High	−0.3	$V_{REF} - 0.05$	$V_{REF} + 0.05$	3.6	0.4	–	25	25
2.5 V GTL	25 mA ³	High	−0.3	$V_{REF} - 0.05$	$V_{REF} + 0.05$	2.7	0.4	–	25	25
3.3 V GTL+	35 mA	High	−0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	3.6	0.6	–	51	51
2.5 V GTL+	33 mA	High	−0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	2.7	0.6	–	40	40
HSTL (I)	8 mA	High	−0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	1.575	0.4	$V_{CCI} - 0.4$	8	8
HSTL (II)	15 mA ³	High	−0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	1.575	0.4	$V_{CCI} - 0.4$	15	15
SSTL2 (I)	15 mA	High	−0.3	$V_{REF} - 0.2$	$V_{REF} + 0.2$	2.7	0.54	$V_{CCI} - 0.62$	15	15
SSTL2 (II)	18 mA	High	−0.3	$V_{REF} - 0.2$	$V_{REF} + 0.2$	2.7	0.35	$V_{CCI} - 0.43$	18	18
SSTL3 (I)	14 mA	High	−0.3	$V_{REF} - 0.2$	$V_{REF} + 0.2$	3.6	0.7	$V_{CCI} - 1.1$	14	14
SSTL3 (II)	21 mA	High	−0.3	$V_{REF} - 0.2$	$V_{REF} + 0.2$	3.6	0.5	$V_{CCI} - 0.9$	21	21

Notes:

1. Currents are measured at 85°C junction temperature.
2. All LVCMOS 3.3 V software macros support LVCMOS 3.3 V wide range as specified in the JEDEC8a specification.
3. Output drive strength is below JEDEC specification.
4. Output slew rate can be extracted using the IBIS Models.

Table 2-23 • Summary of Maximum and Minimum DC Input and Output Levels Applicable to Commercial and Industrial Conditions—Software Default Settings
Applicable to Advanced I/O Banks

I/O Standard	Drive Strength	Slew Rate	V_{IL}		V_{IH}		V_{OL}	V_{OH}	I_{OL}^1	I_{OH}^1
			Min, V	Max, V	Min, V	Max, V	Max, V	Min, V	mA	mA
3.3 V LVTTTL / 3.3 V LVCMOS	12 mA	High	−0.3	0.8	2	3.6	0.4	2.4	12	12
3.3 V LVCMOS Wide Range	Any ³	High	−0.3	0.8	2	3.6	0.2	$V_{CC1} - 0.2$	0.1	0.1
2.5 V LVCMOS	12 mA	High	−0.3	0.7	1.7	2.7	0.7	1.7	12	12
1.8 V LVCMOS	12 mA	High	−0.3	$0.35 * V_{CC1}$	$0.65 * V_{CC1}$	1.9	0.45	$V_{CC1} - 0.45$	12	12
1.5 V LVCMOS	12 mA	High	−0.3	$0.35 * V_{CC1}$	$0.65 * V_{CC1}$	1.575	$0.25 * V_{CC1}$	$0.75 * V_{CC1}$	12	12
1.2 V LVCMOS	2 mA	High	−0.3	$0.35 * V_{CC1}$	$0.65 * V_{CC1}$	1.26	$0.25 * V_{CC1}$	$0.75 * V_{CC1}$	2	2
3.3 V PCI	Per PCI specifications									
3.3 V PCI-X	Per PCI-X specifications									

Notes:

1. Currents are measured at 85°C junction temperature.
2. Output slew rate can be extracted using the IBIS Models
3. All LVCMOS 3.3 V software macros support LVCMOS 3.3 V wide range as specified in the JDEC8a specification.

Table 2-24 • Summary of Maximum and Minimum DC Input and Output Levels Applicable to Commercial and Industrial Conditions—Software Default Settings
Applicable to Standard Plus I/O Banks

I/O Standard	Drive Strength	Slew Rate	V_{IL}		V_{IH}		V_{OL}	V_{OH}	I_{OL}^1	I_{OH}^1
			Min, V	Max, V	Min, V	Max, V	Max, V	Min, V	mA	mA
3.3 V LVTTTL / 3.3 V LVCMOS	12 mA	High	−0.3	0.8	2	3.6	0.4	2.4	12	12
3.3 V LVCMOS Wide Range	Any ³	High	−0.3	0.8	2	3.6	0.2	$V_{CC1} - 0.2$	0.1	0.1
2.5 V LVCMOS	12 mA	High	−0.3	0.7	1.7	2.7	0.7	1.7	12	12
1.8 V LVCMOS	8 mA	High	−0.3	$0.35 * V_{CC1}$	$0.65 * V_{CC1}$	1.9	0.45	$V_{CC1} - 0.45$	8	8
1.5 V LVCMOS	4 mA	High	−0.3	$0.35 * V_{CC1}$	$0.65 * V_{CC1}$	1.575	$0.25 * V_{CC1}$	$0.75 * V_{CC1}$	4	4
1.2 V LVCMOS	2 mA	High	−0.3	$0.35 * V_{CC1}$	$0.65 * V_{CC1}$	1.26	$0.25 * V_{CC1}$	$0.75 * V_{CC1}$	2	2
3.3 V PCI	Per PCI specifications									
3.3 V PCI-X	Per PCI-X specifications									

Notes:

1. Currents are measured at 85°C junction temperature.
2. Output slew rate can be extracted using the IBIS Models.
3. All LVCMOS 3.3 V software macros support LVCMOS 3.3 V wide range as specified in the JDEC8a specification.

**Table 2-25 • Summary of Maximum and Minimum DC Input Levels
Applicable to Commercial and Industrial Conditions**

DC I/O Standard	Commercial ¹		Industrial ²	
	I _{IL}	I _{IH}	I _{IL}	I _{IH}
	μA	μA	μA	μA
3.3 V LVTTTL / 3.3 V LVCMOS	10	10	15	15
3.3 V LVCMOS Wide Range	10	10	15	15
2.5 V LVCMOS	10	10	15	15
1.8 V LVCMOS	10	10	15	15
1.5 V LVCMOS	10	10	15	15
1.2 V LVCMOS	10	10	15	15
3.3 V PCI	10	10	15	15
3.3 V PCI-X	10	10	15	15
3.3 V GTL	10	10	15	15
2.5 V GTL	10	10	15	15
3.3 V GTL+	10	10	15	15
2.5 V GTL+	10	10	15	15
HSTL (I)	10	10	15	15
HSTL (II)	10	10	15	15
SSTL2 (I)	10	10	15	15
SSTL2 (II)	10	10	15	15
SSTL3 (I)	10	10	15	15
SSTL3 (II)	10	10	15	15

Notes:

1. Commercial range ($0^{\circ}\text{C} < T_A < 70^{\circ}\text{C}$)
2. Industrial range ($-40^{\circ}\text{C} < T_A < 85^{\circ}\text{C}$)

Summary of I/O Timing Characteristics – Default I/O Software Settings

Table 2-26 • Summary of AC Memory Points

Standard	Input Reference Voltage (V_{REF_TYP})	Board Termination Voltage (V_{TT_REF})	Measuring Trip Point (V_{trip})
3.3 V LVTTTL / 3.3 V LVCMOS	–	–	1.4 V
3.3 V LVCMOS Wide Range	–	–	1.4 V
2.5 V LVCMOS	–	–	1.2 V
1.8 V LVCMOS	–	–	0.90 V
1.5 V LVCMOS	–	–	0.75 V
1.2 V LVCMOS	–	–	0.6V
3.3 V PCI	–	–	$0.285 * V_{CCI} (RR)$
			$0.615 * V_{CCI} (FF)$
3.3 V PCI-X	–	–	$0.285 * V_{CCI} (RR)$
			$0.615 * V_{CCI} (FF)$
3.3 V GTL	0.8 V	1.2 V	V_{REF}
2.5 V GTL	0.8 V	1.2 V	V_{REF}
3.3 V GTL+	1.0 V	1.5 V	V_{REF}
2.5 V GTL+	1.0 V	1.5 V	V_{REF}
HSTL (I)	0.75 V	0.75 V	V_{REF}
HSTL (II)	0.75 V	0.75 V	V_{REF}
SSTL2 (I)	1.25 V	1.25 V	V_{REF}
SSTL2 (II)	1.25 V	1.25 V	V_{REF}
SSTL3 (I)	1.5 V	1.485 V	V_{REF}
SSTL3 (II)	1.5 V	1.485 V	V_{REF}
LVDS	–	–	Cross point
LVPECL	–	–	Cross point

Table 2-27 • I/O AC Parameter Definitions

Parameter	Parameter Definition
t_{DP}	Data to Pad delay through the Output Buffer
t_{PY}	Pad to Data delay through the Input Buffer
t_{DOUT}	Data to Output Buffer delay through the I/O interface
t_{EOUT}	Enable to Output Buffer Tristate Control delay through the I/O interface
t_{DIN}	Input Buffer to Data delay through the I/O interface
t_{HZ}	Enable to Pad delay through the Output Buffer—HIGH to Z
t_{ZH}	Enable to Pad delay through the Output Buffer—Z to HIGH
t_{LZ}	Enable to Pad delay through the Output Buffer—LOW to Z
t_{ZL}	Enable to Pad delay through the Output Buffer—Z to LOW
t_{ZHS}	Enable to Pad delay through the Output Buffer with delayed enable—Z to HIGH
t_{ZLS}	Enable to Pad delay through the Output Buffer with delayed enable—Z to LOW

1.5 V DC Core Voltage

Table 2-28 • Summary of I/O Timing Characteristics—Software Default Settings
–1 Speed Grade, Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst Case $V_{CC} = 1.425\text{V}$, Worst Case V_{CCI}
Pro I/O Banks

Standard	Drive Strength (mA)	Slew Rate	Capacitive Load (pF)	External Resistor (Ω)	t_{DOUT} (ns)	t_{DP} (ns)	t_{DIN} (ns)	t_{PY} (ns)	t_{PYS} (ns)	t_{EOUT} (ns)	t_{ZL} (ns)	t_{ZH} (ns)	t_{LZ} (ns)	t_{HZ} (ns)	t_{ZLS} (ns)	t_{ZHS} (ns)	Units
3.3 V LVTTTL / 3.3 V LVCMOS	12 mA	High	5	–	0.50	1.89	0.03	1.34	1.85	0.33	1.93	1.42	2.51	2.77	3.64	3.13	ns
2.5 V LVCMOS	12 mA	High	5	–	0.50	1.92	0.03	1.58	1.97	0.33	1.96	1.59	2.58	2.68	3.67	3.30	ns
1.8 V LVCMOS	12 mA	High	5	–	0.50	2.14	0.03	1.53	2.17	0.33	2.18	1.76	2.86	3.24	3.89	3.47	ns
1.5 V LVCMOS	12 mA	High	5	–	0.50	2.46	0.03	1.69	2.36	0.33	2.51	2.04	3.03	3.35	4.22	3.75	ns
3.3 V PCI	Per PCI spec.	High	5	–	0.50	2.15	0.03	2.10	2.84	0.33	2.19	1.53	2.51	2.77	3.90	3.24	ns
3.3 V PCI-X	Per PCI-X spec.	High	10	25	0.50	2.15	0.03	2.10	2.84	0.33	2.19	1.53	2.51	2.77	3.90	3.24	ns
3.3 V GTL	25 mA	High	10	25	0.50	1.59	0.03	1.80	–	0.33	1.56	1.59	–	–	3.27	3.30	ns
2.5 V GTL	25 mA	High	10	25	0.50	1.63	0.03	1.75	–	0.33	1.66	1.63	–	–	3.37	3.34	ns
3.3 V GTL+	35 mA	High	10	25	0.50	1.57	0.03	1.80	–	0.33	1.60	1.57	–	–	3.31	3.29	ns
2.5 V GTL+	33 mA	High	10	25	0.50	1.69	0.03	1.75	–	0.33	1.72	1.61	–	–	3.43	3.32	ns
HSTL (I)	8 mA	High	20	25	0.50	2.43	0.03	2.12	–	0.33	2.48	2.41	–	–	4.19	4.12	ns
HSTL (II)	15 mA	High	20	50	0.50	2.32	0.03	2.12	–	0.33	2.36	2.08	–	–	4.07	3.79	ns
SSTL2 (I)	15 mA	High	30	25	0.50	1.63	0.03	1.61	–	0.33	1.66	1.41	–	–	1.66	1.41	ns
SSTL2 (II)	18 mA	High	30	50	0.50	1.66	0.03	1.61	–	0.33	1.69	1.36	–	–	1.69	1.36	ns
SSTL3 (I)	14 mA	High	30	25	0.50	1.77	0.03	1.54	–	0.33	1.80	1.41	–	–	1.80	1.41	ns
SSTL3 (II)	21 mA	High	30	50	0.50	1.58	0.03	1.54	–	0.33	1.61	1.28	–	–	1.61	1.28	ns
LVDS	24 mA	High	–	–	0.50	1.40	0.03	1.85	–	–	–	–	–	–	–	–	ns
LVPECL	24 mA	High	–	–	0.50	1.40	0.03	1.67	–	–	–	–	–	–	–	–	ns

Notes:

- For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.
- Resistance is used to measure I/O propagation delays as defined in PCI specifications. See [Figure 2-12 on page 2-75](#) for connectivity. This resistor is not required during normal operation.

Table 2-29 • Summary of I/O Timing Characteristics—Software Default Settings
–1 Speed Grade, Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst Case $V_{CC} = 1.425\text{ V}$, Worst Case V_{CCI}
Advanced I/O Banks

I/O Standard	Drive Strength (mA)	Slew Rate	Capacitive Load (pF)	External Resistor (Ω)	t_{DOUT} (ns)	t_{DP} (ns)	t_{DIN} (ns)	t_{PY} (ns)	t_{EOUT} (ns)	t_{ZL} (ns)	t_{ZH} (ns)	t_{LZ} (ns)	t_{HZ} (ns)	t_{ZLS} (ns)	t_{ZHS} (ns)	Units
3.3 V LVTTTL / 3.3 V LVCMOS	12 mA	High	5pF	–	0.46	1.83	0.03	0.78	0.33	1.87	1.39	2.46	2.74	3.58	3.10	ns
2.5 V LVCMOS	12 mA	High	5 pF	–	0.46	1.85	0.03	1.00	0.33	1.88	1.55	2.53	2.63	3.59	3.26	ns
1.8 V LVCMOS	12 mA	High	5 pF	–	0.46	2.04	0.03	0.93	0.33	2.08	1.73	2.83	3.12	3.79	3.45	ns
1.5 V LVCMOS	12 mA	High	5 pF	–	0.46	2.33	0.03	1.10	0.33	2.37	2.01	3.02	3.22	4.08	3.72	ns
3.3 V PCI	Per PCI spec.	High	5 pF	25 ²	0.46	2.05	0.03	0.66	0.33	2.09	1.49	2.46	2.74	3.80	3.21	ns
3.3 V PCI-X	Per PCI-X spec.	High	10 pF	25 ²	0.46	2.05	0.03	0.64	0.33	2.09	1.49	2.46	2.74	3.80	3.21	ns
LVDS	24 mA	High	–	–	0.46	1.40	0.03	1.23	N/A	N/A	N/A	N/A	N/A	N/A	N/A	ns
LVPECL	24 mA	High	–	–	0.46	1.38	0.03	1.08	N/A	N/A	N/A	N/A	N/A	N/A	N/A	ns

Notes:

1. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.
2. Resistance is used to measure I/O propagation delays as defined in PCI specifications. See [Figure 2-12 on page 2-75](#) for connectivity. This resistor is not required during normal operation.

Table 2-30 • Summary of I/O Timing Characteristics—Software Default Settings
–1 Speed Grade, Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst Case $V_{CC} = 1.425\text{ V}$, Worst Case $V_{CCI} = 3.0\text{ V}$
Standard Plus I/O Banks

I/O Standard	Drive Strength (mA)	Slew Rate	Capacitive Load (pF)	External Resistor	t_{DOUT} (ns)	t_{DP} (ns)	t_{DIN} (ns)	t_{PY} (ns)	t_{EOUT} (ns)	t_{ZL} (ns)	t_{ZH} (ns)	t_{LZ} (ns)	t_{HZ} (ns)	t_{ZLS} (ns)	t_{ZHS} (ns)	Units
3.3 V LVTTTL / 3.3 V LVCMOS	12 mA	High	5pF	–	0.46	1.56	0.03	0.77	0.33	1.59	1.20	2.14	2.47	3.30	2.91	ns
2.5 V LVCMOS	12 mA	High	5pF	–	0.46	1.59	0.03	0.99	0.33	1.61	1.32	2.16	2.38	3.33	3.03	ns
1.8 V LVCMOS	8 mA	High	5pF	–	0.46	1.59	0.03	0.99	0.33	1.61	1.32	2.16	2.38	3.33	3.03	ns
1.5 V LVCMOS	4 mA	High	5pF	–	0.46	2.15	0.03	1.09	0.33	2.19	1.82	2.32	2.40	3.90	3.53	ns
3.3 V PCI	Per PCI spec.	High	10 pF	25 ²	0.46	1.77	0.03	0.65	0.33	1.80	1.31	2.14	2.47	3.51	3.02	ns
3.3 V PCI-X	Per PCI-X spec.	High	10 pF	25 ²	0.46	1.77	0.03	0.64	0.33	1.80	1.31	2.14	2.47	3.51	3.02	ns

Notes:

1. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.
2. Resistance is used to measure I/O propagation delays as defined in PCI specifications. See [Figure 2-12 on page 2-75](#) for connectivity. This resistor is not required during normal operation.

1.2 V DC Core Voltage

Table 2-31 • Summary of I/O Timing Characteristics—Software Default Settings

–1 Speed Grade, Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst Case $V_{CC} = 1.14\text{ V}$, Worst Case V_{CCI}
Pro I/O Banks

Standard	Drive Strength (mA)	Slew Rate	Capacitive Load (pF)	External Resistor (Ω)	t_{DOUT} (ns)	t_{DP} (ns)	t_{DIN} (ns)	t_{PY} (ns)	t_{PYS} (ns)	t_{EOUT} (ns)	t_{ZL} (ns)	t_{ZH} (ns)	t_{LZ} (ns)	t_{HZ} (ns)	t_{ZLS} (ns)	t_{ZHS} (ns)	Units
3.3 V LVTTTL / 3.3 V LVCMOS	12 mA	High	5	–	0.66	1.89	0.04	1.34	1.85	0.43	1.93	1.42	2.51	2.77	3.64	3.13	ns
2.5 V LVCMOS	12 mA	High	5	–	0.66	1.92	0.04	1.58	1.97	0.43	1.96	1.59	2.58	2.68	3.67	3.30	ns
1.8 V LVCMOS	12 mA	High	5	–	0.66	2.14	0.04	1.53	2.17	0.43	2.18	1.76	2.86	3.24	3.89	3.47	ns
1.5 V LVCMOS	12 mA	High	5	–	0.66	2.46	0.04	1.69	2.36	0.43	2.51	2.04	3.03	3.35	4.22	3.75	ns
1.2 V LVCMOS	2 mA	High	5	–	0.66	4.12	0.04	2.02	2.99	0.43	3.83	3.37	4.06	3.84	5.48	5.02	ns
3.3 V PCI	Per PCI spec.	High	10	–	0.66	2.15	0.04	2.10	2.84	0.43	2.19	1.53	2.51	2.77	3.90	3.24	ns
3.3 V PCI-X	Per PCI-X spec.	High	10	25	0.66	2.15	0.04	2.10	2.84	0.43	2.19	1.53	2.51	2.77	3.90	3.24	ns
3.3 V GTL	25 mA	High	10	25	0.66	1.59	0.04	1.80	–	0.43	1.56	1.59	–	–	3.27	3.30	ns
2.5 V GTL	25 mA	High	10	25	0.66	1.63	0.04	1.75	–	0.43	1.66	1.63	–	–	3.37	3.34	ns
3.3 V GTL+	35 mA	High	10	25	0.66	1.57	0.04	1.80	–	0.43	1.60	1.57	–	–	3.31	3.29	ns
2.5 V GTL+	33 mA	High	10	25	0.66	1.69	0.04	1.75	–	0.43	1.72	1.61	–	–	3.43	3.32	ns
HSTL (I)	8 mA	High	20	25	0.66	2.43	0.04	2.12	–	0.43	2.48	2.41	–	–	4.19	4.12	ns
HSTL (II)	15 mA	High	20	50	0.66	2.32	0.04	2.12	–	0.43	2.36	2.08	–	–	4.07	3.79	ns
SSTL2 (I)	15 mA	High	30	25	0.66	1.63	0.04	1.61	–	0.43	1.66	1.41	–	–	1.66	1.41	ns
SSTL2 (II)	18 mA	High	30	50	0.66	1.66	0.04	1.61	–	0.43	1.69	1.36	–	–	1.69	1.36	ns
SSTL3 (I)	14 mA	High	30	25	0.66	1.77	0.04	1.54	–	0.43	1.80	1.41	–	–	1.80	1.41	ns
SSTL3 (II)	21 mA	High	30	50	0.66	1.58	0.04	1.54	–	0.43	1.61	1.28	–	–	1.61	1.28	ns
LVDS	24 mA	High	–	–	0.66	1.43	0.04	1.85	–	–	–	–	–	–	–	–	ns
LVPECL	24 mA	High	–	–	0.66	1.37	0.04	1.67	–	–	–	–	–	–	–	–	ns

Notes:

1. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.
2. Resistance is used to measure I/O propagation delays as defined in PCI specifications. See [Figure 2-12 on page 2-75](#) for connectivity. This resistor is not required during normal operation.

Table 2-32 • Summary of I/O Timing Characteristics—Software Default Settings
–1 Speed Grade, Commercial-Case Conditions: $T_J = 70^{\circ}\text{C}$, Worst Case $V_{CC} = 1.14\text{ V}$, Worst Case V_{CCI}
Advanced I/O Banks

I/O Standard	Drive Strength (mA)	Slew Rate	Capacitive Load (pF)	External Resistor (Ω)	t_{DOUT} (ns)	t_{DP} (ns)	t_{DIN} (ns)	t_{PY} (ns)	t_{EOUT} (ns)	t_{ZL} (ns)	t_{ZH} (ns)	t_{LZ} (ns)	t_{HZ} (ns)	t_{ZLS} (ns)	t_{ZHS} (ns)	Units
3.3 V LVTTTL / 3.3 V LVCMOS	12 mA	High	5pF	–	0.60	1.83	0.04	0.78	0.43	1.87	1.39	2.46	2.74	3.58	3.10	ns
2.5 V LVCMOS	12 mA	High	5 pF	–	0.60	1.85	0.04	1.00	0.43	1.88	1.55	2.53	2.63	3.59	3.26	ns
1.8 V LVCMOS	12 mA	High	5 pF	–	0.60	2.04	0.04	0.93	0.43	2.08	1.73	2.83	3.12	3.79	3.45	ns
1.5 V LVCMOS	12 mA	High	5 pF	–	0.60	2.33	0.04	1.10	0.43	2.37	2.01	3.02	3.22	4.08	3.72	ns
1.2 V LVCMOS	2 mA	High	5pF	–	0.60	3.17	0.04	1.55	0.43	2.11	1.76	2.38	2.46	3.76	3.41	ns
3.3 V PCI	Per PCI spec.	High	10 pF	25 ²	0.60	2.05	0.04	0.66	0.43	2.09	1.49	2.46	2.74	3.80	3.21	ns
3.3 V PCI-X	Per PCI-X spec.	High	10 pF	25 ²	0.60	2.05	0.04	0.64	0.43	2.09	1.49	2.46	2.74	3.80	3.21	ns
LVDS	24 mA	High	–	–	0.60	1.40	0.04	1.23	N/A	N/A	N/A	N/A	N/A	N/A	N/A	ns
LVPECL	24 mA	High	–	–	0.60	1.38	0.04	1.08	N/A	N/A	N/A	N/A	N/A	N/A	N/A	ns

Notes:

1. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.
2. Resistance is used to measure I/O propagation delays as defined in PCI specifications. See [Figure 2-12 on page 2-75](#) for connectivity. This resistor is not required during normal operation.

Table 2-33 • Summary of I/O Timing Characteristics—Software Default Settings
–1 Speed Grade, Commercial-Case Conditions: $T_J = 70^{\circ}\text{C}$, Worst Case $V_{CC} = 1.14\text{ V}$, Worst Case $V_{CC1} = 3.0\text{ V}$
Standard Plus I/O Banks

I/O Standard	Drive Strength (mA)	Slew Rate	Capacitive Load (pF)	External Resistor	t_{DOUT} (ns)	t_{DP} (ns)	t_{DIN} (ns)	t_{PY} (ns)	t_{EOUT} (ns)	t_{ZL} (ns)	t_{ZH} (ns)	t_{LZ} (ns)	t_{HZ} (ns)	t_{ZLS} (ns)	t_{ZHS} (ns)	Units
3.3 V LVTTTL / 3.3 V LVCMOS	12 mA	High	5pF	–	0.60	1.56	0.04	0.77	0.43	1.59	1.20	2.14	2.47	3.30	2.91	ns
2.5 V LVCMOS	12 mA	High	5pF	–	0.60	1.59	0.04	0.99	0.43	1.61	1.32	2.16	2.38	3.33	3.03	ns
1.8 V LVCMOS	8 mA	High	5pF	–	0.60	1.59	0.04	0.99	0.43	1.61	1.32	2.16	2.38	3.33	3.03	ns
1.5 V LVCMOS	4 mA	High	5pF	–	0.60	2.15	0.04	1.09	0.43	2.19	1.82	2.32	2.40	3.90	3.53	ns
1.2 V LVCMOS	2 mA	High	5pF	–	0.60	3.54	0.04	1.56	0.43	2.37	2.11	3.60	3.87	4.02	3.76	ns
3.3 V PCI	Per PCI spec.	High	10 pF	25 ²	0.60	1.77	0.04	0.65	0.43	1.80	1.31	2.14	2.47	3.51	3.02	ns
3.3 V PCI-X	Per PCI-X spec.	High	10 pF	25 ²	0.60	1.77	0.04	0.64	0.43	1.80	1.31	2.14	2.47	3.51	3.02	ns

Notes:

1. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.
2. Resistance is used to measure I/O propagation delays as defined in PCI specifications. See [Figure 2-12 on page 2-75](#) for connectivity. This resistor is not required during normal operation.

Detailed I/O DC Characteristics

Table 2-34 • Input Capacitance

Symbol	Definition	Conditions	Min.	Max.	Units
C_{IN}	Input capacitance	$V_{IN} = 0$, $f = 1.0\text{ MHz}$		8	pF
C_{INCLK}	Input capacitance on the clock pin	$V_{IN} = 0$, $f = 1.0\text{ MHz}$		8	pF

Table 2-35 • I/O Output Buffer Maximum Resistances¹
Applicable to Pro I/Os

Standard	Drive Strength	R _{PULL-DOWN} (Ω) ²	R _{PULL-UP} (Ω) ³
3.3 V LVTTTL / 3.3 V LVCMOS	4 mA	100	300
	8 mA	50	150
	12 mA	25	75
	16 mA	17	50
	24 mA	11	33
2.5 V LVCMOS	4 mA	100	200
	8 mA	50	100
	12 mA	25	50
	16 mA	20	40
	24 mA	11	22
1.8 V LVCMOS	2 mA	200	225
	4 mA	100	112
	6 mA	50	56
	8 mA	50	56
	12 mA	20	22
	16 mA	20	22
1.5 V LVCMOS	2 mA	200	224
	4 mA	100	112
	6 mA	67	75
	8 mA	33	37
	12 mA	33	37
1.2 V LVCMOS	2 mA	TBD	TBD
3.3 V PCI/PCI-X	Per PCI/PCI-X specification	25	75
3.3 V GTL	25 mA	11	–
2.5 V GTL	25 mA	14	–
3.3 V GTL+	35 mA	12	–
2.5 V GTL+	33 mA	15	–
HSTL (I)	8 mA	50	50
HSTL (II)	15 mA	25	25
SSTL2 (I)	15 mA	27	31
SSTL2 (II)	18 mA	13	15
SSTL3 (I)	14 mA	44	69
SSTL3 (II)	21 mA	18	32

Notes:

1. These maximum values are provided for informational reasons only. Minimum output buffer resistance values depend on V_{CC} , drive strength selection, temperature, and process. For board design considerations and detailed output buffer resistances, use the corresponding IBIS models located on the Actel website at <http://www.actel.com/download/ibis/default.aspx>.
2. $R_{(PULL-DOWN-MAX)} = (V_{OLspec}) / I_{OLspec}$
3. $R_{(PULL-UP-MAX)} = (V_{CCImax} - V_{OHspec}) / I_{OHspec}$

Table 2-36 • I/O Output Buffer Maximum Resistances¹
Applicable to Advanced I/O Banks

Standard	Drive Strength	R _{PULL-DOWN} (Ω) ²	R _{PULL-UP} (Ω) ³
3.3 V LVTTTL / 3.3 V LVCMOS	2 mA	100	300
	4 mA	100	300
	6 mA	50	150
	8 mA	50	150
	12 mA	25	75
	16 mA	17	50
	24 mA	11	33
2.5 V LVCMOS	2 mA	100	300
	4 mA	100	300
	6 mA	50	150
	8 mA	50	150
	12 mA	25	75
	16 mA	17	50
	24 mA	11	33
1.8 V LVCMOS	2 mA	100	200
	4 mA	100	200
	6 mA	50	100
	8 mA	50	100
	12 mA	25	50
	16 mA	20	40
1.5 V LVCMOS	2 mA	200	224
	4 mA	100	112
	6 mA	67	75
	8 mA	33	37
	12 mA	33	37
1.2 V LVCMOS	2 mA	TBD	TBD
3.3 V PCI/PCI-X	Per PCI/PCI-X specification	25	75

Notes:

1. These maximum values are provided for informational reasons only. Minimum output buffer resistance values depend on V_{CCk} drive strength selection, temperature, and process. For board design considerations and detailed output buffer resistances, use the corresponding IBIS models located on the Actel website at <http://www.actel.com/download/ibis/default.aspx>.
2. $R_{(PULL-DOWN-MAX)} = (V_{OLspec}) / I_{OLspec}$
3. $R_{(PULL-UP-MAX)} = (V_{CCImax} - V_{OHspec}) / I_{OHspec}$

Table 2-37 • I/O Output Buffer Maximum Resistances¹
Applicable to Standard Plus I/O Banks

Standard	Drive Strength	R _{PULL-DOWN} (Ω) ²	R _{PULL-UP} (Ω) ³
3.3 V LVTTTL / 3.3 V LVCMOS	2 mA	100	300
	4 mA	100	300
	6 mA	50	150
	8 mA	50	150
	12 mA	25	75
	16 mA	25	75
2.5 V LVCMOS	2 mA	100	200
	4 mA	100	200
	6 mA	50	100
	8 mA	50	100
	12 mA	25	50
1.8 V LVCMOS	2 mA	200	225
	4 mA	100	112
	6 mA	50	56
	8 mA	50	56
1.5 V LVCMOS	2 mA	200	224
	4 mA	100	112
1.2 V LVCMOS	2 mA	TBD	TBD
3.3 V PCI/PCI-X	Per PCI/PCI-X specification	25	75

Notes:

1. These maximum values are provided for informational reasons only. Minimum output buffer resistance values depend on V_{CC} , drive strength selection, temperature, and process. For board design considerations and detailed output buffer resistances, use the corresponding IBIS models located on the Actel website at <http://www.actel.com/download/ibis/default.aspx>.
2. $R_{(PULL-DOWN-MAX)} = (V_{OLspec}) / I_{OLspec}$
3. $R_{(PULL-UP-MAX)} = (V_{CCImax} - V_{OHspec}) / I_{OHspec}$

Table 2-38 • I/O Weak Pull-Up/Pull-Down Resistances
Minimum and Maximum Weak Pull-Up/Pull-Down Resistance Values

V _{CCI}	R _(WEAK PULL-UP) ¹ (Ω)		R _(WEAK PULL-DOWN) ² (Ω)	
	Min.	Max.	Min.	Max.
3.3 V	10 k	45 k	10 k	45 k
2.5 V	11 k	55 k	12 k	74 k
1.8 V	18 k	70 k	17 k	110 k
1.5 V	19 k	90 k	19 k	140 k
1.2 V LVCMOS	TBD	TBD	TBD	TBD

Notes:

1. $R_{(WEAK PULL-UP-MAX)} = (V_{OLspec}) / I_{(WEAK PULL-UP-MIN)}$
2. $R_{(WEAK PULL-UP-MAX)} = (V_{CCI_{max}} - V_{OHspec}) / I_{(WEAK PULL-UP-MIN)}$

Table 2-39 • I/O Short Currents I_{OSH}/I_{OSL}
Applicable to Pro I/Os

	Drive Strength	I_{OSL} (mA)*	I_{OSH} (mA)*
3.3 V LVTTTL / 3.3 V LVCMOS	4 mA	25	27
	8 mA	51	54
	12 mA	103	109
	16 mA	132	127
	24 mA	268	181
2.5 V LVCMOS	4 mA	16	18
	8 mA	32	37
	12 mA	65	74
	16 mA	83	87
	24 mA	169	124
1.8 V LVCMOS	2 mA	9	11
	4 mA	17	22
	6 mA	35	44
	8 mA	45	51
	12 mA	91	74
	16 mA	91	74
1.5 V LVCMOS	2 mA	13	16
	4 mA	25	33
	6 mA	32	39
	8 mA	66	55
	12 mA	66	55
1.2 V LVCMOS	2 mA	TBD	TBD
3.3 V PCI/PCIX	Per PCI/PCI-X Specification	Per PCI Curves	
3.3 V GTL	25 mA	268	181
2.5 V GTL	25 mA	169	124
3.3 V GTL+	35 mA	268	181
2.5 V GTL+	33 mA	169	124
HSTL (I)	8 mA	32	39
HSTL (II)	15 mA	66	55
SSTL2 (I)	15 mA	83	87
SSTL2 (II)	18 mA	169	124
SSTL3 (I)	14 mA	51	54

* $T_J = 100^\circ\text{C}$

Table 2-40 • I/O Short Currents I_{OSH}/I_{OSL}
Applicable to Advanced I/O Banks

	Drive Strength	I_{OSL} (mA)*	I_{OSH} (mA)*
3.3 V LVTTTL / 3.3 V LVCMOS	2 mA	25	27
	4 mA	25	27
	6 mA	51	54
	8 mA	51	54
	12 mA	103	109
	16 mA	132	127
	24 mA	268	181
2.5 V LVCMOS	2 mA	16	18
	4 mA	16	18
	6 mA	32	37
	8 mA	32	37
	12 mA	65	74
	16 mA	83	87
	24 mA	169	124
1.8 V LVCMOS	2 mA	9	11
	4 mA	17	22
	6 mA	35	44
	8 mA	45	51
	12 mA	91	74
	16 mA	91	74
1.5 V LVCMOS	2 mA	13	16
	4 mA	25	33
	6 mA	32	39
	8 mA	66	55
	12 mA	66	55
1.2 V LVCMOS	2 mA	TBD	TBD
3.3 V PCI/PCI-X	Per PCI/PCI-X specification	103	109

* $T_J = 100^\circ\text{C}$

Table 2-41 • I/O Short Currents I_{OSH}/I_{OSL}
Applicable to Standard Plus I/O Banks

	Drive Strength	I_{OSL} (mA)*	I_{OSH} (mA)*
3.3 V LVTTTL / 3.3 V LVCMOS	2 mA	25	27
	4 mA	25	27
	6 mA	51	54
	8 mA	51	54
	12 mA	103	109
	16 mA	103	109
2.5 V LVCMOS	2 mA	16	18
	4 mA	16	18
	6 mA	32	37
	8 mA	32	37
	12 mA	65	74
1.8 V LVCMOS	2 mA	9	11
	4 mA	17	22
	6 mA	35	44
	8 mA	35	44
1.5 V LVCMOS	2 mA	13	16
	4 mA	25	33
1.2 V LVCMOS	2 mA	TBD	TBD
3.3 V PCI/PCI-X	Per PCI/PCI-X specification	103	109

* $T_J = 100^{\circ}\text{C}$

Table 2-42 • Schmitt Trigger Input Hysteresis, Hysteresis Voltage Value (Typ) for Schmitt Mode Input Buffers

Input Buffer Configuration	Hysteresis Value (typ.)
3.3 V LVTTTL/LVCMOS/PCI/PCI-X (Schmitt trigger mode)	240 mV
2.5 V LVCMOS (Schmitt trigger mode)	140 mV
1.8 V LVCMOS (Schmitt trigger mode)	80 mV
1.5 V LVCMOS (Schmitt trigger mode)	60 mV
1.2 V LVCMOS (Schmitt trigger mode)	40 mV

The length of time an I/O can withstand I_{OSH}/I_{OSL} events depends on the junction temperature. The reliability data below is based on a 3.3 V, 12 mA I/O setting, which is the worst case for this type of analysis.

For example, at 110°C , the short current condition would have to be sustained for more than three months to cause a reliability concern. The I/O design does not contain any short circuit protection, but such protection would only be needed in extremely prolonged stress conditions.

Table 2-43 • Duration of Short Circuit Event before Failure

Temperature	Time before Failure
–40°C	> 20 years
0°C	> 20 years
25°C	> 20 years
70°C	5 years
85°C	2 years
100°C	6 months
110°C	3 months

Table 2-44 • I/O Input Rise Time, Fall Time, and Related I/O Reliability

Input Buffer	Input Rise/Fall Time (min.)	Input Rise/Fall Time (max.)	Reliability
LVTTL/LVCMOS	No requirement	10 ns *	20 years (110°C)
LVDS/B-LVDS/ M-LVDS/LVPECL	No requirement	10 ns *	10 years (100°C)

* The maximum input rise/fall time is related to the noise induced into the input buffer trace. If the noise is low, then the rise time and fall time of input buffers can be increased beyond the maximum value. The longer the rise/fall times, the more susceptible the input signal is to the board noise. Actel recommends signal integrity evaluation/characterization of the system to ensure that there is no excessive noise coupling into input signals.

Single-Ended I/O Characteristics

3.3 V LVTTTL / 3.3 V LVCMOS

Low-Voltage Transistor–Transistor Logic (LVTTTL) is a general-purpose standard (EIA/JESD) for 3.3 V applications. It uses an LVTTTL input buffer and push-pull output buffer. Furthermore, all LVCMOS 3.3 V software macros comply with LVCMOS 3.3 V wide range as specified in the JESD8a specification.

Table 2-45 • Minimum and Maximum DC Input and Output Levels
Applicable to Pro I/O Banks

3.3 V LVTTTL / 3.3 V LVCMOS	V _{IL}		V _{IH}		V _{OL}	V _{OH}	I _{OL}	I _{OH}	I _{OSL}	I _{OSH}	I _{IL}	I _{IH}
Drive Strength	Min., V	Max., V	Min., V	Max., V	Max., V	Min., V	mA	mA	Max., mA ¹	Max., mA ¹	μA ²	μA ²
4 mA	–0.3	0.8	2	3.6	0.4	2.4	4	4	25	27	10	10
6 mA	–0.3	0.8	2	3.6	0.4	2.4	8	8	51	54	10	10
8 mA	–0.3	0.8	2	3.6	0.4	2.4	12	12	103	109	10	10
12 mA	–0.3	0.8	2	3.6	0.4	2.4	16	16	132	127	10	10
16 mA	–0.3	0.8	2	3.6	0.4	2.4	24	24	268	181	10	10
24 mA	–0.3	0.8	2	3.6	0.4	2.4	24	24	27	25	10	10

Notes:

1. Currents are measured at 100°C junction temperature and maximum voltage.
2. Currents are measured at 85°C junction temperature.
3. Software default selection highlighted in gray.

Table 2-46 • Minimum and Maximum DC Input and Output Levels
Applicable to Advanced I/O Banks

3.3 V LVTTTL / 3.3 V LVCMOS	V _{IL}		V _{IH}		V _{OL}	V _{OH}	I _{OL}	I _{OH}	I _{OSL}	I _{OSH}	I _{IL}	I _{IH}
Drive Strength	Min., V	Max., V	Min., V	Max., V	Max., V	Min., V	mA	mA	Max., mA ¹	Max., mA ¹	μA ²	μA ²
2 mA	–0.3	0.8	2	3.6	0.4	2.4	2	2	25	27	10	10
4 mA	–0.3	0.8	2	3.6	0.4	2.4	4	4	25	27	10	10
6 mA	–0.3	0.8	2	3.6	0.4	2.4	6	6	51	54	10	10
8 mA	–0.3	0.8	2	3.6	0.4	2.4	8	8	51	54	10	10
12 mA	–0.3	0.8	2	3.6	0.4	2.4	12	12	103	109	10	10
16 mA	–0.3	0.8	2	3.6	0.4	2.4	16	16	132	127	10	10
24 mA	–0.3	0.8	2	3.6	0.4	2.4	24	24	268	181	10	10

Notes:

1. Currents are measured at 100°C junction temperature and maximum voltage.
2. Currents are measured at 85°C junction temperature.
3. Software default selection highlighted in gray.

Table 2-47 • Minimum and Maximum DC Input and Output Levels
Applicable to Standard Plus I/O Banks

3.3 V LVTTTL / 3.3 V LVCMOS	V_{IL}		V_{IH}		V_{OL}	V_{OH}	I_{OL}	I_{OH}	I_{OSL}	I_{OSH}	I_{IL}	I_{IH}
Drive Strength	Min., V	Max., V	Min., V	Max., V	Max., V	Min., V	mA	mA	Max., mA ¹	Max., mA ¹	μA^2	μA^2
2 mA	-0.3	0.8	2	3.6	0.4	2.4	2	2	25	27	10	10
4 mA	-0.3	0.8	2	3.6	0.4	2.4	4	4	25	27	10	10
6 mA	-0.3	0.8	2	3.6	0.4	2.4	6	6	51	54	10	10
8 mA	-0.3	0.8	2	3.6	0.4	2.4	8	8	51	54	10	10
12 mA	-0.3	0.8	2	3.6	0.4	2.4	12	12	103	109	10	10
16 mA	-0.3	0.8	2	3.6	0.4	2.4	16	16	103	109	10	10

Notes:

1. Currents are measured at 100°C junction temperature and maximum voltage.
2. Currents are measured at 85°C junction temperature.
3. Software default selection highlighted in gray.

Table 2-48 • Minimum and Maximum DC Input and Output Levels for LVCMOS 3.3 V Wide Range
Applicable to Pro, Advanced, and Standard Plus I/O Banks

3.3 V LVCMOS Wide Range	V_{IL}		V_{IH}		V_{OL}	V_{OH}	I_{OL}	I_{OH}	I_{IL}	I_{IH}
Drive Strength	Min., V	Max., V	Min., V	Max., V	Max., V	Min., V	mA	mA	μA^2	μA^2
All ²	-0.3	0.8	2	3.6	0.2	$V_{CC1} - 0.2$	0.1	0.1	10	10

Notes:

1. Currents are measured at 85°C junction temperature.
2. All LVCMOS 3.3 V software macros supports LVCMOS 3.3 V wide range as specified in the JDEC8a specification

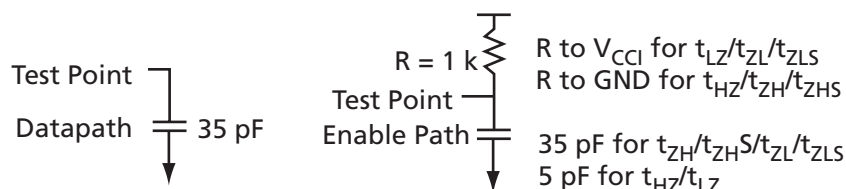


Figure 2-7 • AC Loading

Table 2-49 • AC Waveforms, Measuring Points, and Capacitive Loads

Input LOW (V)	Input HIGH (V)	Measuring Point* (V)	C_{LOAD} (pF)
0	3.3	1.4	5

* Measuring point = V_{trip} . See Table 2-26 on page 2-25 for a complete table of trip points.

Timing Characteristics

1.5 V DC Core Voltage

Table 2-50 • 3.3 V LVTTTL / 3.3 V LVCMOS Low Slew – Applies to 1.5 V DC Core Voltage
Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$, Worst-Case $V_{CCI} = 3.0\text{ V}$
Applicable to Pro I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{PYS}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
4 mA	Std.	0.59	5.48	0.04	1.58	2.17	0.38	5.58	4.40	2.42	2.20	7.60	6.42	ns
	–1	0.50	4.66	0.03	1.34	1.85	0.33	4.75	3.75	2.06	1.87	6.46	5.46	ns
8 mA	Std.	0.59	4.48	0.04	1.58	2.17	0.38	4.56	3.76	2.73	2.76	6.57	5.78	ns
	–1	0.50	3.81	0.03	1.34	1.85	0.33	3.88	3.20	2.33	2.35	5.59	4.91	ns
12 mA	Std.	0.59	3.77	0.04	1.58	2.17	0.38	3.84	3.28	2.95	3.12	5.85	5.29	ns
	–1	0.50	3.21	0.03	1.34	1.85	0.33	3.27	2.79	2.51	2.65	4.98	4.50	ns
16 mA	Std.	0.59	3.57	0.04	1.58	2.17	0.38	3.63	3.18	2.99	3.22	5.64	5.19	ns
	–1	0.50	3.03	0.03	1.34	1.85	0.33	3.09	2.70	2.54	2.74	4.80	4.41	ns
24 mA	Std.	0.59	3.46	0.04	1.58	2.17	0.38	3.52	3.19	3.05	3.57	5.54	5.20	ns
	–1	0.50	2.94	0.03	1.34	1.85	0.33	3.00	2.71	2.59	3.03	4.71	4.42	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-51 • 3.3 V LVTTTL / 3.3 V LVCMOS High Slew – Applies to 1.5 V DC Core Voltage
Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$, Worst-Case $V_{CCI} = 3.0\text{ V}$
Applicable to Pro I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{PYS}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
4 mA	Std.	0.59	3.08	0.04	1.58	2.17	0.38	3.14	2.36	2.42	2.33	5.15	4.38	ns
	–1	0.50	2.62	0.03	1.34	1.85	0.33	2.67	2.01	2.06	1.98	4.38	3.72	ns
8 mA	Std.	0.59	2.53	0.04	1.58	2.17	0.38	2.58	1.89	2.74	2.89	4.59	3.90	ns
	–1	0.50	2.16	0.03	1.34	1.85	0.33	2.20	1.61	2.33	2.46	3.91	3.32	ns
12 mA	Std.	0.59	2.22	0.04	1.58	2.17	0.38	2.27	1.67	2.95	3.25	4.28	3.68	ns
	–1	0.50	1.89	0.03	1.34	1.85	0.33	1.93	1.42	2.51	2.77	3.64	3.13	ns
16 mA	Std.	0.59	2.17	0.04	1.58	2.17	0.38	2.21	1.63	3.00	3.35	4.23	3.64	ns
	–1	0.50	1.85	0.03	1.34	1.85	0.33	1.88	1.38	2.55	2.85	3.59	3.09	ns
24 mA	Std.	0.59	2.19	0.04	1.58	2.17	0.38	2.24	1.57	3.05	3.71	4.25	3.58	ns
	–1	0.50	1.87	0.03	1.34	1.85	0.33	1.90	1.33	2.59	3.16	3.61	3.05	ns

Notes:

1. Software default selection highlighted in gray.
2. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-52 • 3.3 V LVTTTL / 3.3 V LVCMOS Low Slew – Applies to 1.5 V DC Core Voltage
Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$, Worst-Case $V_{CCI} = 3.0\text{ V}$
Applicable to Advanced I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
4 mA	Std.	0.54	5.11	0.04	0.91	0.38	5.21	4.33	2.38	2.21	7.22	6.34	ns
	–1	0.46	4.35	0.03	0.78	0.33	4.43	3.68	2.02	1.88	6.14	5.40	ns
6 mA	Std.	0.54	4.30	0.04	0.91	0.38	4.38	3.75	2.68	2.74	6.39	5.76	ns
	–1	0.46	3.66	0.03	0.78	0.33	3.73	3.19	2.28	2.33	5.44	4.90	ns
8 mA	Std.	0.54	4.30	0.04	0.91	0.38	4.38	3.75	2.68	2.74	6.39	5.76	ns
	–1	0.46	3.66	0.03	0.78	0.33	3.73	3.19	2.28	2.33	5.44	4.90	ns
12 mA	Std.	0.54	3.68	0.04	0.91	0.38	3.75	3.32	2.89	3.07	5.76	5.33	ns
	–1	0.46	3.13	0.03	0.78	0.33	3.19	2.82	2.45	2.62	4.90	4.53	ns
16 mA	Std.	0.54	3.50	0.04	0.91	0.38	3.56	3.21	2.93	3.16	5.57	5.23	ns
	–1	0.46	2.97	0.03	0.78	0.33	3.03	2.73	2.49	2.69	4.74	4.45	ns
24 mA	Std.	0.54	3.39	0.04	0.91	0.38	3.45	3.25	2.99	3.50	5.47	5.26	ns
	–1	0.46	2.88	0.03	0.78	0.33	2.94	2.76	2.54	2.97	4.65	4.48	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-53 • 3.3 V LVTTTL / 3.3 V LVCMOS High Slew – Applies to 1.5 V DC Core Voltage
Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$, Worst-Case $V_{CCI} = 3.0\text{ V}$
Applicable to Advanced I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
4 mA	Std.	0.54	2.90	0.04	0.91	0.38	2.96	2.28	2.38	2.35	4.97	4.29	ns
	–1	0.46	2.47	0.03	0.78	0.33	2.52	1.94	2.03	2.00	4.23	3.65	ns
6 mA	Std.	0.54	2.41	0.04	0.91	0.38	2.46	1.84	2.69	2.88	4.47	3.85	ns
	–1	0.46	2.05	0.03	0.78	0.33	2.09	1.57	2.29	2.45	3.80	3.28	ns
8 mA	Std.	0.54	2.41	0.04	0.91	0.38	2.46	1.84	2.69	2.88	4.47	3.85	ns
	–1	0.46	2.05	0.03	0.78	0.33	2.09	1.57	2.29	2.45	3.80	3.28	ns
12 mA	Std.	0.54	2.16	0.04	0.91	0.38	2.20	1.63	2.89	3.22	4.21	3.64	ns
	–1	0.46	1.83	0.03	0.78	0.33	1.87	1.39	2.46	2.74	3.58	3.10	ns
16 mA	Std.	0.54	2.11	0.04	0.91	0.38	2.15	1.59	2.94	3.31	4.17	3.61	ns
	–1	0.46	1.80	0.03	0.78	0.33	1.83	1.36	2.50	2.82	3.54	3.07	ns
24 mA	Std.	0.54	2.14	0.04	0.91	0.38	2.17	1.55	2.99	3.65	4.19	3.56	ns
	–1	0.46	1.82	0.03	0.78	0.33	1.85	1.32	2.54	3.11	3.56	3.03	ns

Notes:

1. Software default selection highlighted in gray.
2. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-54 • 3.3 V LVTTTL / 3.3 V LVCMOS Low Slew – Applies to 1.5 V DC Core Voltage
Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$, Worst-Case $V_{CCI} = 3.0\text{ V}$
Applicable to Standard Plus I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
4 mA	Std.	0.54	4.61	0.04	0.90	0.38	4.70	3.91	2.05	1.99	6.71	5.92	ns
	–1	0.46	3.92	0.03	0.77	0.33	4.00	3.32	1.74	1.69	5.71	5.04	ns
6 mA	Std.	0.54	3.80	0.04	0.90	0.38	3.87	3.40	2.32	2.47	5.88	5.41	ns
	–1	0.46	3.23	0.03	0.77	0.33	3.29	2.89	1.98	2.10	5.00	4.60	ns
8 mA	Std.	0.54	3.80	0.04	0.90	0.38	3.87	3.40	2.32	2.47	5.88	5.41	ns
	–1	0.46	3.23	0.03	0.77	0.33	3.29	2.89	1.98	2.10	5.00	4.60	ns
12 mA	Std.	0.54	3.22	0.04	0.90	0.38	3.28	3.00	2.51	2.77	5.30	5.01	ns
	–1	0.46	2.74	0.03	0.77	0.33	2.79	2.55	2.14	2.36	4.51	4.27	ns
16 mA	Std.	0.54	3.22	0.04	0.90	0.38	3.28	3.00	2.51	2.77	5.30	5.01	ns
	–1	0.46	2.74	0.03	0.77	0.33	2.79	2.55	2.14	2.36	4.51	4.27	ns

Notes:

1. Software default selection highlighted in gray.
2. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-55 • 3.3 V LVTTTL / 3.3 V LVCMOS High Slew – Applies to 1.5 V DC Core Voltage
Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$, Worst-Case $V_{CCI} = 3.0\text{ V}$
Applicable to Standard Plus I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
4 mA	Std.	0.54	2.51	0.04	0.90	0.38	2.56	2.01	2.05	2.10	4.57	4.02	ns
	–1	0.46	2.14	0.03	0.77	0.33	2.18	1.71	1.74	1.79	3.89	3.42	ns
6 mA	Std.	0.54	2.05	0.04	0.90	0.38	2.09	1.61	2.32	2.59	4.10	3.62	ns
	–1	0.46	1.74	0.03	0.77	0.33	1.78	1.37	1.97	2.20	3.49	3.08	ns
8 mA	Std.	0.54	2.05	0.04	0.90	0.38	2.09	1.61	2.32	2.59	4.10	3.62	ns
	–1	0.46	1.74	0.03	0.77	0.33	1.78	1.37	1.97	2.20	3.49	3.08	ns
12 mA	Std.	0.54	1.83	0.04	0.90	0.38	1.86	1.41	2.51	2.90	3.88	3.42	ns
	–1	0.46	1.56	0.03	0.77	0.33	1.59	1.20	2.14	2.47	3.30	2.91	ns
16 mA	Std.	0.54	1.83	0.04	0.90	0.38	1.86	1.41	2.51	2.90	3.88	3.42	ns
	–1	0.46	1.56	0.03	0.77	0.33	1.59	1.20	2.14	2.47	3.30	2.91	ns

Notes:

1. Software default selection highlighted in gray.
2. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

1.2 V DC Core Voltage

Table 2-56 • 3.3 V LVTTTL / 3.3 V LVCMOS Low Slew – Applies to 1.2 V DC Core Voltage
Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$, Worst-Case $V_{CCI} = 3.0\text{ V}$
Applicable to Pro I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{PYS}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
4 mA	Std.	0.77	5.48	0.05	1.58	2.17	0.50	5.58	4.40	2.42	2.20	7.60	6.42	ns
	–1	0.66	4.66	0.04	1.34	1.85	0.43	4.75	3.75	2.06	1.87	6.46	5.46	ns
8 mA	Std.	0.77	4.48	0.05	1.58	2.17	0.50	4.56	3.76	2.73	2.76	6.57	5.78	ns
	–1	0.66	3.81	0.04	1.34	1.85	0.43	3.88	3.20	2.33	2.35	5.59	4.91	ns
12 mA	Std.	0.77	3.77	0.05	1.58	2.17	0.50	3.84	3.28	2.95	3.12	5.85	5.29	ns
	–1	0.66	3.21	0.04	1.34	1.85	0.43	3.27	2.79	2.51	2.65	4.98	4.50	ns
16 mA	Std.	0.77	3.57	0.05	1.58	2.17	0.50	3.63	3.18	2.99	3.22	5.64	5.19	ns
	–1	0.66	3.03	0.04	1.34	1.85	0.43	3.09	2.70	2.54	2.74	4.80	4.41	ns
24 mA	Std.	0.77	3.46	0.05	1.58	2.17	0.50	3.52	3.19	3.05	3.57	5.54	5.20	ns
	–1	0.66	2.94	0.04	1.34	1.85	0.43	3.00	2.71	2.59	3.03	4.71	4.42	ns

Notes:

1. Software default selection highlighted in gray.
2. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-57 • 3.3 V LVTTTL / 3.3 V LVCMOS High Slew – Applies to 1.2 V DC Core Voltage
Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$, Worst-Case $V_{CCI} = 3.0\text{ V}$
Applicable to Pro I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{PYS}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
4 mA	Std.	0.77	3.08	0.05	1.58	2.17	0.50	3.14	2.36	2.42	2.33	5.15	4.38	ns
	–1	0.66	2.62	0.04	1.34	1.85	0.43	2.67	2.01	2.06	1.98	4.38	3.72	ns
8 mA	Std.	0.77	2.53	0.05	1.58	2.17	0.50	2.58	1.89	2.74	2.89	4.59	3.90	ns
	–1	0.66	2.16	0.04	1.34	1.85	0.43	2.20	1.61	2.33	2.46	3.91	3.32	ns
12 mA	Std.	0.77	2.22	0.05	1.58	2.17	0.50	2.27	1.67	2.95	3.25	4.28	3.68	ns
	–1	0.66	1.89	0.04	1.34	1.85	0.43	1.93	1.42	2.51	2.77	3.64	3.13	ns
16 mA	Std.	0.77	2.17	0.05	1.58	2.17	0.50	2.21	1.63	3.00	3.35	4.23	3.64	ns
	–1	0.66	1.85	0.04	1.34	1.85	0.43	1.88	1.38	2.55	2.85	3.59	3.09	ns
24 mA	Std.	0.77	2.19	0.05	1.58	2.17	0.50	2.24	1.57	3.05	3.71	4.25	3.58	ns
	–1	0.66	1.87	0.04	1.34	1.85	0.43	1.90	1.33	2.59	3.16	3.61	3.05	ns

Notes:

1. Software default selection highlighted in gray.
2. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-58 • 3.3 V LVTTTL / 3.3 V LVCMOS Low Slew – Applies to 1.2 V DC Core Voltage
Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$, Worst-Case $V_{CCI} = 3.0\text{ V}$
Applicable to Advanced I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
4 mA	Std.	0.70	5.11	0.05	0.91	0.50	5.21	4.33	2.38	2.21	7.22	6.34	ns
	–1	0.60	4.35	0.04	0.78	0.43	4.43	3.68	2.02	1.88	6.14	5.40	ns
6 mA	Std.	0.70	4.30	0.05	0.91	0.50	4.38	3.75	2.68	2.74	6.39	5.76	ns
	–1	0.60	3.66	0.04	0.78	0.43	3.73	3.19	2.28	2.33	5.44	4.90	ns
8 mA	Std.	0.70	4.30	0.05	0.91	0.50	4.38	3.75	2.68	2.74	6.39	5.76	ns
	–1	0.60	3.66	0.04	0.78	0.43	3.73	3.19	2.28	2.33	5.44	4.90	ns
12 mA	Std.	0.70	3.68	0.05	0.91	0.50	3.75	3.32	2.89	3.07	5.76	5.33	ns
	–1	0.60	3.13	0.04	0.78	0.43	3.19	2.82	2.45	2.62	4.90	4.53	ns
16 mA	Std.	0.70	3.50	0.05	0.91	0.50	3.56	3.21	2.93	3.16	5.57	5.23	ns
	–1	0.60	2.97	0.04	0.78	0.43	3.03	2.73	2.49	2.69	4.74	4.45	ns
24 mA	Std.	0.70	3.39	0.05	0.91	0.50	3.45	3.25	2.99	3.50	5.47	5.26	ns
	–1	0.60	2.88	0.04	0.78	0.43	2.94	2.76	2.54	2.97	4.65	4.48	ns

Notes:

1. Software default selection highlighted in gray.
2. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-59 • 3.3 V LVTTTL / 3.3 V LVCMOS High Slew – Applies to 1.2 V DC Core Voltage
Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$, Worst-Case $V_{CCI} = 3.0\text{ V}$
Applicable to Advanced I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
4 mA	Std.	0.70	2.90	0.05	0.91	0.50	2.96	2.28	2.38	2.35	4.97	4.29	ns
	–1	0.60	2.47	0.04	0.78	0.43	2.52	1.94	2.03	2.00	4.23	3.65	ns
6 mA	Std.	0.70	2.41	0.05	0.91	0.50	2.46	1.84	2.69	2.88	4.47	3.85	ns
	–1	0.60	2.05	0.04	0.78	0.43	2.09	1.57	2.29	2.45	3.80	3.28	ns
8 mA	Std.	0.70	2.41	0.05	0.91	0.50	2.46	1.84	2.69	2.88	4.47	3.85	ns
	–1	0.60	2.05	0.04	0.78	0.43	2.09	1.57	2.29	2.45	3.80	3.28	ns
12 mA	Std.	0.70	2.16	0.05	0.91	0.50	2.20	1.63	2.89	3.22	4.21	3.64	ns
	–1	0.60	1.83	0.04	0.78	0.43	1.87	1.39	2.46	2.74	3.58	3.10	ns
16 mA	Std.	0.70	2.11	0.05	0.91	0.50	2.15	1.59	2.94	3.31	4.17	3.61	ns
	–1	0.60	1.80	0.04	0.78	0.43	1.83	1.36	2.50	2.82	3.54	3.07	ns
24 mA	Std.	0.70	2.14	0.05	0.91	0.50	2.17	1.55	2.99	3.65	4.19	3.56	ns
	–1	0.60	1.82	0.04	0.78	0.43	1.85	1.32	2.54	3.11	3.56	3.03	ns

Notes:

1. Software default selection highlighted in gray.
2. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-60 • 3.3 V LVTTTL / 3.3 V LVCMOS Low Slew – Applies to 1.2 V DC Core Voltage
 Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$, Worst-Case $V_{CCI} = 3.0\text{ V}$
 Applicable to Standard Plus I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
4 mA	Std.	0.70	4.61	0.05	0.90	0.50	4.70	3.91	2.05	1.99	6.71	5.92	ns
	–1	0.60	3.92	0.04	0.77	0.43	4.00	3.32	1.74	1.69	5.71	5.04	ns
6 mA	Std.	0.70	3.80	0.05	0.90	0.50	3.87	3.40	2.32	2.47	5.88	5.41	ns
	–1	0.60	3.23	0.04	0.77	0.43	3.29	2.89	1.98	2.10	5.00	4.60	ns
8 mA	Std.	0.70	3.80	0.05	0.90	0.50	3.87	3.40	2.32	2.47	5.88	5.41	ns
	–1	0.60	3.23	0.04	0.77	0.43	3.29	2.89	1.98	2.10	5.00	4.60	ns
12 mA	Std.	0.70	3.22	0.05	0.90	0.50	3.28	3.00	2.51	2.77	5.30	5.01	ns
	–1	0.60	2.74	0.04	0.77	0.43	2.79	2.55	2.14	2.36	4.51	4.27	ns
16 mA	Std.	0.70	3.22	0.05	0.90	0.50	3.28	3.00	2.51	2.77	5.30	5.01	ns
	–1	0.60	2.74	0.04	0.77	0.43	2.79	2.55	2.14	2.36	4.51	4.27	ns

Notes:

1. Software default selection highlighted in gray.
2. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-61 • 3.3 V LVTTTL / 3.3 V LVCMOS High Slew – Applies to 1.2 V DC Core Voltage
 Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$, Worst-Case $V_{CCI} = 3.0\text{ V}$
 Applicable to Standard Plus I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
4 mA	Std.	0.70	2.51	0.05	0.90	0.50	2.56	2.01	2.05	2.10	4.57	4.02	ns
	–1	0.60	2.14	0.04	0.77	0.43	2.18	1.71	1.74	1.79	3.89	3.42	ns
6 mA	Std.	0.70	2.05	0.05	0.90	0.50	2.09	1.61	2.32	2.59	4.10	3.62	ns
	–1	0.60	1.74	0.04	0.77	0.43	1.78	1.37	1.97	2.20	3.49	3.08	ns
8 mA	Std.	0.70	2.05	0.05	0.90	0.50	2.09	1.61	2.32	2.59	4.10	3.62	ns
	–1	0.60	1.74	0.04	0.77	0.43	1.78	1.37	1.97	2.20	3.49	3.08	ns
12 mA	Std.	0.70	1.83	0.05	0.90	0.50	1.86	1.41	2.51	2.90	3.88	3.42	ns
	–1	0.60	1.56	0.04	0.77	0.43	1.59	1.20	2.14	2.47	3.30	2.91	ns
16 mA	Std.	0.70	1.83	0.05	0.90	0.50	1.86	1.41	2.51	2.90	3.88	3.42	ns
	–1	0.60	1.56	0.04	0.77	0.43	1.59	1.20	2.14	2.47	3.30	2.91	ns

Notes:

1. Software default selection highlighted in gray.
2. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

2.5 V LVCMOS

Low-Voltage CMOS for 2.5 V is an extension of the LVCMOS standard (JESD8-5) used for general-purpose 2.5 V applications. It uses a 5 V-tolerant input buffer and push-pull output buffer.

Table 2-62 • Minimum and Maximum DC Input and Output Levels
Applicable to Pro I/Os

2.5 V LVCMOS	V_{IL}		V_{IH}		V_{OL}	V_{OH}	I_{OL}	I_{OH}	I_{OSL}	I_{OSH}	I_{IL}	I_{IH}
Drive Strength	Min., V	Max., V	Min., V	Max., V	Max., V	Min., V	mA	mA	Max., mA ¹	Max., mA ¹	μA^2	μA^2
4 mA	−0.3	0.7	1.7	2.7	0.7	1.7	4	4	16	18	10	10
8 mA	−0.3	0.7	1.7	2.7	0.7	1.7	8	8	32	37	10	10
12 mA	−0.3	0.7	1.7	2.7	0.7	1.7	12	12	65	74	10	10
16 mA	−0.3	0.7	1.7	2.7	0.7	1.7	16	16	83	87	10	10
24 mA	−0.3	0.7	1.7	2.7	0.7	1.7	24	24	169	124	10	10

Notes:

1. Currents are measured at 100°C junction temperature and maximum voltage.
2. Currents are measured at 85°C junction temperature.
3. Software default selection highlighted in gray.

Table 2-63 • Minimum and Maximum DC Input and Output Levels
Applicable to Advanced I/O Banks

2.5 V LVCMOS	V_{IL}		V_{IH}		V_{OL}	V_{OH}	I_{OL}	I_{OH}	I_{OSL}	I_{OSH}	I_{IL}	I_{IH}
Drive Strength	Min., V	Max., V	Min., V	Max., V	Max., V	Min., V	mA	mA	Max., mA ¹	Max., mA ¹	μA^2	μA^2
2 mA	−0.3	0.7	1.7	2.7	0.7	1.7	2	2	16	18	10	10
4 mA	−0.3	0.7	1.7	2.7	0.7	1.7	4	4	16	18	10	10
6 mA	−0.3	0.7	1.7	2.7	0.7	1.7	6	6	32	37	10	10
8 mA	−0.3	0.7	1.7	2.7	0.7	1.7	8	8	32	37	10	10
12 mA	−0.3	0.7	1.7	2.7	0.7	1.7	12	12	65	74	10	10
16 mA	−0.3	0.7	1.7	2.7	0.7	1.7	16	16	83	87	10	10
24 mA	−0.3	0.7	1.7	2.7	0.7	1.7	24	24	169	124	10	10

Notes:

1. Currents are measured at 100°C junction temperature and maximum voltage.
2. Currents are measured at 85°C junction temperature.
3. Software default selection highlighted in gray.

Table 2-64 • Minimum and Maximum DC Input and Output Levels
Applicable to Standard Plus I/O Banks

2.5 V LVCMOS	V_{IL}		V_{IH}		V_{OL}	V_{OH}	I_{OL}	I_{OH}	I_{OSL}	I_{OSH}	I_{IL}	I_{IH}
Drive Strength	Min., V	Max., V	Min., V	Max., V	Max., V	Min., V	mA	mA	Max., mA ¹	Max., mA ¹	μA^2	μA^2
2 mA	-0.3	0.7	1.7	2.7	0.7	1.7	2	2	16	18	10	10
4 mA	-0.3	0.7	1.7	2.7	0.7	1.7	4	4	16	18	10	10
6 mA	-0.3	0.7	1.7	2.7	0.7	1.7	6	6	32	37	10	10
8 mA	-0.3	0.7	1.7	2.7	0.7	1.7	8	8	32	37	10	10
12 mA	-0.3	0.7	1.7	2.7	0.7	1.7	12	12	65	74	10	10

Notes:

1. Currents are measured at 100°C junction temperature and maximum voltage.
2. Currents are measured at 85°C junction temperature.
3. Software default selection highlighted in gray.

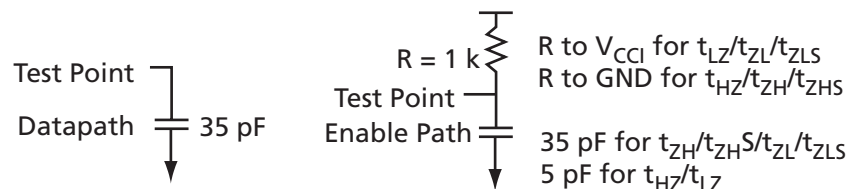


Figure 2-8 • AC Loading

Table 2-65 • AC Waveforms, Measuring Points, and Capacitive Loads

Input LOW (V)	Input HIGH (V)	Measuring Point* (V)	C_{LOAD} (pF)
0	2.5	1.2	5

* Measuring point = V_{trip} . See Table 2-26 on page 2-25 for a complete table of trip points.

Timing Characteristics

1.5 V DC Core Voltage

Table 2-66 • 2.5 V LVC MOS Low Slew – Applies to 1.5 V DC Core Voltage
Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$, Worst-Case $V_{CCI} = 2.3\text{ V}$
Applicable to Pro I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{PYS}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
4 mA	Std.	0.59	6.24	0.04	1.86	2.31	0.38	6.36	5.30	2.45	1.98	8.37	7.31	ns
	–1	0.50	5.31	0.03	1.58	1.97	0.33	5.41	4.51	2.08	1.68	7.12	6.22	ns
8 mA	Std.	0.59	5.10	0.04	1.86	2.31	0.38	5.20	4.49	2.79	2.64	7.21	6.50	ns
	–1	0.50	4.34	0.03	1.58	1.97	0.33	4.42	3.82	2.37	2.24	6.13	5.53	ns
12 mA	Std.	0.59	4.29	0.04	1.86	2.31	0.38	4.37	3.91	3.03	3.05	6.39	5.92	ns
	–1	0.50	3.65	0.03	1.58	1.97	0.33	3.72	3.32	2.58	2.60	5.43	5.04	ns
16 mA	Std.	0.59	4.05	0.04	1.86	2.31	0.38	4.12	3.78	3.08	3.17	6.13	5.79	ns
	–1	0.50	3.44	0.03	1.58	1.97	0.33	3.51	3.22	2.62	2.70	5.22	4.93	ns
24 mA	Std.	0.59	3.94	0.04	1.86	2.31	0.38	4.01	3.80	3.15	3.60	6.03	5.81	ns
	–1	0.50	3.35	0.03	1.58	1.97	0.33	3.41	3.23	2.68	3.06	5.13	4.94	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-67 • 2.5 V LVC MOS High Slew – Applies to 1.5 V DC Core Voltage
Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$, Worst-Case $V_{CCI} = 2.3\text{ V}$
Applicable to Pro I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{PYS}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
4 mA	Std.	0.59	3.18	0.04	1.86	2.31	0.38	3.24	2.84	2.45	2.06	5.25	4.85	ns
	–1	0.50	2.71	0.03	1.58	1.97	0.33	2.76	2.42	2.08	1.75	4.47	4.13	ns
8 mA	Std.	0.59	2.61	0.04	1.86	2.31	0.38	2.65	2.19	2.79	2.73	4.67	4.20	ns
	–1	0.50	2.22	0.03	1.58	1.97	0.33	2.26	1.86	2.37	2.32	3.97	3.57	ns
12 mA	Std.	0.59	2.26	0.04	1.86	2.31	0.38	2.30	1.86	3.03	3.15	4.32	3.88	ns
	–1	0.50	1.92	0.03	1.58	1.97	0.33	1.96	1.59	2.58	2.68	3.67	3.30	ns
16 mA	Std.	0.59	2.20	0.04	1.86	2.31	0.38	2.24	1.80	3.08	3.26	4.26	3.82	ns
	–1	0.50	1.87	0.03	1.58	1.97	0.33	1.91	1.54	2.62	2.77	3.62	3.25	ns
24 mA	Std.	0.59	2.21	0.04	1.86	2.31	0.38	2.25	1.73	3.15	3.70	4.27	3.74	ns
	–1	0.50	1.88	0.03	1.58	1.97	0.33	1.92	1.47	2.68	3.14	3.63	3.18	ns

Notes:

1. Software default selection highlighted in gray.
2. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-68 • 2.5 V LVCMOS Low Slew – Applies to 1.5 V DC Core Voltage
 Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$, Worst-Case $V_{CCI} = 2.3\text{ V}$
 Applicable to Advanced I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
4 mA	Std.	0.54	5.79	0.04	1.18	0.38	5.90	5.18	2.41	1.98	7.91	7.19	ns
	–1	0.46	4.92	0.03	1.00	0.33	5.01	4.40	2.05	1.69	6.73	6.11	ns
6 mA	Std.	0.54	4.84	0.04	1.18	0.38	4.93	4.43	2.74	2.60	6.94	6.44	ns
	–1	0.46	4.11	0.03	1.00	0.33	4.19	3.77	2.33	2.21	5.90	5.48	ns
8 mA	Std.	0.54	4.84	0.04	1.18	0.38	4.93	4.43	2.74	2.60	6.94	6.44	ns
	–1	0.46	4.11	0.03	1.00	0.33	4.19	3.77	2.33	2.21	5.90	5.48	ns
12 mA	Std.	0.54	4.13	0.04	1.18	0.38	4.21	3.92	2.97	2.99	6.22	5.93	ns
	–1	0.46	3.52	0.03	1.00	0.33	3.58	3.33	2.53	2.54	5.29	5.04	ns
16 mA	Std.	0.54	3.91	0.04	1.18	0.38	3.98	3.80	3.02	3.09	5.99	5.81	ns
	–1	0.46	3.32	0.03	1.00	0.33	3.39	3.23	2.57	2.63	5.10	4.94	ns
24 mA	Std.	0.54	3.85	0.04	1.18	0.38	3.87	3.85	3.09	3.48	5.88	5.87	ns
	–1	0.46	3.28	0.03	1.00	0.33	3.29	3.28	2.63	2.96	5.01	4.99	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-69 • 2.5 V LVCMOS High Slew – Applies to 1.5 V DC Core Voltage
 Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$, Worst-Case $V_{CCI} = 2.3\text{ V}$
 Applicable to Advanced I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
4 mA	Std.	0.54	2.97	0.04	1.18	0.38	3.03	2.74	2.41	2.07	5.04	4.75	ns
	–1	0.46	2.53	0.03	1.00	0.33	2.58	2.33	2.05	1.76	4.29	4.04	ns
6 mA	Std.	0.54	2.44	0.04	1.18	0.38	2.49	2.12	2.74	2.70	4.50	4.13	ns
	–1	0.46	2.08	0.03	1.00	0.33	2.12	1.80	2.33	2.30	3.83	3.51	ns
8 mA	Std.	0.54	2.44	0.04	1.18	0.38	2.49	2.12	2.74	2.70	4.50	4.13	ns
	–1	0.46	2.08	0.03	1.00	0.33	2.12	1.80	2.33	2.30	3.83	3.51	ns
12 mA	Std.	0.54	2.17	0.04	1.18	0.38	2.21	1.82	2.97	3.09	4.22	3.83	ns
	–1	0.46	1.85	0.03	1.00	0.33	1.88	1.55	2.53	2.63	3.59	3.26	ns
16 mA	Std.	0.54	2.12	0.04	1.18	0.38	2.16	1.76	3.03	3.19	4.17	3.78	ns
	–1	0.46	1.81	0.03	1.00	0.33	1.84	1.50	2.57	2.72	3.55	3.21	ns
24 mA	Std.	0.54	2.13	0.04	1.18	0.38	2.17	1.71	3.09	3.60	4.19	3.72	ns
	–1	0.46	1.81	0.03	1.00	0.33	1.85	1.45	2.63	3.06	3.56	3.16	ns

Notes:

1. Software default selection highlighted in gray.
2. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-70 • 2.5 V LVCMOS Low Slew – Applies to 1.5 V DC Core Voltage
Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$, Worst-Case $V_{CCI} = 2.3\text{ V}$
Applicable to Standard Plus I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
4 mA	Std.	0.54	5.27	0.04	1.17	0.38	5.37	4.68	2.03	1.79	7.38	6.69	ns
	–1	0.46	4.49	0.03	0.99	0.33	4.57	3.98	1.73	1.52	6.28	5.69	ns
6 mA	Std.	0.54	4.32	0.04	1.17	0.38	4.40	4.03	2.33	2.35	6.42	6.04	ns
	–1	0.46	3.68	0.03	0.99	0.33	3.75	3.43	1.98	2.00	5.46	5.14	ns
8 mA	Std.	0.54	4.32	0.04	1.17	0.38	4.40	4.03	2.33	2.35	6.42	6.04	ns
	–1	0.46	3.68	0.03	0.99	0.33	3.75	3.43	1.98	2.00	5.46	5.14	ns
12 mA	Std.	0.54	3.66	0.04	1.17	0.38	3.73	3.56	2.54	2.71	5.74	5.57	ns
	–1	0.46	3.12	0.03	0.99	0.33	3.17	3.03	2.16	2.30	4.89	4.74	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-71 • 2.5 V LVCMOS High Slew – Applies to 1.5 V DC Core Voltage
Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$, Worst-Case $V_{CCI} = 2.3\text{ V}$
Applicable to Standard Plus I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
4 mA	Std.	0.54	2.60	0.04	1.17	0.38	2.65	2.39	2.03	1.87	4.66	4.40	ns
	–1	0.46	2.21	0.03	0.99	0.33	2.25	2.03	1.72	1.59	3.96	3.74	ns
6 mA	Std.	0.54	2.10	0.04	1.17	0.38	2.14	1.83	2.33	2.44	4.16	3.84	ns
	–1	0.46	1.79	0.03	0.99	0.33	1.82	1.56	1.98	2.07	3.54	3.27	ns
8 mA	Std.	0.54	2.10	0.04	1.17	0.38	2.14	1.83	2.33	2.44	4.16	3.84	ns
	–1	0.46	1.79	0.03	0.99	0.33	1.82	1.56	1.98	2.07	3.54	3.27	ns
12 mA	Std.	0.54	1.86	0.04	1.17	0.38	1.90	1.55	2.54	2.80	3.91	3.57	ns
	–1	0.46	1.59	0.03	0.99	0.33	1.61	1.32	2.16	2.38	3.33	3.03	ns

Notes:

1. Software default selection highlighted in gray.
2. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

1.2 V DC Core Voltage

Table 2-72 • 2.5 V LVCMOS Low Slew – Applies to 1.2 V DC Core Voltage

Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$, Worst-Case $V_{CCI} = 2.3\text{ V}$
Applicable to Pro I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{PYS}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
4 mA	Std.	0.77	6.24	0.05	1.86	2.31	0.50	6.36	5.30	2.45	1.98	8.37	7.31	ns
	–1	0.66	5.31	0.04	1.58	1.97	0.43	5.41	4.51	2.08	1.68	7.12	6.22	ns
8 mA	Std.	0.77	5.10	0.05	1.86	2.31	0.50	5.20	4.49	2.79	2.64	7.21	6.50	ns
	–1	0.66	4.34	0.04	1.58	1.97	0.43	4.42	3.82	2.37	2.24	6.13	5.53	ns
12 mA	Std.	0.77	4.29	0.05	1.86	2.31	0.50	4.37	3.91	3.03	3.05	6.39	5.92	ns
	–1	0.66	3.65	0.04	1.58	1.97	0.43	3.72	3.32	2.58	2.60	5.43	5.04	ns
16 mA	Std.	0.77	4.05	0.05	1.86	2.31	0.50	4.12	3.78	3.08	3.17	6.13	5.79	ns
	–1	0.66	3.44	0.04	1.58	1.97	0.43	3.51	3.22	2.62	2.70	5.22	4.93	ns
24 mA	Std.	0.77	3.94	0.05	1.86	2.31	0.50	4.01	3.80	3.15	3.60	6.03	5.81	ns
	–1	0.66	3.35	0.04	1.58	1.97	0.43	3.41	3.23	2.68	3.06	5.13	4.94	ns

Notes:

1. Software default selection highlighted in gray.
2. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-73 • 2.5 V LVCMOS High Slew – Applies to 1.2 V DC Core Voltage

Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$, Worst-Case $V_{CCI} = 2.3\text{ V}$
Applicable to Pro I/Os

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{PYS}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
4 mA	Std.	0.77	3.18	0.05	1.86	2.31	0.50	3.24	2.84	2.45	2.06	5.25	4.85	ns
	–1	0.66	2.71	0.04	1.58	1.97	0.43	2.76	2.42	2.08	1.75	4.47	4.13	ns
8 mA	Std.	0.77	2.61	0.05	1.86	2.31	0.50	2.65	2.19	2.79	2.73	4.67	4.20	ns
	–1	0.66	2.22	0.04	1.58	1.97	0.43	2.26	1.86	2.37	2.32	3.97	3.57	ns
12 mA	Std.	0.77	2.26	0.05	1.86	2.31	0.50	2.30	1.86	3.03	3.15	4.32	3.88	ns
	–1	0.66	1.92	0.04	1.58	1.97	0.43	1.96	1.59	2.58	2.68	3.67	3.30	ns
16 mA	Std.	0.77	2.20	0.05	1.86	2.31	0.50	2.24	1.80	3.08	3.26	4.26	3.82	ns
	–1	0.66	1.87	0.04	1.58	1.97	0.43	1.91	1.54	2.62	2.77	3.62	3.25	ns
24 mA	Std.	0.77	2.21	0.05	1.86	2.31	0.50	2.25	1.73	3.15	3.70	4.27	3.74	ns
	–1	0.66	1.88	0.04	1.58	1.97	0.43	1.92	1.47	2.68	3.14	3.63	3.18	ns

Notes:

1. Software default selection highlighted in gray.
2. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-74 • 2.5 V LVC MOS Low Slew – Applies to 1.2 V DC Core Voltage
Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$, Worst-Case $V_{CCI} = 2.3\text{ V}$
Applicable to Advanced I/Os

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
4 mA	Std.	0.70	5.79	0.05	1.18	0.50	5.90	5.18	2.41	1.98	7.91	7.19	ns
	–1	0.60	4.92	0.04	1.00	0.43	5.01	4.40	2.05	1.69	6.73	6.11	ns
6 mA	Std.	0.70	4.84	0.05	1.18	0.50	4.93	4.43	2.74	2.60	6.94	6.44	ns
	–1	0.60	4.11	0.04	1.00	0.43	4.19	3.77	2.33	2.21	5.90	5.48	ns
8 mA	Std.	0.70	4.84	0.05	1.18	0.50	4.93	4.43	2.74	2.60	6.94	6.44	ns
	–1	0.60	4.11	0.04	1.00	0.43	4.19	3.77	2.33	2.21	5.90	5.48	ns
12 mA	Std.	0.70	4.13	0.05	1.18	0.50	4.21	3.92	2.97	2.99	6.22	5.93	ns
	–1	0.60	3.52	0.04	1.00	0.43	3.58	3.33	2.53	2.54	5.29	5.04	ns
16 mA	Std.	0.70	3.91	0.05	1.18	0.50	3.98	3.80	3.02	3.09	5.99	5.81	ns
	–1	0.60	3.32	0.04	1.00	0.43	3.39	3.23	2.57	2.63	5.10	4.94	ns
24 mA	Std.	0.70	3.85	0.05	1.18	0.50	3.87	3.85	3.09	3.48	5.88	5.87	ns
	–1	0.60	3.28	0.04	1.00	0.43	3.29	3.28	2.63	2.96	5.01	4.99	ns

Notes:

1. Software default selection highlighted in gray.
2. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-75 • 2.5 V LVC MOS High Slew – Applies to 1.2 V DC Core Voltage
Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$, Worst-Case $V_{CCI} = 2.3\text{ V}$
Applicable to Advanced I/Os

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
4 mA	Std.	0.70	2.97	0.05	1.18	0.50	3.03	2.74	2.41	2.07	5.04	4.75	ns
	–1	0.60	2.53	0.04	1.00	0.43	2.58	2.33	2.05	1.76	4.29	4.04	ns
6 mA	Std.	0.70	2.44	0.05	1.18	0.50	2.49	2.12	2.74	2.70	4.50	4.13	ns
	–1	0.60	2.08	0.04	1.00	0.43	2.12	1.80	2.33	2.30	3.83	3.51	ns
8 mA	Std.	0.70	2.44	0.05	1.18	0.50	2.49	2.12	2.74	2.70	4.50	4.13	ns
	–1	0.60	2.08	0.04	1.00	0.43	2.12	1.80	2.33	2.30	3.83	3.51	ns
12 mA	Std.	0.70	2.17	0.05	1.18	0.50	2.21	1.82	2.97	3.09	4.22	3.83	ns
	–1	0.60	1.85	0.04	1.00	0.43	1.88	1.55	2.53	2.63	3.59	3.26	ns
16 mA	Std.	0.70	2.12	0.05	1.18	0.50	2.16	1.76	3.03	3.19	4.17	3.78	ns
	–1	0.60	1.81	0.04	1.00	0.43	1.84	1.50	2.57	2.72	3.55	3.21	ns
24 mA	Std.	0.70	2.13	0.05	1.18	0.50	2.17	1.71	3.09	3.60	4.19	3.72	ns
	–1	0.60	1.81	0.04	1.00	0.43	1.85	1.45	2.63	3.06	3.56	3.16	ns

Notes:

1. Software default selection highlighted in gray.
2. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-76 • 2.5 V LVCMOS Low Slew – Applies to 1.2 V DC Core Voltage
 Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$, Worst-Case $V_{CCI} = 2.3\text{ V}$
 Applicable to Standard Plus I/Os

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
4 mA	Std.	0.70	5.27	0.05	1.17	0.50	5.37	4.68	2.03	1.79	7.38	6.69	ns
	–1	0.60	4.49	0.04	0.99	0.43	4.57	3.98	1.73	1.52	6.28	5.69	ns
6 mA	Std.	0.70	4.32	0.05	1.17	0.50	4.40	4.03	2.33	2.35	6.42	6.04	ns
	–1	0.60	3.68	0.04	0.99	0.43	3.75	3.43	1.98	2.00	5.46	5.14	ns
8 mA	Std.	0.70	4.32	0.05	1.17	0.50	4.40	4.03	2.33	2.35	6.42	6.04	ns
	–1	0.60	3.68	0.04	0.99	0.43	3.75	3.43	1.98	2.00	5.46	5.14	ns
12 mA	Std.	0.70	3.66	0.05	1.17	0.50	3.73	3.56	2.54	2.71	5.74	5.57	ns
	–1	0.60	3.12	0.04	0.99	0.43	3.17	3.03	2.16	2.30	4.89	4.74	ns

Notes:

1. Software default selection highlighted in gray.
2. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-77 • 2.5 V LVCMOS High Slew – Applies to 1.2 V DC Core Voltage
 Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$, Worst-Case $V_{CCI} = 2.3\text{ V}$
 Applicable to Standard Plus I/Os

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
4 mA	Std.	0.70	2.60	0.05	1.17	0.50	2.65	2.39	2.03	1.87	4.66	4.40	ns
	–1	0.60	2.21	0.04	0.99	0.43	2.25	2.03	1.72	1.59	3.96	3.74	ns
6 mA	Std.	0.70	2.10	0.05	1.17	0.50	2.14	1.83	2.33	2.44	4.16	3.84	ns
	–1	0.60	1.79	0.04	0.99	0.43	1.82	1.56	1.98	2.07	3.54	3.27	ns
8 mA	Std.	0.70	2.10	0.05	1.17	0.50	2.14	1.83	2.33	2.44	4.16	3.84	ns
	–1	0.60	1.79	0.04	0.99	0.43	1.82	1.56	1.98	2.07	3.54	3.27	ns
12 mA	Std.	0.70	1.86	0.05	1.17	0.50	1.90	1.55	2.54	2.80	3.91	3.57	ns
	–1	0.60	1.59	0.04	0.99	0.43	1.61	1.32	2.16	2.38	3.33	3.03	ns

Notes:

1. Software default selection highlighted in gray.
2. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

1.8 V LVCMOS

Low-voltage CMOS for 1.8 V is an extension of the LVCMOS standard (JESD8-5) used for general-purpose 1.8 V applications. It uses a 1.8 V input buffer and a push-pull output buffer.

Table 2-78 • Minimum and Maximum DC Input and Output Levels
Applicable to Pro I/Os

1.8 V LVCMOS	V_{IL}		V_{IH}		V_{OL}	V_{OH}	I_{OL}	I_{OH}	I_{OSL}	I_{OSH}	I_{IL}	I_{IH}
Drive Strength	Min., V	Max., V	Min., V	Max., V	Max., V	Min., V	mA	mA	Max., mA ¹	Max., mA ¹	μA^2	μA^2
2 mA	−0.3	$0.35 * V_{CCI}$	$0.65 * V_{CCI}$	1.9	0.45	$V_{CCI} - 0.45$	2	2	9	11	10	10
4 mA	−0.3	$0.35 * V_{CCI}$	$0.65 * V_{CCI}$	1.9	0.45	$V_{CCI} - 0.45$	4	4	17	22	10	10
6 mA	−0.3	$0.35 * V_{CCI}$	$0.65 * V_{CCI}$	1.9	0.45	$V_{CCI} - 0.45$	6	6	35	44	10	10
8 mA	−0.3	$0.35 * V_{CCI}$	$0.65 * V_{CCI}$	1.9	0.45	$V_{CCI} - 0.45$	8	8	45	51	10	10
12 mA	−0.3	$0.35 * V_{CCI}$	$0.65 * V_{CCI}$	1.9	0.45	$V_{CCI} - 0.45$	12	12	91	74	10	10
16 mA	−0.3	$0.35 * V_{CCI}$	$0.65 * V_{CCI}$	1.9	0.45	$V_{CCI} - 0.45$	16	16	91	74	10	10

Notes:

1. Currents are measured at 100°C junction temperature and maximum voltage.
2. Currents are measured at 85°C junction temperature.
3. Software default selection highlighted in gray.

Table 2-79 • Minimum and Maximum DC Input and Output Levels
Applicable to Advanced I/O Banks

1.8 V LVCMOS	V_{IL}		V_{IH}		V_{OL}	V_{OH}	I_{OL}	I_{OH}	I_{OSL}	I_{OSH}	I_{IL}	I_{IH}
Drive Strength	Min., V	Max., V	Min., V	Max., V	Max., V	Min., V	mA	mA	Max., mA ¹	Max., mA ¹	μA^2	μA^2
2 mA	−0.3	$0.35 * V_{CCI}$	$0.65 * V_{CCI}$	1.9	0.45	$V_{CCI} - 0.45$	2	2	9	11	10	10
4 mA	−0.3	$0.35 * V_{CCI}$	$0.65 * V_{CCI}$	1.9	0.45	$V_{CCI} - 0.45$	4	4	17	22	10	10
6 mA	−0.3	$0.35 * V_{CCI}$	$0.65 * V_{CCI}$	1.9	0.45	$V_{CCI} - 0.45$	6	6	35	44	10	10
8 mA	−0.3	$0.35 * V_{CCI}$	$0.65 * V_{CCI}$	1.9	0.45	$V_{CCI} - 0.45$	8	8	45	51	10	10
12 mA	−0.3	$0.35 * V_{CCI}$	$0.65 * V_{CCI}$	1.9	0.45	$V_{CCI} - 0.45$	12	12	91	74	10	10
16 mA	−0.3	$0.35 * V_{CCI}$	$0.65 * V_{CCI}$	1.9	0.45	$V_{CCI} - 0.45$	16	16	91	74	10	10

Notes:

1. Currents are measured at 100°C junction temperature and maximum voltage.
2. Currents are measured at 85°C junction temperature.
3. Software default selection highlighted in gray.

Table 2-80 • Minimum and Maximum DC Input and Output Levels
Applicable to Standard Plus I/O I/O Banks

1.8 V LVCMOS	V_{IL}		V_{IH}		V_{OL}	V_{OH}	I_{OL}	I_{OH}	I_{OSL}	I_{OSH}	I_{IL}	I_{IH}
Drive Strength	Min., V	Max., V	Min., V	Max., V	Max., V	Min., V	mA	mA	Max., mA ¹	Max., mA ¹	μA^2	μA^2
2 mA	−0.3	$0.35 * V_{CC1}$	$0.65 * V_{CC1}$	1.9	0.45	$V_{CC1} - 0.45$	2	2	9	11	10	10
4 mA	−0.3	$0.35 * V_{CC1}$	$0.65 * V_{CC1}$	1.9	0.45	$V_{CC1} - 0.45$	4	4	17	22	10	10
6 mA	−0.3	$0.35 * V_{CC1}$	$0.65 * V_{CC1}$	1.9	0.45	$V_{CC1} - 0.45$	6	6	35	44	10	10
8 mA	−0.3	$0.35 * V_{CC1}$	$0.65 * V_{CC1}$	1.9	0.45	$V_{CC1} - 0.45$	8	8	35	44	10	10

Notes:

1. Currents are measured at 100°C junction temperature and maximum voltage.
2. Currents are measured at 85°C junction temperature.
3. Software default selection highlighted in gray.

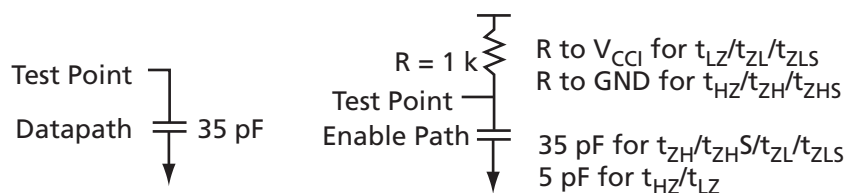


Figure 2-9 • AC Loading

Table 2-81 • AC Waveforms, Measuring Points, and Capacitive Loads

Input LOW (V)	Input HIGH (V)	Measuring Point* (V)	C_{LOAD} (pF)
0	1.8	0.9	5

* Measuring point = V_{trip} . See Table 2-26 on page 2-25 for a complete table of trip points.

Timing Characteristics

1.5 V DC Core Voltage

Table 2-82 • 1.8 V LVCMOS Low Slew – Applies to 1.5 V DC Core Voltage
Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$, Worst-Case $V_{CCI} = 1.7\text{ V}$
Applicable to Pro I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{PYS}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
2 mA	Std.	0.59	8.32	0.04	1.80	2.55	0.38	8.48	6.99	2.50	1.42	10.49	9.00	ns
	–1	0.50	7.08	0.03	1.53	2.17	0.33	7.21	5.95	2.13	1.21	8.92	7.66	ns
4 mA	Std.	0.59	6.85	0.04	1.80	2.55	0.38	6.98	5.89	2.93	2.50	8.99	7.90	ns
	–1	0.50	5.83	0.03	1.53	2.17	0.33	5.94	5.01	2.49	2.12	7.65	6.72	ns
6 mA	Std.	0.59	5.81	0.04	1.80	2.55	0.38	5.92	5.13	3.21	3.02	7.93	7.15	ns
	–1	0.50	4.94	0.03	1.53	2.17	0.33	5.03	4.37	2.73	2.57	6.75	6.08	ns
8 mA	Std.	0.59	5.46	0.04	1.80	2.55	0.38	5.56	4.99	3.28	3.17	7.57	7.00	ns
	–1	0.50	4.64	0.03	1.53	2.17	0.33	4.73	4.24	2.79	2.70	6.44	5.95	ns
12 mA	Std.	0.59	5.36	0.04	1.80	2.55	0.38	5.46	4.99	3.37	3.70	7.47	7.01	ns
	–1	0.50	4.56	0.03	1.53	2.17	0.33	4.64	4.25	2.86	3.14	6.35	5.96	ns
16 mA	Std.	0.59	5.36	0.04	1.80	2.55	0.38	5.46	4.99	3.37	3.70	7.47	7.01	ns
	–1	0.50	4.56	0.03	1.53	2.17	0.33	4.64	4.25	2.86	3.14	6.35	5.96	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-83 • 1.8 V LVCMOS High Slew – Applies to 1.5 V DC Core Voltage
Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$, Worst-Case $V_{CCI} = 1.7\text{ V}$
Applicable to Pro I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{PYS}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
2 mA	Std.	0.59	3.76	0.04	1.80	2.55	0.38	3.83	3.68	2.50	1.47	5.84	5.70	ns
	–1	0.50	3.20	0.03	1.53	2.17	0.33	3.26	3.13	2.13	1.25	4.97	4.85	ns
4 mA	Std.	0.59	3.05	0.04	1.80	2.55	0.38	3.11	2.73	2.92	2.58	5.12	4.75	ns
	–1	0.50	2.59	0.03	1.53	2.17	0.33	2.64	2.33	2.49	2.19	4.35	4.04	ns
6 mA	Std.	0.59	2.61	0.04	1.80	2.55	0.38	2.66	2.27	3.21	3.12	4.67	4.28	ns
	–1	0.50	2.22	0.03	1.53	2.17	0.33	2.26	1.93	2.73	2.65	3.98	3.64	ns
8 mA	Std.	0.59	2.53	0.04	1.80	2.55	0.38	2.58	2.18	3.27	3.26	4.59	4.19	ns
	–1	0.50	2.15	0.03	1.53	2.17	0.33	2.19	1.85	2.78	2.77	3.90	3.57	ns
12 mA	Std.	0.59	2.52	0.04	1.80	2.55	0.38	2.56	2.07	3.36	3.81	4.58	4.08	ns
	–1	0.50	2.14	0.03	1.53	2.17	0.33	2.18	1.76	2.86	3.24	3.89	3.47	ns
16 mA	Std.	0.59	2.52	0.04	1.80	2.55	0.38	2.56	2.07	3.36	3.81	4.58	4.08	ns
	–1	0.50	2.14	0.03	1.53	2.17	0.33	2.18	1.76	2.86	3.24	3.89	3.47	ns

Notes:

- Software default selection highlighted in gray.
- For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-84 • 1.8 V LVCMOS Low Slew – Applies to 1.5 V DC Core Voltage
 Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$, Worst-Case $V_{CCI} = 1.7\text{ V}$
 Applicable to Advanced I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
2 mA	Std.	0.54	7.77	0.04	1.18	0.38	7.92	6.80	2.50	1.44	9.93	8.81	ns
	–1	0.46	6.61	0.03	1.00	0.33	6.73	5.78	2.13	1.22	8.45	7.49	ns
4 mA	Std.	0.54	6.38	0.04	1.18	0.38	6.50	5.78	2.91	2.46	8.51	7.79	ns
	–1	0.46	5.43	0.03	1.00	0.33	5.53	4.91	2.47	2.09	7.24	6.63	ns
6 mA	Std.	0.54	5.48	0.04	1.18	0.38	5.58	5.11	3.18	2.94	7.59	7.12	ns
	–1	0.46	4.66	0.03	1.00	0.33	4.75	4.35	2.71	2.51	6.46	6.06	ns
8 mA	Std.	0.54	5.17	0.04	1.18	0.38	5.26	4.97	3.24	3.07	7.27	6.98	ns
	–1	0.46	4.40	0.03	1.00	0.33	4.48	4.23	2.76	2.61	6.19	5.94	ns
12 mA	Std.	0.54	5.06	0.04	1.18	0.38	5.15	5.03	3.34	3.55	7.17	7.04	ns
	–1	0.46	4.30	0.03	1.00	0.33	4.38	4.28	2.84	3.02	6.10	5.99	ns
16 mA	Std.	0.54	5.06	0.04	1.18	0.38	5.15	5.03	3.34	3.55	7.17	7.04	ns
	–1	0.46	4.30	0.03	1.00	0.33	4.38	4.28	2.84	3.02	6.10	5.99	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-85 • 1.8 V LVCMOS High Slew – Applies to 1.5 V DC Core Voltage
 Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$, Worst-Case $V_{CCI} = 1.7\text{ V}$
 Applicable to Advanced I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
2 mA	Std.	0.54	3.60	0.04	1.10	0.38	3.66	3.52	2.49	1.49	5.68	5.53	ns
	–1	0.46	3.06	0.03	0.93	0.33	3.12	3.00	2.12	1.27	4.83	4.71	ns
4 mA	Std.	0.54	2.81	0.04	1.10	0.38	2.87	2.64	2.90	2.55	4.88	4.65	ns
	–1	0.46	2.39	0.03	0.93	0.33	2.44	2.25	2.47	2.17	4.15	3.96	ns
6 mA	Std.	0.54	2.47	0.04	1.10	0.38	2.51	2.21	3.18	3.04	4.53	4.22	ns
	–1	0.46	2.10	0.03	0.93	0.33	2.14	1.88	2.70	2.59	3.85	3.59	ns
8 mA	Std.	0.54	2.40	0.04	1.10	0.38	2.45	2.13	3.24	3.17	4.46	4.14	ns
	–1	0.46	2.04	0.03	0.93	0.33	2.08	1.81	2.76	2.70	3.79	3.52	ns
12 mA	Std.	0.54	2.39	0.04	1.10	0.38	2.44	2.04	3.33	3.67	4.45	4.05	ns
	–1	0.46	2.04	0.03	0.93	0.33	2.08	1.73	2.83	3.12	3.79	3.45	ns
16 mA	Std.	0.54	2.39	0.04	1.10	0.38	2.44	2.04	3.33	3.67	4.45	4.05	ns
	–1	0.46	2.04	0.03	0.93	0.33	2.08	1.73	2.83	3.12	3.79	3.45	ns

Notes:

1. Software default selection highlighted in gray.
2. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-86 • 1.8 V LVCMOS Low Slew – Applies to 1.5 V DC Core Voltage
Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$, Worst-Case $V_{CCI} = 1.7\text{ V}$
Applicable to Standard Plus I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
2 mA	Std.	0.54	7.21	0.04	1.17	0.38	7.35	6.14	2.03	1.32	9.36	8.16	ns
	–1	0.46	6.13	0.03	0.99	0.33	6.25	5.23	1.72	1.12	7.96	6.94	ns
4 mA	Std.	0.54	5.81	0.04	1.17	0.38	5.92	5.26	2.39	2.25	7.93	7.27	ns
	–1	0.46	4.94	0.03	0.99	0.33	5.03	4.47	2.03	1.91	6.74	6.19	ns
6 mA	Std.	0.54	4.96	0.04	1.17	0.38	5.05	4.65	2.64	2.69	7.06	6.66	ns
	–1	0.46	4.22	0.03	0.99	0.33	4.30	3.96	2.25	2.29	6.01	5.67	ns
8 mA	Std.	0.54	4.96	0.04	1.17	0.38	5.05	4.65	2.64	2.69	7.06	6.66	ns
	–1	0.46	4.22	0.03	0.99	0.33	4.30	3.96	2.25	2.29	6.01	5.67	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-87 • 1.8 V LVCMOS High Slew – Applies to 1.5 V DC Core Voltage
Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$, Worst-Case $V_{CCI} = 1.7\text{ V}$
Applicable to Standard Plus I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
2 mA	Std.	0.54	3.22	0.04	1.08	0.38	3.28	3.04	2.02	1.37	5.30	5.06	ns
	–1	0.46	2.74	0.03	0.92	0.33	2.79	2.59	1.72	1.17	4.50	4.30	ns
4 mA	Std.	0.54	2.48	0.04	1.08	0.38	2.53	2.25	2.38	2.34	4.54	4.26	ns
	–1	0.46	2.11	0.03	0.92	0.33	2.15	1.92	2.03	1.99	3.86	3.63	ns
6 mA	Std.	0.54	2.17	0.04	1.08	0.38	2.21	1.86	2.64	2.79	4.22	3.87	ns
	–1	0.46	1.85	0.03	0.92	0.33	1.88	1.58	2.24	2.37	3.59	3.29	ns
8 mA	Std.	0.54	2.17	0.04	1.08	0.38	2.21	1.86	2.64	2.79	4.22	3.87	ns
	–1	0.46	1.85	0.03	0.92	0.33	1.88	1.58	2.24	2.37	3.59	3.29	ns

Notes:

1. Software default selection highlighted in gray.
2. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

1.2 V DC Core Voltage

Table 2-88 • 1.8 V LVCMOS Low Slew – Applies to 1.2 V DC Core Voltage

Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$, Worst-Case $V_{CCI} = 1.7\text{ V}$
 Applicable to Pro I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{PYS}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
2 mA	Std.	0.77	8.32	0.05	1.80	2.55	0.50	8.48	6.99	2.50	1.42	10.49	9.00	ns
	–1	0.66	7.08	0.04	1.53	2.17	0.43	7.21	5.95	2.13	1.21	8.92	7.66	ns
4 mA	Std.	0.77	6.85	0.05	1.80	2.55	0.50	6.98	5.89	2.93	2.50	8.99	7.90	ns
	–1	0.66	5.83	0.04	1.53	2.17	0.43	5.94	5.01	2.49	2.12	7.65	6.72	ns
6 mA	Std.	0.77	5.81	0.05	1.80	2.55	0.50	5.92	5.13	3.21	3.02	7.93	7.15	ns
	–1	0.66	4.94	0.04	1.53	2.17	0.43	5.03	4.37	2.73	2.57	6.75	6.08	ns
8 mA	Std.	0.77	5.46	0.05	1.80	2.55	0.50	5.56	4.99	3.28	3.17	7.57	7.00	ns
	–1	0.66	4.64	0.04	1.53	2.17	0.43	4.73	4.24	2.79	2.70	6.44	5.95	ns
12 mA	Std.	0.77	5.36	0.05	1.80	2.55	0.50	5.46	4.99	3.37	3.70	7.47	7.01	ns
	–1	0.66	4.56	0.04	1.53	2.17	0.43	4.64	4.25	2.86	3.14	6.35	5.96	ns
16 mA	Std.	0.77	5.36	0.05	1.80	2.55	0.50	5.46	4.99	3.37	3.70	7.47	7.01	ns
	–1	0.66	4.56	0.04	1.53	2.17	0.43	4.64	4.25	2.86	3.14	6.35	5.96	ns

Notes:

1. Software default selection highlighted in gray.
2. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-89 • 1.8 V LVCMOS High Slew – Applies to 1.2 V DC Core Voltage

Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$, Worst-Case $V_{CCI} = 1.7\text{ V}$
 Applicable to Pro I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{PYS}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
2 mA	Std.	0.77	3.76	0.05	1.80	2.55	0.50	3.83	3.68	2.50	1.47	5.84	5.70	ns
	–1	0.66	3.20	0.04	1.53	2.17	0.43	3.26	3.13	2.13	1.25	4.97	4.85	ns
4 mA	Std.	0.77	3.05	0.05	1.80	2.55	0.50	3.11	2.73	2.92	2.58	5.12	4.75	ns
	–1	0.66	2.59	0.04	1.53	2.17	0.43	2.64	2.33	2.49	2.19	4.35	4.04	ns
6 mA	Std.	0.77	2.61	0.05	1.80	2.55	0.50	2.66	2.27	3.21	3.12	4.67	4.28	ns
	–1	0.66	2.22	0.04	1.53	2.17	0.43	2.26	1.93	2.73	2.65	3.98	3.64	ns
8 mA	Std.	0.77	2.53	0.05	1.80	2.55	0.50	2.58	2.18	3.27	3.26	4.59	4.19	ns
	–1	0.66	2.15	0.04	1.53	2.17	0.43	2.19	1.85	2.78	2.77	3.90	3.57	ns
12 mA	Std.	0.77	2.52	0.05	1.80	2.55	0.50	2.56	2.07	3.36	3.81	4.58	4.08	ns
	–1	0.66	2.14	0.04	1.53	2.17	0.43	2.18	1.76	2.86	3.24	3.89	3.47	ns
16 mA	Std.	0.77	2.52	0.05	1.80	2.55	0.50	2.56	2.07	3.36	3.81	4.58	4.08	ns
	–1	0.66	2.14	0.04	1.53	2.17	0.43	2.18	1.76	2.86	3.24	3.89	3.47	ns

Notes:

1. Software default selection highlighted in gray.
2. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-90 • 1.8 V LVC MOS Low Slew – Applies to 1.2 V DC Core Voltage
Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$, Worst-Case $V_{CCI} = 1.7\text{ V}$
Applicable to Advanced I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
2 mA	Std.	0.70	7.77	0.05	1.18	0.50	7.92	6.80	2.50	1.44	9.93	8.81	ns
	–1	0.60	6.61	0.04	1.00	0.43	6.73	5.78	2.13	1.22	8.45	7.49	ns
4 mA	Std.	0.70	6.38	0.05	1.18	0.50	6.50	5.78	2.91	2.46	8.51	7.79	ns
	–1	0.60	5.43	0.04	1.00	0.43	5.53	4.91	2.47	2.09	7.24	6.63	ns
6 mA	Std.	0.70	5.48	0.05	1.18	0.50	5.58	5.11	3.18	2.94	7.59	7.12	ns
	–1	0.60	4.66	0.04	1.00	0.43	4.75	4.35	2.71	2.51	6.46	6.06	ns
8 mA	Std.	0.70	5.17	0.05	1.18	0.50	5.26	4.97	3.24	3.07	7.27	6.98	ns
	–1	0.60	4.40	0.04	1.00	0.43	4.48	4.23	2.76	2.61	6.19	5.94	ns
12 mA	Std.	0.70	5.06	0.05	1.18	0.50	5.15	5.03	3.34	3.55	7.17	7.04	ns
	–1	0.60	4.30	0.04	1.00	0.43	4.38	4.28	2.84	3.02	6.10	5.99	ns
16 mA	Std.	0.70	5.06	0.05	1.18	0.50	5.15	5.03	3.34	3.55	7.17	7.04	ns
	–1	0.60	4.30	0.04	1.00	0.43	4.38	4.28	2.84	3.02	6.10	5.99	ns

Notes:

1. Software default selection highlighted in gray.
2. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-91 • 1.8 V LVC MOS High Slew – Applies to 1.2 V DC Core Voltage
Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$, Worst-Case $V_{CCI} = 1.7\text{ V}$
Applicable to Advanced I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
2 mA	Std.	0.70	3.60	0.05	1.10	0.50	3.66	3.52	2.49	1.49	5.68	5.53	ns
	–1	0.60	3.06	0.04	0.93	0.43	3.12	3.00	2.12	1.27	4.83	4.71	ns
4 mA	Std.	0.70	2.81	0.05	1.10	0.50	2.87	2.64	2.90	2.55	4.88	4.65	ns
	–1	0.60	2.39	0.04	0.93	0.43	2.44	2.25	2.47	2.17	4.15	3.96	ns
6 mA	Std.	0.70	2.47	0.05	1.10	0.50	2.51	2.21	3.18	3.04	4.53	4.22	ns
	–1	0.60	2.10	0.04	0.93	0.43	2.14	1.88	2.70	2.59	3.85	3.59	ns
8 mA	Std.	0.70	2.40	0.05	1.10	0.50	2.45	2.13	3.24	3.17	4.46	4.14	ns
	–1	0.60	2.04	0.04	0.93	0.43	2.08	1.81	2.76	2.70	3.79	3.52	ns
12 mA	Std.	0.70	2.39	0.05	1.10	0.50	2.44	2.04	3.33	3.67	4.45	4.05	ns
	–1	0.60	2.04	0.04	0.93	0.43	2.08	1.73	2.83	3.12	3.79	3.45	ns
16 mA	Std.	0.70	2.39	0.05	1.10	0.50	2.44	2.04	3.33	3.67	4.45	4.05	ns
	–1	0.60	2.04	0.04	0.93	0.43	2.08	1.73	2.83	3.12	3.79	3.45	ns

Notes:

1. Software default selection highlighted in gray.
2. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-92 • 1.8 V LVCMOS Low Slew – Applies to 1.2 V DC Core Voltage
Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$, Worst-Case $V_{CCI} = 1.7\text{ V}$
Applicable to Standard Plus I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
2 mA	Std.	0.70	7.21	0.05	1.17	0.50	7.35	6.14	2.03	1.32	9.36	8.16	ns
	–1	0.60	6.13	0.04	0.99	0.43	6.25	5.23	1.72	1.12	7.96	6.94	ns
4 mA	Std.	0.70	5.81	0.05	1.17	0.50	5.92	5.26	2.39	2.25	7.93	7.27	ns
	–1	0.60	4.94	0.04	0.99	0.43	5.03	4.47	2.03	1.91	6.74	6.19	ns
6 mA	Std.	0.70	4.96	0.05	1.17	0.50	5.05	4.65	2.64	2.69	7.06	6.66	ns
	–1	0.60	4.22	0.04	0.99	0.43	4.30	3.96	2.25	2.29	6.01	5.67	ns
8 mA	Std.	0.70	4.96	0.05	1.17	0.50	5.05	4.65	2.64	2.69	7.06	6.66	ns
	–1	0.60	4.22	0.04	0.99	0.43	4.30	3.96	2.25	2.29	6.01	5.67	ns

Notes:

1. Software default selection highlighted in gray.
2. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-93 • 1.8 V LVCMOS High Slew – Applies to 1.2 V DC Core Voltage
Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$, Worst-Case $V_{CCI} = 1.7\text{ V}$
Applicable to Standard Plus I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
2 mA	Std.	0.70	3.22	0.05	1.08	0.50	3.28	3.04	2.02	1.37	5.30	5.06	ns
	–1	0.60	2.74	0.04	0.92	0.43	2.79	2.59	1.72	1.17	4.50	4.30	ns
4 mA	Std.	0.70	2.48	0.05	1.08	0.50	2.53	2.25	2.38	2.34	4.54	4.26	ns
	–1	0.60	2.11	0.04	0.92	0.43	2.15	1.92	2.03	1.99	3.86	3.63	ns
6 mA	Std.	0.70	2.17	0.05	1.08	0.50	2.21	1.86	2.64	2.79	4.22	3.87	ns
	–1	0.60	1.85	0.04	0.92	0.43	1.88	1.58	2.24	2.37	3.59	3.29	ns
8 mA	Std.	0.70	2.17	0.05	1.08	0.50	2.21	1.86	2.64	2.79	4.22	3.87	ns
	–1	0.60	1.85	0.04	0.92	0.43	1.88	1.58	2.24	2.37	3.59	3.29	ns

Notes:

1. Software default selection highlighted in gray.
2. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

1.5 V LVCMOS (JESD8-11)

Low-Voltage CMOS for 1.5 V is an extension of the LVCMOS standard (JESD8-5) used for general-purpose 1.5 V applications. It uses a 1.5 V input buffer and a push-pull output buffer.

Table 2-94 • Minimum and Maximum DC Input and Output Levels
Applicable to Pro I/Os

1.5 V LVCMOS	V _{IL}		V _{IH}		V _{OL}	V _{OH}	I _{OL}	I _{OH}	I _{OSL}	I _{OSH}	I _{IL}	I _{IH}
Drive Strength	Min., V	Max., V	Min., V	Max., V	Max., V	Min., V	mA	mA	Max., mA ¹	Max., mA ¹	μA ²	μA ²
2 mA	−0.3	0.35 * V _{CCl}	0.65 * V _{CCl}	1.575	0.25 * V _{CCl}	0.75 * V _{CCl}	2	2	13	16	10	10
4 mA	−0.3	0.35 * V _{CCl}	0.65 * V _{CCl}	1.575	0.25 * V _{CCl}	0.75 * V _{CCl}	4	4	25	33	10	10
6 mA	−0.3	0.35 * V _{CCl}	0.65 * V _{CCl}	1.575	0.25 * V _{CCl}	0.75 * V _{CCl}	6	6	32	39	10	10
8 mA	−0.3	0.35 * V _{CCl}	0.65 * V _{CCl}	1.575	0.25 * V _{CCl}	0.75 * V _{CCl}	8	8	66	55	10	10
12 mA	−0.3	0.35 * V _{CCl}	0.65 * V _{CCl}	1.575	0.25 * V _{CCl}	0.75 * V _{CCl}	12	12	66	55	10	10

Notes:

1. Currents are measured at 100°C junction temperature and maximum voltage.
2. Currents are measured at 85°C junction temperature.
3. Software default selection highlighted in gray.

Table 2-95 • Minimum and Maximum DC Input and Output Levels
Applicable to Advanced I/O Banks

1.5 V LVCMOS	V _{IL}		V _{IH}		V _{OL}	V _{OH}	I _{OL}	I _{OH}	I _{OSL}	I _{OSH}	I _{IL}	I _{IH}
Drive Strength	Min., V	Max., V	Min., V	Max., V	Max., V	Min., V	mA	mA	Max., mA ¹	Max., mA ¹	μA ²	μA ²
2 mA	−0.3	0.35 * V _{CCl}	0.65 * V _{CCl}	1.575	0.25 * V _{CCl}	0.75 * V _{CCl}	2	2	13	16	10	10
4 mA	−0.3	0.35 * V _{CCl}	0.65 * V _{CCl}	1.575	0.25 * V _{CCl}	0.75 * V _{CCl}	4	4	25	33	10	10
6 mA	−0.3	0.35 * V _{CCl}	0.65 * V _{CCl}	1.575	0.25 * V _{CCl}	0.75 * V _{CCl}	6	6	32	39	10	10
8 mA	−0.3	0.35 * V _{CCl}	0.65 * V _{CCl}	1.575	0.25 * V _{CCl}	0.75 * V _{CCl}	8	8	66	55	10	10
12 mA	−0.3	0.35 * V _{CCl}	0.65 * V _{CCl}	1.575	0.25 * V _{CCl}	0.75 * V _{CCl}	12	12	66	55	10	10

Notes:

1. Currents are measured at 100°C junction temperature and maximum voltage.
2. Currents are measured at 85°C junction temperature.
3. Software default selection highlighted in gray.

Table 2-96 • Minimum and Maximum DC Input and Output Levels
Applicable to Standard Plus I/O Banks

1.5 V LVCMOS	V_{IL}		V_{IH}		V_{OL}	V_{OH}	I_{OL}	I_{OH}	I_{OSL}	I_{OSH}	I_{IL}	I_{IH}
Drive Strength	Min., V	Max., V	Min., V	Max., V	Max., V	Min., V	mA	mA	Max., mA ¹	Max., mA ¹	μA^2	μA^2
2 mA	-0.3	$0.35 * V_{CCl}$	$0.65 * V_{CCl}$	1.575	$0.25 * V_{CCl}$	$0.75 * V_{CCl}$	2	2	13	16	10	10
4 mA	-0.3	$0.35 * V_{CCl}$	$0.65 * V_{CCl}$	1.575	$0.25 * V_{CCl}$	$0.75 * V_{CCl}$	4	4	25	33	10	10

Notes:

1. Currents are measured at 100°C junction temperature and maximum voltage.
2. Currents are measured at 85°C junction temperature.
3. Software default selection highlighted in gray.

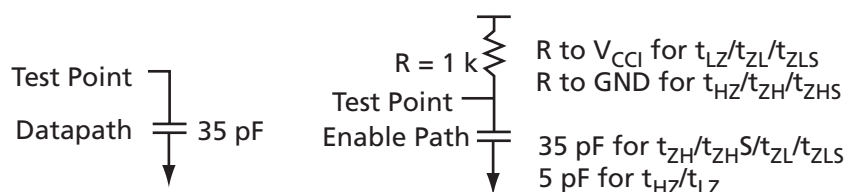


Figure 2-10 • AC Loading

Table 2-97 • AC Waveforms, Measuring Points, and Capacitive Loads

Input LOW (V)	Input HIGH (V)	Measuring Point* (V)	C_{LOAD} (pF)
0	1.5	0.75	5

* Measuring point = V_{trip} . See Table 2-26 on page 2-25 for a complete table of trip points.

Timing Characteristics

1.5 V DC Core Voltage

Table 2-98 • 1.5 V LVC MOS Low Slew – Applies to 1.5 V DC Core Voltage
Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$, Worst-Case $V_{CCI} = 1.4\text{ V}$
Applicable to Pro I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{PYS}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
2 mA	Std.	0.59	8.65	0.04	1.99	2.77	0.38	8.81	7.17	3.06	2.41	10.83	9.18	ns
	–1	0.50	7.36	0.03	1.69	2.36	0.33	7.50	6.10	2.61	2.05	9.21	7.81	ns
4 mA	Std.	0.59	7.40	0.04	1.99	2.77	0.38	7.53	6.26	3.39	3.02	9.55	8.27	ns
	–1	0.50	6.29	0.03	1.69	2.36	0.33	6.41	5.33	2.89	2.57	8.12	7.04	ns
6 mA	Std.	0.59	6.94	0.04	1.99	2.77	0.38	7.07	6.09	3.46	3.19	9.08	8.11	ns
	–1	0.50	5.91	0.03	1.69	2.36	0.33	6.01	5.18	2.94	2.72	7.73	6.90	ns
8 mA	Std.	0.59	6.85	0.04	1.99	2.77	0.38	6.98	6.10	3.57	3.80	8.99	8.11	ns
	–1	0.50	5.83	0.03	1.69	2.36	0.33	5.94	5.19	3.04	3.23	7.65	6.90	ns
12 mA	Std.	0.59	6.85	0.04	1.99	2.77	0.38	6.98	6.10	3.57	3.80	8.99	8.11	ns
	–1	0.50	5.83	0.03	1.69	2.36	0.33	5.94	5.19	3.04	3.23	7.65	6.90	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-99 • 1.5 V LVC MOS High Slew – Applies to 1.5 V DC Core Voltage
Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$, Worst-Case $V_{CCI} = 1.4\text{ V}$
Applicable to Pro I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{PYS}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
2 mA	Std.	0.59	3.55	0.04	1.99	2.77	0.38	3.62	3.22	3.05	2.51	5.63	5.23	ns
	–1	0.50	3.02	0.03	1.69	2.36	0.33	3.08	2.74	2.60	2.14	4.79	4.45	ns
4 mA	Std.	0.59	3.03	0.04	1.99	2.77	0.38	3.08	2.64	3.38	3.13	5.10	4.65	ns
	–1	0.50	2.58	0.03	1.69	2.36	0.33	2.62	2.25	2.87	2.66	4.34	3.96	ns
6 mA	Std.	0.59	2.93	0.04	1.99	2.77	0.38	2.98	2.53	3.45	3.30	4.99	4.54	ns
	–1	0.50	2.49	0.03	1.69	2.36	0.33	2.54	2.15	2.93	2.81	4.25	3.86	ns
8 mA	Std.	0.59	2.90	0.04	1.99	2.77	0.38	2.95	2.39	3.57	3.94	4.96	4.41	ns
	–1	0.50	2.46	0.03	1.69	2.36	0.33	2.51	2.04	3.03	3.35	4.22	3.75	ns
12 mA	Std.	0.59	2.90	0.04	1.99	2.77	0.38	2.95	2.39	3.57	3.94	4.96	4.41	ns
	–1	0.50	2.46	0.03	1.69	2.36	0.33	2.51	2.04	3.03	3.35	4.22	3.75	ns

Notes:

1. Software default selection highlighted in gray.
2. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-100 • 1.5 V LVCMOS Low Slew – Applies to 1.5 V DC Core VoltageCommercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$, Worst-Case $V_{CCI} = 1.4\text{ V}$

Applicable to Advanced I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
2 mA	Std.	0.54	8.00	0.04	1.18	0.38	8.15	7.01	3.06	2.38	10.16	9.02	ns
	–1	0.46	6.80	0.03	1.00	0.33	6.93	5.96	2.60	2.02	8.64	7.68	ns
4 mA	Std.	0.54	6.91	0.04	1.18	0.38	7.04	6.21	3.37	2.94	9.05	8.22	ns
	–1	0.46	5.88	0.03	1.00	0.33	5.99	5.28	2.87	2.50	7.70	7.00	ns
6 mA	Std.	0.54	6.51	0.04	1.18	0.38	6.63	6.05	3.45	3.09	8.64	8.06	ns
	–1	0.46	5.54	0.03	1.00	0.33	5.64	5.15	2.93	2.63	7.35	6.86	ns
8 mA	Std.	0.54	6.41	0.04	1.18	0.38	6.53	6.11	3.56	3.64	8.54	8.12	ns
	–1	0.46	5.45	0.03	1.00	0.33	5.56	5.20	3.03	3.10	7.27	6.91	ns
12 mA	Std.	0.54	6.41	0.04	1.18	0.38	6.53	6.11	3.56	3.64	8.54	8.12	ns
	–1	0.46	5.45	0.03	1.00	0.33	5.56	5.20	3.03	3.10	7.27	6.91	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-101 • 1.5 V LVCMOS High Slew – Applies to 1.5 V DC Core VoltageCommercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$, Worst-Case $V_{CCI} = 1.4\text{ V}$

Applicable to Advanced I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
2 mA	Std.	0.54	3.60	0.04	1.10	0.38	3.66	3.52	2.49	1.49	5.68	5.53	ns
	–1	0.46	3.06	0.03	0.93	0.33	3.12	3.00	2.12	1.27	4.83	4.71	ns
4 mA	Std.	0.54	2.81	0.04	1.10	0.38	2.87	2.64	2.90	2.55	4.88	4.65	ns
	–1	0.46	2.39	0.03	0.93	0.33	2.44	2.25	2.47	2.17	4.15	3.96	ns
6 mA	Std.	0.54	2.47	0.04	1.10	0.38	2.51	2.21	3.18	3.04	4.53	4.22	ns
	–1	0.46	2.10	0.03	0.93	0.33	2.14	1.88	2.70	2.59	3.85	3.59	ns
8 mA	Std.	0.54	2.40	0.04	1.10	0.38	2.45	2.13	3.24	3.17	4.46	4.14	ns
	–1	0.46	2.04	0.03	0.93	0.33	2.08	1.81	2.76	2.70	3.79	3.52	ns
12 mA	Std.	0.54	2.39	0.04	1.10	0.38	2.44	2.04	3.33	3.67	4.45	4.05	ns
	–1	0.46	2.04	0.03	0.93	0.33	2.08	1.73	2.83	3.12	3.79	3.45	ns

Notes:

1. Software default selection highlighted in gray.
2. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-102 • 1.5 V LVC MOS Low Slew – Applies to 1.5 V DC Core Voltage
Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$, Worst-Case $V_{CCI} = 1.4\text{ V}$
Applicable to Standard Plus I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
2 mA	Std.	0.54	7.32	0.04	1.17	0.38	7.45	6.38	2.44	2.18	9.46	8.40	ns
	–1	0.46	6.22	0.03	0.99	0.33	6.34	5.43	2.08	1.86	8.05	7.14	ns
4 mA	Std.	0.54	6.29	0.04	1.17	0.38	6.40	5.65	2.73	2.70	8.42	7.67	ns
	–1	0.46	5.35	0.03	0.99	0.33	5.45	4.81	2.33	2.29	7.16	6.52	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-103 • 1.5 V LVC MOS High Slew – Applies to 1.5 V DC Core Voltage
Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$, Worst-Case $V_{CCI} = 1.4\text{ V}$
Applicable to Standard Plus I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
2 mA	Std.	0.54	2.90	0.04	1.28	0.38	2.95	2.63	2.44	2.29	4.97	4.64	ns
	–1	0.46	2.47	0.03	1.09	0.33	2.51	2.24	2.07	1.95	4.23	3.95	ns
4 mA	Std.	0.54	2.52	0.04	1.28	0.38	2.57	2.14	2.73	2.82	4.58	4.15	ns
	–1	0.46	2.15	0.03	1.09	0.33	2.19	1.82	2.32	2.40	3.90	3.53	ns

Notes:

1. Software default selection highlighted in gray.
2. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

1.2 V DC Core Voltage

Table 2-104 • 1.5 V LVC MOS Low Slew – Applies to 1.2 V DC Core Voltage

Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$, Worst-Case $V_{CCI} = 1.4\text{ V}$
 Applicable to Pro I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{PYS}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
2 mA	Std.	0.77	8.65	0.05	1.99	2.77	0.50	8.81	7.17	3.06	2.41	10.83	9.18	ns
	–1	0.66	7.36	0.04	1.69	2.36	0.43	7.50	6.10	2.61	2.05	9.21	7.81	ns
4 mA	Std.	0.77	7.40	0.05	1.99	2.77	0.50	7.53	6.26	3.39	3.02	9.55	8.27	ns
	–1	0.66	6.29	0.04	1.69	2.36	0.43	6.41	5.33	2.89	2.57	8.12	7.04	ns
6 mA	Std.	0.77	6.94	0.05	1.99	2.77	0.50	7.07	6.09	3.46	3.19	9.08	8.11	ns
	–1	0.66	5.91	0.04	1.69	2.36	0.43	6.01	5.18	2.94	2.72	7.73	6.90	ns
8 mA	Std.	0.77	6.85	0.05	1.99	2.77	0.50	6.98	6.10	3.57	3.80	8.99	8.11	ns
	–1	0.66	5.83	0.04	1.69	2.36	0.43	5.94	5.19	3.04	3.23	7.65	6.90	ns
12 mA	Std.	0.77	6.85	0.05	1.99	2.77	0.50	6.98	6.10	3.57	3.80	8.99	8.11	ns
	–1	0.66	5.83	0.04	1.69	2.36	0.43	5.94	5.19	3.04	3.23	7.65	6.90	ns

Notes:

1. Software default selection highlighted in gray.
2. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-105 • 1.5 V LVC MOS High Slew – Applies to 1.2 V DC Core Voltage

Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$, Worst-Case $V_{CCI} = 1.4\text{ V}$
 Applicable to Pro I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{PYS}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
2 mA	Std.	0.77	3.55	0.05	1.99	2.77	0.50	3.62	3.22	3.05	2.51	5.63	5.23	ns
	–1	0.66	3.02	0.04	1.69	2.36	0.43	3.08	2.74	2.60	2.14	4.79	4.45	ns
4 mA	Std.	0.77	3.03	0.05	1.99	2.77	0.50	3.08	2.64	3.38	3.13	5.10	4.65	ns
	–1	0.66	2.58	0.04	1.69	2.36	0.43	2.62	2.25	2.87	2.66	4.34	3.96	ns
6 mA	Std.	0.77	2.93	0.05	1.99	2.77	0.50	2.98	2.53	3.45	3.30	4.99	4.54	ns
	–1	0.66	2.49	0.04	1.69	2.36	0.43	2.54	2.15	2.93	2.81	4.25	3.86	ns
8 mA	Std.	0.77	2.90	0.05	1.99	2.77	0.50	2.95	2.39	3.57	3.94	4.96	4.41	ns
	–1	0.66	2.46	0.04	1.69	2.36	0.43	2.51	2.04	3.03	3.35	4.22	3.75	ns
12 mA	Std.	0.77	2.90	0.05	1.99	2.77	0.50	2.95	2.39	3.57	3.94	4.96	4.41	ns
	–1	0.66	2.46	0.04	1.69	2.36	0.43	2.51	2.04	3.03	3.35	4.22	3.75	ns

Notes:

1. Software default selection highlighted in gray.
2. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-106 • 1.5 V LVCMOS Low Slew – Applies to 1.2 V DC Core Voltage

Commercial-Case Conditions: $T_J = 70^{\circ}\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$, Worst-Case $V_{CCI} = 1.4\text{ V}$

Applicable to Advanced I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
2 mA	Std.	0.70	8.00	0.05	1.18	0.50	8.15	7.01	3.06	2.38	10.16	9.02	ns
	–1	0.60	6.80	0.04	1.00	0.43	6.93	5.96	2.60	2.02	8.64	7.68	ns
4 mA	Std.	0.70	6.91	0.05	1.18	0.50	7.04	6.21	3.37	2.94	9.05	8.22	ns
	–1	0.60	5.88	0.04	1.00	0.43	5.99	5.28	2.87	2.50	7.70	7.00	ns
6 mA	Std.	0.70	6.51	0.05	1.18	0.50	6.63	6.05	3.45	3.09	8.64	8.06	ns
	–1	0.60	5.54	0.04	1.00	0.43	5.64	5.15	2.93	2.63	7.35	6.86	ns
8 mA	Std.	0.70	6.41	0.05	1.18	0.50	6.53	6.11	3.56	3.64	8.54	8.12	ns
	–1	0.60	5.45	0.04	1.00	0.43	5.56	5.20	3.03	3.10	7.27	6.91	ns
12 mA	Std.	0.70	6.41	0.05	1.18	0.50	6.53	6.11	3.56	3.64	8.54	8.12	ns
	–1	0.60	5.45	0.04	1.00	0.43	5.56	5.20	3.03	3.10	7.27	6.91	ns

Notes:

1. Software default selection highlighted in gray.
2. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-107 • 1.5 V LVCMOS High Slew – Applies to 1.2 V DC Core Voltage

Commercial-Case Conditions: $T_J = 70^{\circ}\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$, Worst-Case $V_{CCI} = 1.4\text{ V}$

Applicable to Advanced I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
2 mA	Std.	0.70	3.26	0.05	1.30	0.50	3.32	3.11	3.05	2.49	5.33	5.12	ns
	–1	0.60	2.77	0.04	1.10	0.43	2.82	2.64	2.59	2.12	4.53	4.36	ns
4 mA	Std.	0.70	2.84	0.05	1.30	0.50	2.89	2.57	3.37	3.06	4.90	4.59	ns
	–1	0.60	2.41	0.04	1.10	0.43	2.46	2.19	2.86	2.60	4.17	3.90	ns
6 mA	Std.	0.70	2.76	0.05	1.30	0.50	2.81	2.47	3.44	3.21	4.82	4.48	ns
	–1	0.60	2.35	0.04	1.10	0.43	2.39	2.10	2.92	2.73	4.10	3.81	ns
8 mA	Std.	0.70	2.74	0.05	1.30	0.50	2.79	2.36	3.55	3.78	4.80	4.37	ns
	–1	0.60	2.33	0.04	1.10	0.43	2.37	2.01	3.02	3.22	4.08	3.72	ns
12 mA	Std.	0.70	2.74	0.05	1.30	0.50	2.79	2.36	3.55	3.78	4.80	4.37	ns
	–1	0.60	2.33	0.04	1.10	0.43	2.37	2.01	3.02	3.22	4.08	3.72	ns

Notes:

1. Software default selection highlighted in gray.
2. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-108 • 1.5 V LVCMOS Low Slew – Applies to 1.2 V DC Core Voltage

Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$, Worst-Case $V_{CCI} = 1.4\text{ V}$

Applicable to Standard Plus I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
2 mA	Std.	0.70	7.32	0.05	1.17	0.50	7.45	6.38	2.44	2.18	9.46	8.40	ns
	–1	0.60	6.22	0.04	0.99	0.43	6.34	5.43	2.08	1.86	8.05	7.14	ns
4 mA	Std.	0.70	6.29	0.05	1.17	0.50	6.40	5.65	2.73	2.70	8.42	7.67	ns
	–1	0.60	5.35	0.04	0.99	0.43	5.45	4.81	2.33	2.29	7.16	6.52	ns

Notes:

1. Software default selection highlighted in gray.
2. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-109 • 1.5 V LVCMOS High Slew – Applies to 1.2 V DC Core Voltage

Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$, Worst-Case $V_{CCI} = 1.4\text{ V}$

Applicable to Standard Plus I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
2 mA	Std.	0.70	2.90	0.05	1.28	0.50	2.95	2.63	2.44	2.29	4.97	4.64	ns
	–1	0.60	2.47	0.04	1.09	0.43	2.51	2.24	2.07	1.95	4.23	3.95	ns
4 mA	Std.	0.70	2.52	0.05	1.28	0.50	2.57	2.14	2.73	2.82	4.58	4.15	ns
	–1	0.60	2.15	0.04	1.09	0.43	2.19	1.82	2.32	2.40	3.90	3.53	ns

Notes:

1. Software default selection highlighted in gray.
2. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

1.2 V LVCMOS (JESD8-12A)

Low-Voltage CMOS for 1.2 V complies with the LVCMOS standard JESD8-12A for general purpose 1.2 V applications. It uses a 1.2 V input buffer and a push-pull output buffer.

Table 2-110 • Minimum and Maximum DC Input and Output Levels
Applicable to Advanced I/O Banks

1.2 V LVCMOS	V_{IL}		V_{IH}		V_{OL}	V_{OH}	I_{OL}	I_{OH}	I_{OSH}^1	I_{OSL}^1	I_{IL}^2	I_{IH}^2
Drive Strength	Min., V	Max., V	Min., V	Max., V	Max., V	Min., V	mA	mA	Max., mA	Max., mA	μA	μA
2 mA	-0.3	$0.35 * V_{CCI}$	$0.65 * V_{CCI}$	1.26	$0.25 * V_{CCI}$	$0.75 * V_{CCI}$	2	2	TBD	TBD	10	10

Notes:

1. Currents are measured at 100°C junction temperature and maximum voltage.
2. Currents are measured at 85°C junction temperature.
3. Software default selection highlighted in gray.

Table 2-111 • Minimum and Maximum DC Input and Output Levels
Applicable to Standard Plus I/O Banks

1.2 V LVCMOS	V_{IL}		V_{IH}		V_{OL}	V_{OH}	I_{OL}	I_{OH}	I_{OSH}^1	I_{OSL}^1	I_{IL}^2	I_{IH}^2
Drive Strength	Min., V	Max., V	Min., V	Max., V	Max., V	Min., V	mA	mA	Max., mA	Max., mA	μA	μA
2 mA	-0.3	$0.35 * V_{CCI}$	$0.65 * V_{CCI}$	1.26	$0.25 * V_{CCI}$	$0.75 * V_{CCI}$	2	2	TBD	TBD	10	10

Notes:

1. Currents are measured at 100°C junction temperature and maximum voltage.
2. Currents are measured at 85°C junction temperature.
3. Software default selection highlighted in gray.

Table 2-112 • Minimum and Maximum DC Input and Output Levels
Applicable to Standard I/O Banks

1.2 V LVCMOS	V_{IL}		V_{IH}		V_{OL}	V_{OH}	I_{OL}	I_{OH}	I_{OSH}^1	I_{OSL}^1	I_{IL}^2	I_{IH}^2
Drive Strength	Min., V	Max., V	Min., V	Max., V	Max., V	Min., V	mA	mA	Max., mA	Max., mA	μA	μA
2 mA	-0.3	$0.35 * V_{CCI}$	$0.65 * V_{CCI}$	1.26	$0.25 * V_{CCI}$	$0.75 * V_{CCI}$	2	2	TBD	TBD	10	10

Notes:

1. Currents are measured at 100°C junction temperature and maximum voltage.
2. Currents are measured at 85°C junction temperature.
3. Software default selection highlighted in gray.

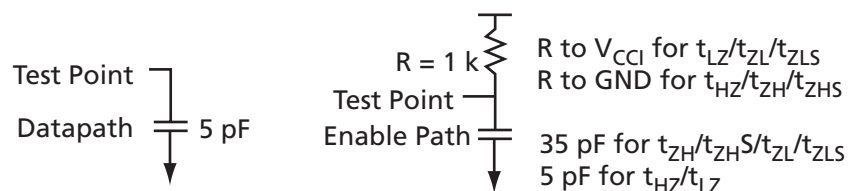


Figure 2-11 • AC Loading

Table 2-113 • AC Waveforms, Measuring Points, and Capacitive Loads

Input LOW (V)	Input HIGH (V)	Measuring Point* (V)	C_{LOAD} (pF)
0	1.2	0.6	5

* Measuring point = V_{trip} . See [Table 2-26 on page 2-25](#) for a complete table of trip points.

Timing Characteristics

1.2 V DC Core Voltage

Table 2-114 • 1.2 V LVC MOS Low Slew

Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$, Worst-Case $V_{CCI} = 1.4\text{ V}$
Applicable to Pro I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{PYS}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
2 mA	Std.	0.77	11.80	0.05	2.38	3.52	0.50	10.97	8.61	4.79	4.38	12.91	10.55	ns
	–1	0.66	10.04	0.04	2.02	2.99	0.43	9.33	7.32	4.08	3.72	10.98	8.97	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-115 • 1.2 V LVC MOS High Slew

Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$, Worst-Case $V_{CCI} = 1.4\text{ V}$
Applicable to Pro I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{PYS}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
2 mA	Std.	0.77	4.84	0.05	2.38	3.52	0.50	4.50	3.96	4.78	4.51	6.44	5.90	ns
	–1	0.66	4.12	0.04	2.02	2.99	0.43	3.83	3.37	4.06	3.84	5.48	5.02	ns

Notes:

1. Software default selection highlighted in gray.
2. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-116 • 1.2 V LVC MOS High Slew

Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$, Worst-Case $V_{CCI} = 1.14\text{ V}$
Applicable to Advanced I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
2 mA	Std.	0.70	8.77	0.05	1.82	0.50	6.17	5.45	2.80	2.77	8.11	7.39	ns
	–1	0.60	7.46	0.04	1.55	0.43	5.25	4.63	2.39	2.35	6.90	6.28	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-117 • 1.2 V LVC MOS High Slew

Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$, Worst-Case $V_{CCI} = 1.14\text{ V}$
Applicable to Advanced I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
2 mA	Std.	0.70	3.73	0.05	1.82	0.50	2.48	2.06	2.80	2.89	4.42	4.00	ns
	–1	0.60	3.17	0.04	1.55	0.43	2.11	1.76	2.38	2.46	3.76	3.41	ns

Notes:

1. Software default selection highlighted in gray.
2. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-118 • 1.2 V LVCMOS High Slew

Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$, Worst-Case $V_{CCI} = 1.14\text{ V}$

Applicable to Standard Plus I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
2 mA	Std.	0.70	9.67	0.05	1.83	0.50	6.78	5.99	4.08	4.57	8.72	7.93	ns
	–1	0.60	8.23	0.04	1.56	0.43	5.77	5.09	3.47	3.88	7.42	6.74	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-119 • 1.2 V LVCMOS High Slew

Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$, Worst-Case $V_{CCI} = 1.14\text{ V}$

Applicable to Standard Plus I/O Banks

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
2 mA	Std.	0.70	4.17	0.05	1.83	0.50	2.79	2.48	4.23	4.55	4.73	4.42	ns
	–1	0.60	3.54	0.04	1.56	0.43	2.37	2.11	3.60	3.87	4.02	3.76	ns

Notes:

1. Software default selection highlighted in gray.
2. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

3.3 V PCI, 3.3 V PCI-X

Peripheral Component Interface for 3.3 V standard specifies support for 33 MHz and 66 MHz PCI Bus applications.

Table 2-120 • Minimum and Maximum DC Input and Output Levels

3.3 V PCI/PCI-X	V _{IL}		V _{IH}		V _{OL}	V _{OH}	I _{OL}	I _{OH}	I _{OSL}	I _{OSH}	I _{IL}	I _{IH}
Drive Strength	Min, V	Max, V	Min, V	Max, V	Max, V	Min, V	mA	mA	Max, mA ¹	Max, mA ¹	μA ²	μA ²
Per PCI specification	Per PCI curves										10	10

Notes:

1. Currents are measured at 100°C junction temperature and maximum voltage.
2. Currents are measured at 85°C junction temperature.

AC loadings are defined per the PCI/PCI-X specifications for the database; Actel loadings for enable path characterization are described in [Figure 2-12](#).

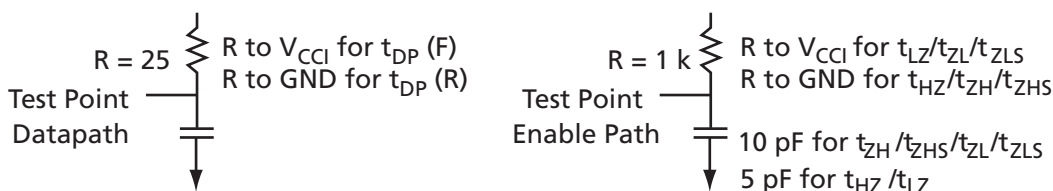


Figure 2-12 • AC Loading

AC loadings are defined per PCI/PCI-X specifications for the datapath; Actel loading for tristate is described in [Table 2-121](#).

Table 2-121 • AC Waveforms, Measuring Points, and Capacitive Loads

Input LOW (V)	Input HIGH (V)	Measuring Point* (V)	C _{LOAD} (pF)
0	3.3	0.285 * V _{CCI} for t _{DP(R)} 0.615 * V _{CCI} for t _{DP(F)}	10

* Measuring point = V_{trip}. See [Table 2-26 on page 2-25](#) for a complete table of trip points.

Timing Characteristics

1.5 V DC Core Voltage

Table 2-122 • 3.3 V PCI/PCI-X – Applies to 1.5 V DC Core Voltage

Commercial-Case Conditions: T_J = 70°C, Worst-Case V_{CC} = 1.425 V, Worst-Case V_{CCI} = 3.0 V
Applicable to Pro I/O Banks

Speed Grade	t _{DOUT}	t _{DP}	t _{DIN}	t _{PY}	t _{PYS}	t _{EOUT}	t _{ZL}	t _{ZH}	t _{LZ}	t _{HZ}	t _{ZLS}	t _{ZHS}	Units
Std.	0.59	2.52	0.04	2.47	3.33	0.38	2.57	1.80	2.95	3.25	4.58	3.81	ns
–1	0.50	2.15	0.03	2.10	2.84	0.33	2.19	1.53	2.51	2.77	3.90	3.24	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-123 • 3.3 V PCI/PCI-X – Applies to 1.5 V DC Core VoltageCommercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$, Worst-Case $V_{CCI} = 3.0\text{ V}$

Applicable to Advanced I/O Banks

Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{PYS}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
Std.	0.54	2.41	0.04	0.78	0.38	2.46	1.76	2.89	3.22	4.47	3.77	ns	0.54
–1	0.46	2.05	0.03	0.66	0.33	2.09	1.49	2.46	2.74	3.80	3.21	ns	0.46

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-124 • 3.3 V PCI/PCI-X – Applies to 1.5 V DC Core VoltageCommercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$, Worst-Case $V_{CCI} = 3.0\text{ V}$

Applicable to Standard Plus I/O Banks

Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{PYS}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
Std.	0.54	2.08	0.04	0.77	0.38	2.12	1.53	2.51	2.90	4.13	3.55	ns	0.54
–1	0.46	1.77	0.03	0.65	0.33	1.80	1.31	2.14	2.47	3.51	3.02	ns	0.46

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

1.2 V DC Core Voltage**Table 2-125 • 3.3 V PCI/PCI-X – Applies to 1.2 V DC Core Voltage**Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$, Worst-Case $V_{CCI} = 3.0\text{ V}$

Applicable to Pro I/O Banks

Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{PYS}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
Std.	0.77	2.52	0.05	2.47	3.33	0.50	2.57	1.80	2.95	3.25	4.58	3.81	ns
–1	0.66	2.15	0.04	2.10	2.84	0.43	2.19	1.53	2.51	2.77	3.90	3.24	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-126 • 3.3 V PCI/PCI-X – Applies to 1.2 V DC Core VoltageCommercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$, Worst-Case $V_{CCI} = 3.0\text{ V}$

Applicable to Advanced I/O Banks

Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{PYS}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
Std.	0.70	2.41	0.05	0.78	0.50	2.46	1.76	2.89	3.22	4.47	3.77	0.73	ns
–1	0.60	2.05	0.04	0.66	0.43	2.09	1.49	2.46	2.74	3.80	3.21	0.62	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-127 • 3.3 V PCI/PCI-X – Applies to 1.2 V DC Core VoltageCommercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$, Worst-Case $V_{CCI} = 3.0\text{ V}$

Applicable to Standard Plus I/O Banks

Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{PYS}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
Std.	0.70	2.08	0.05	0.77	0.50	2.12	1.53	2.51	2.90	4.13	3.55	0.73	ns
–1	0.60	1.77	0.04	0.65	0.43	1.80	1.31	2.14	2.47	3.51	3.02	0.62	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Voltage-Referenced I/O Characteristics

3.3 V GTL

Gunning Transceiver Logic is a high-speed bus standard (JESD8-3). It provides a differential amplifier input buffer and an open-drain output buffer. The V_{CCI} pin should be connected to 3.3 V.

Table 2-128 • Minimum and Maximum DC Input and Output Levels

3.3 V GTL	V_{IL}		V_{IH}		V_{OL}	V_{OH}	I_{OL}	I_{OH}	I_{OSL}	I_{OSH}	I_{IL}	I_{IH}
Drive Strength	Min., V	Max., V	Min., V	Max., V	Max., V	Min., V	mA	mA	Max., mA ¹	Max., mA ¹	μA^2	μA^2
25 mA ³	-0.3	$V_{REF} - 0.05$	$V_{REF} + 0.05$	3.6	0.4	-	25	25	268	181	10	10

Notes:

1. Currents are measured at 100°C junction temperature and maximum voltage.
2. Currents are measured at 85°C junction temperature.
3. Output drive strength is below JEDEC specification.

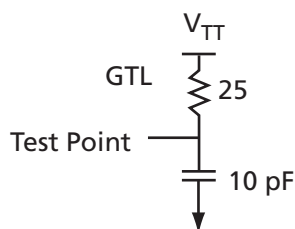


Figure 2-13 • AC Loading

Table 2-129 • AC Waveforms, Measuring Points, and Capacitive Loads

Input LOW (V)	Input HIGH (V)	Measuring Point* (V)	V_{REF} (typ.) (V)	V_{TT} (typ.) (V)	C_{LOAD} (pF)
$V_{REF} - 0.05$	$V_{REF} + 0.05$	0.8	0.8	1.2	10

* Measuring point = V_{trip} . See Table 2-15 on page 2-12 for a complete table of trip points.

Timing Characteristics

Table 2-130 • 3.3 V GTL – Applies to 1.5 V DC Core Voltage
Commercial-Case Conditions: $T_J = 70^\circ C$, Worst-Case $V_{CC} = 1.425 V$,
Worst-Case $V_{CCI} = 3.0 V$ $V_{REF} = 0.8 V$
Applicable to Pro I/O Banks

Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
Std.	0.59	1.87	0.04	2.12	0.38	1.83	1.87			3.85	3.88	ns
-1	0.50	1.59	0.03	1.80	0.33	1.56	1.59			3.27	3.30	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.

Table 2-131 • 3.3 V GTL – Applies to 1.2 V DC Core Voltage
Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$,
Worst-Case $V_{CCI} = 3.0\text{ V}$ $V_{REF} = 0.8\text{ V}$
Applicable to Pro I/Os

Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
Std.	0.77	1.87	0.05	2.12	0.50	1.83	1.87			3.85	3.88	ns
–1	0.66	1.59	0.04	1.80	0.43	1.56	1.59			3.27	3.30	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

2.5 V GTL

Gunning Transceiver Logic is a high-speed bus standard (JESD8-3). It provides a differential amplifier input buffer and an open-drain output buffer. The V_{CCI} pin should be connected to 2.5 V

Table 2-132 • Minimum and Maximum DC Input and Output Levels

2.5 GTL	V_{IL}		V_{IH}		V_{OL}	V_{OH}	I_{OL}	I_{OH}	I_{OSL}	I_{OSH}	I_{IL}	I_{IH}
Drive Strength	Min., V	Max., V	Min., V	Max., V	Max., V	Min., V	mA	mA	Max., mA ¹	Max., mA ¹	μA^2	μA^2
25 mA ³	–0.3	$V_{REF} - 0.05$	$V_{REF} + 0.05$	2.7	0.4	–	25	25	169	124	10	10

Notes:

1. Currents are measured at 100°C junction temperature and maximum voltage.
2. Currents are measured at 85°C junction temperature.
3. Output drive strength is below JEDEC specification.

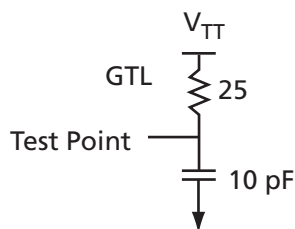


Figure 2-14 • AC Loading

Table 2-133 • AC Waveforms, Measuring Points, and Capacitive Loads

Input LOW (V)	Input HIGH (V)	Measuring Point* (V)	V_{REF} (typ.) (V)	V_{TT} (typ.) (V)	C_{LOAD} (pF)
$V_{REF} - 0.05$	$V_{REF} + 0.05$	0.8	0.8	1.2	10

* Measuring point = V_{trip} . See [Table 2-15 on page 2-12](#) for a complete table of trip points.

Timing Characteristics

Table 2-134 • 2.5 V GTL – Applies to 1.5 V DC Core Voltage

Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$,
Worst-Case $V_{CCI} = 3.0\text{ V}$ $V_{REF} = 0.8\text{ V}$
Applicable to Pro I/O Banks

Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
Std.	0.59	1.92	0.04	2.05	0.38	1.95	1.92			3.96	3.93	ns
–1	0.50	1.63	0.03	1.75	0.33	1.66	1.63			3.37	3.34	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-135 • 2.5 V GTL – Applies to 1.2 V DC Core Voltage

Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$,
Worst-Case $V_{CCI} = 3.0\text{ V}$ $V_{REF} = 0.8\text{ V}$
Applicable to Pro I/O Banks

Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
Std.	0.77	1.92	0.05	2.05	0.50	1.95	1.92			3.96	3.93	ns
–1	0.66	1.63	0.04	1.75	0.43	1.66	1.63			3.37	3.34	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

3.3 V GTL+

Gunning Transceiver Logic Plus is a high-speed bus standard (JESD8-3). It provides a differential amplifier input buffer and an open-drain output buffer. The V_{CCI} pin should be connected to 3.3 V

Table 2-136 • Minimum and Maximum DC Input and Output Levels

3.3 V GTL+	V_{IL}		V_{IH}		V_{OL}	V_{OH}	I_{OL}	I_{OH}	I_{OSL}	I_{OSH}	I_{IL}	I_{IH}
Drive Strength	Min., V	Max., V	Min., V	Max., V	Max., V	Min., V	mA	mA	Max., mA ¹	Max., mA ¹	μA^2	μA^2
35 mA	–0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	3.6	0.6	–	35	35	268	181	10	10

Notes:

1. Currents are measured at 100°C junction temperature and maximum voltage.
2. Currents are measured at 85°C junction temperature.

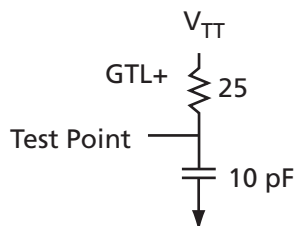


Figure 2-15 • AC Loading

Table 2-137 • AC Waveforms, Measuring Points, and Capacitive Loads

Input LOW (V)	Input HIGH (V)	Measuring Point* (V)	V _{REF} (typ.) (V)	V _{TT} (typ.) (V)	C _{LOAD} (pF)
V _{REF} – 0.1	V _{REF} + 0.1	1.0	1.0	1.5	10

* Measuring point = V_{trip}. See [Table 2-15 on page 2-12](#) for a complete table of trip points.

Timing Characteristics

Table 2-138 • 3.3 V GTL+ – Applies to 1.5 V DC Core Voltage

Commercial-Case Conditions: T_J = 70°C, Worst-Case V_{CC} = 1.425 V,

Worst-Case V_{CCI} = 3.0 V V_{REF} = 1.0 V

Applicable to Pro I/O Banks

Speed Grade	t _{DOUT}	t _{DP}	t _{DIN}	t _{PY}	t _{EOUT}	t _{ZL}	t _{ZH}	t _{LZ}	t _{HZ}	t _{ZLS}	t _{ZHS}	Units
Std.	0.59	1.85	0.04	2.12	0.38	1.88	1.85			3.90	3.86	ns
–1	0.50	1.57	0.03	1.80	0.33	1.60	1.57			3.31	3.29	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-139 • 3.3 V GTL+ – Applies to 1.2 V DC Core Voltage

Commercial-Case Conditions: T_J = 70°C, Worst-Case V_{CC} = 1.14 V,

Worst-Case V_{CCI} = 3.0 V V_{REF} = 1.0 V

Applicable to Pro I/O Banks

Speed Grade	t _{DOUT}	t _{DP}	t _{DIN}	t _{PY}	t _{EOUT}	t _{ZL}	t _{ZH}	t _{LZ}	t _{HZ}	t _{ZLS}	t _{ZHS}	Units
Std.	0.77	1.85	0.05	2.12	0.50	1.88	1.85			3.90	3.86	ns
–1	0.66	1.57	0.04	1.80	0.43	1.60	1.57			3.31	3.29	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

2.5 V GTL+

Gunning Transceiver Logic Plus is a high-speed bus standard (JESD8-3). It provides a differential amplifier input buffer and an open-drain output buffer. The V_{CCI} pin should be connected to 2.5 V.

Table 2-140 • Minimum and Maximum DC Input and Output Levels

2.5 V GTL+	V_{IL}		V_{IH}		V_{OL}	V_{OH}	I_{OL}	I_{OH}	I_{OSL}	I_{OSH}	I_{IL}	I_{IH}
Drive Strength	Min., V	Max., V	Min., V	Max., V	Max., V	Min., V	mA	mA	Max., mA ¹	Max., mA ¹	μA^2	μA^2
33 mA	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	2.7	0.6	–	33	33	169	124	10	10

Notes:

1. Currents are measured at 100°C junction temperature and maximum voltage.
2. Currents are measured at 85°C junction temperature.

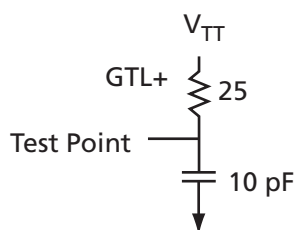


Figure 2-16 • AC Loading

Table 2-141 • AC Waveforms, Measuring Points, and Capacitive Loads

Input LOW (V)	Input HIGH (V)	Measuring Point* (V)	V_{REF} (typ.) (V)	V_{TT} (typ.) (V)	C_{LOAD} (pF)
$V_{REF} - 0.1$	$V_{REF} + 0.1$	1.0	1.0	1.5	10

* Measuring point = V_{trip} . See Table 2-15 on page 2-12 for a complete table of trip points.

Timing Characteristics

Table 2-142 • 2.5 V GTL+ – Applies to 1.5 V DC Core Voltage
Commercial-Case Conditions: $T_J = 70^\circ C$, Worst-Case $V_{CC} = 1.425 V$,
Worst-Case $V_{CCI} = 2.3 V$ $V_{REF} = 1.0 V$
Applicable to Pro I/O Banks

Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
Std.	0.59	1.99	0.04	2.05	0.38	2.02	1.89			4.03	3.90	ns
-1	0.50	1.69	0.03	1.75	0.33	1.72	1.61			3.43	3.32	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-15 on page 2-12 for derating values.

Table 2-143 • 2.5 V GTL+ – Applies to 1.2 V DC Core Voltage
Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$,
Worst-Case $V_{CCI} = 2.3\text{ V}$ $V_{REF} = 1.0\text{ V}$
Applicable to Pro I/O Banks

Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
Std.	0.77	1.99	0.05	2.05	0.50	2.02	1.89			4.03	3.90	ns
–1	0.66	1.69	0.04	1.75	0.43	1.72	1.61			3.43	3.32	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-15 on page 2-12](#) for derating values.

HSTL Class I

High-Speed Transceiver Logic is a general-purpose high-speed 1.5 V bus standard (EIA/JESD8-6). ProASIC3E devices support Class I. This provides a differential amplifier input buffer and a push-pull output buffer.

Table 2-144 • Minimum and Maximum DC Input and Output Levels

HSTL Class I	V_{IL}		V_{IH}		V_{OL}	V_{OH}	I_{OL}	I_{OH}	I_{OSL}	I_{OSH}	I_{IL}	I_{IH}
Drive Strength	Min., V	Max., V	Min., V	Max., V	Max., V	Min., V	mA	mA	Max., mA ¹	Max., mA ¹	μA^2	μA^2
8 mA	–0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	1.575	0.4	$V_{CCI} - 0.4$	8	8	32	39	10	10

Notes:

1. Currents are measured at 100°C junction temperature and maximum voltage.
2. Currents are measured at 85°C junction temperature.

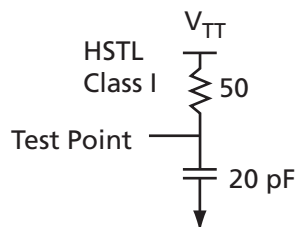


Figure 2-17 • AC Loading

Table 2-145 • AC Waveforms, Measuring Points, and Capacitive Loads

Input LOW (V)	Input HIGH (V)	Measuring Point* (V)	V_{REF} (typ.) (V)	V_{TT} (typ.) (V)	C_{LOAD} (pF)
$V_{REF} - 0.1$	$V_{REF} + 0.1$	0.75	0.75	0.75	20

* Measuring point = V_{trip} . See [Table 2-15 on page 2-12](#) for a complete table of trip points.

Timing Characteristics

Table 2-146 • HSTL Class I – Applies to 1.5 V DC Core Voltage
Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$,
Worst-Case $V_{CCI} = 1.4\text{ V}$ $V_{REF} = 0.75\text{ V}$
Applicable to Pro I/O Banks

Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
Std.	0.59	2.86	0.04	2.50	0.38	2.91	2.83			4.93	4.84	ns
–1	0.50	2.43	0.03	2.12	0.33	2.48	2.41			4.19	4.12	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-147 • HSTL Class I – Applies to 1.2 V DC Core Voltage
Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$,
Worst-Case $V_{CCI} = 1.4\text{ V}$ $V_{REF} = 0.75\text{ V}$
Applicable to Pro I/O Banks

Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
Std.	0.77	2.86	0.05	2.50	0.50	2.91	2.83			4.93	4.84	ns
–1	0.66	2.43	0.04	2.12	0.43	2.48	2.41			4.19	4.12	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

HSTL Class II

High-Speed Transceiver Logic is a general-purpose high-speed 1.5 V bus standard (EIA/JESD8-6). ProASIC3E devices support Class II. This provides a differential amplifier input buffer and a push-pull output buffer.

Table 2-148 • Minimum and Maximum DC Input and Output Levels

HSTL Class II	V_{IL}		V_{IH}		V_{OL}	V_{OH}	I_{OL}	I_{OH}	I_{OSL}	I_{OSH}	I_{IL}	I_{IH}
Drive Strength	Min., V	Max., V	Min., V	Max., V	Max., V	Min., V	mA	mA	Max., mA ¹	Max., mA ¹	μA^2	μA^2
15 mA ³	–0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	1.575	0.4	$V_{CCI} - 0.4$	15	15	66	55	10	10

Notes:

1. Currents are measured at 100°C junction temperature and maximum voltage.
2. Currents are measured at 85°C junction temperature.
3. Output drive strength is below JEDEC specification.

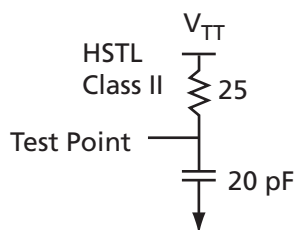


Figure 2-18 • AC Loading

Table 2-149 • AC Waveforms, Measuring Points, and Capacitive Loads

Input LOW (V)	Input HIGH (V)	Measuring Point* (V)	V _{REF} (typ.) (V)	V _{TT} (typ.) (V)	C _{LOAD} (pF)
V _{REF} – 0.1	V _{REF} + 0.1	0.75	0.75	0.75	20

* Measuring point = V_{trip}. See [Table 2-15 on page 2-12](#) for a complete table of trip points.

Timing Characteristics

Table 2-150 • HSTL Class II – Applies to 1.5 V DC Core Voltage

Commercial-Case Conditions: T_J = 70°C, Worst-Case V_{CC} = 1.425 V,

Worst-Case V_{CCI} = 1.4 V V_{REF} = 0.75 V

Applicable to Pro I/O Banks

Speed Grade	t _{DOUT}	t _{DP}	t _{DIN}	t _{PY}	t _{EOUT}	t _{ZL}	t _{ZH}	t _{LZ}	t _{HZ}	t _{ZLS}	t _{ZHS}	Units
Std.	0.59	2.72	0.04	2.50	0.38	2.77	2.44			4.78	4.45	ns
–1	0.50	2.32	0.03	2.12	0.33	2.36	2.08			4.07	3.79	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-151 • HSTL Class II – Applies to 1.2 V DC Core Voltage

Commercial-Case Conditions: T_J = 70°C, Worst-Case V_{CC} = 1.14 V,

Worst-Case V_{CCI} = 1.4 V V_{REF} = 0.75 V

Applicable to Pro I/O Banks

Speed Grade	t _{DOUT}	t _{DP}	t _{DIN}	t _{PY}	t _{EOUT}	t _{ZL}	t _{ZH}	t _{LZ}	t _{HZ}	t _{ZLS}	t _{ZHS}	Units
Std.	0.77	2.72	0.05	2.50	0.50	2.77	2.44			4.78	4.45	ns
–1	0.66	2.32	0.04	2.12	0.43	2.36	2.08			4.07	3.79	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

SSTL2 Class I

Stub-Speed Terminated Logic for 2.5 V memory bus standard (JESD8-9). ProASIC3E devices support Class I. This provides a differential amplifier input buffer and a push-pull output buffer.

Table 2-152 • Minimum and Maximum DC Input and Output Levels

SSTL2 Class I	V_{IL}		V_{IH}		V_{OL}	V_{OH}	I_{OL}	I_{OH}	I_{OSL}	I_{OSH}	I_{IL}	I_{IH}
	Min., V	Max., V	Min., V	Max., V	Max., V	Min., V	mA	mA	Max., mA ¹	Max., mA ¹	μA^2	μA^2
15 mA	-0.3	$V_{REF} - 0.2$	$V_{REF} + 0.2$	2.7	0.54	$V_{CCI} - 0.62$	15	15	83	87	10	10

Notes:

1. Currents are measured at 100°C junction temperature and maximum voltage.
2. Currents are measured at 85°C junction temperature.

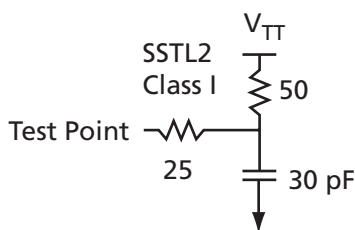


Figure 2-19 • AC Loading

Table 2-153 • AC Waveforms, Measuring Points, and Capacitive Loads

Input LOW (V)	Input HIGH (V)	Measuring Point* (V)	V_{REF} (typ.) (V)	V_{TT} (typ.) (V)	C_{LOAD} (pF)
$V_{REF} - 0.2$	$V_{REF} + 0.2$	1.25	1.25	1.25	30

* Measuring point = V_{trip} . See Table 2-15 on page 2-12 for a complete table of trip points.

Timing Characteristics

Table 2-154 • SSTL2 Class I – Applies to 1.5 V DC Core Voltage

Commercial-Case Conditions: $T_J = 70^\circ C$, Worst-Case $V_{CC} = 1.425 V$,
Worst-Case $V_{CCI} = 2.3 V$ $V_{REF} = 1.25 V$
Applicable to Pro I/Os

Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
Std.	0.59	1.91	0.04	1.89	0.38	1.95	1.66			1.95	1.66	ns
-1	0.50	1.63	0.03	1.61	0.33	1.66	1.41			1.66	1.41	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.

Table 2-155 • SSTL2 Class I – Applies to 1.2 V DC Core Voltage

Commercial-Case Conditions: $T_J = 70^{\circ}\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$,

Worst-Case $V_{CCI} = 2.3\text{ V}$ $V_{REF} = 1.25\text{ V}$

Applicable to Pro I/O Banks

Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
Std.	0.77	1.91	0.05	1.89	0.50	1.95	1.66			1.95	1.66	ns
–1	0.66	1.63	0.04	1.61	0.43	1.66	1.41			1.66	1.41	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

SSTL2 Class II

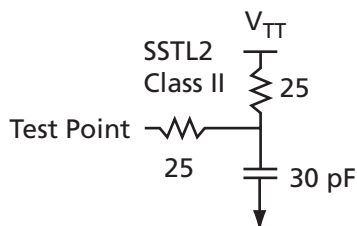
Stub-Speed Terminated Logic for 2.5 V memory bus standard (JESD8-9). ProASIC3E devices support Class II. This provides a differential amplifier input buffer and a push-pull output buffer.

Table 2-156 • Minimum and Maximum DC Input and Output Levels

SSTL2 Class II	V_{IL}		V_{IH}		V_{OL}	V_{OH}	I_{OL}	I_{OH}	I_{OSL}	I_{OSH}	I_{IL}	I_{IH}
Drive Strength	Min., V	Max., V	Min., V	Max., V	Max., V	Min., V	mA	mA	Max., mA ¹	Max., mA ¹	μA^2	μA^2
18 mA	–0.3	$V_{REF} - 0.2$	$V_{REF} + 0.2$	2.7	0.35	$V_{CCI} - 0.43$	18	18	169	124	10	10

Notes:

1. Currents are measured at 100°C junction temperature and maximum voltage.
2. Currents are measured at 85°C junction temperature.


Figure 2-20 • AC Loading
Table 2-157 • AC Waveforms, Measuring Points, and Capacitive Loads

Input LOW (V)	Input HIGH (V)	Measuring Point* (V)	V_{REF} (typ.) (V)	V_{TT} (typ.) (V)	C_{LOAD} (pF)
$V_{REF} - 0.2$	$V_{REF} + 0.2$	1.25	1.25	1.25	30

* Measuring point = V_{trip} . See [Table 2-15 on page 2-12](#) for a complete table of trip points.

Timing Characteristics

Table 2-158 • SSTL2 Class II – Applies to 1.5 V DC Core Voltage
Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$,
Worst-Case $V_{CCI} = 2.3\text{ V}$ $V_{REF} = 1.25\text{ V}$
Applicable to Pro I/O Banks

Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
Std.	0.59	1.95	0.04	1.89	0.38	1.99	1.59			1.99	1.59	ns
–1	0.50	1.66	0.03	1.61	0.33	1.69	1.36			1.69	1.36	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-159 • SSTL2 Class II – Applies to 1.2 V DC Core Voltage
Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$,
Worst-Case $V_{CCI} = 2.3\text{ V}$ $V_{REF} = 1.25\text{ V}$
Applicable to Pro I/O Banks

Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
Std.	0.77	1.95	0.05	1.89	0.50	1.99	1.59			1.99	1.59	ns
–1	0.66	1.66	0.04	1.61	0.43	1.69	1.36			1.69	1.36	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

SSTL3 Class I

Stub-Speed Terminated Logic for 3.3 V memory bus standard (JESD8-8). ProASIC3E devices support Class I. This provides a differential amplifier input buffer and a push-pull output buffer.

Table 2-160 • Minimum and Maximum DC Input and Output Levels

SSTL3 Class I	V_{IL}		V_{IH}		V_{OL}	V_{OH}	I_{OL}	I_{OH}	I_{OSL}	I_{OSH}	I_{IL}	I_{IH}
Drive Strength	Min., V	Max., V	Min., V	Max., V	Max., V	Min., V	mA	mA	Max., mA ¹	Max., mA ¹	μA^2	μA^2
14 mA	–0.3	$V_{REF} - 0.2$	$V_{REF} + 0.2$	3.6	0.7	$V_{CCI} - 1.1$	14	14	51	54	10	10

Notes:

1. Currents are measured at 100°C junction temperature and maximum voltage.
2. Currents are measured at 85°C junction temperature.

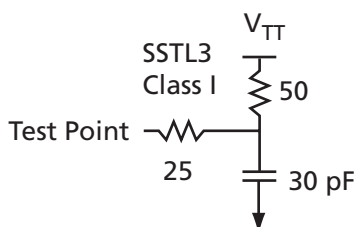


Figure 2-21 • AC Loading

Table 2-161 • AC Waveforms, Measuring Points, and Capacitive Loads

Input LOW (V)	Input HIGH (V)	Measuring Point* (V)	V _{REF} (typ.) (V)	V _{TT} (typ.) (V)	C _{LOAD} (pF)
V _{REF} – 0.2	V _{REF} + 0.2	1.5	1.5	1.485	30

* Measuring point = V_{trip}. See [Table 2-15 on page 2-12](#) for a complete table of trip points.

Timing Characteristics

Table 2-162 • SSTL3 Class I – Applies to 1.5 V DC Core Voltage

Commercial-Case Conditions: T_J = 70°C, Worst-Case V_{CC} = 1.425 V,

Worst-Case V_{CCI} = 3.0 V V_{REF} = 1.5 V

Applicable to Pro I/O Banks

Speed Grade	t _{DOUT}	t _{DP}	t _{DIN}	t _{PY}	t _{EOUT}	t _{ZL}	t _{ZH}	t _{LZ}	t _{HZ}	t _{ZLS}	t _{ZHS}	Units
Std.	0.59	2.08	0.04	1.81	0.38	2.11	1.65			2.11	1.65	ns
–1	0.50	1.77	0.03	1.54	0.33	1.80	1.41			1.80	1.41	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-163 • SSTL3 Class I – Applies to 1.2 V DC Core Voltage

Commercial-Case Conditions: T_J = 70°C, Worst-Case V_{CC} = 1.14 V,

Worst-Case V_{CCI} = 3.0 V V_{REF} = 1.5 V

Applicable to Pro I/O Banks

Speed Grade	t _{DOUT}	t _{DP}	t _{DIN}	t _{PY}	t _{EOUT}	t _{ZL}	t _{ZH}	t _{LZ}	t _{HZ}	t _{ZLS}	t _{ZHS}	Units
Std.	0.77	2.08	0.05	1.81	0.50	2.11	1.65			2.11	1.65	ns
–1	0.66	1.77	0.04	1.54	0.43	1.80	1.41			1.80	1.41	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

SSTL3 Class II

Stub-Speed Terminated Logic for 3.3 V memory bus standard (JESD8-8). ProASIC3E devices support Class II. This provides a differential amplifier input buffer and a push-pull output buffer.

Table 2-164 • Minimum and Maximum DC Input and Output Levels

SSTL3 Class II	V _{IL}		V _{IH}		V _{OL}	V _{OH}	I _{OL}	I _{OH}	I _{OSL}	I _{OSH}	I _{IL}	I _{IH}
Drive Strength	Min., V	Max., V	Min., V	Max., V	Max., V	Min., V	mA	mA	Max., mA ¹	Max., mA ¹	μA ²	μA ²
21 mA	–0.3	V _{REF} – 0.2	V _{REF} + 0.2	3.6	0.5	V _{CCI} – 0.9	21	21	103	109	10	10

Notes:

1. Currents are measured at 100°C junction temperature and maximum voltage.
2. Currents are measured at 85°C junction temperature.

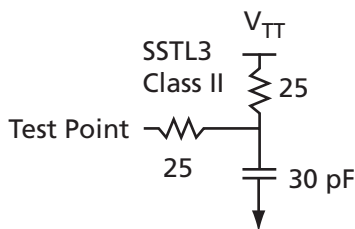


Figure 2-22 • AC Loading

Table 2-165 • AC Waveforms, Measuring Points, and Capacitive Loads

Input LOW (V)	Input HIGH (V)	Measuring Point* (V)	V _{REF} (typ.) (V)	V _{TT} (typ.) (V)	C _{LOAD} (pF)
V _{REF} - 0.2	V _{REF} + 0.2	1.5	1.5	1.485	30

* Measuring point = V_{trip}. See Table 2-15 on page 2-12 for a complete table of trip points.

Timing Characteristics

Table 2-166 • SSTL3 Class II – Applies to 1.5 V DC Core Voltage

Commercial-Case Conditions: T_J = 70°C, Worst-Case V_{CC} = 1.425 V,
Worst-Case V_{CCI} = 3.0 V V_{REF} = 1.5 V
Applicable to Pro I/O Banks

Speed Grade	t _{DOUT}	t _{DP}	t _{DIN}	t _{PY}	t _{EOUT}	t _{ZL}	t _{ZH}	t _{LZ}	t _{HZ}	t _{ZLS}	t _{ZHS}	Units
Std.	0.59	1.86	0.04	1.81	0.38	1.89	1.50			1.89	1.50	ns
-1	0.50	1.58	0.03	1.54	0.33	1.61	1.28			1.61	1.28	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.

Table 2-167 • SSTL3 Class II – Applies to 1.2 V DC Core Voltage

Commercial-Case Conditions: T_J = 70°C, Worst-Case V_{CC} = 1.14 V,
Worst-Case V_{CCI} = 3.0 V V_{REF} = 1.5 V
Applicable to Pro I/O Banks

Speed Grade	t _{DOUT}	t _{DP}	t _{DIN}	t _{PY}	t _{EOUT}	t _{ZL}	t _{ZH}	t _{LZ}	t _{HZ}	t _{ZLS}	t _{ZHS}	Units
Std.	0.77	1.86	0.05	1.81	0.50	1.89	1.50			1.89	1.50	ns
-1	0.66	1.58	0.04	1.54	0.43	1.61	1.28			1.61	1.28	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.

Differential I/O Characteristics

Physical Implementation

Configuration of the I/O modules as a differential pair is handled by Actel Designer software when the user instantiates a differential I/O macro in the design.

Differential I/Os can also be used in conjunction with the embedded Input Register (InReg), Output Register (OutReg), Enable Register (EnReg), and Double Data Rate (DDR). However, there is no support for bidirectional I/Os or tristates with the LVPECL standards.

LVDS

Low-Voltage Differential Signaling (ANSI/TIA/EIA-644) is a high-speed, differential I/O standard. It requires that one data bit be carried through two signal lines, so two pins are needed. It also requires external resistor termination.

The full implementation of the LVDS transmitter and receiver is shown in an example in [Figure 2-23](#). The building blocks of the LVDS transmitter-receiver are one transmitter macro, one receiver macro, three board resistors at the transmitter end, and one resistor at the receiver end. The values for the three driver resistors are different from those used in the LVPECL implementation because the output standard specifications are different.

Along with LVDS I/O, ProASIC3 also supports Bus LVDS structure and Multipoint LVDS (M-LVDS) configuration (up to 40 nodes).

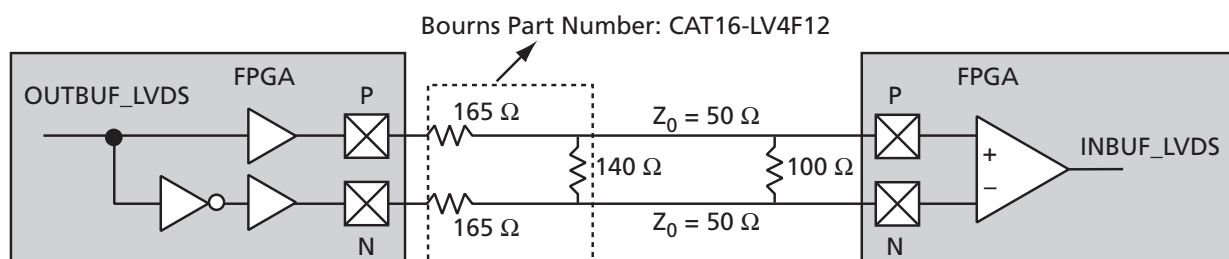


Figure 2-23 • LVDS Circuit Diagram and Board-Level Implementation

Table 2-168 • Minimum and Maximum DC Input and Output Levels

DC Parameter	Description	Min.	Typ.	Max.	Units
V_{CCI}	Supply Voltage	2.375	2.5	2.625	V
V_{OL}	Output Low Voltage	0.9	1.075	1.25	V
V_{OH}	Output High Voltage	1.25	1.425	1.6	V
I_{OL}^4	Output Lower Current	0.65	0.91	1.16	mA
I_{OH}^4	Output High Current	0.65	0.91	1.16	mA
V_I	Input Voltage	0		2.925	V
I_{IH}^3	Input High Leakage Current			10	μ A
I_{IL}^3	Input Low Leakage Current			10	μ A
V_{ODIFF}	Differential Output Voltage	250	350	450	mV
V_{OCM}	Output Common Mode Voltage	1.125	1.25	1.375	V
V_{ICM}	Input Common Mode Voltage	0.05	1.25	2.35	V
V_{IDIFF}	Input Differential Voltage	100	350		mV

Notes:

1. $\pm 5\%$
2. Differential input voltage = ± 350 mV.
3. Currents are measured at 85°C junction temperature.
4. I_{OL}/I_{OH} is defined by $V_{ODIFF}/(\text{Resistor Network})$.

Table 2-169 • AC Waveforms, Measuring Points, and Capacitive Loads

Input LOW (V)	Input HIGH (V)	Measuring Point* (V)
1.075	1.325	Cross point

* Measuring point = V_{trip} . See Table 2-26 on page 2-25 for a complete table of trip points.

Timing Characteristics

1.5 V DC Core Voltage

Table 2-170 • LVDS – Applies to 1.5 V DC Core Voltage

Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$, Worst-Case $V_{CCI} = 2.3\text{ V}$

Applicable to Pro I/O Banks

Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	Units
Std.	0.59	1.65	0.04	2.18	ns
–1	0.50	1.40	0.03	1.85	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-171 • LVDS – Applies to 1.5 V DC Core Voltage

Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$, Worst-Case $V_{CCI} = 2.3\text{ V}$

Applicable to Advanced I/O Banks

Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	Units
Std.	0.54	1.65	0.04	1.44	ns
–1	0.46	1.40	0.03	1.23	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

1.2 V DC Core Voltage

Table 2-172 • LVDS – Applies to 1.2 V DC Core Voltage

Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$, Worst-Case $V_{CCI} = 2.3\text{ V}$

Applicable to Pro I/O Banks

Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	Units
Std.	0.77	1.68	0.05	2.18	ns
–1	0.66	1.43	0.04	1.85	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-173 • LVDS – Applies to 1.2 V DC Core Voltage

Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$, Worst-Case $V_{CCI} = 2.3\text{ V}$

Applicable to Advanced I/O Banks

Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	Units
Std.	0.70	1.65	0.05	1.44	ns
–1	0.60	1.40	0.04	1.23	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

B-LVDS/M-LVDS

Bus LVDS (B-LVDS) and Multipoint LVDS (M-LVDS) specifications extend the existing LVDS standard to high-performance multipoint bus applications. Multidrop and multipoint bus configurations may contain any combination of drivers, receivers, and transceivers. Actel LVDS drivers provide the higher drive current required by B-LVDS and M-LVDS to accommodate the loading. The drivers require series terminations for better signal quality and to control voltage swing. Termination is also required at both ends of the bus since the driver can be located anywhere on the bus. These configurations can be implemented using the TRIBUF_LVDS and BIBUF_LVDS macros along with appropriate terminations. Multipoint designs using Actel LVDS macros can achieve up to 200 MHz with a maximum of 20 loads. A sample application is given in Figure 2-24. The input and output buffer delays are available in the LVDS section in Table 2-168 on page 2-91.

Example: For a bus consisting of 20 equidistant loads, the following terminations provide the required differential voltage, in worst-case Industrial operating conditions, at the farthest receiver: $R_S = 60 \Omega$ and $R_T = 70 \Omega$, given $Z_0 = 50 \Omega$ (2") and $Z_{stub} = 50 \Omega$ (~1.5").

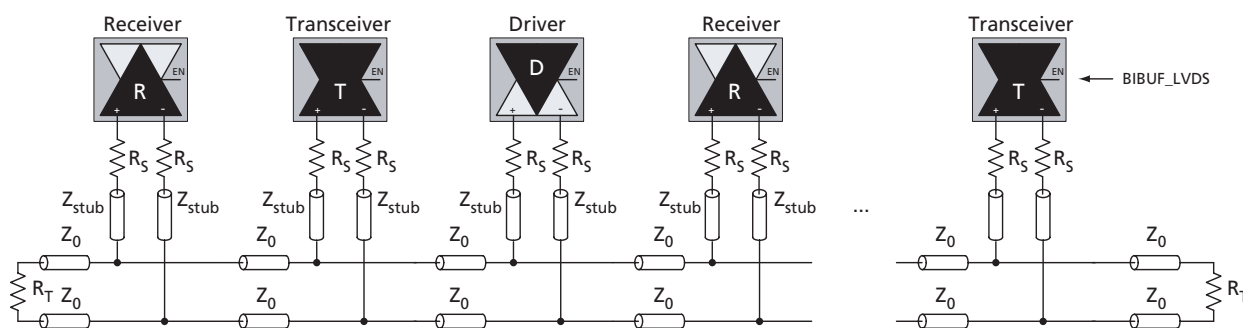


Figure 2-24 • B-LVDS/M-LVDS Multipoint Application Using LVDS I/O Buffers

LVPECL

Low-Voltage Positive Emitter-Coupled Logic (LVPECL) is another differential I/O standard. It requires that one data bit be carried through two signal lines. Like LVDS, two pins are needed. It also requires external resistor termination.

The full implementation of the LVDS transmitter and receiver is shown in an example in [Figure 2-25](#). The building blocks of the LVPECL transmitter-receiver are one transmitter macro, one receiver macro, three board resistors at the transmitter end, and one resistor at the receiver end. The values for the three driver resistors are different from those used in the LVDS implementation because the output standard specifications are different.

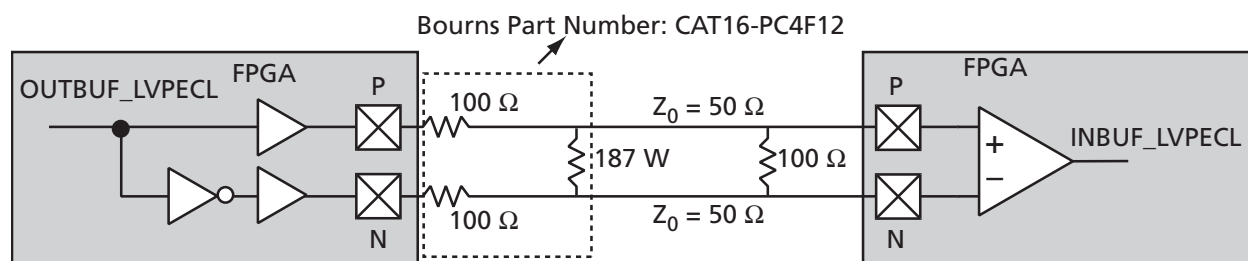


Figure 2-25 • LVPECL Circuit Diagram and Board-Level Implementation

Table 2-174 • Minimum and Maximum DC Input and Output Levels

DC Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	Units
V_{CCI}	Supply Voltage	3.0	3.3	3.6				V
V_{OL}	Output LOW Voltage	0.96	1.27	1.06	1.43	1.30	1.57	V
V_{OH}	Output HIGH Voltage	1.8	2.11	1.92	2.28	2.13	2.41	V
V_{IL}, V_{IH}	Input LOW, Input HIGH Voltages	0	3.3	0	3.6	0	3.9	V
V_{ODIFF}	Differential Output Voltage	0.625	0.97	0.625	0.97	0.625	0.97	V
V_{OCM}	Output Common-Mode Voltage	1.762	1.98	1.762	1.98	1.762	1.98	V
V_{ICM}	Input Common-Mode Voltage	1.01	2.57	1.01	2.57	1.01	2.57	V
V_{IDIFF}	Input Differential Voltage	300		300		300		mV

Table 2-175 • AC Waveforms, Measuring Points, and Capacitive Loads

Input LOW (V)	Input HIGH (V)	Measuring Point* (V)
1.64	1.94	Cross point

* Measuring point = V_{trip} . See [Table 2-26 on page 2-25](#) for a complete table of trip points.

Timing Characteristics

1.5 V DC Core Voltage

Table 2-176 • LVPECL – Applies to 1.5 V DC Core Voltage

Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$, Worst-Case $V_{CCI} = 3.0\text{ V}$

Applicable to Pro I/O Banks

Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	Units
Std.	0.59	1.64	0.04	1.97	ns
–1	0.50	1.40	0.03	1.67	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-177 • LVPECL – Applies to 1.5 V DC Core Voltage

Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$, Worst-Case $V_{CCI} = 3.0\text{ V}$

Applicable to Advanced I/O Banks

Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	Units
Std.	0.54	1.62	0.04	1.26	ns
–1	0.46	1.38	0.03	1.08	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

1.2 V DC Core Voltage

Table 2-178 • LVPECL – Applies to 1.2 V DC Core Voltage

Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$, Worst-Case $V_{CCI} = 3.0\text{ V}$

Applicable to Pro I/O Banks

Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	Units
Std.	0.77	1.62	0.05	1.97	ns
–1	0.66	1.37	0.04	1.67	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-179 • LVPECL – Applies to 1.2 V DC Core Voltage

Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$, Worst-Case $V_{CCI} = 3.0\text{ V}$

Applicable to Advanced I/O Banks

Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	Units
Std.	0.70	1.62	0.05	1.26	ns
–1	0.60	1.38	0.04	1.08	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

I/O Register Specifications

Fully Registered I/O Buffers with Synchronous Enable and Asynchronous Preset

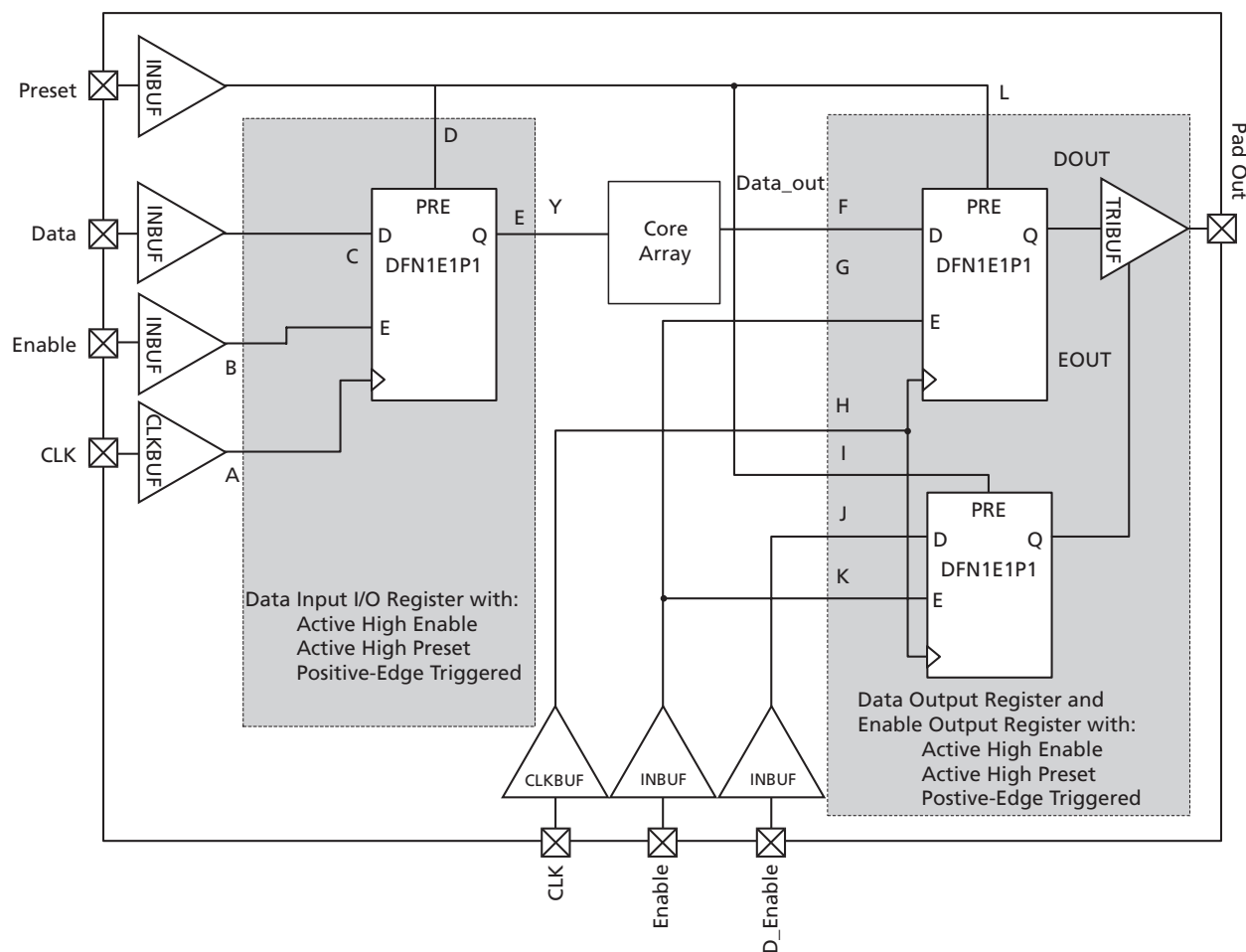


Figure 2-26 • Timing Model of Registered I/O Buffers with Synchronous Enable and Asynchronous Preset

Table 2-180 • Parameter Definition and Measuring Nodes

Parameter Name	Parameter Definition	Measuring Nodes (from, to)*
t _{OCLKQ}	Clock-to-Q of the Output Data Register	H, DOUT
t _{OSUD}	Data Setup Time for the Output Data Register	F, H
t _{OHD}	Data Hold Time for the Output Data Register	F, H
t _{OSUE}	Enable Setup Time for the Output Data Register	G, H
t _{OHE}	Enable Hold Time for the Output Data Register	G, H
t _{OPRE2Q}	Asynchronous Preset-to-Q of the Output Data Register	L, DOUT
t _{OEMPRE}	Asynchronous Preset Removal Time for the Output Data Register	L, H
t _{ORECPRE}	Asynchronous Preset Recovery Time for the Output Data Register	L, H
t _{OCLKQ}	Clock-to-Q of the Output Enable Register	H, EOUT
t _{OESUD}	Data Setup Time for the Output Enable Register	J, H
t _{OEHd}	Data Hold Time for the Output Enable Register	J, H
t _{OESUE}	Enable Setup Time for the Output Enable Register	K, H
t _{OEHd}	Enable Hold Time for the Output Enable Register	K, H
t _{OEPRE2Q}	Asynchronous Preset-to-Q of the Output Enable Register	I, EOUT
t _{OEMPRE}	Asynchronous Preset Removal Time for the Output Enable Register	I, H
t _{OERCPRE}	Asynchronous Preset Recovery Time for the Output Enable Register	I, H
t _{ICLKQ}	Clock-to-Q of the Input Data Register	A, E
t _{ISUD}	Data Setup Time for the Input Data Register	C, A
t _{IHD}	Data Hold Time for the Input Data Register	C, A
t _{ISUE}	Enable Setup Time for the Input Data Register	B, A
t _{IHE}	Enable Hold Time for the Input Data Register	B, A
t _{IPRE2Q}	Asynchronous Preset-to-Q of the Input Data Register	D, E
t _{IEMPRE}	Asynchronous Preset Removal Time for the Input Data Register	D, A
t _{IRECPRE}	Asynchronous Preset Recovery Time for the Input Data Register	D, A

* See Figure 2-26 on page 2-96 for more information.

Fully Registered I/O Buffers with Synchronous Enable and Asynchronous Clear

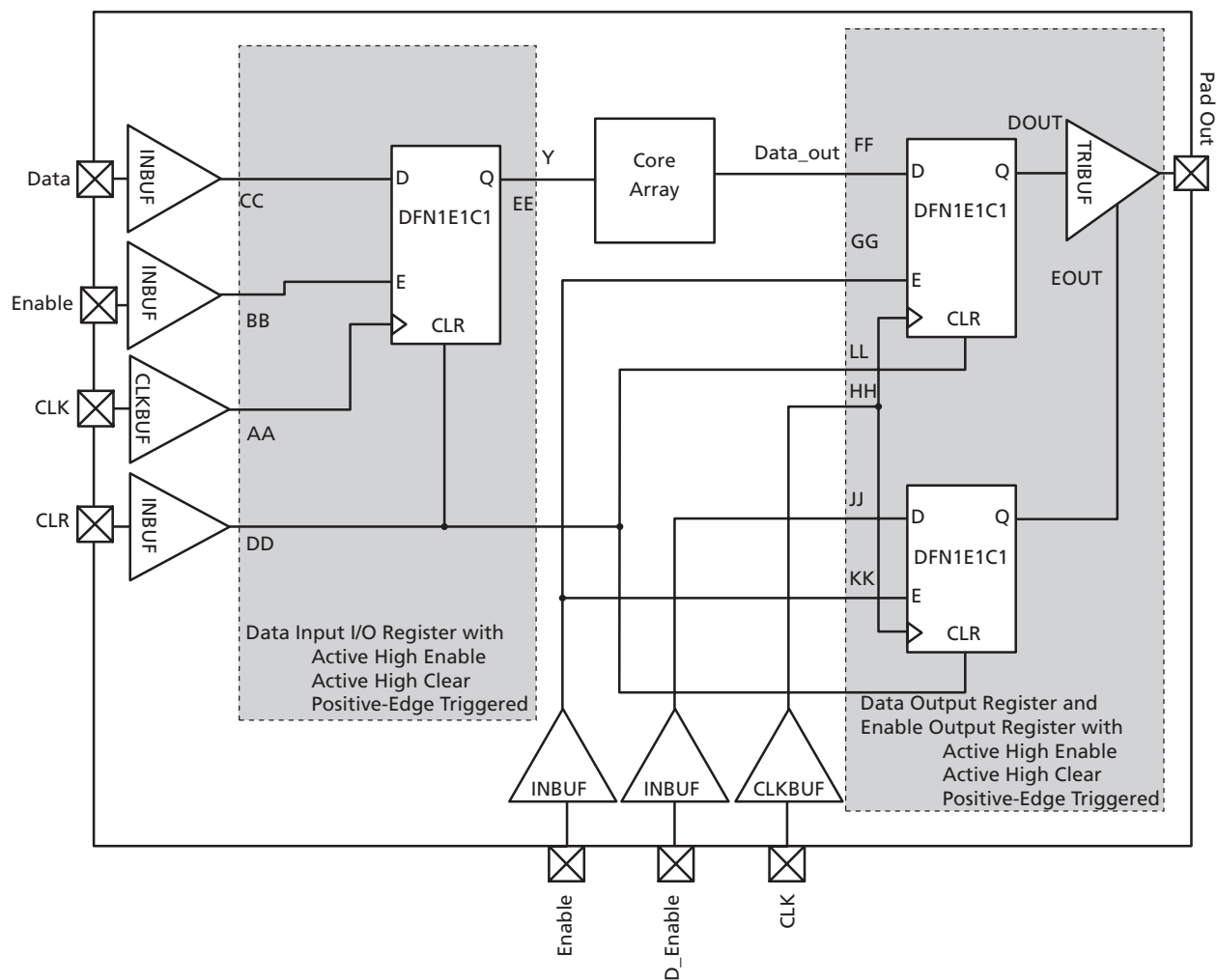


Figure 2-27 • Timing Model of the Registered I/O Buffers with Synchronous Enable and Asynchronous Clear

Table 2-181 • Parameter Definition and Measuring Nodes

Parameter Name	Parameter Definition	Measuring Nodes (from, to)*
t _{CLKQ}	Clock-to-Q of the Output Data Register	HH, DOUT
t _{OSUD}	Data Setup Time for the Output Data Register	FF, HH
t _{OHD}	Data Hold Time for the Output Data Register	FF, HH
t _{OSUE}	Enable Setup Time for the Output Data Register	GG, HH
t _{OHE}	Enable Hold Time for the Output Data Register	GG, HH
t _{OCLR2Q}	Asynchronous Clear-to-Q of the Output Data Register	LL, DOUT
t _{OEREMCLR}	Asynchronous Clear Removal Time for the Output Data Register	LL, HH
t _{OERECCLR}	Asynchronous Clear Recovery Time for the Output Data Register	LL, HH
t _{OECLKQ}	Clock-to-Q of the Output Enable Register	HH, EOUT
t _{OESUD}	Data Setup Time for the Output Enable Register	JJ, HH
t _{OEHD}	Data Hold Time for the Output Enable Register	JJ, HH
t _{OESUE}	Enable Setup Time for the Output Enable Register	KK, HH
t _{OEHHE}	Enable Hold Time for the Output Enable Register	KK, HH
t _{OECLR2Q}	Asynchronous Clear-to-Q of the Output Enable Register	II, EOUT
t _{OEREMCLR}	Asynchronous Clear Removal Time for the Output Enable Register	II, HH
t _{OERECCLR}	Asynchronous Clear Recovery Time for the Output Enable Register	II, HH
t _{ICLKQ}	Clock-to-Q of the Input Data Register	AA, EE
t _{ISUD}	Data Setup Time for the Input Data Register	CC, AA
t _{IHD}	Data Hold Time for the Input Data Register	CC, AA
t _{ISUE}	Enable Setup Time for the Input Data Register	BB, AA
t _{IHE}	Enable Hold Time for the Input Data Register	BB, AA
t _{ICLR2Q}	Asynchronous Clear-to-Q of the Input Data Register	DD, EE
t _{IEMCLR}	Asynchronous Clear Removal Time for the Input Data Register	DD, AA
t _{IIECCLR}	Asynchronous Clear Recovery Time for the Input Data Register	DD, AA

* See Figure 2-27 on page 2-98 for more information.

Input Register

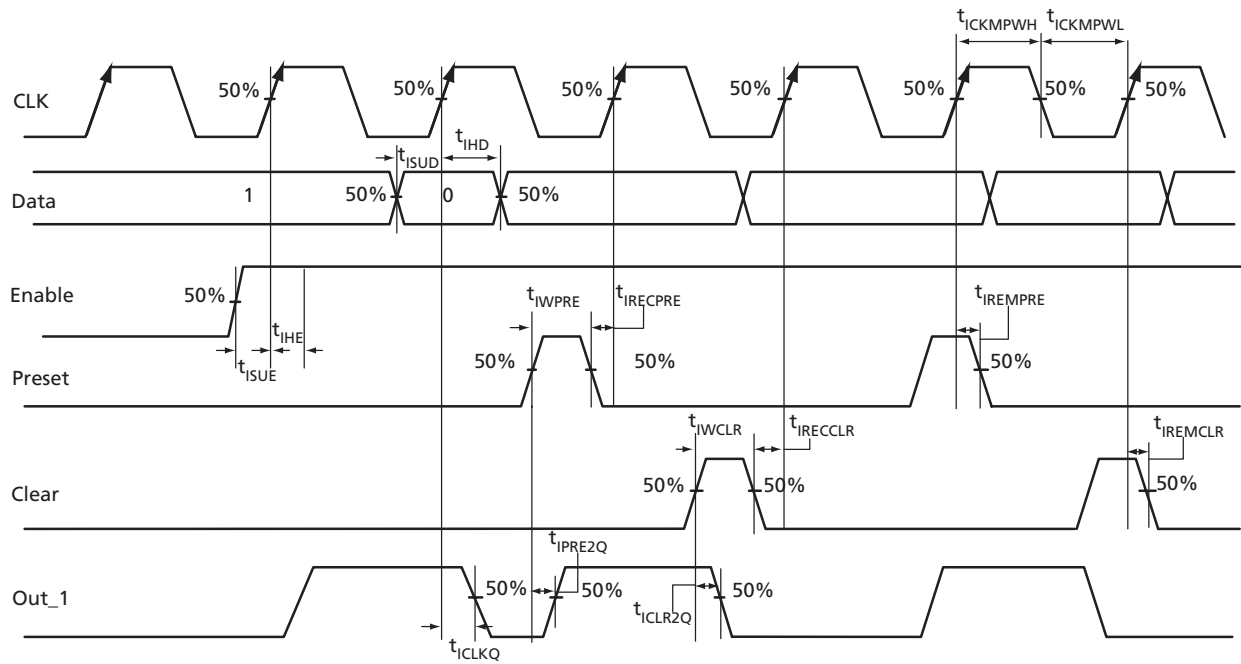


Figure 2-28 • Input Register Timing Diagram

Timing Characteristics

1.5 V DC Core Voltage

Table 2-182 • Input Data Register Propagation Delays
Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$

Parameter	Description	–1	Std.	Units
t_{CLKQ}	Clock-to-Q of the Input Data Register	0.24	0.29	ns
t_{ISUD}	Data Setup Time for the Input Data Register	0.27	0.31	ns
t_{IHD}	Data Hold Time for the Input Data Register	0.00	0.00	ns
t_{ISUE}	Enable Setup Time for the Input Data Register	0.38	0.45	ns
t_{IHE}	Enable Hold Time for the Input Data Register	0.00	0.00	ns
t_{ICLR2Q}	Asynchronous Clear-to-Q of the Input Data Register	0.46	0.54	ns
t_{IPRE2Q}	Asynchronous Preset-to-Q of the Input Data Register	0.46	0.54	ns
t_{IREMCLR}	Asynchronous Clear Removal Time for the Input Data Register	0.00	0.00	ns
t_{IRECCLR}	Asynchronous Clear Recovery Time for the Input Data Register	0.23	0.27	ns
t_{IREMPRE}	Asynchronous Preset Removal Time for the Input Data Register	0.00	0.00	ns
t_{IRECPRE}	Asynchronous Preset Recovery Time for the Input Data Register	0.23	0.27	ns
t_{IWCLR}	Asynchronous Clear Minimum Pulse Width for the Input Data Register	0.19	0.22	ns
t_{IWPRE}	Asynchronous Preset Minimum Pulse Width for the Input Data Register	0.19	0.22	ns
t_{ICKMPWH}	Clock Minimum Pulse Width HIGH for the Input Data Register	0.31	0.36	ns
t_{ICKMPWL}	Clock Minimum Pulse Width LOW for the Input Data Register	0.28	0.32	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

1.2 V DC Core Voltage

Table 2-183 • Input Data Register Propagation Delays
Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$

Parameter	Description	–1	Std.	Units
t_{CLKQ}	Clock-to-Q of the Input Data Register	0.32	0.37	ns
t_{ISUD}	Data Setup Time for the Input Data Register	0.35	0.41	ns
t_{IHD}	Data Hold Time for the Input Data Register	0.00	0.00	ns
t_{ISUE}	Enable Setup Time for the Input Data Register	0.50	0.58	ns
t_{IHE}	Enable Hold Time for the Input Data Register	0.00	0.00	ns
t_{ICLR2Q}	Asynchronous Clear-to-Q of the Input Data Register	0.60	0.71	ns
t_{IPRE2Q}	Asynchronous Preset-to-Q of the Input Data Register	0.60	0.71	ns
t_{IREMCLR}	Asynchronous Clear Removal Time for the Input Data Register	0.00	0.00	ns
t_{IRECCLR}	Asynchronous Clear Recovery Time for the Input Data Register	0.30	0.35	ns
t_{IREMPRE}	Asynchronous Preset Removal Time for the Input Data Register	0.00	0.00	ns
t_{IRECPRE}	Asynchronous Preset Recovery Time for the Input Data Register	0.30	0.35	ns
t_{IWCLR}	Asynchronous Clear Minimum Pulse Width for the Input Data Register	0.19	0.22	ns
t_{IWPRE}	Asynchronous Preset Minimum Pulse Width for the Input Data Register	0.19	0.22	ns
t_{ICKMPWH}	Clock Minimum Pulse Width HIGH for the Input Data Register	0.31	0.36	ns
t_{ICKMPWL}	Clock Minimum Pulse Width LOW for the Input Data Register	0.28	0.32	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Output Register

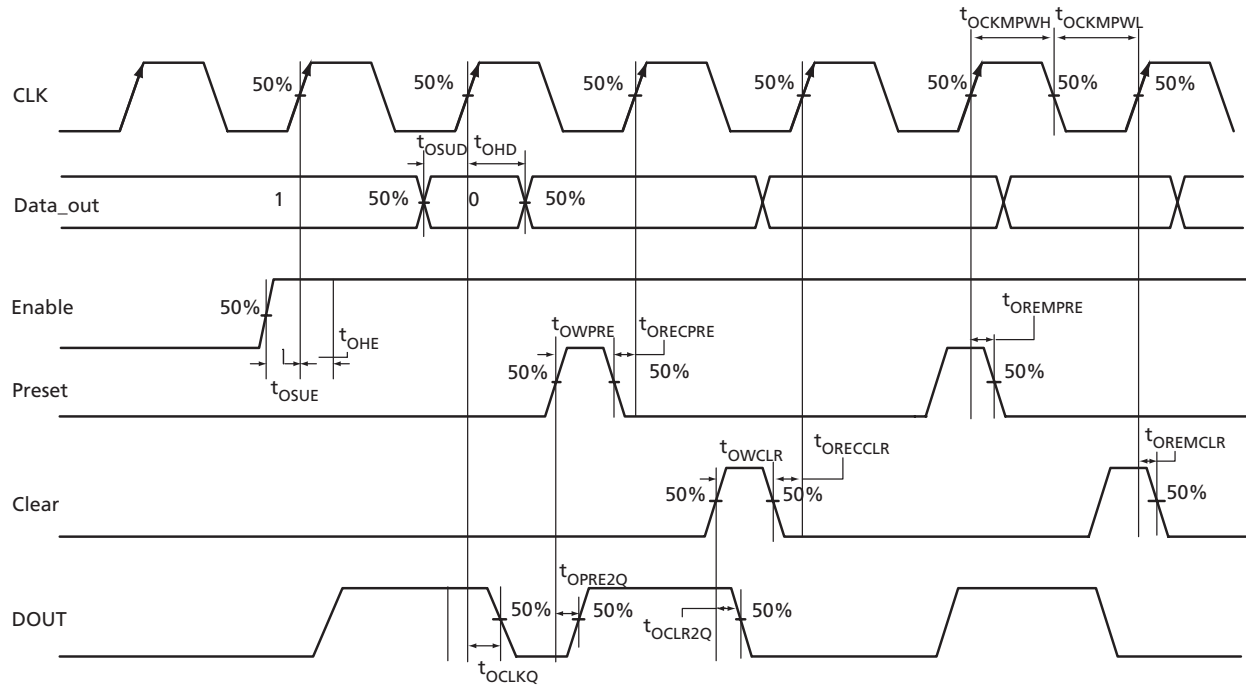


Figure 2-29 • Output Register Timing Diagram

Timing Characteristics

1.5 V DC Core Voltage

Table 2-184 • Output Data Register Propagation Delays
Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$

Parameter	Description	-1	Std.	Units
t_{OCLKQ}	Clock-to-Q of the Output Data Register	0.60	0.71	ns
t_{OSUD}	Data Setup Time for the Output Data Register	0.32	0.37	ns
t_{OHD}	Data Hold Time for the Output Data Register	0.00	0.00	ns
t_{OSUE}	Enable Setup Time for the Output Data Register	0.45	0.53	ns
t_{OHE}	Enable Hold Time for the Output Data Register	0.00	0.00	ns
t_{OCLR2Q}	Asynchronous Clear-to-Q of the Output Data Register	0.82	0.96	ns
t_{OPRE2Q}	Asynchronous Preset-to-Q of the Output Data Register	0.82	0.96	ns
t_{OREMCLR}	Asynchronous Clear Removal Time for the Output Data Register	0.00	0.00	ns
t_{ORECCLR}	Asynchronous Clear Recovery Time for the Output Data Register	0.23	0.27	ns
t_{OREMPRE}	Asynchronous Preset Removal Time for the Output Data Register	0.00	0.00	ns
t_{ORECPRE}	Asynchronous Preset Recovery Time for the Output Data Register	0.23	0.27	ns
t_{OWCLR}	Asynchronous Clear Minimum Pulse Width for the Output Data Register	0.19	0.22	ns
t_{OWPRE}	Asynchronous Preset Minimum Pulse Width for the Output Data Register	0.19	0.22	ns
t_{OCKMPWH}	Clock Minimum Pulse Width HIGH for the Output Data Register	0.31	0.36	ns
t_{OCKMPWL}	Clock Minimum Pulse Width LOW for the Output Data Register	0.28	0.32	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

1.2 V DC Core Voltage

Table 2-185 • Output Data Register Propagation Delays
Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$

Parameter	Description	-1	Std.	Units
t_{OCLKQ}	Clock-to-Q of the Output Data Register	0.78	0.92	ns
t_{OSUD}	Data Setup Time for the Output Data Register	0.42	0.49	ns
t_{OHD}	Data Hold Time for the Output Data Register	0.00	0.00	ns
t_{OSUE}	Enable Setup Time for the Output Data Register	0.58	0.69	ns
t_{OHE}	Enable Hold Time for the Output Data Register	0.00	0.00	ns
t_{OCLR2Q}	Asynchronous Clear-to-Q of the Output Data Register	1.07	1.26	ns
t_{OPRE2Q}	Asynchronous Preset-to-Q of the Output Data Register	1.07	1.26	ns
t_{OREMCLR}	Asynchronous Clear Removal Time for the Output Data Register	0.00	0.00	ns
t_{ORECCLR}	Asynchronous Clear Recovery Time for the Output Data Register	0.30	0.35	ns
t_{OREMPRE}	Asynchronous Preset Removal Time for the Output Data Register	0.00	0.00	ns
t_{ORECPRE}	Asynchronous Preset Recovery Time for the Output Data Register	0.30	0.35	ns
t_{OWCLR}	Asynchronous Clear Minimum Pulse Width for the Output Data Register	0.19	0.22	ns
t_{OWPRE}	Asynchronous Preset Minimum Pulse Width for the Output Data Register	0.19	0.22	ns
t_{OCKMPWH}	Clock Minimum Pulse Width HIGH for the Output Data Register	0.31	0.36	ns
t_{OCKMPWL}	Clock Minimum Pulse Width LOW for the Output Data Register	0.28	0.32	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Output Enable Register

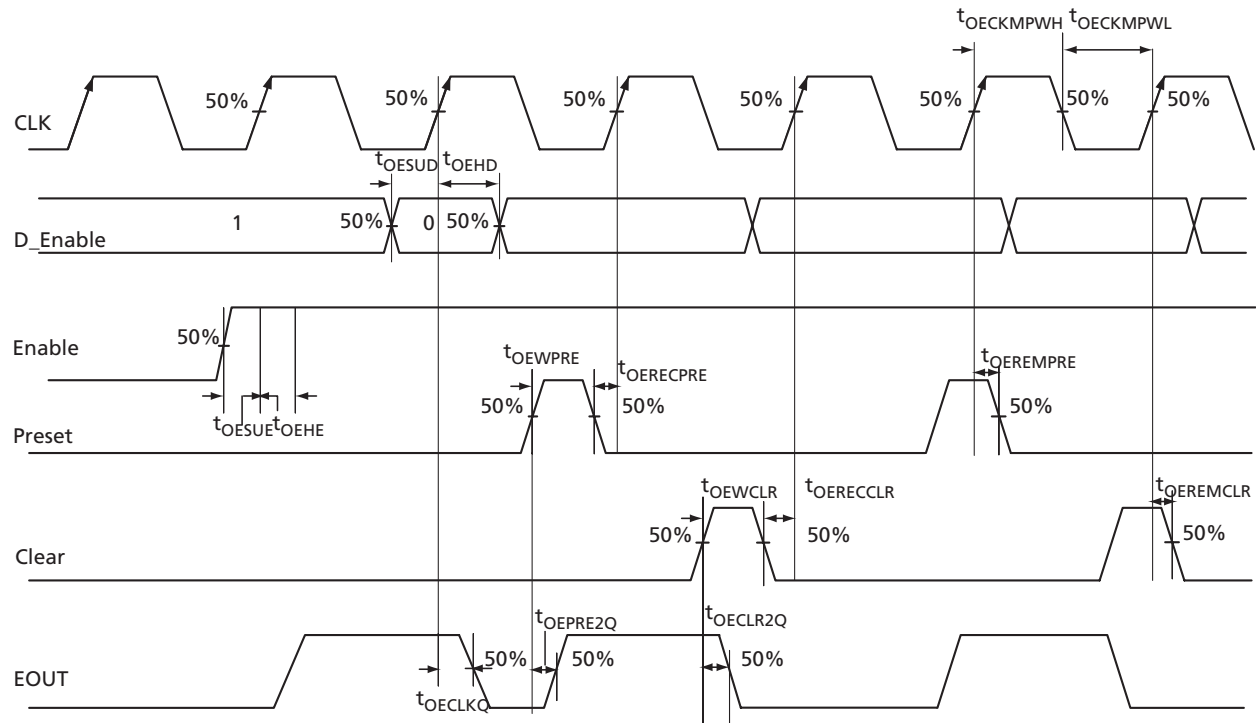


Figure 2-30 • Output Enable Register Timing Diagram

Timing Characteristics

1.5 V DC Core Voltage

Table 2-186 • Output Enable Register Propagation Delays
Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$

Parameter	Description	-1	Std.	Units
t_{OECLKQ}	Clock-to-Q of the Output Enable Register	0.45	0.53	ns
t_{OESUD}	Data Setup Time for the Output Enable Register	0.32	0.37	ns
t_{OEHD}	Data Hold Time for the Output Enable Register	0.00	0.00	ns
t_{OESUE}	Enable Setup Time for the Output Enable Register	0.44	0.52	ns
t_{OEHE}	Enable Hold Time for the Output Enable Register	0.00	0.00	ns
$t_{OECLR2Q}$	Asynchronous Clear-to-Q of the Output Enable Register	0.68	0.80	ns
$t_{OEPRE2Q}$	Asynchronous Preset-to-Q of the Output Enable Register	0.68	0.80	ns
$t_{OEREMCLR}$	Asynchronous Clear Removal Time for the Output Enable Register	0.00	0.00	ns
$t_{OERECCLR}$	Asynchronous Clear Recovery Time for the Output Enable Register	0.23	0.27	ns
$t_{OEREMPRE}$	Asynchronous Preset Removal Time for the Output Enable Register	0.00	0.00	ns
$t_{OERECPRE}$	Asynchronous Preset Recovery Time for the Output Enable Register	0.23	0.27	ns
$t_{OEWCCLR}$	Asynchronous Clear Minimum Pulse Width for the Output Enable Register	0.19	0.22	ns
t_{OEWPPE}	Asynchronous Preset Minimum Pulse Width for the Output Enable Register	0.19	0.22	ns
$t_{OECKMPWH}$	Clock Minimum Pulse Width HIGH for the Output Enable Register	0.31	0.36	ns
$t_{OECKMPWL}$	Clock Minimum Pulse Width LOW for the Output Enable Register	0.28	0.32	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

1.2 V DC Core Voltage

Table 2-187 • Output Enable Register Propagation Delays
Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$

Parameter	Description	-1	Std.	Units
t_{OECLKQ}	Clock-to-Q of the Output Enable Register	0.59	0.70	ns
t_{OESUD}	Data Setup Time for the Output Enable Register	0.42	0.49	ns
t_{OEHD}	Data Hold Time for the Output Enable Register	0.00	0.00	ns
t_{OESUE}	Enable Setup Time for the Output Enable Register	0.58	0.68	ns
t_{OEHE}	Enable Hold Time for the Output Enable Register	0.00	0.00	ns
$t_{OECLR2Q}$	Asynchronous Clear-to-Q of the Output Enable Register	0.89	1.04	ns
$t_{OEPRE2Q}$	Asynchronous Preset-to-Q of the Output Enable Register	0.89	1.04	ns
$t_{OEREMCLR}$	Asynchronous Clear Removal Time for the Output Enable Register	0.00	0.00	ns
$t_{OERECCLR}$	Asynchronous Clear Recovery Time for the Output Enable Register	0.30	0.35	ns
$t_{OEREMPRE}$	Asynchronous Preset Removal Time for the Output Enable Register	0.00	0.00	ns
$t_{OERECPRE}$	Asynchronous Preset Recovery Time for the Output Enable Register	0.30	0.35	ns
$t_{OEWCCLR}$	Asynchronous Clear Minimum Pulse Width for the Output Enable Register	0.19	0.22	ns
t_{OEWPPE}	Asynchronous Preset Minimum Pulse Width for the Output Enable Register	0.19	0.22	ns
$t_{OECKMPWH}$	Clock Minimum Pulse Width HIGH for the Output Enable Register	0.31	0.36	ns
$t_{OECKMPWL}$	Clock Minimum Pulse Width LOW for the Output Enable Register	0.28	0.32	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

DDR Module Specifications

Input DDR Module

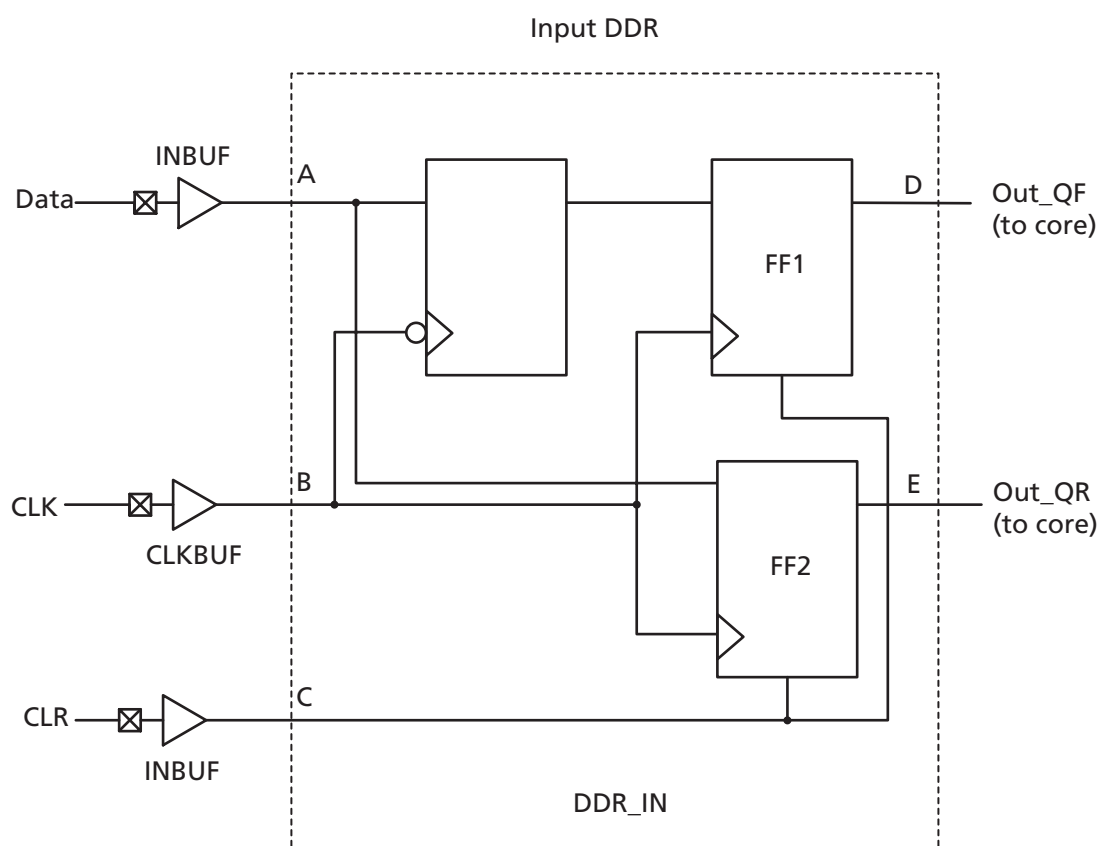


Figure 2-31 • Input DDR Timing Model

Table 2-188 • Parameter Definitions

Parameter Name	Parameter Definition	Measuring Nodes (from, to)
t_{DDRICKQ1}	Clock-to-Out Out_QR	B, D
t_{DDRICKQ2}	Clock-to-Out Out_QF	B, E
t_{DDRISUD}	Data Setup Time of DDR input	A, B
t_{DDRiHD}	Data Hold Time of DDR input	A, B
$t_{\text{DDRICLR2Q1}}$	Clear-to-Out Out_QR	C, D
$t_{\text{DDRICLR2Q2}}$	Clear-to-Out Out_QF	C, E
$t_{\text{DDRIREMCLR}}$	Clear Removal	C, B
$t_{\text{DDRIRECCLR}}$	Clear Recovery	C, B



1.5 V DC Core Voltage

Table 2-189 • Input DDR Propagation Delays
Commercial-Case Conditions: $T_J = 70^{\circ}\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

1.2 V DC Core Voltage

Table 2-190 • Input DDR Propagation Delays

Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$

Parameter	Description	–1	Std.	Units
t_{DDRICKQ1}	Clock-to-Out Out_QR for Input DDR	0.43	0.37	ns
t_{DDRICKQ2}	Clock-to-Out Out_QF for Input DDR	0.61	0.52	ns
t_{DDRISUD1}	Data Setup for Input DDR (fall)	0.44	0.38	ns
t_{DDRISUD2}	Data Setup for Input DDR (rise)	0.39	0.33	ns
t_{DDRIRD1}	Data Hold for Input DDR (fall)	0.00	0.00	ns
t_{DDRIRD2}	Data Hold for Input DDR (rise)	0.00	0.00	ns
$t_{\text{DDRICLR2Q1}}$	Asynchronous Clear-to-Out Out_QR for Input DDR	0.73	0.62	ns
$t_{\text{DDRICLR2Q2}}$	Asynchronous Clear-to-Out Out_QF for Input DDR	0.89	0.76	ns
$t_{\text{DDRIRECLR}}$	Asynchronous Clear Removal Time for Input DDR	0.00	0.00	ns
$t_{\text{DDRIRECLR}}$	Asynchronous Clear Recovery Time for Input DDR	0.35	0.30	ns
$t_{\text{DDRIRWCLR}}$	Asynchronous Clear Minimum Pulse Width for Input DDR	0.22	0.19	ns
$t_{\text{DDRICKMPWH}}$	Clock Minimum Pulse Width HIGH for Input DDR	0.36	0.31	ns
$t_{\text{DDRICKMPWL}}$	Clock Minimum Pulse Width LOW for Input DDR	0.32	0.28	ns
F_{DDRIMAX}	Maximum Frequency for Input DDR	TBD	TBD	MHz

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Output DDR Module

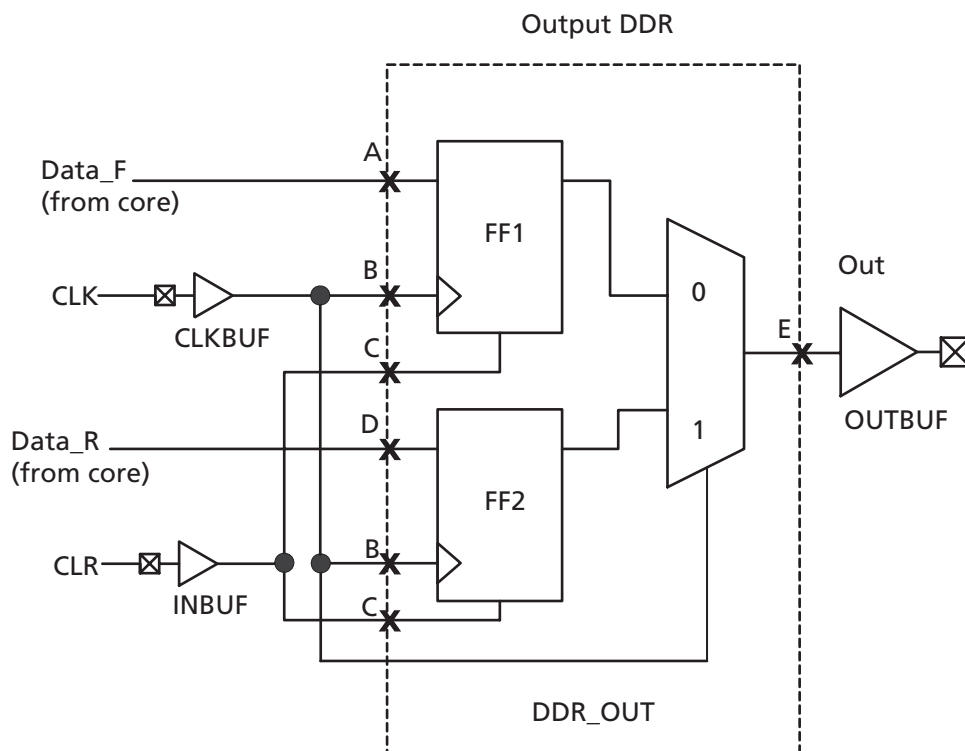


Figure 2-33 • Output DDR Timing Model

Table 2-191 • Parameter Definitions

Parameter Name	Parameter Definition	Measuring Nodes (from, to)
$t_{DDROCLKQ}$	Clock-to-Out	B, E
$t_{DDROCLR2Q}$	Asynchronous Clear-to-Out	C, E
$t_{DDROREMCLR}$	Clear Removal	C, B
$t_{DDRORECCLR}$	Clear Recovery	C, B
$t_{DDROSUD1}$	Data Setup Data_F	A, B
$t_{DDROSUD2}$	Data Setup Data_R	D, B
$t_{DDROHD1}$	Data Hold Data_F	A, B
$t_{DDROHD2}$	Data Hold Data_R	D, B

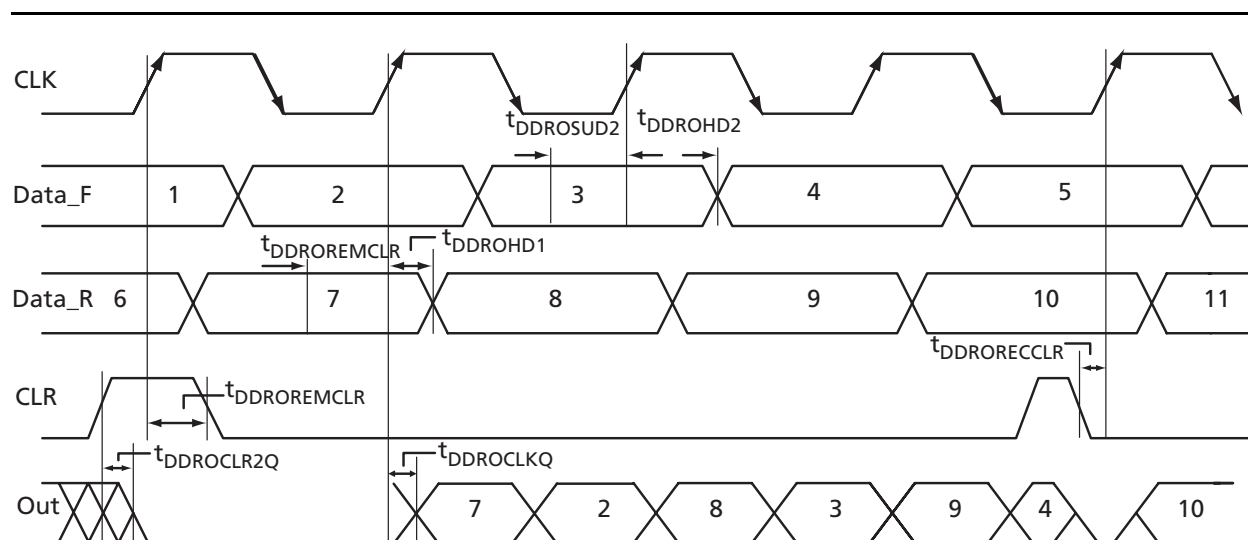


Figure 2-34 • Output DDR Timing Diagram

Timing Characteristics

1.5 V DC Core Voltage

Table 2-192 • Output DDR Propagation Delays

Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$

Parameter	Description	–1	Std.	Units
$t_{DDROCLKQ}$	Clock-to-Out of DDR for Output DDR	0.72	0.84	ns
$t_{DDRISUD1}$	Data_F Data Setup for Output DDR	0.39	0.45	ns
$t_{DDROSUD2}$	Data_R Data Setup for Output DDR	0.39	0.45	ns
$t_{DDROHD1}$	Data_F Data Hold for Output DDR	0.00	0.00	ns
$t_{DDROHD2}$	Data_R Data Hold for Output DDR	0.00	0.00	ns
$t_{DDROCLR2Q}$	Asynchronous Clear-to-Out for Output DDR	0.82	0.96	ns
$t_{DDROEMCLR}$	Asynchronous Clear Removal Time for Output DDR	0.00	0.00	ns
$t_{DDROECCLR}$	Asynchronous Clear Recovery Time for Output DDR	0.23	0.27	ns
$t_{DDROWCLR1}$	Asynchronous Clear Minimum Pulse Width for Output DDR	0.19	0.22	ns
$t_{DDROCKMPWH}$	Clock Minimum Pulse Width HIGH for the Output DDR	0.31	0.36	ns
$t_{DDROCKMPWL}$	Clock Minimum Pulse Width LOW for the Output DDR	0.28	0.32	ns
F_{DDOMAX}	Maximum Frequency for the Output DDR			MHz

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

1.2 V DC Core Voltage

Table 2-193 • Output DDR Propagation Delays

Commercial-Case Conditions: $T_J = 70^{\circ}\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$

Parameter	Description	–1	Std.	Units
t_{DDROCLKQ}	Clock-to-Out of DDR for Output DDR	1.10	0.94	ns
t_{DDRISUD1}	Data_F Data Setup for Output DDR	0.59	0.50	ns
t_{DDROSUD2}	Data_R Data Setup for Output DDR	0.59	0.50	ns
t_{DDROHD1}	Data_F Data Hold for Output DDR	0.00	0.00	ns
t_{DDROHD2}	Data_R Data Hold for Output DDR	0.00	0.00	ns
$t_{\text{DDROCLR2Q}}$	Asynchronous Clear-to-Out for Output DDR	1.26	1.07	ns
$t_{\text{DDROREMCLR}}$	Asynchronous Clear Removal Time for Output DDR	0.00	0.00	ns
$t_{\text{DDRORECCLR}}$	Asynchronous Clear Recovery Time for Output DDR	0.35	0.30	ns
$t_{\text{DDROWCLR1}}$	Asynchronous Clear Minimum Pulse Width for Output DDR	0.22	0.19	ns
$t_{\text{DDROCKMPWH}}$	Clock Minimum Pulse Width HIGH for the Output DDR	0.36	0.31	ns
$t_{\text{DDROCKMPWL}}$	Clock Minimum Pulse Width LOW for the Output DDR	0.32	0.28	ns
F_{DDOMAX}	Maximum Frequency for the Output DDR	TBD	TBD	MHz

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

VersaTile Characteristics

VersaTile Specifications as a Combinatorial Module

The ProASIC3 library offers all combinations of LUT-3 combinatorial functions. In this section, timing characteristics are presented for a sample of the library. For more details, refer to the *IGLOO[®] Fusion, and ProASIC3 Macro Library Guide*.

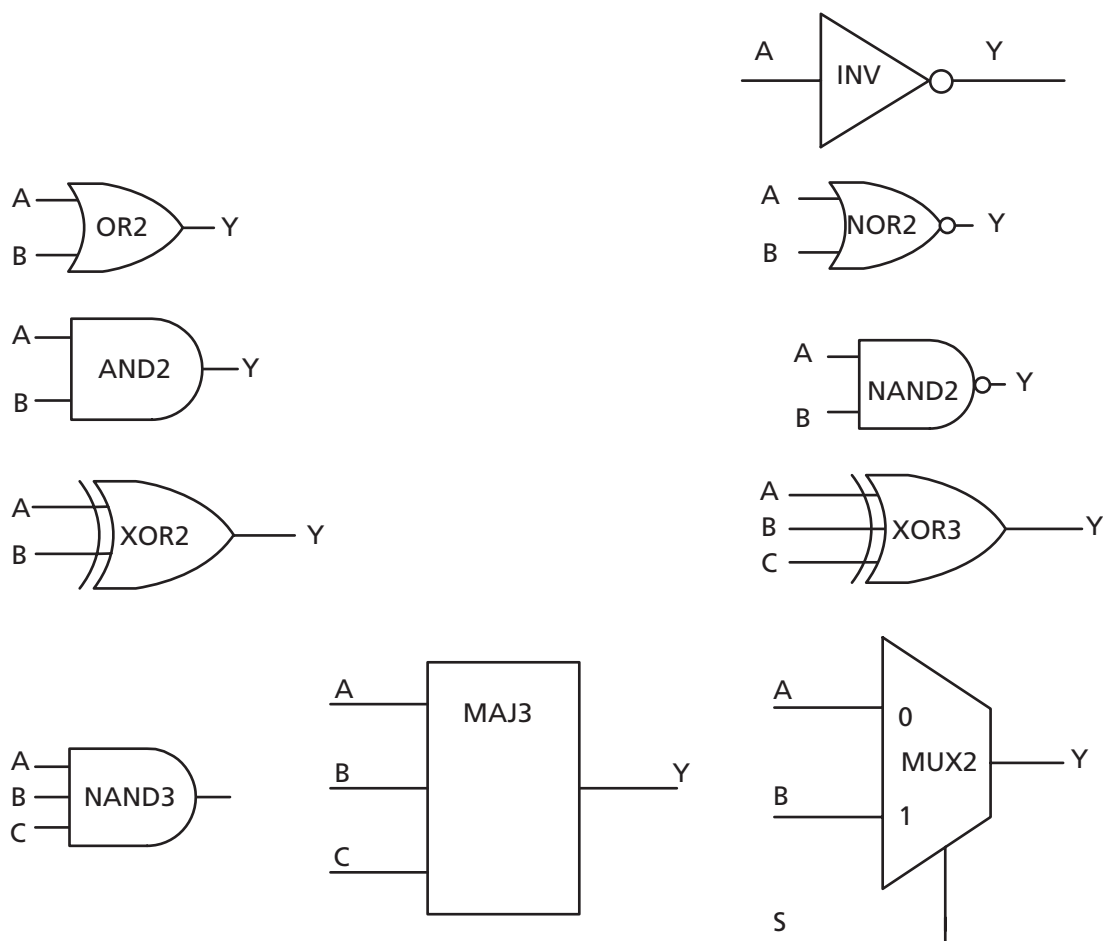


Figure 2-35 • Sample of Combinatorial Cells

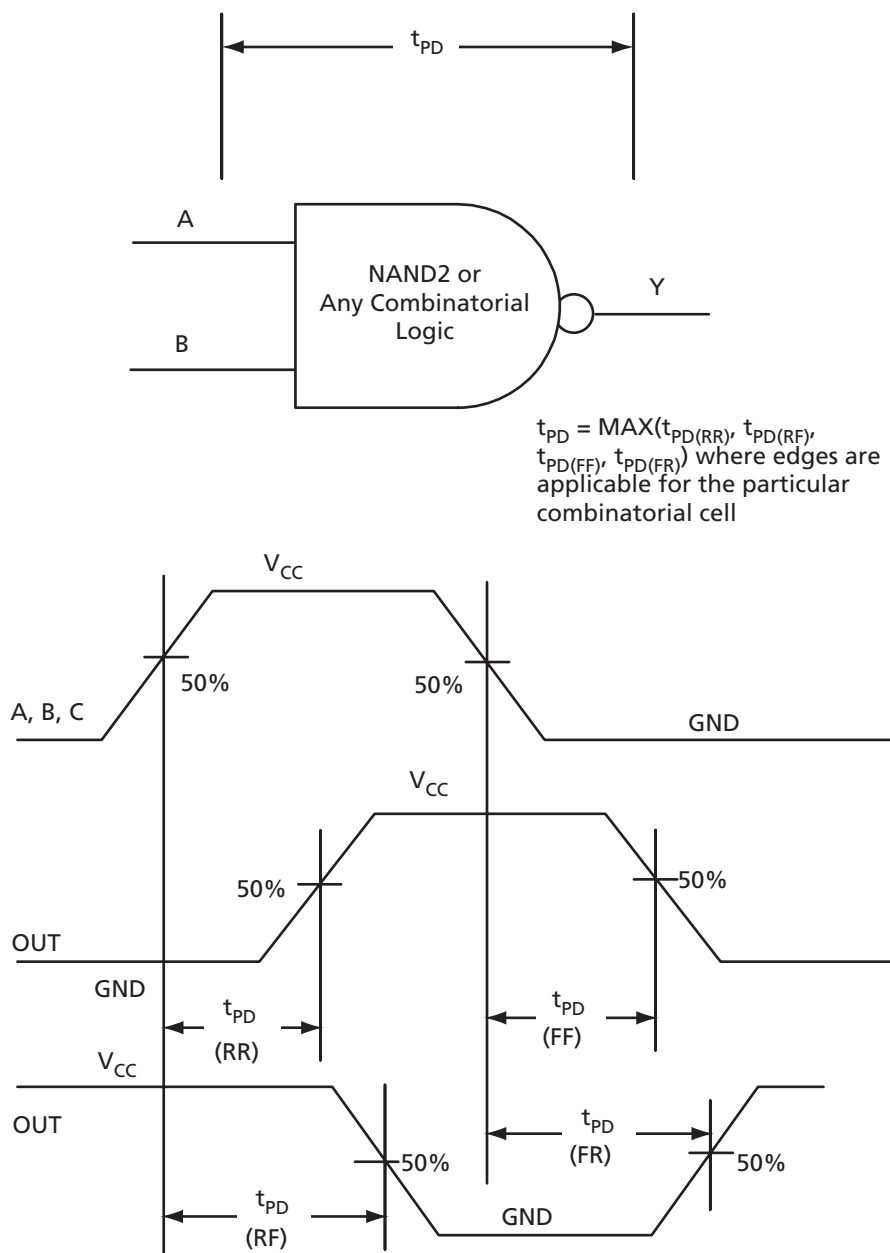


Figure 2-36 • Timing Model and Waveforms

Timing Characteristics

1.5 V DC Core Voltage

Table 2-194 • Combinatorial Cell Propagation Delays

Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$

Combinatorial Cell	Equation	Parameter	–1	Std.	Units
INV	$Y = !A$	t_{PD}	0.41	0.48	ns
AND2	$Y = A \cdot B$	t_{PD}	0.48	0.57	ns
NAND2	$Y = !(A \cdot B)$	t_{PD}	0.48	0.57	ns
OR2	$Y = A + B$	t_{PD}	0.50	0.58	ns
NOR2	$Y = !(A + B)$	t_{PD}	0.50	0.58	ns
XOR2	$Y = A \oplus B$	t_{PD}	0.75	0.88	ns
MAJ3	$Y = \text{MAJ}(A, B, C)$	t_{PD}	0.71	0.84	ns
XOR3	$Y = A \oplus B \oplus C$	t_{PD}	0.89	1.05	ns
MUX2	$Y = A \text{ !S} + B \text{ S}$	t_{PD}	0.52	0.61	ns
AND3	$Y = A \cdot B \cdot C$	t_{PD}	0.57	0.67	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

1.2 V DC Core Voltage

Table 2-195 • Combinatorial Cell Propagation Delays

Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$

Combinatorial Cell	Equation	Parameter	–1	Std.	Units
INV	$Y = !A$	t_{PD}	0.54	0.63	ns
AND2	$Y = A \cdot B$	t_{PD}	0.63	0.74	ns
NAND2	$Y = !(A \cdot B)$	t_{PD}	0.63	0.74	ns
OR2	$Y = A + B$	t_{PD}	0.65	0.76	ns
NOR2	$Y = !(A + B)$	t_{PD}	0.65	0.76	ns
XOR2	$Y = A \oplus B$	t_{PD}	0.98	1.16	ns
MAJ3	$Y = \text{MAJ}(A, B, C)$	t_{PD}	0.93	1.09	ns
XOR3	$Y = A \oplus B \oplus C$	t_{PD}	1.17	1.37	ns
MUX2	$Y = A \text{ !S} + B \text{ S}$	t_{PD}	0.68	0.79	ns
AND3	$Y = A \cdot B \cdot C$	t_{PD}	0.75	0.88	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

VersaTile Specifications as a Sequential Module

The ProASIC3 library offers a wide variety of sequential cells, including flip-flops and latches. Each has a data input and optional enable, clear, or preset. In this section, timing characteristics are presented for a representative sample from the library. For more details, refer to the *IGLOO, Fusion, and ProASIC3 Macro Library Guide*.

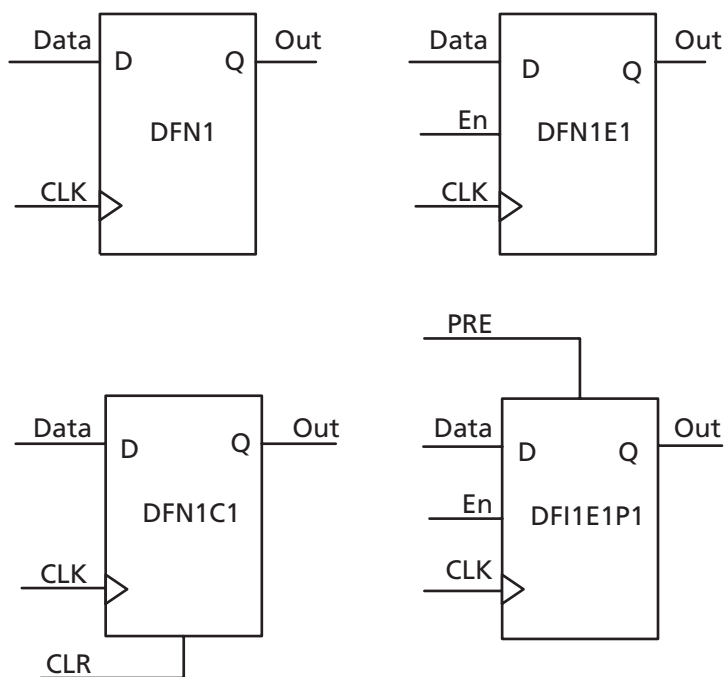


Figure 2-37 • Sample of Sequential Cells

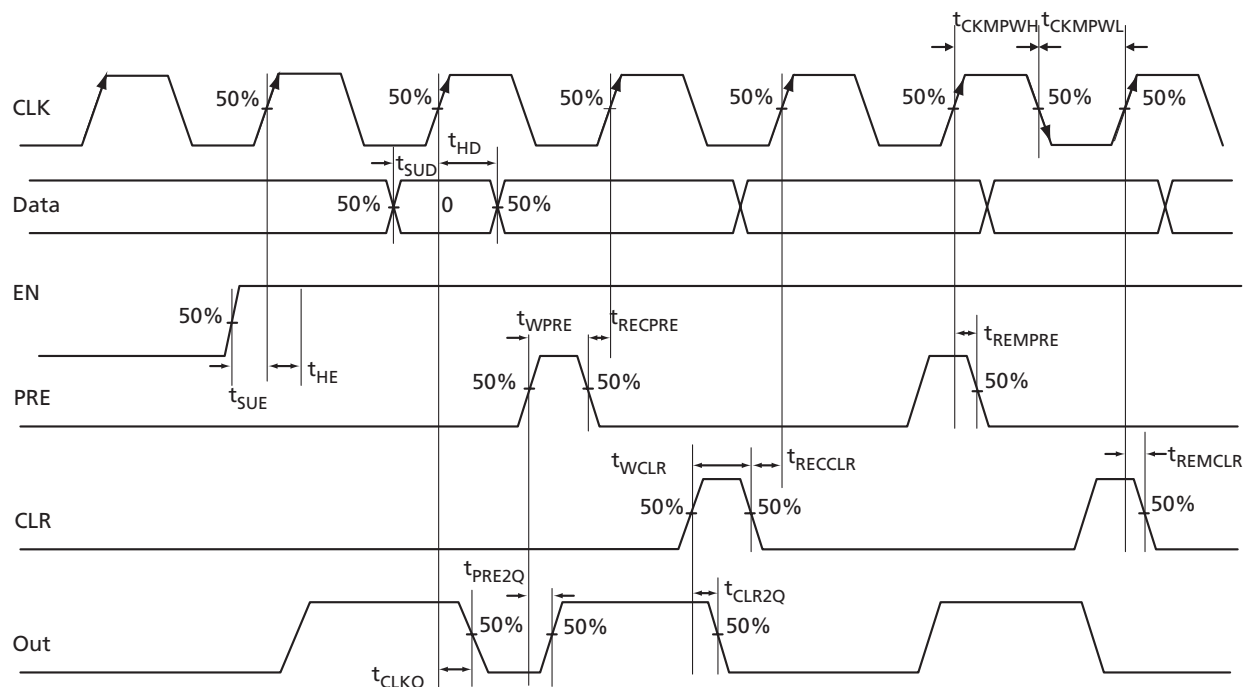


Figure 2-38 • Timing Model and Waveforms

Timing Characteristics

1.5 V DC Core Voltage

Table 2-196 • Register Delays

Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$

Parameter	Description	-1	Std.	Units
t_{CLKQ}	Clock-to-Q of the Core Register	0.56	0.66	ns
t_{SUD}	Data Setup Time for the Core Register	0.44	0.51	ns
t_{HD}	Data Hold Time for the Core Register	0.00	0.00	ns
t_{SUE}	Enable Setup Time for the Core Register	0.46	0.55	ns
t_{HE}	Enable Hold Time for the Core Register	0.00	0.00	ns
t_{CLR2Q}	Asynchronous Clear-to-Q of the Core Register	0.41	0.48	ns
t_{PRE2Q}	Asynchronous Preset-to-Q of the Core Register	0.41	0.48	ns
$t_{REMCCLR}$	Asynchronous Clear Removal Time for the Core Register	0.00	0.00	ns
t_{RECCLR}	Asynchronous Clear Recovery Time for the Core Register	0.23	0.27	ns
t_{REMPRE}	Asynchronous Preset Removal Time for the Core Register	0.00	0.00	ns
t_{RECPRE}	Asynchronous Preset Recovery Time for the Core Register	0.23	0.27	ns
t_{WCLR}	Asynchronous Clear Minimum Pulse Width for the Core Register	0.30	0.34	ns
t_{WPRE}	Asynchronous Preset Minimum Pulse Width for the Core Register	0.30	0.34	ns
t_{CKMPWH}	Clock Minimum Pulse Width HIGH for the Core Register	0.56	0.64	ns
t_{CKMPWL}	Clock Minimum Pulse Width LOW for the Core Register	0.56	0.64	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.

1.2 V DC Core Voltage

Table 2-197 • Register Delays

Commercial-Case Conditions: $T_J = 70^{\circ}\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$

Parameter	Description	–1	Std.	Units
t_{CLKQ}	Clock-to-Q of the Core Register	0.73	0.86	ns
t_{SUD}	Data Setup Time for the Core Register	0.57	0.67	ns
t_{HD}	Data Hold Time for the Core Register	0.00	0.00	ns
t_{SUE}	Enable Setup Time for the Core Register	0.61	0.71	ns
t_{HE}	Enable Hold Time for the Core Register	0.00	0.00	ns
t_{CLR2Q}	Asynchronous Clear-to-Q of the Core Register	0.53	0.63	ns
t_{PRE2Q}	Asynchronous Preset-to-Q of the Core Register	0.53	0.63	ns
t_{REMCLR}	Asynchronous Clear Removal Time for the Core Register	0.00	0.00	ns
t_{RECCLR}	Asynchronous Clear Recovery Time for the Core Register	0.30	0.35	ns
t_{REMPRE}	Asynchronous Preset Removal Time for the Core Register	0.00	0.00	ns
t_{RECPRE}	Asynchronous Preset Recovery Time for the Core Register	0.30	0.35	ns
t_{WCLR}	Asynchronous Clear Minimum Pulse Width for the Core Register	0.30	0.34	ns
t_{WPRE}	Asynchronous Preset Minimum Pulse Width for the Core Register	0.30	0.34	ns
t_{CKMPWH}	Clock Minimum Pulse Width HIGH for the Core Register	0.56	0.64	ns
t_{CKMPWL}	Clock Minimum Pulse Width LOW for the Core Register	0.56	0.64	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

A3P250L Clock Tree Topology

Diagram illustrating a grid structure, likely representing a tiling or architectural layout. The grid is composed of 12 columns and 12 rows of rectangular tiles. A central 3x3 grid of tiles is highlighted with a dashed border. Labels and arrows indicate specific features:

- CCC**: Points to the left edge of the grid.
- Central Global Rib**: Points to the central horizontal line separating the top and bottom halves of the grid.
- VersaTile Rows**: Points to the central 3x3 grid of tiles.
- Global Spine**: Points to the right edge of the grid.

Advance v0.6

Global Tree Timing Characteristics

Global clock delays include the central rib delay, the spine delay, and the row delay. Delays do not include I/O input buffer clock delays, as these are I/O standard-dependent, and the clock may be driven and conditioned internally by the CCC module. For more details on clock conditioning capabilities, refer to the ["Clock Conditioning Circuits" section on page 2-123](#). [Table 2-198](#) to [Table 2-204 on page 2-122](#) present minimum and maximum global clock delays within each device. Minimum and maximum delays are measured with minimum and maximum loading.

Timing Characteristics

Table 2-198 • A3P250L Global Resource – Applies to 1.5 V DC Core Voltage
Commercial-Case Conditions: $T_J = 70^{\circ}\text{C}$, $V_{CC} = 1.425\text{ V}$

Parameter	Description	–1		Std.		Units
		Min. ¹	Max. ²	Min. ¹	Max. ²	
t_{RCKL}	Input LOW Delay for Global Clock	0.82	1.06	0.96	1.25	ns
t_{RCKH}	Input HIGH Delay for Global Clock	0.80	1.09	0.94	1.28	ns
$t_{RCKMPWH}$	Minimum Pulse Width HIGH for Global Clock					ns
$t_{RCKMPWL}$	Minimum Pulse Width LOW for Global Clock					ns
t_{RCKSW}	Maximum Skew for Global Clock		0.29		0.34	ns
F_{RMAX}	Maximum Frequency for Global Clock					MHz

Notes:

1. Value reflects minimum load. The delay is measured from the CCC output to the clock pin of a sequential element, located in a lightly loaded row (single element is connected to the global net).
2. Value reflects maximum load. The delay is measured on the clock pin of the farthest sequential element, located in a fully loaded row (all available flip-flops are connected to the global net in the row).
3. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-199 • A3P250L Global Resource – Applies to 1.2 V DC Core Voltage
Commercial-Case Conditions: $T_J = 70^{\circ}\text{C}$, $V_{CC} = 1.14\text{ V}$

Parameter	Description	–1		Std.		Units
		Min. ¹	Max. ²	Min. ¹	Max. ²	
t_{RCKL}	Input LOW Delay for Global Clock	1.40	1.68	1.64	1.97	ns
t_{RCKH}	Input HIGH Delay for Global Clock	1.38	1.71	1.62	2.01	ns
$t_{RCKMPWH}$	Minimum Pulse Width HIGH for Global Clock					ns
$t_{RCKMPWL}$	Minimum Pulse Width LOW for Global Clock					ns
t_{RCKSW}	Maximum Skew for Global Clock		0.33		0.39	ns
F_{RMAX}	Maximum Frequency for Global Clock					MHz

Notes:

1. Value reflects minimum load. The delay is measured from the CCC output to the clock pin of a sequential element, located in a lightly loaded row (single element is connected to the global net).
2. Value reflects maximum load. The delay is measured on the clock pin of the farthest sequential element, located in a fully loaded row (all available flip-flops are connected to the global net in the row).
3. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-200 • A3P600L Global Resource – Applies to 1.5 V DC Core Voltage
Commercial-Case Conditions: $T_J = 70^{\circ}\text{C}$, $V_{CC} = 1.425\text{ V}$

Parameter	Description	–1		Std.		Units
		Min. ¹	Max. ²	Min. ¹	Max. ²	
t_{RCKL}	Input LOW Delay for Global Clock	0.90	1.14	1.06	1.34	ns
t_{RCKH}	Input HIGH Delay for Global Clock	0.89	1.17	1.04	1.38	ns
$t_{RCKMPWH}$	Minimum Pulse Width HIGH for Global Clock					ns
$t_{RCKMPWL}$	Minimum Pulse Width LOW for Global Clock					ns
t_{RCKSW}	Maximum Skew for Global Clock		0.28		0.33	ns
F_{RMAX}	Maximum Frequency for Global Clock					MHz

Notes:

1. Value reflects minimum load. The delay is measured from the CCC output to the clock pin of a sequential element, located in a lightly loaded row (single element is connected to the global net).
2. Value reflects maximum load. The delay is measured on the clock pin of the farthest sequential element, located in a fully loaded row (all available flip-flops are connected to the global net in the row).
3. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-201 • A3P600L Global Resource – Applies to 1.2 V DC Core Voltage
Commercial-Case Conditions: $T_J = 70^{\circ}\text{C}$, $V_{CC} = 1.14\text{ V}$

Parameter	Description	–1		Std.		Units
		Min. ¹	Max. ²	Min. ¹	Max. ²	
t_{RCKL}	Input LOW Delay for Global Clock	1.48	1.76	1.74	2.07	ns
t_{RCKH}	Input HIGH Delay for Global Clock	1.47	1.80	1.72	2.11	ns
$t_{RCKMPWH}$	Minimum Pulse Width HIGH for Global Clock					ns
$t_{RCKMPWL}$	Minimum Pulse Width LOW for Global Clock					ns
t_{RCKSW}	Maximum Skew for Global Clock		0.33		0.39	ns
F_{RMAX}	Maximum Frequency for Global Clock					MHz

Notes:

1. Value reflects minimum load. The delay is measured from the CCC output to the clock pin of a sequential element, located in a lightly loaded row (single element is connected to the global net).
2. Value reflects maximum load. The delay is measured on the clock pin of the farthest sequential element, located in a fully loaded row (all available flip-flops are connected to the global net in the row).
3. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-202 • A3P1000L Global Resource – Applies to 1.5 V DC Core Voltage
Commercial-Case Conditions: $T_J = 70^{\circ}\text{C}$, $V_{CC} = 1.425\text{ V}$

Parameter	Description	–1		Std.		Units
		Min. ¹	Max. ²	Min. ¹	Max. ²	
t_{RCKL}	Input LOW Delay for Global Clock	1.02	1.26	1.20	1.48	ns
t_{RCKH}	Input HIGH Delay for Global Clock	1.01	1.29	1.18	1.52	ns
t_{RCKMPWH}	Minimum Pulse Width HIGH for Global Clock					ns
t_{RCKMPWL}	Minimum Pulse Width LOW for Global Clock					ns
t_{RCKSW}	Maximum Skew for Global Clock		0.28		0.33	ns
F_{RMAX}	Maximum Frequency for Global Clock					MHz

Notes:

1. Value reflects minimum load. The delay is measured from the CCC output to the clock pin of a sequential element, located in a lightly loaded row (single element is connected to the global net).
2. Value reflects maximum load. The delay is measured on the clock pin of the farthest sequential element, located in a fully loaded row (all available flip-flops are connected to the global net in the row).
3. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-203 • A3P1000L Global Resource – Applies to 1.2 V DC Core Voltage
Commercial-Case Conditions: $T_J = 70^{\circ}\text{C}$, $V_{CC} = 1.14\text{ V}$

Parameter	Description	–1		Std.		Units
		Min. ¹	Max. ²	Min. ¹	Max. ²	
t_{RCKL}	Input LOW Delay for Global Clock	1.61	1.89	1.89	2.22	ns
t_{RCKH}	Input HIGH Delay for Global Clock	1.60	1.92	1.88	2.26	ns
t_{RCKMPWH}	Minimum Pulse Width HIGH for Global Clock					ns
t_{RCKMPWL}	Minimum Pulse Width LOW for Global Clock					ns
t_{RCKSW}	Maximum Skew for Global Clock		0.33		0.39	ns
F_{RMAX}	Maximum Frequency for Global Clock					MHz

Notes:

1. Value reflects minimum load. The delay is measured from the CCC output to the clock pin of a sequential element, located in a lightly loaded row (single element is connected to the global net).
2. Value reflects maximum load. The delay is measured on the clock pin of the farthest sequential element, located in a fully loaded row (all available flip-flops are connected to the global net in the row).
3. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-204 • A3PE3000L Global Resource – Applies to 1.5 V DC Core Voltage
Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, $V_{CC} = 1.425\text{ V}$

Parameter	Description	–1		Std.		Units
		Min. ¹	Max. ²	Min. ¹	Max. ²	
t_{RCKL}	Input LOW Delay for Global Clock	1.53	1.75	1.79	2.06	ns
t_{RCKH}	Input HIGH Delay for Global Clock	1.51	1.77	1.78	2.08	ns
$t_{RCKMPWH}$	Minimum Pulse Width HIGH for Global Clock					ns
$t_{RCKMPWL}$	Minimum Pulse Width LOW for Global Clock					ns
t_{RCKSW}	Maximum Skew for Global Clock		0.26		0.30	ns
F_{RMAX}	Maximum Frequency for Global Clock					MHz

Notes:

1. Value reflects minimum load. The delay is measured from the CCC output to the clock pin of a sequential element, located in a lightly loaded row (single element is connected to the global net).
2. Value reflects maximum load. The delay is measured on the clock pin of the farthest sequential element, located in a fully loaded row (all available flip-flops are connected to the global net in the row).
3. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-205 • A3PE3000L Global Resource – Applies to 1.2 V DC Core Voltage
Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, $V_{CC} = 1.14\text{ V}$

Parameter	Description	–1		Std.		Units
		Min. ¹	Max. ²	Min. ¹	Max. ²	
t_{RCKL}	Input LOW Delay for Global Clock	1.52	1.94	1.78	2.28	ns
t_{RCKH}	Input HIGH Delay for Global Clock	1.49	1.96	1.76	2.30	ns
$t_{RCKMPWH}$	Minimum Pulse Width HIGH for Global Clock					ns
$t_{RCKMPWL}$	Minimum Pulse Width LOW for Global Clock					ns
t_{RCKSW}	Maximum Skew for Global Clock		0.47		0.55	ns
F_{RMAX}	Maximum Frequency for Global Clock					MHz

Notes:

1. Value reflects minimum load. The delay is measured from the CCC output to the clock pin of a sequential element, located in a lightly loaded row (single element is connected to the global net).
2. Value reflects maximum load. The delay is measured on the clock pin of the farthest sequential element, located in a fully loaded row (all available flip-flops are connected to the global net in the row).
3. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Clock Conditioning Circuits

CCC Electrical Specifications

Timing Characteristics

Table 2-206 • ProASIC3LP CCC/PLL Specification
CCC/PLL Operating at 1.2 V

Parameter	Min.	Typ.	Max.	Units
Clock Conditioning Circuitry Input Frequency f_{IN_CCC}	1.5		250	MHz
Clock Conditioning Circuitry Output Frequency f_{OUT_CCC}	0.75		250	MHz
Delay Increments in Programmable Delay Blocks ^{1, 2}		270		ps
Number of Programmable Values in Each Programmable Delay Block			32	
Serial Clock (SCLK) for Dynamic PLL ⁴			100	MHz
Input Cycle-to-Cycle Jitter (peak magnitude)			1	ns
CCC Output Peak-to-Peak Period Jitter F_{CCC_OUT}	Max Peak-to-Peak Period Jitter			
	1 Global Network Used	External FB Used	3 Global Networks Used	
0.75 MHz to 24 MHz	0.50%	0.75%	0.70%	
24 MHz to 100 MHz	1.00%	1.50%	1.20%	
100 MHz to 250 MHz	2.50%	3.75%	2.75%	
Acquisition Time				
	LockControl = 0		300	μs
	LockControl = 1		6.0	ms
Tracking Jitter				
	LockControl = 0		2	ns
	LockControl = 1		1	ns
Output Duty Cycle	48.5		51.5	%
Delay Range in Block: Programmable Delay 1 ^{1, 2}	1.2		15.65	ns
Delay Range in Block: Programmable Delay 2 ^{1, 2}	0.025		15.65	ns
Delay Range in Block: Fixed Delay ^{1, 2}		3.1		ns

Notes:

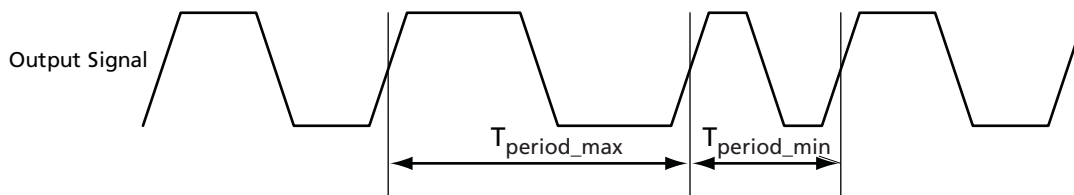
1. This delay is a function of voltage and temperature. See [Table 2-6 on page 2-7](#) for deratings.
2. $T_J = 25^\circ\text{C}$, $V_{CC} = 1.2\text{ V}$
3. Tracking jitter is defined as the variation in clock edge position of PLL outputs with reference to PLL input clock edge. Tracking jitter does not measure the variation in PLL output period, which is covered by the period jitter parameter.
4. Maximum value obtained for a –1 speed grade device in worst-case commercial conditions. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-207 • ProASIC3LP CCC/PLL Specification
CCC/PLL Operating at 1.5 V

Parameter	Min.	Typ.	Max.	Units
Clock Conditioning Circuitry Input Frequency f_{IN_CCC}	1.5		350	MHz
Clock Conditioning Circuitry Output Frequency f_{OUT_CCC}	0.75		350	MHz
Serial Clock (SCLK) for Dynamic PLL ⁴			110	
Delay Increments in Programmable Delay Blocks ^{1, 2}		160		ps
Number of Programmable Values in Each Programmable Delay Block			32	
Input Period Jitter			1.5	ns
CCC Output Peak-to-Peak Period Jitter F_{CCC_OUT}	Max Peak-to-Peak Period Jitter			
	1 Global Network Used		3 Global Networks Used	
0.75 MHz to 24 MHz	0.50%		0.70%	
24 MHz to 100 MHz	1.00%		1.20%	
100 MHz to 250 MHz	1.75%		2.00%	
250 MHz to 350 MHz	2.50%		5.60%	
Acquisition Time	LockControl = 0		300	μ s
	LockControl = 1		6.0	ms
Tracking Jitter	LockControl = 0		1.6	ns
	LockControl = 1		0.8	ns
Output Duty Cycle	48.5		51.5	%
Delay Range in Block: Programmable Delay 1 ^{1, 2}	0.6		5.56	ns
Delay Range in Block: Programmable Delay 2 ^{1, 2}	0.025		5.56	ns
Delay Range in Block: Fixed Delay ^{1, 2}		2.2		ns

Notes:

1. This delay is a function of voltage and temperature. See [Table 2-6 on page 2-7](#) for deratings.
2. $T_J = 25^\circ\text{C}$, $V_{CC} = 1.5\text{ V}$
3. Tracking jitter is defined as the variation in clock edge position of PLL outputs with reference to PLL input clock edge. Tracking jitter does not measure the variation in PLL output period, which is covered by the period jitter parameter.
4. Maximum value obtained for a -1 speed grade device in worst-case commercial conditions. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.



Note: Peak-to-peak jitter measurements are defined by $T_{peak-to-peak} = T_{period_max} - T_{period_min}$

Figure 2-40 • Peak-to-Peak Jitter Definition

Embedded SRAM and FIFO Characteristics

SRAM

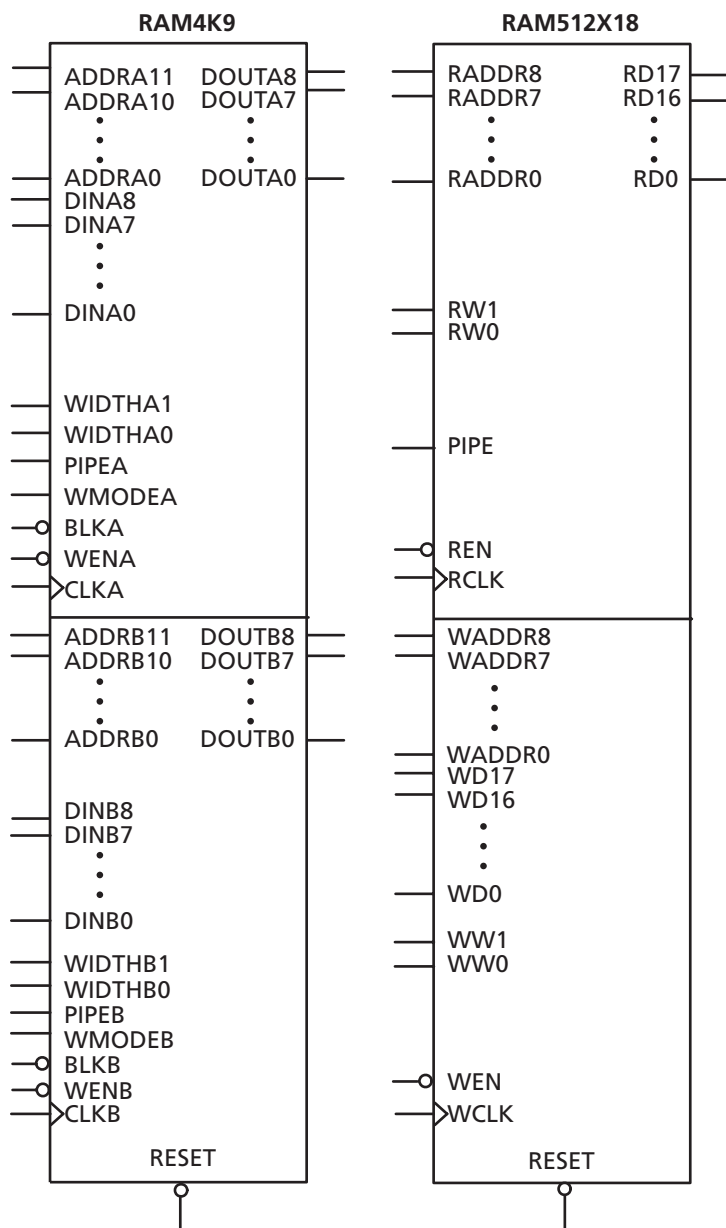


Figure 2-41 • RAM Models

Timing Waveforms

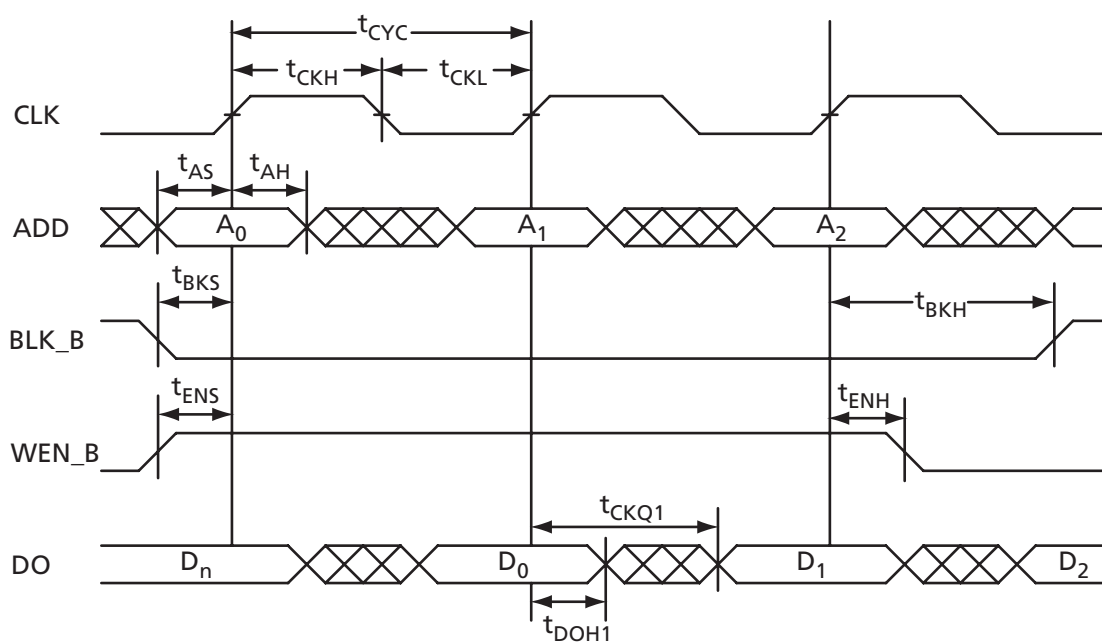


Figure 2-42 • RAM Read for Pass-Through Output

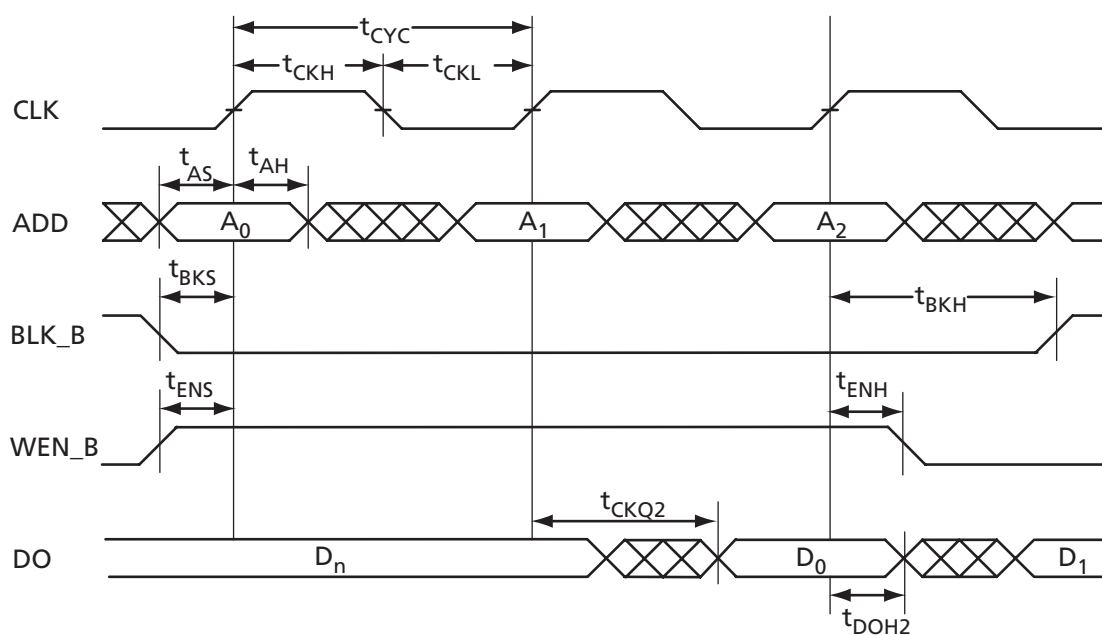


Figure 2-43 • RAM Read for Pipelined Output

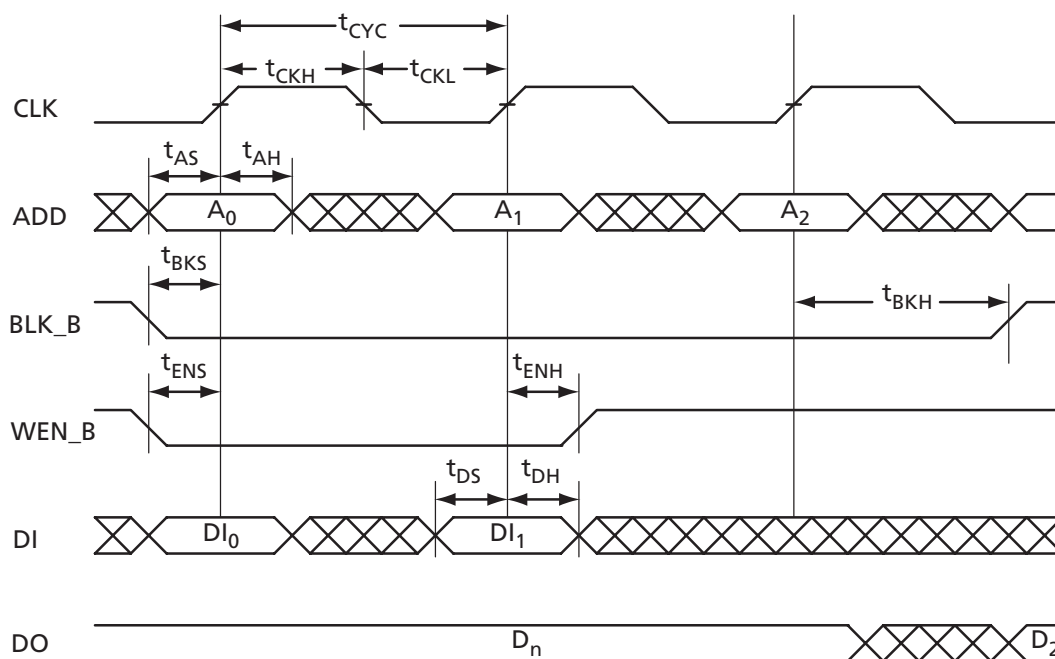


Figure 2-44 • RAM Write, Output Retained (WMODE = 0)

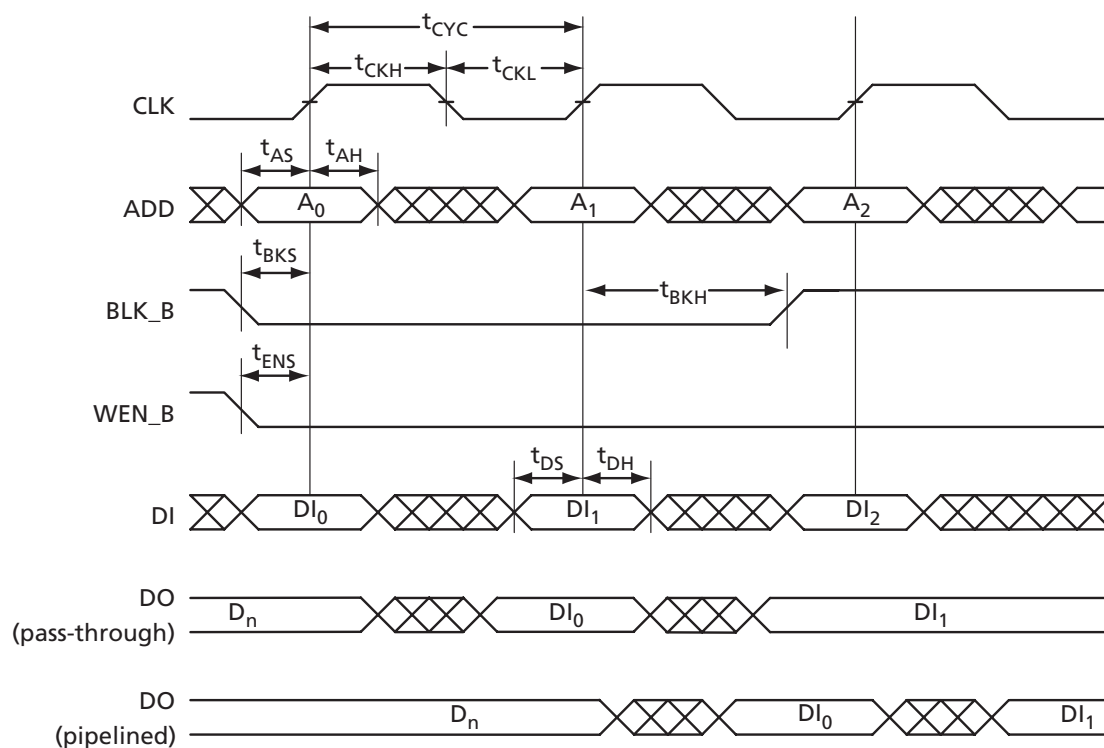


Figure 2-45 • RAM Write, Output as Write Data (WMODE = 1)

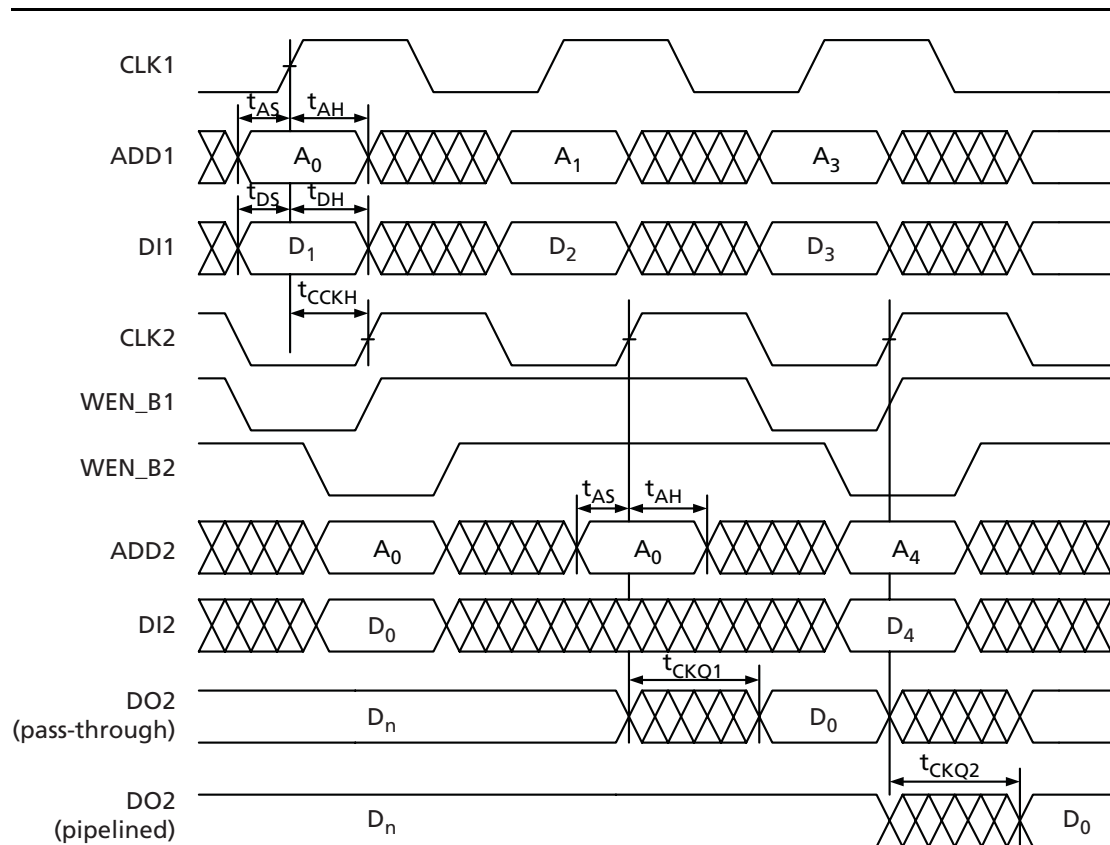


Figure 2-46 • Write Access after Write onto Same Address

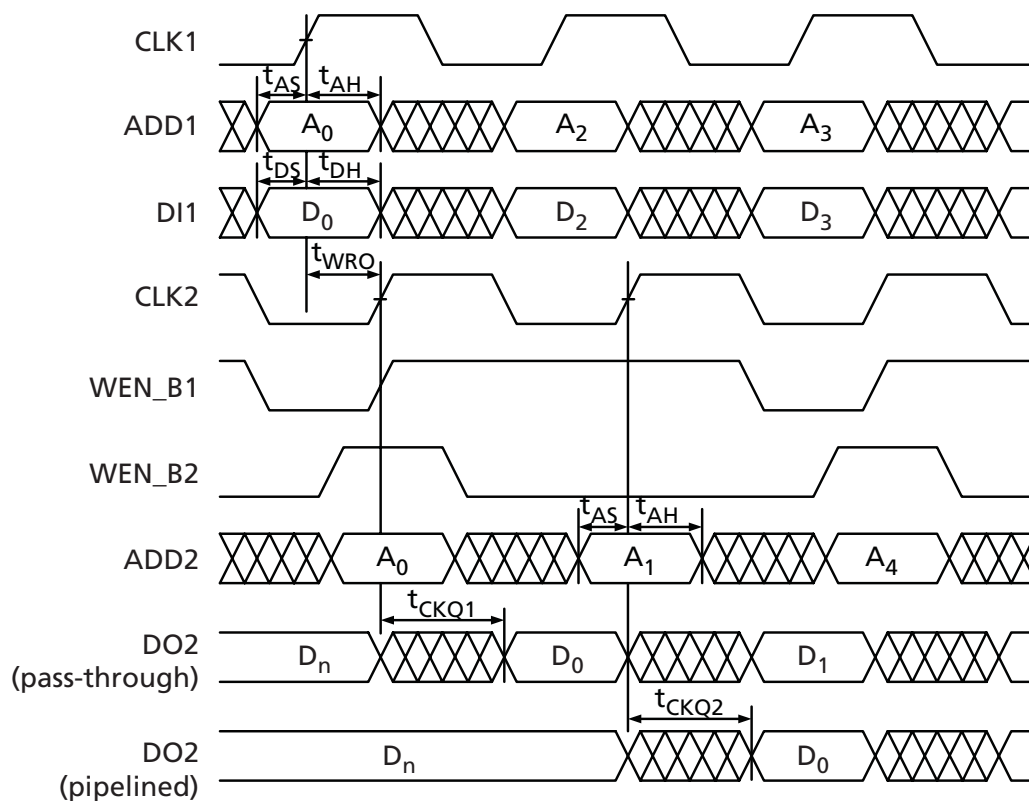


Figure 2-47 • Read Access after Write onto Same Address

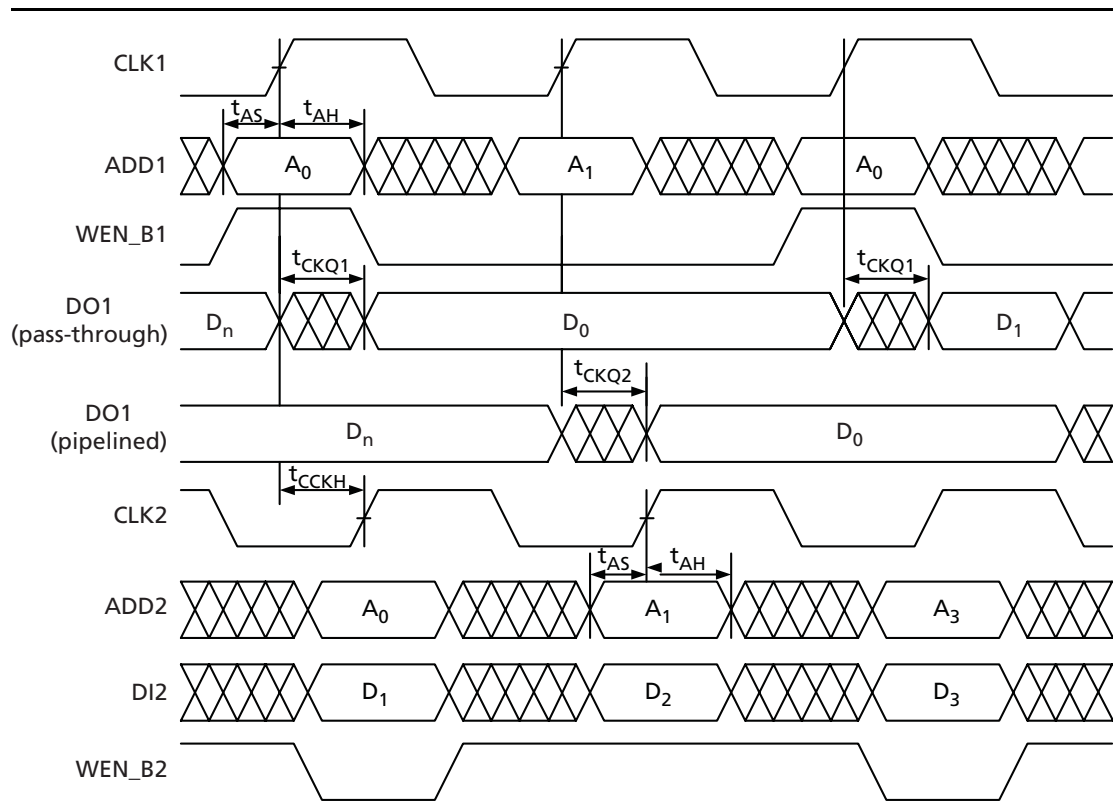


Figure 2-48 • Write Access after Read onto Same Address

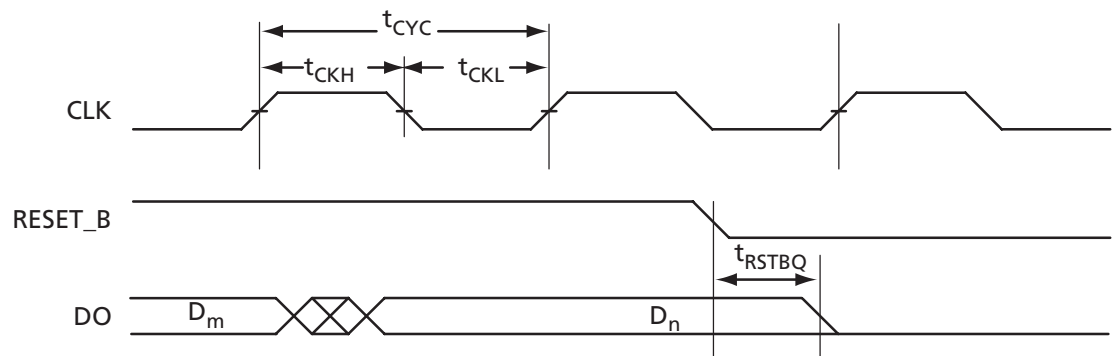


Figure 2-49 • RAM Reset

Timing Characteristics

Table 2-208 • RAM4K9 – Applies to 1.5 V DC Core Voltage
Commercial-Case Conditions: $T_J = 70^{\circ}\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$

Parameter	Description	–1	Std.	Units
t_{AS}	Address setup time	0.25	0.30	ns
t_{AH}	Address hold time	0.00	0.00	ns
t_{ENS}	REN_B, WEN_B setup time	0.15	0.17	ns
t_{ENH}	REN_B, WEN_B hold time	0.10	0.12	ns
t_{BKS}	BLK_B setup time	0.24	0.28	ns
t_{BKH}	BLK_B hold time	0.02	0.02	ns
t_{DS}	Input data (DI) setup time	0.19	0.22	ns
t_{DH}	Input data (DI) hold time	0.00	0.00	ns
t_{CKQ1}	Clock HIGH to new data valid on DO (output retained, WMODE = 0)	1.82	2.14	ns
	Clock HIGH to new data valid on DO (flow-through, WMODE = 1)	2.40	2.83	ns
t_{CKQ2}	Clock HIGH to new data valid on DO (pipelined)	0.91	1.07	ns
t_{WRO}	Address collision clk-to-clk delay for reliable read access after write on same address	TBD	TBD	ns
t_{CCKH}	Address collision clk-to-clk delay for reliable write access after write/read on same address	TBD	TBD	ns
t_{RSTBQ}	RESET_B LOW to data out LOW on DO (flow-through)	0.94	1.11	ns
	RESET_B LOW to data out LOW on DO (pipelined)	0.94	1.11	ns
$t_{REMRSTB}$	RESET_B removal	0.29	0.34	ns
$t_{RECRSTB}$	RESET_B recovery	1.53	1.80	ns
$t_{MPWRSTB}$	RESET_B minimum pulse width	0.55	0.64	ns
t_{CYC}	Clock cycle time	5.10	5.87	ns
F_{MAX}	Maximum frequency	196	170	MHz

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-209 • RAM4K9 – Applies to 1.2 V DC Core Voltage
Commercial-Case Conditions: $T_J = 70^{\circ}\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$

Parameter	Description	–1	Std.	Units
t_{AS}	Address setup time	0.33	0.39	ns
t_{AH}	Address hold time	0.00	0.00	ns
t_{ENS}	REN_B, WEN_B setup time	0.19	0.22	ns
t_{ENH}	REN_B, WEN_B hold time	0.13	0.15	ns
t_{BKS}	BLK_B setup time	0.31	0.36	ns
t_{BKH}	BLK_B hold time	0.02	0.03	ns
t_{DS}	Input data (DI) setup time	0.24	0.29	ns
t_{DH}	Input data (DI) hold time	0.00	0.00	ns
t_{CKQ1}	Clock HIGH to new data valid on DO (output retained, WMODE = 0)	2.38	2.80	ns
	Clock HIGH to new data valid on DO (flow-through, WMODE = 1)	3.14	3.69	ns
t_{CKQ2}	Clock HIGH to new data valid on DO (pipelined)	1.19	1.40	ns
t_{WRO}	Address collision clk-to-clk delay for reliable read access after write on same address	TBD	TBD	ns
t_{CCKH}	Address collision clk-to-clk delay for reliable write access after write/read on same address	TBD	TBD	ns
t_{RSTBQ}	RESET_B LOW to data out LOW on DO (flow-through)	1.23	1.45	ns
	RESET_B LOW to data out LOW on DO (pipelined)	1.23	1.45	ns
$t_{REMRSTB}$	RESET_B removal	0.38	0.45	ns
$t_{RECRSTB}$	RESET_B recovery	2.00	2.35	ns
$t_{MPWRSTB}$	RESET_B minimum pulse width	0.63	0.72	ns
t_{CYC}	Clock cycle time	5.75	6.61	ns
F_{MAX}	Maximum frequency	174	151	MHz

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-210 • RAM512X18 – Applies to 1.5 V DC Core Voltage
Commercial-Case Conditions: $T_J = 70^{\circ}\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$

Parameter	Description	–1	Std.	Units
t_{AS}	Address setup time	0.25	0.30	ns
t_{AH}	Address hold time	0.00	0.00	ns
t_{ENS}	REN_B, WEN_B setup time	0.09	0.11	ns
t_{ENH}	REN_B, WEN_B hold time	0.06	0.07	ns
t_{DS}	Input data (DI) setup time	0.19	0.22	ns
t_{DH}	Input data (DI) hold time	0.00	0.00	ns
t_{CKQ1}	Clock HIGH to new data valid on DO (output retained, WMODE = 0)	2.20	2.59	ns
t_{CKQ2}	Clock HIGH to new data valid on DO (pipelined)	0.91	1.07	ns
t_{WRO}	Address collision clk-to-clk delay for reliable read access after write on same address	TBD	TBD	ns
t_{CCKH}	Address collision clk-to-clk delay for reliable write access after write/read on same address	TBD	TBD	ns
t_{RSTBQ}	RESET_B LOW to data out LOW on DO (flow through)	0.94	1.11	ns
	RESET_B LOW to data out LOW on DO (pipelined)	0.94	1.11	ns
$t_{REMRSTB}$	RESET_B removal	0.29	0.34	ns
$t_{RECRSTB}$	RESET_B recovery	1.53	1.80	ns
$t_{MPWRSTB}$	RESET_B minimum pulse width	0.55	0.64	ns
t_{CYC}	Clock cycle time	5.10	5.87	ns
F_{MAX}	Maximum frequency	196	170	MHz

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-211 • RAM512X18 – Applies to 1.2 V DC Core Voltage
Commercial-Case Conditions: $T_J = 70^{\circ}\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$

Parameter	Description	–1	Std.	Units
t_{AS}	Address setup time	0.33	0.39	ns
t_{AH}	Address hold time	0.00	0.00	ns
t_{ENS}	REN_B, WEN_B setup time	0.12	0.14	ns
t_{ENH}	REN_B, WEN_B hold time	0.08	0.09	ns
t_{DS}	Input data (DI) setup time	0.24	0.29	ns
t_{DH}	Input data (DI) hold time	0.00	0.00	ns
t_{CKQ1}	Clock HIGH to new data valid on DO (output retained, WMODE = 0)	2.88	3.39	ns
t_{CKQ2}	Clock HIGH to new data valid on DO (pipelined)	1.19	1.40	ns
t_{WRO}	Address collision clk-to-clk delay for reliable read access after write on same address	TBD	TBD	ns
t_{CCKH}	Address collision clk-to-clk delay for reliable write access after write/read on same address	TBD	TBD	ns
t_{RSTBQ}	RESET_B LOW to data out LOW on DO (flow-through)	1.23	1.45	ns
	RESET_B LOW to data out LOW on DO (pipelined)	1.23	1.45	ns
$t_{REMRSTB}$	RESET_B removal	0.38	0.45	ns
$t_{RECRSTB}$	RESET_B recovery	2.00	2.35	ns
$t_{MPWRSTB}$	RESET_B minimum pulse width	0.63	0.72	ns
t_{CYC}	Clock cycle time	5.75	6.61	ns
F_{MAX}	Maximum frequency	174	151	MHz

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

FIFO

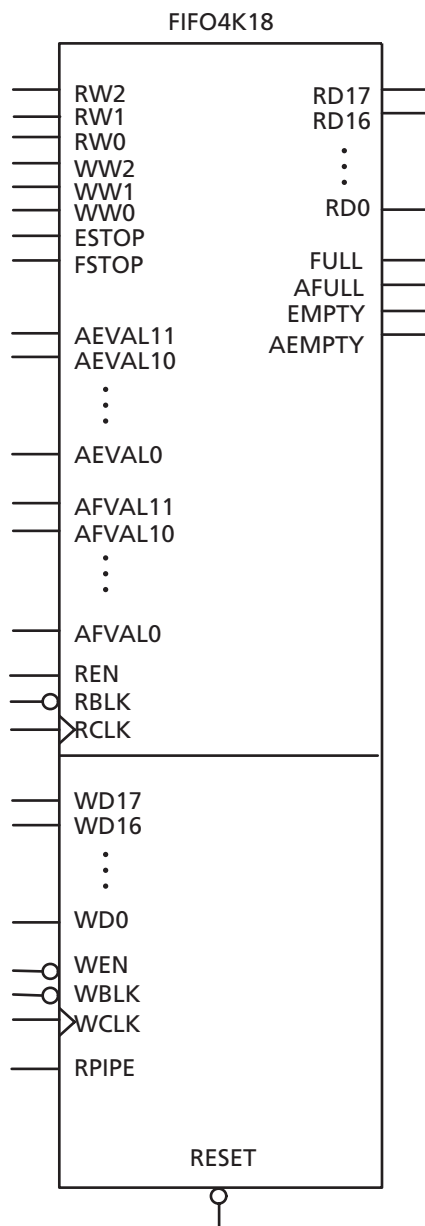


Figure 2-50 • FIFO Model

Timing Waveforms

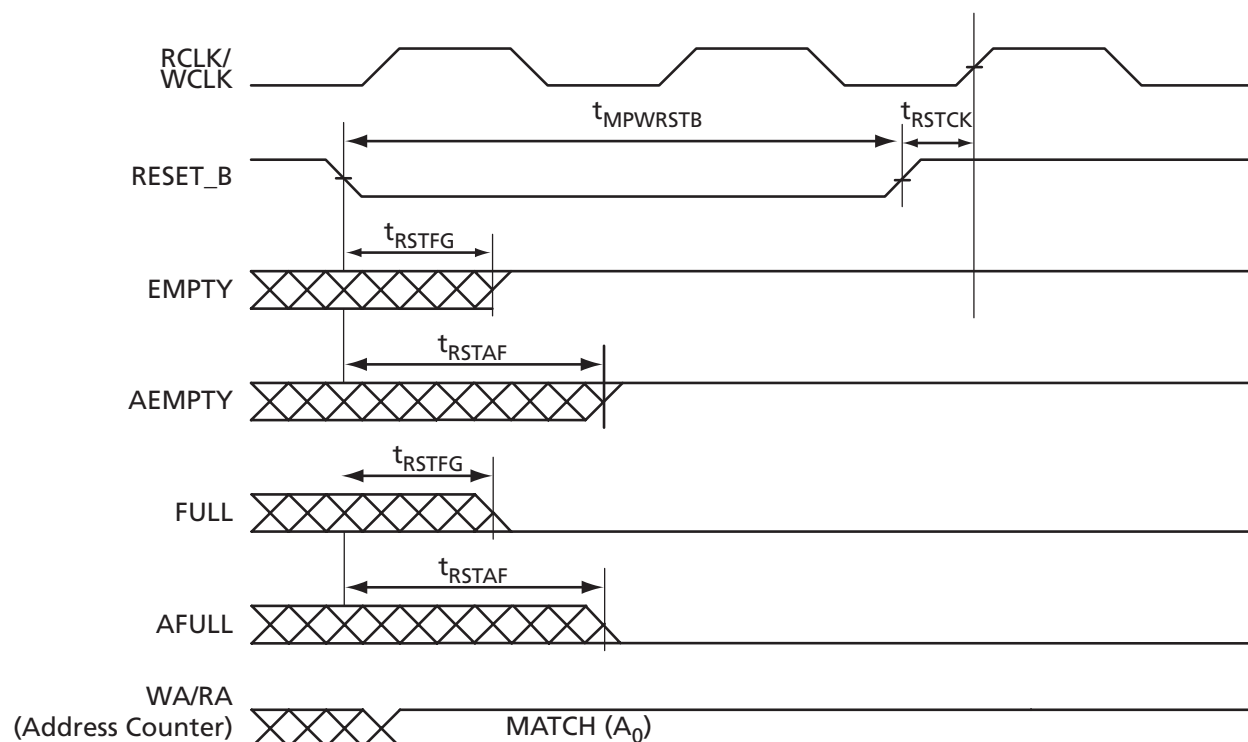


Figure 2-51 • FIFO Reset

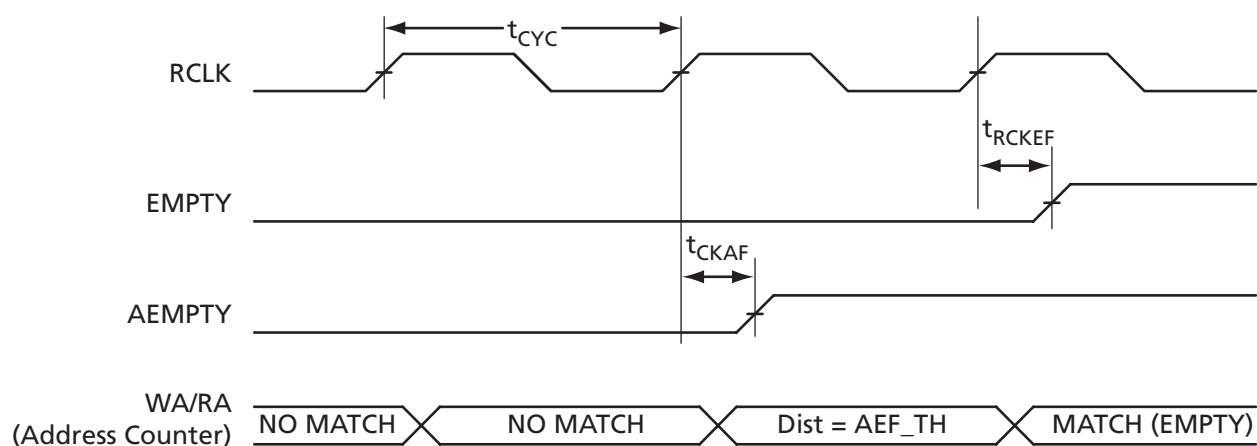


Figure 2-52 • FIFO EMPTY Flag and AEMPTY Flag Assertion

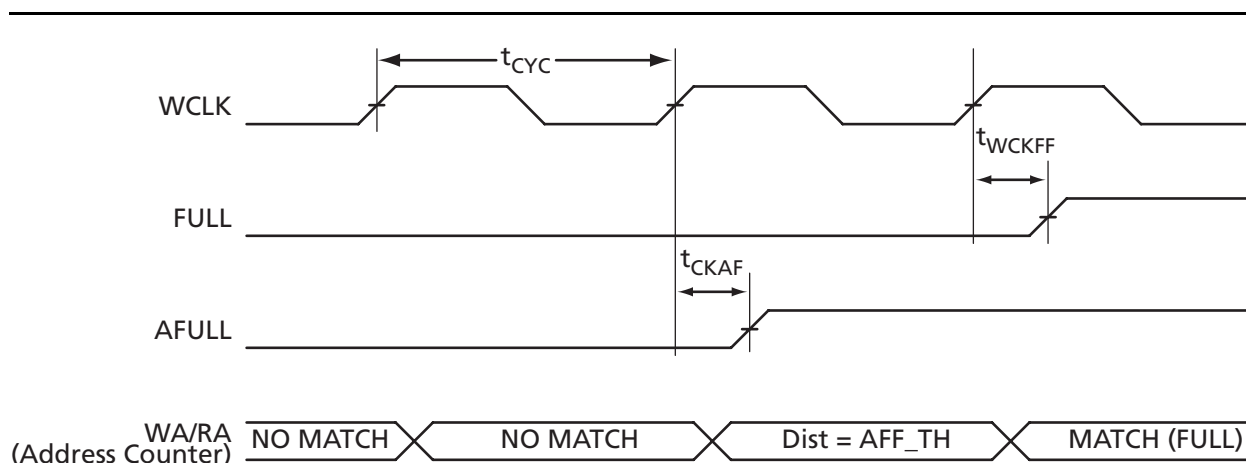


Figure 2-53 • FIFO FULL Flag and AFULL Flag Assertion

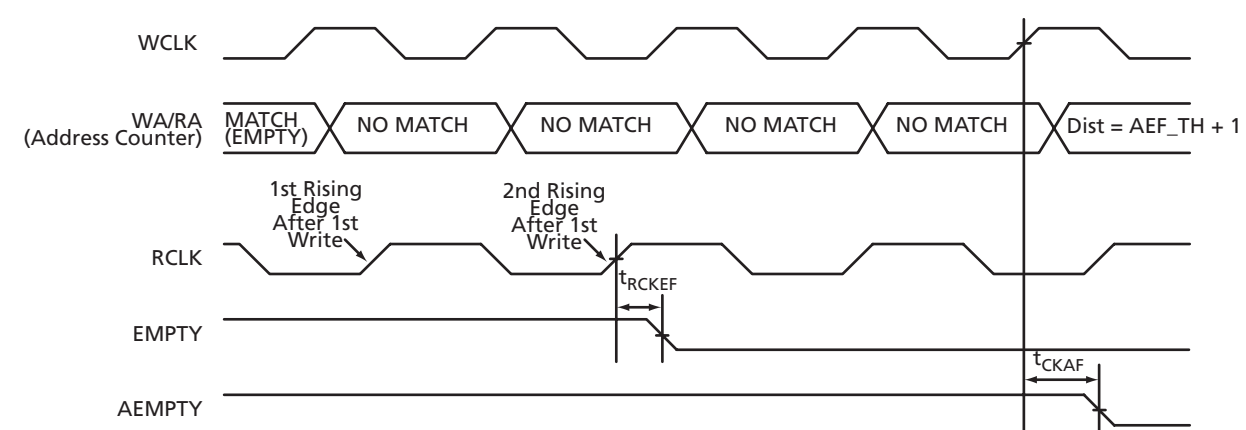


Figure 2-54 • FIFO EMPTY Flag and AEMPTY Flag Deassertion

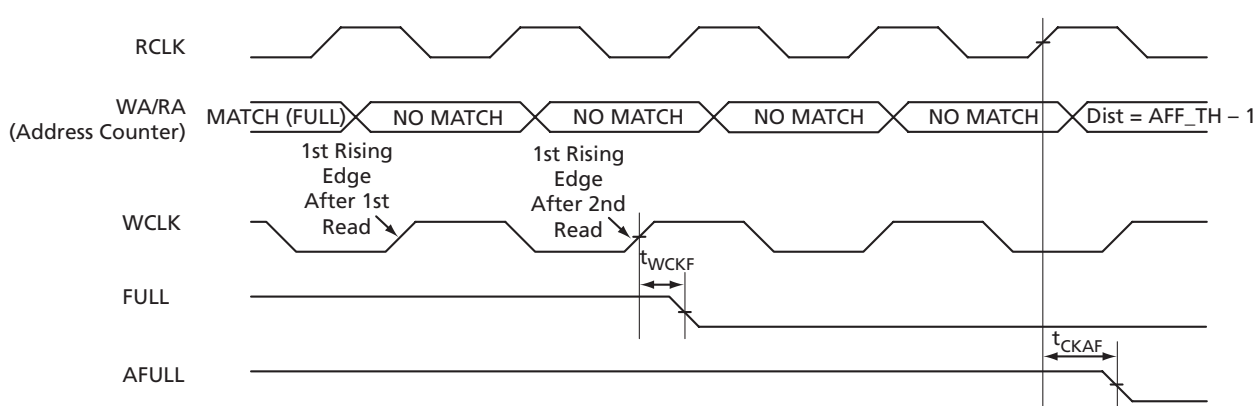


Figure 2-55 • FIFO FULL Flag and AFULL Flag Deassertion

Timing Characteristics

Table 2-212 • FIFO – Applies to 1.5 V DC Core Voltage

Worst Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, $V_{CC} = 1.425\text{ V}$

Parameter	Description	–1	Std.	Units
t_{ENS}	REN_B, WEN_B Setup Time	1.40	1.65	ns
t_{ENH}	REN_B, WEN_B Hold Time	0.02	0.02	ns
t_{BKS}	BLK_B Setup Time	0.40	0.47	ns
t_{BKH}	BLK_B Hold Time	0.00	0.00	ns
t_{DS}	Input Data (DI) Setup Time	0.19	0.22	ns
t_{DH}	Input Data (DI) Hold Time	0.00	0.00	ns
t_{CKQ1}	Clock HIGH to New Data Valid on DO (flow-through)	2.40	2.83	ns
t_{CKQ2}	Clock HIGH to New Data Valid on DO (pipelined)	0.91	1.07	ns
t_{RCKEF}	RCLK HIGH to Empty Flag Valid	1.75	2.06	ns
t_{WCKFF}	WCLK HIGH to Full Flag Valid	1.66	1.96	ns
t_{CKAF}	Clock HIGH to Almost Empty/Full Flag Valid	6.31	7.42	ns
t_{RSTFG}	RESET_B LOW to Empty/Full Flag Valid	1.73	2.03	ns
t_{RSTAF}	RESET_B LOW to Almost Empty/Full Flag Valid	6.25	7.35	ns
t_{RSTBQ}	RESET_B LOW to Data Out LOW on DO (flow-through)	0.94	1.11	ns
	RESET_B LOW to Data Out LOW on DO (pipelined)	0.94	1.11	ns
$t_{REMRSTB}$	RESET_B Removal	0.29	0.34	ns
$t_{RECRSTB}$	RESET_B Recovery	1.53	1.80	ns
$t_{MPWRSTB}$	RESET_B Minimum Pulse Width	0.55	0.64	ns
t_{CYC}	Clock Cycle Time	5.10	5.87	ns
F_{MAX}	Maximum Frequency for FIFO	196	170	MHz

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Table 2-213 • FIFO – Applies to 1.2 V DC Core Voltage
Worst Commercial-Case Conditions: $T_J = 70^{\circ}\text{C}$, $V_{CC} = 1.14\text{ V}$

Parameter	Description	–1	Std.	Units
t_{ENS}	REN_B, WEN_B Setup Time	1.84	2.16	ns
t_{ENH}	REN_B, WEN_B Hold Time	0.02	0.03	ns
t_{BKS}	BLK_B Setup Time	0.40	0.47	ns
t_{BKH}	BLK_B Hold Time	0.00	0.00	ns
t_{DS}	Input Data (DI) Setup Time	0.24	0.29	ns
t_{DH}	Input Data (DI) Hold Time	0.00	0.00	ns
t_{CKQ1}	Clock HIGH to New Data Valid on DO (flow-through)	3.14	3.69	ns
t_{CKQ2}	Clock HIGH to New Data Valid on DO (pipelined)	1.19	1.40	ns
t_{RCKEF}	RCLK HIGH to Empty Flag Valid	2.29	2.69	ns
t_{WCKFF}	WCLK HIGH to Full Flag Valid	2.18	2.56	ns
t_{CKAF}	Clock HIGH to Almost Empty/Full Flag Valid	8.25	9.70	ns
t_{RSTFG}	RESET_B LOW to Empty/Full Flag Valid	2.26	2.65	ns
t_{RSTAF}	RESET_B LOW to Almost Empty/Full Flag Valid	8.17	9.60	ns
t_{RSTBQ}	RESET_B LOW to Data Out LOW on DO (flow-through)	1.23	1.45	ns
	RESET_B LOW to Data Out LOW on DO (pipelined)	1.23	1.45	ns
$t_{REMRSTB}$	RESET_B Removal	0.38	0.45	ns
$t_{RECRSTB}$	RESET_B Recovery	2.00	2.35	ns
$t_{MPWRSTB}$	RESET_B Minimum Pulse Width	0.63	0.72	ns
t_{CYC}	Clock Cycle Time	5.75	6.61	ns
F_{MAX}	Maximum Frequency for FIFO	174	151	MHz

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-7](#) for derating values.

Embedded FlashROM Characteristics

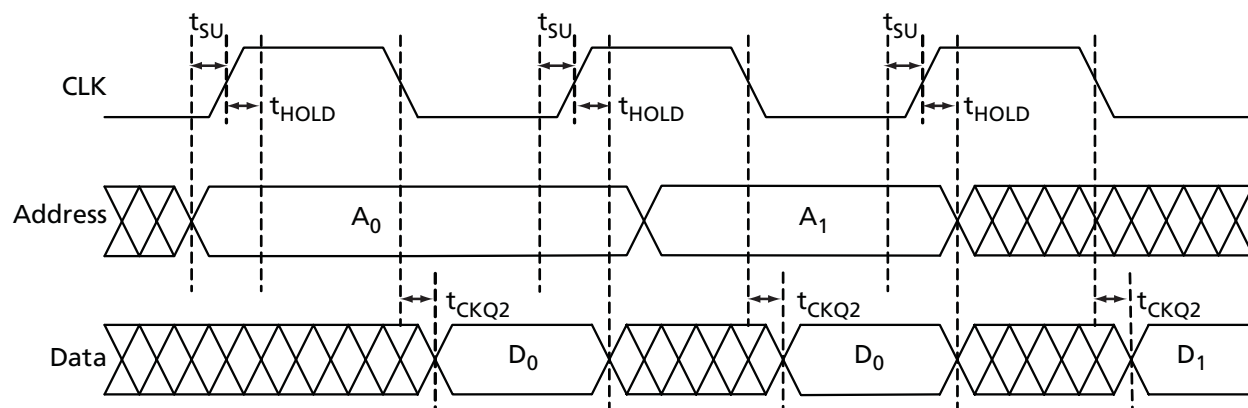


Figure 2-56 • Timing Diagram

Timing Characteristics

Table 2-214 • Embedded FlashROM Access Time – Applies to 1.5 V DC Core Voltage
Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$

Parameter	Description	–1	Std.	Units
t_{SU}	Address Setup Time	0.54	0.64	ns
t_{HOLD}	Address Hold Time	0.00	0.00	ns
t_{CKQ2}	Clock to Out	16.55	19.46	ns
F_{MAX}	Maximum Clock Frequency	15	15	MHz

Table 2-215 • Embedded FlashROM Access Time– Applies to 1.2 V DC Core Voltage
Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$

Parameter	Description	–1	Std.	Units
t_{SU}	Address Setup Time	0.71	0.83	ns
t_{HOLD}	Address Hold Time	0.00	0.00	ns
t_{CKQ2}	Clock to Out	21.64	25.44	ns
F_{MAX}	Maximum Clock Frequency	15	15	MHz

JTAG 1532 Characteristics

JTAG timing delays do not include JTAG I/Os. To obtain complete JTAG timing, add I/O buffer delays to the corresponding standard selected; refer to the I/O timing characteristics in the "User I/O Characteristics" section on page 2-18 for more details.

Timing Characteristics

Table 2-216 • JTAG 1532 – Applies to 1.5 V DC Core Voltage
Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$

Parameter	Description	–1	Std.	Units
t_{DISU}	Test Data Input Setup Time	0.57	0.67	ns
t_{DIHD}	Test Data Input Hold Time	1.13	1.33	ns
t_{TMSSU}	Test Mode Select Setup Time	0.57	0.67	ns
t_{TMDHD}	Test Mode Select Hold Time	1.13	1.33	ns
t_{TCK2Q}	Clock to Q (data out)	5.67	6.67	ns
t_{RSTB2Q}	Reset to Q (data out)	22.67	26.67	ns
F_{TCKMAX}	TCK Maximum Frequency	24.00	21.00	MHz
$t_{TRSTREM}$	ResetB Removal Time	0.00	0.00	ns
$t_{TRSTREC}$	ResetB Recovery Time	0.23	0.27	ns
$t_{TRSTMPW}$	ResetB Minimum Pulse	TBD	TBD	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.

Table 2-217 • JTAG 1532 – Applies to 1.2 V DC Core Voltage
Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$

Parameter	Description	–1	Std.	Units
t_{DISU}	Test Data Input Setup Time	0.75	0.88	ns
t_{DIHD}	Test Data Input Hold Time	1.50	1.76	ns
t_{TMSSU}	Test Mode Select Setup Time	0.75	0.88	ns
t_{TMDHD}	Test Mode Select Hold Time	1.50	1.76	ns
t_{TCK2Q}	Clock to Q (data out)	6.00	7.06	ns
t_{RSTB2Q}	Reset to Q (data out)	25.00	29.41	ns
F_{TCKMAX}	TCK Maximum Frequency	20.00	17.00	MHz
$t_{TRSTREM}$	ResetB Removal Time	0.45	0.53	ns
$t_{TRSTREC}$	ResetB Recovery Time	0.00	0.00	ns
$t_{TRSTMPW}$	ResetB Minimum Pulse	TBD	TBD	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.

Part Number and Revision Date

Part Number 51700100-002-5

Revised August 2008

List of Changes

The following table lists critical changes that were made in the current version of the chapter.

Previous Version	Changes in Current Version (Advance v0.6)	Page
Advance v0.5 (August 2008)	3.0 V LVCMOS wide range support data was added to Table 2-2 · Recommended Operating Conditions ¹ .	2-2
	3.3 V LVCMOS wide range support data was added to Table 2-22 · Summary of Maximum and Minimum DC Input and Output Levels Applicable to Commercial and Industrial Conditions—Software Default Settings to Table 2-24 · Summary of Maximum and Minimum DC Input and Output Levels Applicable to Commercial and Industrial Conditions—Software Default Settings .	2-22 to 2-23
	3.3 V LVCMOS wide range support data was added to Table 2-26 · Summary of AC Memory Points .	2-25
	3.3 V LVCMOS wide range support text was added to "3.3 V LVTTTL / 3.3 V LVCMOS".	2-39
	Table 2-48 · Minimum and Maximum DC Input and Output Levels for LVCMOS 3.3 V Wide Range is new.	2-40
Advance v0.4 (July 2008)	Table 2-6 · Temperature and Voltage Derating Factors for Timing Delays was updated to add several new rows of values.	2-7
	Table 2-7 · Quiescent Supply Current (I_{DD}) Characteristics, ProASIC3L Flash*Freeze Mode* through Table 2-10 · Quiescent Supply Current (I_{DD}), No ProASIC3L Flash*Freeze Mode1 were updated to add 1.5 V core voltage.	2-7 to 2-8
	Table 2-18 · Different Components Contributing to Dynamic Power Consumption in ProASIC3L Devices at 1.5 V V_{CC} is new.	2-14
	Table 2-19 · Different Components Contributing to the Static Power Consumption in ProASIC3L Devices was updated to add the static PLL contribution at 1.5 V core operation.	2-14
	Timing tables were updated to include tables for 1.5 V core voltage.	N/A
	Table 2-206 · ProASIC3LP CCC/PLL Specification was updated for core voltage 1.2 V and Table 2-207 · ProASIC3LP CCC/PLL Specification for 1.5 V is new.	2-123, 2-124
Advance v0.3 (June 2008)	As a result of the Libero IDE v8.4 release, Actel now offers a wide range of core voltage support. The document was updated to change 1.2 V / 1.5 V to 1.2 V to 1.5 V.	N/A
Advance v0.2 (February 2008)	Tables have been updated to include the LVCMOS 1.2 V I/O set. DDR Tables have two additional data points added to reflect both edges for Input DDR setup and hold time. Power data table has been updated to match SmartPower data rather than simulation values.	N/A
	Table 2-1 · Absolute Maximum Ratings was updated to add VMV to the V _{CCI} parameter row and to remove the word "output" from the parameter description for V _{CCI} . Table note 3 was added.	2-1

Previous Version	Changes in Current Version (Advance v0.6)	Page
Advance v0.2 (continued)	Table 2-2 · Recommended Operating Conditions ¹ was updated to add table note references and rearrange the order of notes. VMV was added to the V _{CCI} parameter row. A new row was added for V _{CC} , 1.5 V DC core supply voltage. The table note stating that 1.5 V data will be released at a later date is new. The table note on VMV pins is new.	2-2
	Table 2-4 · Overshoot and Undershoot Limits ¹ . The title was revised to remove "as measured on quiet I/Os." Table note 2 was revised to remove "estimated SSO density over cycles." Table note 3 was revised to remove "refers only to overshoot/undershoot limits for simultaneous switching I/Os."	2-3
	EQ 2-2 was updated. The temperature was changed to 100°C, and therefore the end result changed.	2-6
	The table notes for Table 2-7 · Quiescent Supply Current (I _{DD}) Characteristics, ProASIC3L Flash*Freeze Mode* and Table 2-8 · Quiescent Supply Current (I _{DD}) Characteristics, ProASIC3L Sleep Mode (V _{CC} = 0 V)* were updated to remove VMV and include P _{DC6} and P _{DC7} . The table note for Table 2-7 · Quiescent Supply Current (I _{DD}) Characteristics, ProASIC3L Flash*Freeze Mode* was updated to include V _{JTAG} .	2-7
	Table 2-9 · Quiescent Supply Current (I _{DD}) Characteristics, Shutdown Mode (V _{CC} , V _{CCI} = 0 V) is new.	2-7
	Note 2 of Table 2-10 · Quiescent Supply Current (I _{DD}), No ProASIC3L Flash*Freeze Mode1 was updated to include V _{CCPLL} . Note 4 was updated to include P _{DC6} and P _{DC7} .	2-8
	Table 2-11 · Summary of I/O Input Buffer Power (per pin) – Default I/O Software Settings through Table 2-16 · Summary of I/O Output Buffer Power (per pin) – Default I/O Software Settings ¹ were updated to change P _{DC2} to P _{DC6} and P _{DC3} to P _{DC7} . The table notes were updated to reflect that power was measured on V _{CCI} . The subtitle of the table was changed from "Applicable to Advanced I/O Banks" to "Applicable to Pro I/O Banks."	2-9 through 2-12
	The word "input" in the titles of Table 2-14 · Summary of I/O Output Buffer Power (per pin) – Default I/O Software Settings ¹ and Table 2-15 · Summary of I/O Output Buffer Power (per pin) – Default I/O Software Settings ¹ , was changed to "output."	2-11, 2-12
	The value of C _{LOAD} for single-ended 3.3 V PCI was changed to 10 from 5 in Table 2-14 · Summary of I/O Output Buffer Power (per pin) – Default I/O Software Settings ¹ through Table 2-16 · Summary of I/O Output Buffer Power (per pin) – Default I/O Software Settings ¹ .	2-11 through 2-12
	The last section of Table 2-17 · Different Components Contributing to Dynamic Power Consumption in ProASIC3L Devices at 1.2 V V _{CC} was made into a new table: Table 2-19 · Different Components Contributing to the Static Power Consumption in ProASIC3L Devices. The table numbers referenced for device-specific dynamic power for P _{AC9} and P _{AC10} were changed in Table 2-17 · Different Components Contributing to Dynamic Power Consumption in ProASIC3L Devices at 1.2 V V _{CC} . The definition of P _{DC5} was updated and parameters P _{DC6} and P _{DC7} were added to Table 2-19 · Different Components Contributing to the Static Power Consumption in ProASIC3L Devices.	2-13
	The "Total Static Power Consumption—P _{STAT} " section was updated to revise the calculation of P _{STAT} , including P _{DC6} and P _{DC7} .	2-15
	Footnote 1 was updated to include information about P _{AC13} .	2-16

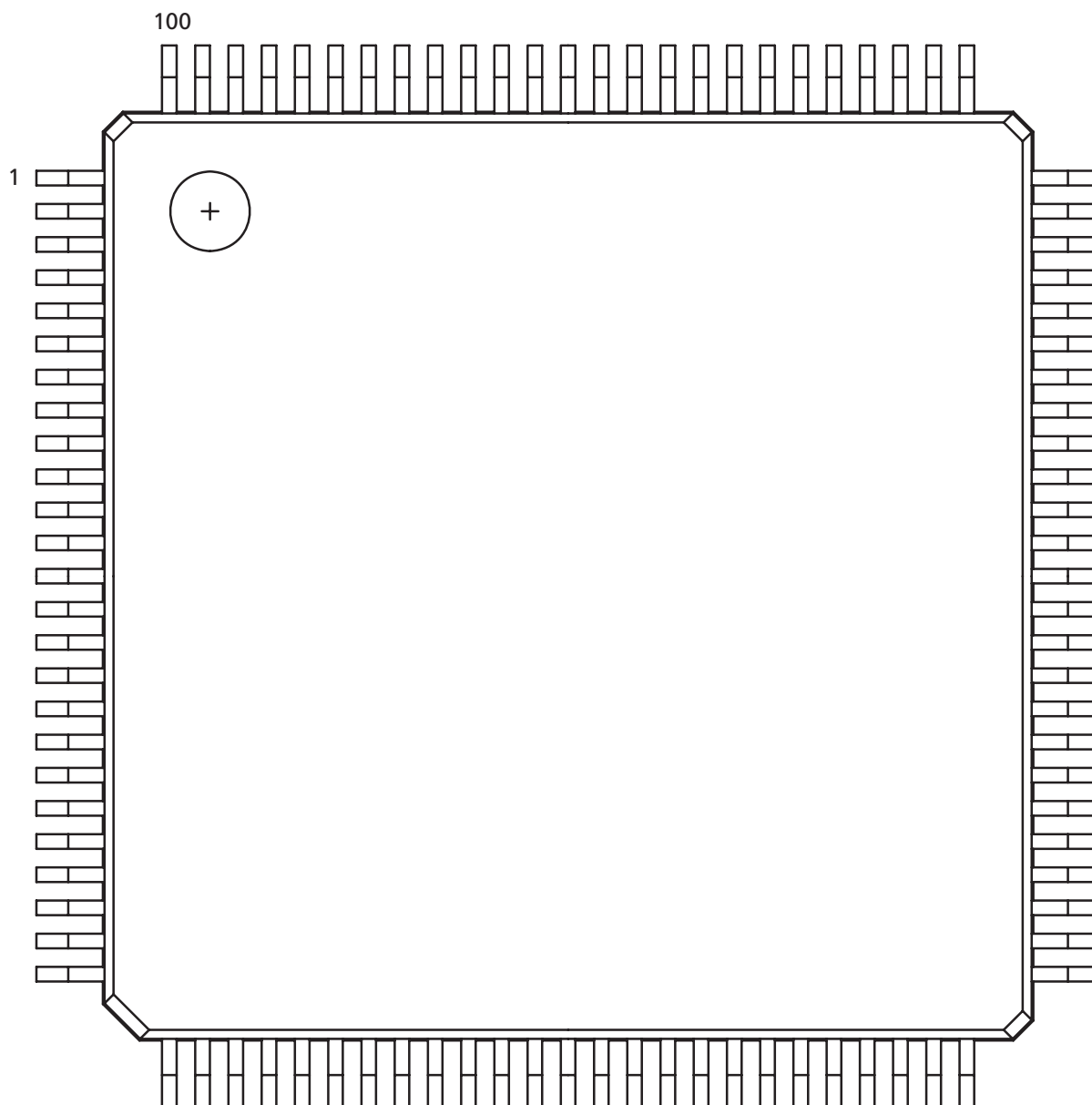
Previous Version	Changes in Current Version (Advance v0.6)	Page
Advance v0.2 (continued)	Table 2-42 · Schmitt Trigger Input Hysteresis, Hysteresis Voltage Value (Typ) for Schmitt Mode Input Buffers was updated to include the hysteresis value for 1.2 V LVCMOS.	2-37
	The "1.2 V LVCMOS (JESD8-12A)" section is new.	2-71
Advance v0.1 (January 2008)	The "PLL Behavior at Brownout Condition" section is new.	2-4
	Table 2-198 · A3P250L Global Resource – Applies to 1.5 V DC Core Voltage, Table 2-200 · A3P600L Global Resource – Applies to 1.5 V DC Core Voltage, Table 2-202 · A3P1000L Global Resource – Applies to 1.5 V DC Core Voltage, and Table 2-204 · A3PE3000L Global Resource – Applies to 1.5 V DC Core Voltage were updated with values for t_{RCKL} , t_{RCKH} , and t_{RCKSW} .	2-119 – 2-121
	The worst-case commercial conditions were added to Table 2-215 · Embedded FlashROM Access Time– Applies to 1.2 V DC Core Voltage.	2-140
	Table 2-17 · Different Components Contributing to Dynamic Power Consumption in ProASIC3L Devices at 1.2 V V_{CC} was updated to revise the value for P_{AC14} and add parameters P_{DC1} through P_{DC5} to the table.	2-13

Actel Safety Critical, Life Support, and High-Reliability Applications Policy

The Actel products described in this advance status datasheet may not have completed Actel's qualification process. Actel may amend or enhance products during the product introduction and qualification process, resulting in changes in device functionality or performance. It is the responsibility of each customer to ensure the fitness of any Actel product (but especially a new product) for a particular purpose, including appropriateness for safety-critical, life-support, and other high-reliability applications. Consult Actel's Terms and Conditions for specific liability exclusions relating to life-support applications. A reliability report covering all of Actel's products is available on the Actel website at http://www.actel.com/documents/ORT_Report.pdf. Actel also offers a variety of enhanced qualification and lot acceptance screening procedures. Contact your local Actel sales office for additional reliability information.

3 – Package Pin Assignments

100-Pin VQFP



Note: This is the top view of the package.

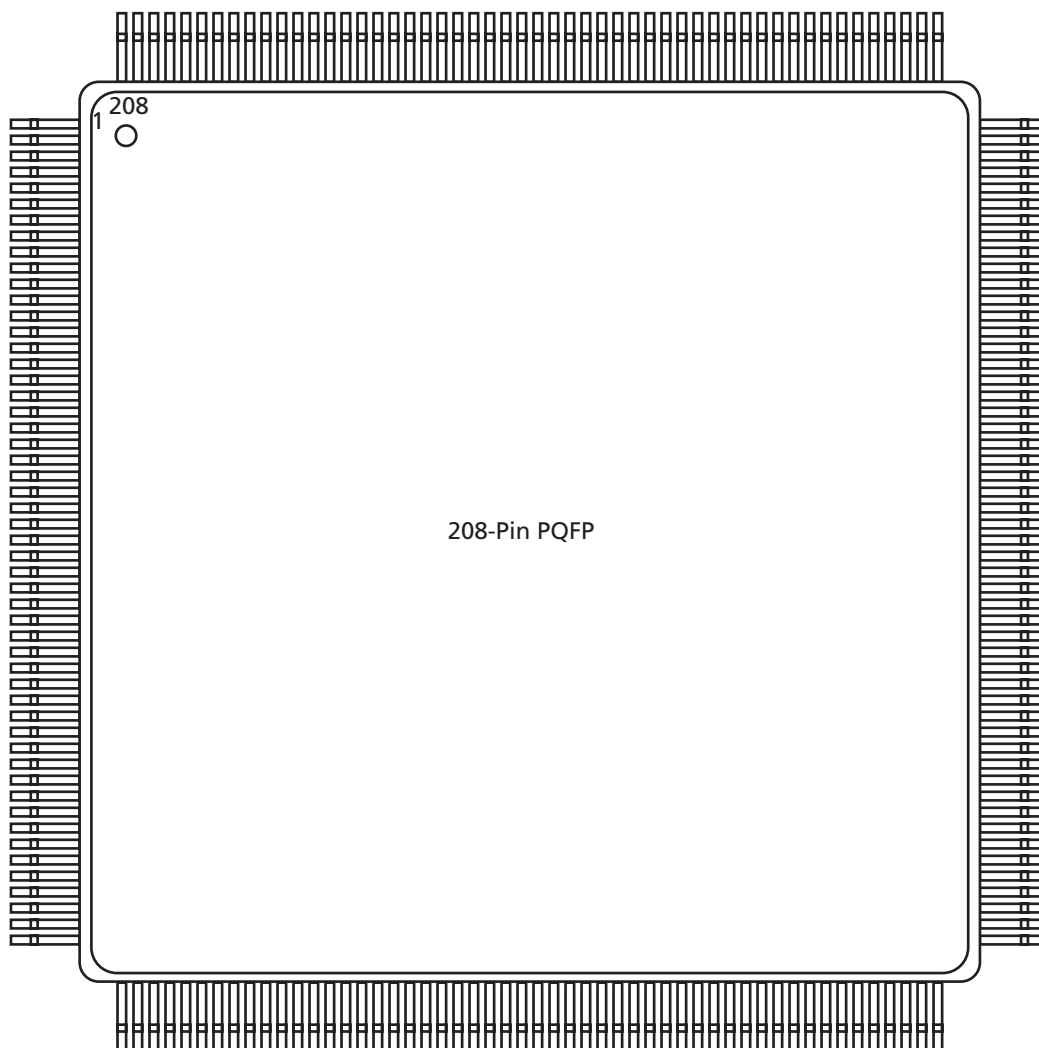
Figure 3-1 •

Note

For Package Manufacturing and Environmental information, visit the Resource Center at <http://www.actel.com/products/solutions/package/docs.aspx>.

100-Pin VQFP		100-Pin VQFP		100-Pin VQFP	
Pin Number	A3P250L Function	Pin Number	A3P250L Function	Pin Number	A3P250L Function
1	GND	37	V _{CC}	73	GBA2/IO41PDB1
2	GAA2/IO118UDB3	38	GND	74	VMV1
3	IO118VDB3	39	V _{CC} B2	75	GNDQ
4	GAB2/IO117UDB3	40	IO77RSB2	76	GBA1/IO40RSB0
5	IO117VDB3	41	IO74RSB2	77	GBA0/IO39RSB0
6	GAC2/IO116UDB3	42	IO71RSB2	78	GBB1/IO38RSB0
7	IO116VDB3	43	GDC2/IO63RSB2	79	GBB0/IO37RSB0
8	IO112PSB3	44	GDB2/IO62RSB2	80	GBC1/IO36RSB0
9	GND	45	GDA2/IO61RSB2	81	GBC0/IO35RSB0
10	GFB1/IO109PDB3	46	GNDQ	82	IO29RSB0
11	GFB0/IO109NDB3	47	TCK	83	IO27RSB0
12	V _{COMPLF}	48	TDI	84	IO25RSB0
13	GFA0/IO108NPB3	49	TMS	85	IO23RSB0
14	V _{CCPLF}	50	VMV2	86	IO21RSB0
15	GFA1/IO108PPB3	51	GND	87	V _{CC} B0
16	GFA2/IO107PSB3	52	V _{PUMP}	88	GND
17	V _{CC}	53	NC	89	V _{CC}
18	V _{CC} B3	54	TDO	90	IO15RSB0
19	GFC2/IO105PSB3	55	TRST	91	IO13RSB0
20	GEC1/IO100PDB3	56	V _{JTAG}	92	IO11RSB0
21	GEC0/IO100NDB3	57	GDA1/IO60USB1	93	GAC1/IO05RSB0
22	GEA1/IO98PDB3	58	GDC0/IO58VDB1	94	GAC0/IO04RSB0
23	GEA0/IO98NDB3	59	GDC1/IO58UDB1	95	GAB1/IO03RSB0
24	VMV3	60	IO52NDB1	96	GAB0/IO02RSB0
25	GNDQ	61	GCB2/IO52PDB1	97	GAA1/IO01RSB0
26	GEA2/IO97RSB2	62	GCA1/IO50PDB1	98	GAA0/IO00RSB0
27	FF/GE2/IO96RSB2	63	GCA0/IO50NDB1	99	GNDQ
28	GEC2/IO95RSB2	64	GCC0/IO48NDB1	100	VMV0
29	IO93RSB2	65	GCC1/IO48PDB1		
30	IO92RSB2	66	V _{CC} B1		
31	IO91RSB2	67	GND		
32	IO90RSB2	68	V _{CC}		
33	IO88RSB2	69	IO43NDB1		
34	IO86RSB2	70	GBC2/IO43PDB1		
35	IO85RSB2	71	GBB2/IO42PSB1		
36	IO84RSB2	72	IO41NDB1		

208-Pin PQFP



Note: This is the top view of the package.

Figure 3-2 •

Note

For Package Manufacturing and Environmental information, visit the Resource Center at <http://www.actel.com/products/solutions/package/docs.aspx>.

208-Pin PQFP		208-Pin PQFP		208-Pin PQFP	
Pin Number	A3PL600 Function	Pin Number	A3PL600 Function	Pin Number	A3PL600 Function
1	GND	37	IO152PDB3	73	IO120RSB2
2	GAA2/IO174PDB3	38	IO152NDB3	74	IO119RSB2
3	IO174NDB3	39	IO150PSB3	75	IO118RSB2
4	GAB2/IO173PDB3	40	V _{CC} B3	76	IO117RSB2
5	IO173NDB3	41	GND	77	IO116RSB2
6	GAC2/IO172PDB3	42	IO147PDB3	78	IO115RSB2
7	IO172NDB3	43	IO147NDB3	79	IO114RSB2
8	IO171PDB3	44	GEC1/IO146PDB3	80	IO112RSB2
9	IO171NDB3	45	GEC0/IO146NDB3	81	GND
10	IO170PDB3	46	GEB1/IO145PDB3	82	IO111RSB2
11	IO170NDB3	47	GEB0/IO145NDB3	83	IO110RSB2
12	IO169PDB3	48	GEA1/IO144PDB3	84	IO109RSB2
13	IO169NDB3	49	GEA0/IO144NDB3	85	IO108RSB2
14	IO168PDB3	50	VMV3	86	IO107RSB2
15	IO168NDB3	51	GNDQ	87	IO106RSB2
16	V _{CC}	52	GND	88	V _{CC}
17	GND	53	VMV2	89	V _{CC} B2
18	V _{CC} B3	54	GEA2/IO143RSB2	90	IO104RSB2
19	IO166PDB3	55	FF/GEB2/IO142RSB2	91	IO102RSB2
20	IO166NDB3	56	GEC2/IO141RSB2	92	IO100RSB2
21	GFC1/IO164PDB3	57	IO140RSB2	93	IO98RSB2
22	GFC0/IO164NDB3	58	IO139RSB2	94	IO96RSB2
23	GFB1/IO163PDB3	59	IO138RSB2	95	IO92RSB2
24	GFB0/IO163NDB3	60	IO137RSB2	96	GDC2/IO91RSB2
25	V _{COMPLF}	61	IO136RSB2	97	GND
26	GFA0/IO162NPB3	62	V _{CC} B2	98	GDB2/IO90RSB2
27	V _{CC} PLF	63	IO135RSB2	99	GDA2/IO89RSB2
28	GFA1/IO162PPB3	64	IO133RSB2	100	GNDQ
29	GND	65	GND	101	TCK
30	GFA2/IO161PDB3	66	IO131RSB2	102	TDI
31	IO161NDB3	67	IO129RSB2	103	TMS
32	GFB2/IO160PDB3	68	IO127RSB2	104	VMV2
33	IO160NDB3	69	IO125RSB2	105	GND
34	GFC2/IO159PDB3	70	IO123RSB2	106	V _{PUMP}
35	IO159NDB3	71	V _{CC}	107	GNDQ
36	V _{CC}	72	V _{CC} B2	108	TDO

208-Pin PQFP		208-Pin PQFP		208-Pin PQFP	
Pin Number	A3PL600 Function	Pin Number	A3PL600 Function	Pin Number	A3PL600 Function
109	TRST	145	IO64PDB1	181	IO27RSB0
110	V _{JTAG}	146	IO63NDB1	182	IO26RSB0
111	GDA0/IO88NDB1	147	IO63PDB1	183	IO25RSB0
112	GDA1/IO88PDB1	148	IO62NDB1	184	IO24RSB0
113	GDB0/IO87NDB1	149	GBC2/IO62PDB1	185	IO23RSB0
114	GDB1/IO87PDB1	150	IO61NDB1	186	V _{CC} B0
115	GDC0/IO86NDB1	151	GGB2/IO61PDB1	187	V _{CC}
116	GDC1/IO86PDB1	152	IO60NDB1	188	IO20RSB0
117	IO84NDB1	153	GBA2/IO60PDB1	189	IO19RSB0
118	IO84PDB1	154	VMV1	190	IO18RSB0
119	IO82NDB1	155	GNDQ	191	IO17RSB0
120	IO82PDB1	156	GND	192	IO16RSB0
121	IO81PSB1	157	VMV0	193	IO14RSB0
122	GND	158	GBA1/IO59RSB0	194	IO12RSB0
123	V _{CC} B1	159	GBA0/IO58RSB0	195	GND
124	IO77NDB1	160	GGB1/IO57RSB0	196	IO10RSB0
125	IO77PDB1	161	GGB0/IO56RSB0	197	IO09RSB0
126	NC	162	GND	198	IO08RSB0
127	IO74NDB1	163	GBC1/IO55RSB0	199	IO07RSB0
128	GCC2/IO74PDB1	164	GBC0/IO54RSB0	200	V _{CC} B0
129	GCB2/IO73PSB1	165	IO52RSB0	201	GAC1/IO05RSB0
130	GND	166	IO50RSB0	202	GAC0/IO04RSB0
131	GCA2/IO72PSB1	167	IO48RSB0	203	GAB1/IO03RSB0
132	GCA1/IO71PDB1	168	IO46RSB0	204	GAB0/IO02RSB0
133	GCA0/IO71NDB1	169	IO44RSB0	205	GAA1/IO01RSB0
134	GCB0/IO70NDB1	170	V _{CC} B0	206	GAA0/IO00RSB0
135	GCB1/IO70PDB1	171	V _{CC}	207	GNDQ
136	GCC0/IO69NDB1	172	IO36RSB0	208	VMV0
137	GCC1/IO69PDB1	173	IO35RSB0		
138	IO67NDB1	174	IO34RSB0		
139	IO67PDB1	175	IO33RSB0		
140	V _{CC} B1	176	IO32RSB0		
141	GND	177	IO31RSB0		
142	V _{CC}	178	GND		
143	IO65PSB1	179	IO29RSB0		
144	IO64NDB1	180	IO28RSB0		

208-Pin PQFP		208-Pin PQFP		208-Pin PQFP	
Pin Number	A3PL250 Function	Pin Number	A3PL250 Function	Pin Number	A3PL250 Function
1	GND	37	IO104PDB3	73	IO83RSB2
2	GAA2/IO118UDB3	38	IO104NDB3	74	IO82RSB2
3	IO118VDB3	39	IO103PSB3	75	IO81RSB2
4	GAB2/IO117UDB3	40	V _{CC} B3	76	IO80RSB2
5	IO117VDB3	41	GND	77	IO79RSB2
6	GAC2/IO116UDB3	42	IO101PDB3	78	IO78RSB2
7	IO116VDB3	43	IO101NDB3	79	IO77RSB2
8	IO115UDB3	44	GEC1/IO100PDB3	80	IO76RSB2
9	IO115VDB3	45	GEC0/IO100NDB3	81	GND
10	IO114UDB3	46	GEB1/IO99PDB3	82	IO75RSB2
11	IO114VDB3	47	GEB0/IO99NDB3	83	IO74RSB2
12	IO113PDB3	48	GEA1/IO98PDB3	84	IO73RSB2
13	IO113NDB3	49	GEA0/IO98NDB3	85	IO72RSB2
14	IO112PDB3	50	VMV3	86	IO71RSB2
15	IO112NDB3	51	GNDQ	87	IO70RSB2
16	V _{CC}	52	GND	88	V _{CC}
17	GND	53	NC	89	V _{CC} B2
18	V _{CC} B3	54	NC	90	IO69RSB2
19	IO111PDB3	55	GEA2/IO97RSB2	91	IO68RSB2
20	IO111NDB3	56	FF/GEB2/IO96RSB2	92	IO67RSB2
21	GFC1/IO110PDB3	57	GEC2/IO95RSB2	93	IO66RSB2
22	GFC0/IO110NDB3	58	IO94RSB2	94	IO65RSB2
23	GFB1/IO109PDB3	59	IO93RSB2	95	IO64RSB2
24	GFB0/IO109NDB3	60	IO92RSB2	96	GDC2/IO63RSB2
25	V _{COMPLF}	61	IO91RSB2	97	GND
26	GFA0/IO108NPB3	62	V _{CC} B2	98	GDB2/IO62RSB2
27	V _{CC} PLF	63	IO90RSB2	99	GDA2/IO61RSB2
28	GFA1/IO108PPB3	64	IO89RSB2	100	GNDQ
29	GND	65	GND	101	TCK
30	GFA2/IO107PDB3	66	IO88RSB2	102	TDI
31	IO107NDB3	67	IO87RSB2	103	TMS
32	GFB2/IO106PDB3	68	IO86RSB2	104	VMV2
33	IO106NDB3	69	IO85RSB2	105	GND
34	GFC2/IO105PDB3	70	IO84RSB2	106	V _{PUMP}
35	IO105NDB3	71	V _{CC}	107	NC
36	NC	72	V _{CC} B2	108	TDO

208-Pin PQFP		208-Pin PQFP		208-Pin PQFP	
Pin Number	A3PL250 Function	Pin Number	A3PL250 Function	Pin Number	A3PL250 Function
109	TRST	145	IO45PDB1	181	IO21RSB0
110	V _{JTAG}	146	IO44NDB1	182	IO20RSB0
111	GDA0/IO60VDB1	147	IO44PDB1	183	IO19RSB0
112	GDA1/IO60UDB1	148	IO43NDB1	184	IO18RSB0
113	GDB0/IO59VDB1	149	GBC2/IO43PDB1	185	IO17RSB0
114	GDB1/IO59UDB1	150	IO42NDB1	186	V _{CC} B0
115	GDC0/IO58VDB1	151	GBB2/IO42PDB1	187	V _{CC}
116	GDC1/IO58UDB1	152	IO41NDB1	188	IO16RSB0
117	IO57VDB1	153	GBA2/IO41PDB1	189	IO15RSB0
118	IO57UDB1	154	VMV1	190	IO14RSB0
119	IO56NDB1	155	GNDQ	191	IO13RSB0
120	IO56PDB1	156	GND	192	IO12RSB0
121	IO55RSB1	157	NC	193	IO11RSB0
122	GND	158	GBA1/IO40RSB0	194	IO10RSB0
123	V _{CC} B1	159	GBA0/IO39RSB0	195	GND
124	NC	160	GBB1/IO38RSB0	196	IO09RSB0
125	NC	161	GBB0/IO37RSB0	197	IO08RSB0
126	V _{CC}	162	GND	198	IO07RSB0
127	IO53NDB1	163	GBC1/IO36RSB0	199	IO06RSB0
128	GCC2/IO53PDB1	164	GBC0/IO35RSB0	200	V _{CC} B0
129	GCB2/IO52PSB1	165	IO34RSB0	201	GAC1/IO05RSB0
130	GND	166	IO33RSB0	202	GAC0/IO04RSB0
131	GCA2/IO51PSB1	167	IO32RSB0	203	GAB1/IO03RSB0
132	GCA1/IO50PDB1	168	IO31RSB0	204	GAB0/IO02RSB0
133	GCA0/IO50NDB1	169	IO30RSB0	205	GAA1/IO01RSB0
134	GCB0/IO49NDB1	170	V _{CC} B0	206	GAA0/IO00RSB0
135	GCB1/IO49PDB1	171	V _{CC}	207	GNDQ
136	GCC0/IO48NDB1	172	IO29RSB0	208	VMV0
137	GCC1/IO48PDB1	173	IO28RSB0		
138	IO47NDB1	174	IO27RSB0		
139	IO47PDB1	175	IO26RSB0		
140	V _{CC} B1	176	IO25RSB0		
141	GND	177	IO24RSB0		
142	V _{CC}	178	GND		
143	IO46RSB1	179	IO23RSB0		
144	IO45NDB1	180	IO22RSB0		

208-Pin PQFP	
Pin Number	APL1000 Function
1	GND
2	GAA2/IO225PDB3
3	IO225NDB3
4	GAB2/IO224PDB3
5	IO224NDB3
6	GAC2/IO223PDB3
7	IO223NDB3
8	IO222PDB3
9	IO222NDB3
10	IO220PDB3
11	IO220NDB3
12	IO218PDB3
13	IO218NDB3
14	IO216PDB3
15	IO216NDB3
16	V _{CC}
17	GND
18	V _{CCI} B3
19	IO212PDB3
20	IO212NDB3
21	GFC1/IO209PDB3
22	GFC0/IO209NDB3
23	GFB1/IO208PDB3
24	GFB0/IO208NDB3
25	V _{CCPLF}
26	GFA0/IO207NPB3
27	V _{CCPLF}
28	GFA1/IO207PPB3
29	GND
30	GFA2/IO206PDB3
31	IO206NDB3
32	GFB2/IO205PDB3
33	IO205NDB3
34	GFC2/IO204PDB3
35	IO204NDB3
36	V _{CC}

208-Pin PQFP	
Pin Number	APL1000 Function
37	IO199PDB3
38	IO199NDB3
39	IO197PSB3
40	V _{CCI} B3
41	GND
42	IO191PDB3
43	IO191NDB3
44	GEC1/IO190PDB3
45	GEC0/IO190NDB3
46	GEB1/IO189PDB3
47	GEB0/IO189NDB3
48	GEA1/IO188PDB3
49	GEA0/IO188NDB3
50	VMV3
51	GNDQ
52	GND
53	VMV2
54	GEA2/IO187RSB2
55	FF/GEB2/IO186RSB2
56	GEC2/IO185RSB2
57	IO184RSB2
58	IO183RSB2
59	IO182RSB2
60	IO181RSB2
61	IO180RSB2
62	V _{CCI} B2
63	IO178RSB2
64	IO176RSB2
65	GND
66	IO174RSB2
67	IO172RSB2
68	IO170RSB2
69	IO168RSB2
70	IO166RSB2
71	V _{CC}
72	V _{CCI} B2

208-Pin PQFP	
Pin Number	APL1000 Function
73	IO162RSB2
74	IO160RSB2
75	IO158RSB2
76	IO156RSB2
77	IO154RSB2
78	IO152RSB2
79	IO150RSB2
80	IO148RSB2
81	GND
82	IO143RSB2
83	IO141RSB2
84	IO139RSB2
85	IO137RSB2
86	IO135RSB2
87	IO133RSB2
88	V _{CC}
89	V _{CCI} B2
90	IO128RSB2
91	IO126RSB2
92	IO124RSB2
93	IO122RSB2
94	IO120RSB2
95	IO118RSB2
96	GDC2/IO116RSB2
97	GND
98	GDB2/IO115RSB2
99	GDA2/IO114RSB2
100	GNDQ
101	TCK
102	TDI
103	TMS
104	VMV2
105	GND
106	V _{PUMP}
107	GNDQ
108	TDO

208-Pin PQFP		208-Pin PQFP		208-Pin PQFP	
Pin Number	APL1000 Function	Pin Number	APL1000 Function	Pin Number	APL1000 Function
109	TRST	145	IO84PDB1	181	IO33RSB0
110	V _{JTAG}	146	IO82NDB1	182	IO31RSB0
111	GDA0/IO113NDB1	147	IO82PDB1	183	IO29RSB0
112	GDA1/IO113PDB1	148	IO80NDB1	184	IO27RSB0
113	GDB0/IO112NDB1	149	GBC2/IO80PDB1	185	IO25RSB0
114	GDB1/IO112PDB1	150	IO79NDB1	186	V _{CC} B0
115	GDC0/IO111NDB1	151	GBB2/IO79PDB1	187	V _{CC}
116	GDC1/IO111PDB1	152	IO78NDB1	188	IO22RSB0
117	IO109NDB1	153	GBA2/IO78PDB1	189	IO20RSB0
118	IO109PDB1	154	VMV1	190	IO18RSB0
119	IO106NDB1	155	GNDQ	191	IO16RSB0
120	IO106PDB1	156	GND	192	IO15RSB0
121	IO104PSB1	157	VMV0	193	IO14RSB0
122	GND	158	GBA1/IO77RSB0	194	IO13RSB0
123	V _{CC} B1	159	GBA0/IO76RSB0	195	GND
124	IO99NDB1	160	GBB1/IO75RSB0	196	IO12RSB0
125	IO99PDB1	161	GBB0/IO74RSB0	197	IO11RSB0
126	NC	162	GND	198	IO10RSB0
127	IO96NDB1	163	GBC1/IO73RSB0	199	IO09RSB0
128	GCC2/IO96PDB1	164	GBC0/IO72RSB0	200	V _{CC} B0
129	GCB2/IO95PSB1	165	IO70RSB0	201	GAC1/IO05RSB0
130	GND	166	IO67RSB0	202	GAC0/IO04RSB0
131	GCA2/IO94PSB1	167	IO63RSB0	203	GAB1/IO03RSB0
132	GCA1/IO93PDB1	168	IO60RSB0	204	GAB0/IO02RSB0
133	GCA0/IO93NDB1	169	IO57RSB0	205	GAA1/IO01RSB0
134	GCB0/IO92NDB1	170	V _{CC} B0	206	GAA0/IO00RSB0
135	GCB1/IO92PDB1	171	V _{CC}	207	GNDQ
136	GCC0/IO91NDB1	172	IO54RSB0	208	VMV0
137	GCC1/IO91PDB1	173	IO51RSB0		
138	IO88NDB1	174	IO48RSB0		
139	IO88PDB1	175	IO45RSB0		
140	V _{CC} B1	176	IO42RSB0		
141	GND	177	IO40RSB0		
142	V _{CC}	178	GND		
143	IO86PSB1	179	IO38RSB0		
144	IO84NDB1	180	IO35RSB0		

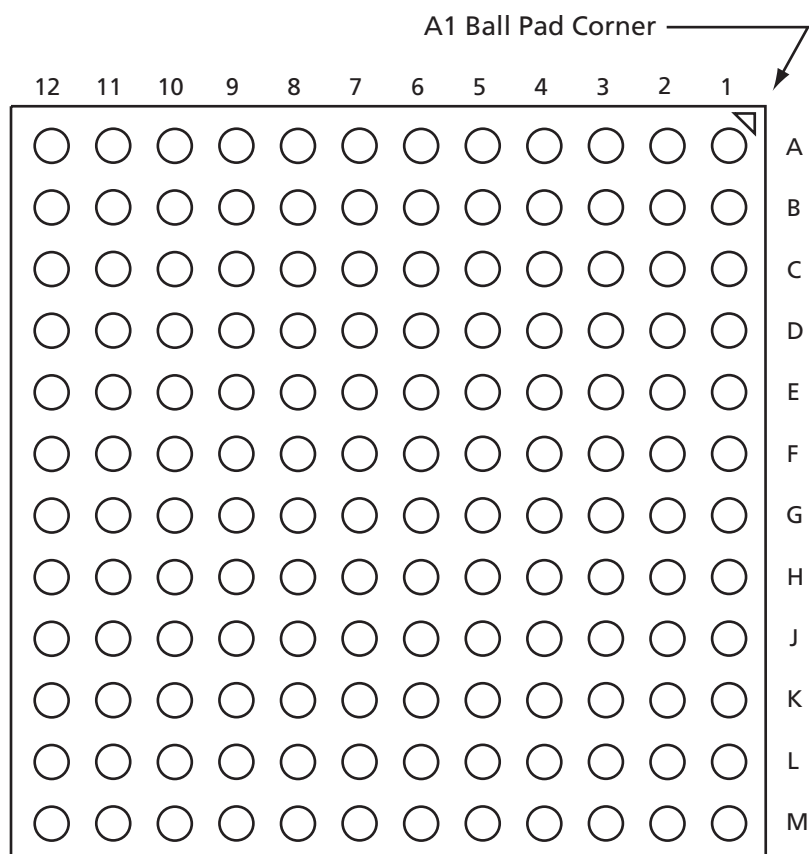
208-Pin PQFP	
Pin Number	A3PE3000L Function
1	GND
2	GNDQ
3	VMV7
4	GAB2/IO308PSB7V4
5	GAA2/IO309PDB7V4
6	IO309NDB7V4
7	GAC2/IO307PDB7V4
8	IO307NDB7V4
9	IO303PDB7V3
10	IO303NDB7V3
11	IO299PDB7V3
12	IO299NDB7V3
13	IO295PDB7V2
14	IO295NDB7V2
15	IO291PSB7V2
16	V _{CC}
17	GND
18	V _{CC} B7
19	IO285PDB7V1
20	IO285NDB7V1
21	IO279PSB7V0
22	GFC1/IO275PSB7V0
23	GFB1/IO274PDB7V0
24	GFB0/IO274NDB7V0
25	V _{COMPLF}
26	GFA0/IO273NPB6V4
27	V _{CCPLF}
28	GFA1/IO273PPB6V4
29	GND
30	GFA2/IO272PDB6V4
31	IO272NDB6V4
32	GFB2/IO271PPB6V4
33	GFC2/IO270PPB6V4
34	IO271NPB6V4
35	IO270NPB6V4
36	V _{CC}
36	V _{CC}

208-Pin PQFP	
Pin Number	A3PE3000L Function
37	IO252PDB6V2
38	IO252NDB6V2
39	IO248PSB6V1
40	V _{CC} B6
41	GND
42	IO244PDB6V1
43	IO244NDB6V1
44	GEC1/IO236PDB6V0
45	GEC0/IO236NDB6V0
46	GEB1/IO235PPB6V0
47	GEA1/IO234PPB6V0
48	GEB0/IO235NPB6V0
49	GEA0/IO234NPB6V0
50	VMV6
51	GNDQ
52	GND
53	VMV5
54	GNDQ
55	IO233NDB5V4
56	GEA2/IO233PDB5V4
57	IO232NDB5V4
58	FF/GEB2/IO232PDB5V4
59	IO231NDB5V4
60	GEC2/IO231PDB5V4
61	IO230PSB5V4
62	V _{CC} B5
62	V _{CC} B5
63	IO218NDB5V3
64	IO218PDB5V3
65	GND
66	IO214PSB5V2
67	IO212NDB5V2
68	IO212PDB5V2
69	IO208NDB5V1
70	IO208PDB5V1
71	V _{CC}

208-Pin PQFP	
Pin Number	A3PE3000L Function
72	V _{CC} B5
73	IO202NDB5V1
74	IO202PDB5V1
75	IO198NDB5V0
76	IO198PDB5V0
77	IO197NDB5V0
78	IO197PDB5V0
79	IO194NDB5V0
80	IO194PDB5V0
81	GND
82	IO184NDB4V3
83	IO184PDB4V3
84	IO180NDB4V3
85	IO180PDB4V3
86	IO176NDB4V2
87	IO176PDB4V2
88	V _{CC}
89	V _{CC} B4
90	IO170NDB4V2
91	IO170PDB4V2
92	IO166NDB4V1
93	IO166PDB4V1
94	IO156NDB4V0
95	GDC2/IO156PDB4V0
96	IO154NPB4V0
97	GND
98	GDB2/IO155PSB4V0
99	GDA2/IO154PPB4V0
100	GNDQ
101	TCK
102	TDI
103	TMS
104	VMV4
105	GND
106	V _{PUMP}
107	GNDQ
108	TDO

208-Pin PQFP		208-Pin PQFP		208-Pin PQFP	
Pin Number	A3PE3000L Function	Pin Number	A3PE3000L Function	Pin Number	A3PE3000L Function
109	TRST	146	IO96PDB2V1	182	IO35PDB0V4
110	V _{JTAG}	147	IO91NDB2V1	183	IO35NDB0V4
111	VMV3	148	IO91PDB2V1	184	IO32PDB0V3
112	GDA0/IO153NPB3V4	149	IO88NDB2V0	185	IO32NDB0V3
113	GDB0/IO152NPB3V4	150	IO88PDB2V0	186	V _{CC} B0
114	GDA1/IO153PPB3V4	151	GBC2/IO84PSB2V0	187	V _{CC}
115	GDB1/IO152PPB3V4	152	GBA2/IO82PSB2V0	188	IO28PDB0V3
116	GDC0/IO151NDB3V4	153	GBB2/IO83PSB2V0	189	IO28NDB0V3
117	GDC1/IO151PDB3V4	154	VMV2	190	IO24PDB0V2
118	IO134NDB3V2	155	GNDQ	191	IO24NDB0V2
119	IO134PDB3V2	156	GND	192	IO21PSB0V2
120	IO132NDB3V2	157	VMV1	193	IO16PDB0V1
121	IO132PDB3V2	158	GNDQ	194	IO16NDB0V1
122	GND	159	GBA1/IO81PDB1V4	195	GND
123	V _{CC} B3	160	GBA0/IO81NDB1V4	196	IO11PDB0V1
124	GCC2/IO117PSB3V0	161	GBB1/IO80PDB1V4	197	IO11NDB0V1
125	GCB2/IO116PSB3V0	162	GND	198	IO08PDB0V0
126	NC	163	GBB0/IO80NDB1V4	199	IO08NDB0V0
127	IO115NDB3V0	164	GBC1/IO79PDB1V4	200	V _{CC} B0
128	GCA2/IO115PDB3V0	165	GBC0/IO79NDB1V4	201	GAC1/IO02PDB0V0
129	GCA1/IO114PPB3V0	166	IO74PDB1V4	202	GAC0/IO02NDB0V0
130	GND	167	IO74NDB1V4	203	GAB1/IO01PDB0V0
131	V _{CC} PLC	168	IO70PDB1V3	204	GAB0/IO01NDB0V0
132	GCA0/IO114NPB3V0	169	IO70NDB1V3	205	GAA1/IO00PDB0V0
133	V _{COM} PLC	170	V _{CC} B1	206	GAA0/IO00NDB0V0
134	GCB0/IO113NDB2V3	171	V _{CC}	207	GNDQ
135	GCB1/IO113PDB2V3	171	V _{CC}	208	VMV0
136	GCC1/IO112PSB2V3	172	IO56PSB1V1		
137	IO110NDB2V3	173	IO55PDB1V1		
138	IO110PDB2V3	174	IO55NDB1V1		
139	IO106PSB2V3	175	IO54PDB1V1		
140	V _{CC} B2	176	IO54NDB1V1		
141	GND	177	IO40PDB0V4		
142	V _{CC}	178	GND		
143	IO99NDB2V2	179	IO40NDB0V4		
144	IO99PDB2V2	180	IO37PDB0V4		
145	IO96NDB2V1	181	IO37NDB0V4		

144-Pin FBGA



Note: This is the bottom view of the package.

Figure 3-3 •

Note

For Package Manufacturing and Environmental information, visit the Resource Center at <http://www.actel.com/products/solutions/package/docs.aspx>.

144-Pin FBGA		144-Pin FBGA		144-Pin FBGA	
Pin Number	A3P250L Function	Pin Number	A3P250L Function	Pin Number	A3P250L Function
A1	GNDQ	D1	IO112NDB3	G1	GFA1/IO108PPB3
A2	VMV0	D2	IO112PDB3	G2	GND
A3	GAB0/IO02RSB0	D3	IO116VDB3	G3	V _{CCPLF}
A4	GAB1/IO03RSB0	D4	GAA2/IO118UPB3	G4	GFA0/IO108NPB3
A5	IO16RSB0	D5	GAC0/IO04RSB0	G5	GND
A6	GND	D6	GAC1/IO05RSB0	G6	GND
A7	IO29RSB0	D7	GBC0/IO35RSB0	G7	GND
A8	V _{CC}	D8	GBC1/IO36RSB0	G8	GDC1/IO58UPB1
A9	IO33RSB0	D9	GBB2/IO42PDB1	G9	IO53NDB1
A10	GBA0/IO39RSB0	D10	IO42NDB1	G10	GCC2/IO53PDB1
A11	GBA1/IO40RSB0	D11	IO43NPB1	G11	IO52NDB1
A12	GNDQ	D12	GCB1/IO49PPB1	G12	GCB2/IO52PDB1
B1	GAB2/IO117UDB3	E1	V _{CC}	H1	V _{CC}
B2	GND	E2	GFC0/IO110NDB3	H2	GFB2/IO106PDB3
B3	GAA0/IO00RSB0	E3	GFC1/IO110PDB3	H3	GFC2/IO105PSB3
B4	GAA1/IO01RSB0	E4	V _{CC} B3	H4	GEC1/IO100PDB3
B5	IO14RSB0	E5	IO118VPB3	H5	V _{CC}
B6	IO19RSB0	E6	V _{CC} B0	H6	IO79RSB2
B7	IO22RSB0	E7	V _{CC} B0	H7	IO65RSB2
B8	IO30RSB0	E8	GCC1/IO48PDB1	H8	GDB2/IO62RSB2
B9	GBB0/IO37RSB0	E9	V _{CC} B1	H9	GDC0/IO58VPB1
B10	GBB1/IO38RSB0	E10	V _{CC}	H10	V _{CC} B1
B11	GND	E11	GCA0/IO50NDB1	H11	IO54PSB1
B12	VMV1	E12	IO51NDB1	H12	V _{CC}
C1	IO117VDB3	F1	GFB0/IO109NPB3	J1	GEB1/IO99PDB3
C2	GFA2/IO107PPB3	F2	V _{COMPLF}	J2	IO106NDB3
C3	GAC2/IO116UDB3	F3	GFB1/IO109PPB3	J3	V _{CC} B3
C4	V _{CC}	F4	IO107NPB3	J4	GEC0/IO100NDB3
C5	IO12RSB0	F5	GND	J5	IO88RSB2
C6	IO17RSB0	F6	GND	J6	IO81RSB2
C7	IO24RSB0	F7	GND	J7	V _{CC}
C8	IO31RSB0	F8	GCC0/IO48NDB1	J8	TCK
C9	IO34RSB0	F9	GCB0/IO49NPB1	J9	GDA2/IO61RSB2
C10	GBA2/IO41PDB1	F10	GND	J10	TDO
C11	IO41NDB1	F11	GCA1/IO50PDB1	J11	GDA1/IO60UDB1
C12	GBC2/IO43PPB1	F12	GCA2/IO51PDB1	J12	GDB1/IO59UDB1

144-Pin FBGA	
Pin Number	A3P250L Function
K1	GEB0/IO99NDB3
K2	GEA1/IO98PDB3
K3	GEA0/IO98NDB3
K4	GEA2/IO97RSB2
K5	IO90RSB2
K6	IO84RSB2
K7	GND
K8	IO66RSB2
K9	GDC2/IO63RSB2
K10	GND
K11	GDA0/IO60VDB1
K12	GDB0/IO59VDB1
L1	GND
L2	VMV3
L3	FF/GEB2/IO96RSB2
L4	IO91RSB2
L5	V _{CC} B2
L6	IO82RSB2
L7	IO80RSB2
L8	IO72RSB2
L9	TMS
L10	V _{JTAG}
L11	VMV2
L12	TRST
M1	GNDQ
M2	GEC2/IO95RSB2
M3	IO92RSB2
M4	IO89RSB2
M5	IO87RSB2
M6	IO85RSB2
M7	IO78RSB2
M8	IO76RSB2
M9	TDI
M10	V _{CC} B2
M11	V _{PUMP}
M12	GNDQ

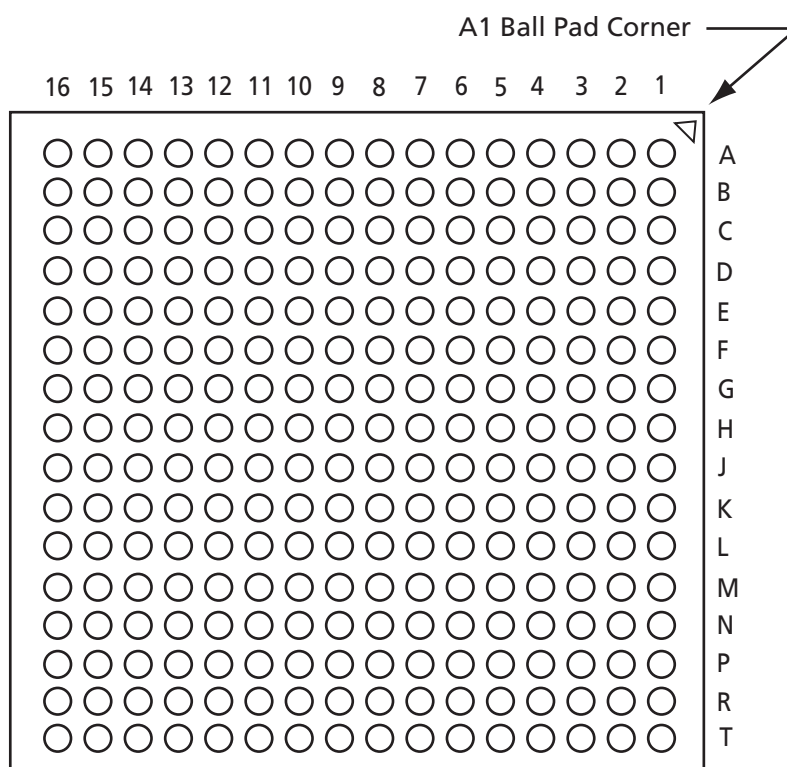
144-Pin FBGA		144-Pin FBGA		144-Pin FBGA	
Pin Number	A3P600L Function	Pin Number	A3P600L Function	Pin Number	A3P600L Function
A1	GNDQ	D1	IO169PDB3	G1	GFA1/IO162PPB3
A2	VMV0	D2	IO169NDB3	G2	GND
A3	GAB0/IO02RSB0	D3	IO172NDB3	G3	VCCPLF
A4	GAB1/IO03RSB0	D4	GAA2/IO174PPB3	G4	GFA0/IO162NPB3
A5	IO10RSB0	D5	GAC0/IO04RSB0	G5	GND
A6	GND	D6	GAC1/IO05RSB0	G6	GND
A7	IO34RSB0	D7	GBC0/IO54RSB0	G7	GND
A8	V _{CC}	D8	GBC1/IO55RSB0	G8	GDC1/IO86PPB1
A9	IO50RSB0	D9	GBB2/IO61PDB1	G9	IO74NDB1
A10	GBA0/IO58RSB0	D10	IO61NDB1	G10	GCC2/IO74PDB1
A11	GBA1/IO59RSB0	D11	IO62NPB1	G11	IO73NDB1
A12	GNDQ	D12	GCB1/IO70PPB1	G12	GCB2/IO73PDB1
B1	GAB2/IO173PDB3	E1	V _{CC}	H1	V _{CC}
B2	GND	E2	GFC0/IO164NDB3	H2	GFB2/IO160PDB3
B3	GAA0/IO00RSB0	E3	GFC1/IO164PDB3	H3	GFC2/IO159PSB3
B4	GAA1/IO01RSB0	E4	V _{CC} B3	H4	GEC1/IO146PDB3
B5	IO13RSB0	E5	IO174NPB3	H5	V _{CC}
B6	IO19RSB0	E6	V _{CC} B0	H6	IO80PDB1
B7	IO31RSB0	E7	V _{CC} B0	H7	IO80NDB1
B8	IO39RSB0	E8	GCC1/IO69PDB1	H8	GDB2/IO90RSB2
B9	GBB0/IO56RSB0	E9	V _{CC} B1	H9	GDC0/IO86NPB1
B10	GBB1/IO57RSB0	E10	V _{CC}	H10	V _{CC} B1
B11	GND	E11	GCA0/IO71NDB1	H11	IO84PSB1
B12	VMV1	E12	IO72NDB1	H12	V _{CC}
C1	IO173NDB3	F1	GFB0/IO163NPB3	J1	GEB1/IO145PDB3
C2	GFA2/IO161PPB3	F2	V _{COMPLF}	J2	IO160NDB3
C3	GAC2/IO172PDB3	F3	GFB1/IO163PPB3	J3	V _{CC} B3
C4	V _{CC}	F4	IO161NPB3	J4	GEC0/IO146NDB3
C5	IO16RSB0	F5	GND	J5	IO129RSB2
C6	IO25RSB0	F6	GND	J6	IO131RSB2
C7	IO28RSB0	F7	GND	J7	V _{CC}
C8	IO42RSB0	F8	GCC0/IO69NDB1	J8	TCK
C9	IO45RSB0	F9	GCB0/IO70NPB1	J9	GDA2/IO89RSB2
C10	GBA2/IO60PDB1	F10	GND	J10	TDO
C11	IO60NDB1	F11	GCA1/IO71PDB1	J11	GDA1/IO88PDB1
C12	GBC2/IO62PPB1	F12	GCA2/IO72PDB1	J12	GDB1/IO87PDB1

144-Pin FBGA	
Pin Number	A3P600L Function
K1	GEB0/IO145NDB3
K2	GEA1/IO144PDB3
K3	GEA0/IO144NDB3
K4	GEA2/IO143RSB2
K5	IO119RSB2
K6	IO111RSB2
K7	GND
K8	IO94RSB2
K9	GDC2/IO91RSB2
K10	GND
K11	GDA0/IO88NDB1
K12	GDB0/IO87NDB1
L1	GND
L2	VMV3
L3	FF/GEB2/IO142RSB2
L4	IO136RSB2
L5	V _{CC} B2
L6	IO115RSB2
L7	IO103RSB2
L8	IO97RSB2
L9	TMS
L10	V _{JTAG}
L11	VMV2
L12	TRST
M1	GNDQ
M2	GEC2/IO141RSB2
M3	IO138RSB2
M4	IO123RSB2
M5	IO126RSB2
M6	IO134RSB2
M7	IO108RSB2
M8	IO99RSB2
M9	TDI
M10	V _{CC} B2
M11	V _{PUMP}
M12	GNDQ

144-Pin FBGA		144-Pin FBGA		144-Pin FBGA	
Pin Number	A3P1000L Function	Pin Number	A3P1000L Function	Pin Number	A3P1000L Function
A1	GNDQ	D1	IO213PDB3	G1	GFA1/IO207PPB3
A2	VMV0	D2	IO213NDB3	G2	GND
A3	GAB0/IO02RSB0	D3	IO223NDB3	G3	V _{CCPLF}
A4	GAB1/IO03RSB0	D4	GAA2/IO225PPB3	G4	GFA0/IO207NPB3
A5	IO10RSB0	D5	GAC0/IO04RSB0	G5	GND
A6	GND	D6	GAC1/IO05RSB0	G6	GND
A7	IO44RSB0	D7	GBC0/IO72RSB0	G7	GND
A8	V _{CC}	D8	GBC1/IO73RSB0	G8	GDC1/IO111PPB1
A9	IO69RSB0	D9	GBB2/IO79PDB1	G9	IO96NDB1
A10	GBA0/IO76RSB0	D10	IO79NDB1	G10	GCC2/IO96PDB1
A11	GBA1/IO77RSB0	D11	IO80NPB1	G11	IO95NDB1
A12	GNDQ	D12	GCB1/IO92PPB1	G12	GCB2/IO95PDB1
B1	GAB2/IO224PDB3	E1	V _{CC}	H1	V _{CC}
B2	GND	E2	GFC0/IO209NDB3	H2	GFB2/IO205PDB3
B3	GAA0/IO00RSB0	E3	GFC1/IO209PDB3	H3	GFC2/IO204PSB3
B4	GAA1/IO01RSB0	E4	V _{CC} B3	H4	GEC1/IO190PDB3
B5	IO13RSB0	E5	IO225NPB3	H5	V _{CC}
B6	IO26RSB0	E6	V _{CC} B0	H6	IO105PDB1
B7	IO35RSB0	E7	V _{CC} B0	H7	IO105NDB1
B8	IO60RSB0	E8	GCC1/IO91PDB1	H8	GDB2/IO115RSB2
B9	GBB0/IO74RSB0	E9	V _{CC} B1	H9	GDC0/IO111NPB1
B10	GBB1/IO75RSB0	E10	V _{CC}	H10	V _{CC} B1
B11	GND	E11	GCA0/IO93NDB1	H11	IO101PSB1
B12	VMV1	E12	IO94NDB1	H12	V _{CC}
C1	IO224NDB3	F1	GFB0/IO208NPB3	J1	GEB1/IO189PDB3
C2	GFA2/IO206PPB3	F2	V _{COMPLF}	J2	IO205NDB3
C3	GAC2/IO223PDB3	F3	GFB1/IO208PPB3	J3	V _{CC} B3
C4	V _{CC}	F4	IO206NPB3	J4	GEC0/IO190NDB3
C5	IO16RSB0	F5	GND	J5	IO160RSB2
C6	IO29RSB0	F6	GND	J6	IO157RSB2
C7	IO32RSB0	F7	GND	J7	V _{CC}
C8	IO63RSB0	F8	GCC0/IO91NDB1	J8	TCK
C9	IO66RSB0	F9	GCB0/IO92NPB1	J9	GDA2/IO114RSB2
C10	GBA2/IO78PDB1	F10	GND	J10	TDO
C11	IO78NDB1	F11	GCA1/IO93PDB1	J11	GDA1/IO113PDB1
C12	GBC2/IO80PPB1	F12	GCA2/IO94PDB1	J12	GDB1/IO112PDB1

144-Pin FBGA	
Pin Number	A3P1000L Function
K1	GEB0/IO189NDB3
K2	GEA1/IO188PDB3
K3	GEA0/IO188NDB3
K4	GEA2/IO187RSB2
K5	IO169RSB2
K6	IO152RSB2
K7	GND
K8	IO117RSB2
K9	GDC2/IO116RSB2
K10	GND
K11	GDA0/IO113NDB1
K12	GDB0/IO112NDB1
L1	GND
L2	VMV3
L3	FF/GEB2/IO186RSB2
L4	IO172RSB2
L5	V _{CC} B2
L6	IO153RSB2
L7	IO144RSB2
L8	IO140RSB2
L9	TMS
L10	V _{JTAG}
L11	VMV2
L12	TRST
M1	GNDQ
M2	GEC2/IO185RSB2
M3	IO173RSB2
M4	IO168RSB2
M5	IO161RSB2
M6	IO156RSB2
M7	IO145RSB2
M8	IO141RSB2
M9	TDI
M10	V _{CC} B2
M11	V _{PUMP}
M12	GNDQ

256-Pin FBGA



Note: This is the bottom view of the package.

Figure 3-4 •

Note

For Package Manufacturing and Environmental information, visit the Resource Center at <http://www.actel.com/products/solutions/package/docs.aspx>.

256-Pin FBGA		256-Pin FBGA		256-Pin FBGA	
Pin Number	A3P250L Function	Pin Number	A3P250L Function	Pin Number	A3P250L Function
A1	GND	C5	GAC0/IO04RSB0	E9	IO24RSB0
A2	GAA0/IO00RSB0	C6	GAC1/IO05RSB0	E10	V _{CC} B0
A3	GAA1/IO01RSB0	C7	IO13RSB0	E11	V _{CC} B0
A4	GAB0/IO02RSB0	C8	IO17RSB0	E12	VMV1
A5	IO07RSB0	C9	IO22RSB0	E13	GBC2/IO43PDB1
A6	IO10RSB0	C10	IO27RSB0	E14	IO46RSB1
A7	IO11RSB0	C11	IO31RSB0	E15	NC
A8	IO15RSB0	C12	GBC0/IO35RSB0	E16	IO45PDB1
A9	IO20RSB0	C13	IO34RSB0	F1	IO113NDB3
A10	IO25RSB0	C14	NC	F2	IO112PPB3
A11	IO29RSB0	C15	IO42NPB1	F3	NC
A12	IO33RSB0	C16	IO44PDB1	F4	IO115VDB3
A13	GBB1/IO38RSB0	D1	IO114VDB3	F5	V _{CC} B3
A14	GBA0/IO39RSB0	D2	IO114UDB3	F6	GND
A15	GBA1/IO40RSB0	D3	GAC2/IO116UDB3	F7	V _{CC}
A16	GND	D4	NC	F8	V _{CC}
B1	GAB2/IO117UDB3	D5	GNDQ	F9	V _{CC}
B2	GAA2/IO118UDB3	D6	IO08RSB0	F10	V _{CC}
B3	NC	D7	IO14RSB0	F11	GND
B4	GAB1/IO03RSB0	D8	IO18RSB0	F12	V _{CC} B1
B5	IO06RSB0	D9	IO23RSB0	F13	IO43NDB1
B6	IO09RSB0	D10	IO28RSB0	F14	NC
B7	IO12RSB0	D11	IO32RSB0	F15	IO47PPB1
B8	IO16RSB0	D12	GNDQ	F16	IO45NDB1
B9	IO21RSB0	D13	NC	G1	IO111NDB3
B10	IO26RSB0	D14	GBB2/IO42PPB1	G2	IO111PDB3
B11	IO30RSB0	D15	NC	G3	IO112NPB3
B12	GBC1/IO36RSB0	D16	IO44NDB1	G4	GFC1/IO110PPB3
B13	GBB0/IO37RSB0	E1	IO113PDB3	G5	V _{CC} B3
B14	NC	E2	NC	G6	V _{CC}
B15	GBA2/IO41PDB1	E3	IO116VDB3	G7	GND
B16	IO41NDB1	E4	IO115UDB3	G8	GND
C1	IO117VDB3	E5	VMV0	G9	GND
C2	IO118VDB3	E6	V _{CC} B0	G10	GND
C3	NC	E7	V _{CC} B0	G11	V _{CC}
C4	NC	E8	IO19RSB0	G12	V _{CC} B1

256-Pin FBGA		256-Pin FBGA		256-Pin FBGA	
Pin Number	A3P250L Function	Pin Number	A3P250L Function	Pin Number	A3P250L Function
G13	GCC1/IO48PPB1	K1	GFC2/IO105PDB3	M5	VMV3
G14	IO47NPB1	K2	IO107NPB3	M6	V _{CC} B2
G15	IO54PDB1	K3	IO104PPB3	M7	V _{CC} B2
G16	IO54NDB1	K4	NC	M8	NC
H1	GFB0/IO109NPB3	K5	V _{CC} B3	M9	IO74RSB2
H2	GFA0/IO108NDB3	K6	V _{CC}	M10	V _{CC} B2
H3	GFB1/IO109PPB3	K7	GND	M11	V _{CC} B2
H4	V _{COMPLF}	K8	GND	M12	VMV2
H5	GFC0/IO110NPB3	K9	GND	M13	NC
H6	V _{CC}	K10	GND	M14	GDB1/IO59UPB1
H7	GND	K11	V _{CC}	M15	GDC1/IO58UDB1
H8	GND	K12	V _{CC} B1	M16	IO56NDB1
H9	GND	K13	IO52NPB1	N1	IO103NDB3
H10	GND	K14	IO55RSB1	N2	IO101PPB3
H11	V _{CC}	K15	IO53NPB1	N3	GEC1/IO100PPB3
H12	GCC0/IO48NPB1	K16	IO51NDB1	N4	NC
H13	GCB1/IO49PPB1	L1	IO105NDB3	N5	GNDQ
H14	GCA0/IO50NPB1	L2	IO104NPB3	N6	GEA2/IO97RSB2
H15	NC	L3	NC	N7	IO86RSB2
H16	GCB0/IO49NPB1	L4	IO102RSB3	N8	IO82RSB2
J1	GFA2/IO107PPB3	L5	V _{CC} B3	N9	IO75RSB2
J2	GFA1/IO108PDB3	L6	GND	N10	IO69RSB2
J3	V _{CC} PLF	L7	V _{CC}	N11	IO64RSB2
J4	IO106NDB3	L8	V _{CC}	N12	GNDQ
J5	GFB2/IO106PDB3	L9	V _{CC}	N13	NC
J6	V _{CC}	L10	V _{CC}	N14	V _{JTAG}
J7	GND	L11	GND	N15	GDC0/IO58VDB1
J8	GND	L12	V _{CC} B1	N16	GDA1/IO60UDB1
J9	GND	L13	GDB0/IO59VPB1	P1	GEB1/IO99PDB3
J10	GND	L14	IO57VDB1	P2	GEB0/IO99NDB3
J11	V _{CC}	L15	IO57UDB1	P3	NC
J12	GCB2/IO52PPB1	L16	IO56PDB1	P4	NC
J13	GCA1/IO50PPB1	M1	IO103PDB3	P5	IO92RSB2
J14	GCC2/IO53PPB1	M2	NC	P6	IO89RSB2
J15	NC	M3	IO101NPB3	P7	IO85RSB2
J16	GCA2/IO51PDB1	M4	GEC0/IO100NPB3	P8	IO81RSB2

256-Pin FBGA	
Pin Number	A3P250L Function
P9	IO76RSB2
P10	IO71RSB2
P11	IO66RSB2
P12	NC
P13	TCK
P14	V _{PUMP}
P15	TRST
P16	GDA0/IO60VDB1
R1	GEA1/IO98PDB3
R2	GEA0/IO98NDB3
R3	NC
R4	GEC2/IO95RSB2
R5	IO91RSB2
R6	IO88RSB2
R7	IO84RSB2
R8	IO80RSB2
R9	IO77RSB2
R10	IO72RSB2
R11	IO68RSB2
R12	IO65RSB2
R13	GDB2/IO62RSB2
R14	TDI
R15	NC
R16	TDO
T1	GND
T2	IO94RSB2
T3	FF/GEA2/IO96RSB2
T4	IO93RSB2
T5	IO90RSB2
T6	IO87RSB2
T7	IO83RSB2
T8	IO79RSB2
T9	IO78RSB2
T10	IO73RSB2
T11	IO70RSB2
T12	GDC2/IO63RSB2

256-Pin FBGA	
Pin Number	A3P250L Function
T13	IO67RSB2
T14	GDA2/IO61RSB2
T15	TMS
T16	GND

256-Pin FBGA		256-Pin FBGA		256-Pin FBGA	
Pin Number	A3P600L Function	Pin Number	A3P600L Function	Pin Number	A3P600L Function
A1	GND	C5	GAC0/IO04RSB0	E9	IO31RSB0
A2	GAA0/IO00RSB0	C6	GAC1/IO05RSB0	E10	V _{CCI} B0
A3	GAA1/IO01RSB0	C7	IO20RSB0	E11	V _{CCI} B0
A4	GAB0/IO02RSB0	C8	IO24RSB0	E12	VMV1
A5	IO11RSB0	C9	IO33RSB0	E13	GBC2/IO62PDB1
A6	IO16RSB0	C10	IO39RSB0	E14	IO67PPB1
A7	IO18RSB0	C11	IO44RSB0	E15	IO64PPB1
A8	IO28RSB0	C12	GBC0/IO54RSB0	E16	IO66PDB1
A9	IO34RSB0	C13	IO51RSB0	F1	IO166NDB3
A10	IO37RSB0	C14	VMV0	F2	IO168NPB3
A11	IO41RSB0	C15	IO61NPB1	F3	IO167PPB3
A12	IO43RSB0	C16	IO63PDB1	F4	IO169PDB3
A13	GBB1/IO57RSB0	D1	IO171NDB3	F5	V _{CCI} B3
A14	GBA0/IO58RSB0	D2	IO171PDB3	F6	GND
A15	GBA1/IO59RSB0	D3	GAC2/IO172PDB3	F7	V _{CC}
A16	GND	D4	IO06RSB0	F8	V _{CC}
B1	GAB2/IO173PDB3	D5	GNDQ	F9	V _{CC}
B2	GAA2/IO174PDB3	D6	IO10RSB0	F10	V _{CC}
B3	GNDQ	D7	IO19RSB0	F11	GND
B4	GAB1/IO03RSB0	D8	IO26RSB0	F12	V _{CCI} B1
B5	IO13RSB0	D9	IO30RSB0	F13	IO62NDB1
B6	IO14RSB0	D10	IO40RSB0	F14	IO64NPB1
B7	IO21RSB0	D11	IO45RSB0	F15	IO65PPB1
B8	IO27RSB0	D12	GNDQ	F16	IO66NDB1
B9	IO32RSB0	D13	IO50RSB0	G1	IO165NDB3
B10	IO38RSB0	D14	GBB2/IO61PPB1	G2	IO165PDB3
B11	IO42RSB0	D15	IO53RSB0	G3	IO168PPB3
B12	GBC1/IO55RSB0	D16	IO63NDB1	G4	GFC1/IO164PPB3
B13	GBB0/IO56RSB0	E1	IO166PDB3	G5	V _{CCI} B3
B14	IO52RSB0	E2	IO167NPB3	G6	V _{CC}
B15	GBA2/IO60PDB1	E3	IO172NDB3	G7	GND
B16	IO60NDB1	E4	IO169NDB3	G8	GND
C1	IO173NDB3	E5	VMV0	G9	GND
C2	IO174NDB3	E6	V _{CCI} B0	G10	GND
C3	VMV3	E7	V _{CCI} B0	G11	V _{CC}
C4	IO07RSB0	E8	IO25RSB0	G12	V _{CCI} B1

256-Pin FBGA		256-Pin FBGA		256-Pin FBGA	
Pin Number	A3P600L Function	Pin Number	A3P600L Function	Pin Number	A3P600L Function
G13	GCC1/IO69PPB1	K1	GFC2/IO159PDB3	M5	VMV3
G14	IO65NPB1	K2	IO161NPB3	M6	V _{CCI} B2
G15	IO75PDB1	K3	IO156PPB3	M7	V _{CCI} B2
G16	IO75NDB1	K4	IO129RSB2	M8	IO117RSB2
H1	GFB0/IO163NPB3	K5	V _{CCI} B3	M9	IO110RSB2
H2	GFA0/IO162NDB3	K6	V _{CC}	M10	V _{CCI} B2
H3	GFB1/IO163PPB3	K7	GND	M11	V _{CCI} B2
H4	V _{COMPLF}	K8	GND	M12	VMV2
H5	GFC0/IO164NPB3	K9	GND	M13	IO94RSB2
H6	V _{CC}	K10	GND	M14	GDB1/IO87PPB1
H7	GND	K11	V _{CC}	M15	GDC1/IO86PDB1
H8	GND	K12	V _{CCI} B1	M16	IO84NDB1
H9	GND	K13	IO73NPB1	N1	IO150NDB3
H10	GND	K14	IO80NPB1	N2	IO147PPB3
H11	V _{CC}	K15	IO74NPB1	N3	GEC1/IO146PPB3
H12	GCC0/IO69NPB1	K16	IO72NDB1	N4	IO140RSB2
H13	GCB1/IO70PPB1	L1	IO159NDB3	N5	GNDQ
H14	GCA0/IO71NPB1	L2	IO156NPB3	N6	GEA2/IO143RSB2
H15	IO67NPB1	L3	IO151PPB3	N7	IO126RSB2
H16	GCB0/IO70NPB1	L4	IO158PSB3	N8	IO120RSB2
J1	GFA2/IO161PPB3	L5	V _{CCI} B3	N9	IO108RSB2
J2	GFA1/IO162PDB3	L6	GND	N10	IO103RSB2
J3	V _{CCPLF}	L7	V _{CC}	N11	IO99RSB2
J4	IO160NDB3	L8	V _{CC}	N12	GNDQ
J5	GFB2/IO160PDB3	L9	V _{CC}	N13	IO92RSB2
J6	V _{CC}	L10	V _{CC}	N14	V _{JTAG}
J7	GND	L11	GND	N15	GDC0/IO86NDB1
J8	GND	L12	V _{CCI} B1	N16	GDA1/IO88PDB1
J9	GND	L13	GDB0/IO87NPB1	P1	GEB1/IO145PDB3
J10	GND	L14	IO85NDB1	P2	GEB0/IO145NDB3
J11	V _{CC}	L15	IO85PDB1	P3	VMV2
J12	GCB2/IO73PPB1	L16	IO84PDB1	P4	IO138RSB2
J13	GCA1/IO71PPB1	M1	IO150PDB3	P5	IO136RSB2
J14	GCC2/IO74PPB1	M2	IO151NPB3	P6	IO131RSB2
J15	IO80PPB1	M3	IO147NPB3	P7	IO124RSB2
J16	GCA2/IO72PDB1	M4	GEC0/IO146NPB3	P8	IO119RSB2

256-Pin FBGA	
Pin Number	A3P600L Function
P9	IO107RSB2
P10	IO104RSB2
P11	IO97RSB2
P12	VMV1
P13	TCK
P14	VPUMP
P15	TRST
P16	GDA0/IO88NDB1
R1	GEA1/IO144PDB3
R2	GEA0/IO144NDB3
R3	IO139RSB2
R4	GEC2/IO141RSB2
R5	IO132RSB2
R6	IO127RSB2
R7	IO121RSB2
R8	IO114RSB2
R9	IO109RSB2
R10	IO105RSB2
R11	IO98RSB2
R12	IO96RSB2
R13	GDB2/IO90RSB2
R14	TDI
R15	GNDQ
R16	TDO
T1	GND
T2	IO137RSB2
T3	FF/GEB2/IO142RSB2
T4	IO134RSB2
T5	IO125RSB2
T6	IO123RSB2
T7	IO118RSB2
T8	IO115RSB2
T9	IO111RSB2
T10	IO106RSB2
T11	IO102RSB2
T12	GDC2/IO91RSB2

256-Pin FBGA	
Pin Number	A3P600L Function
T13	IO93RSB2
T14	GDA2/IO89RSB2
T15	TMS
T16	GND

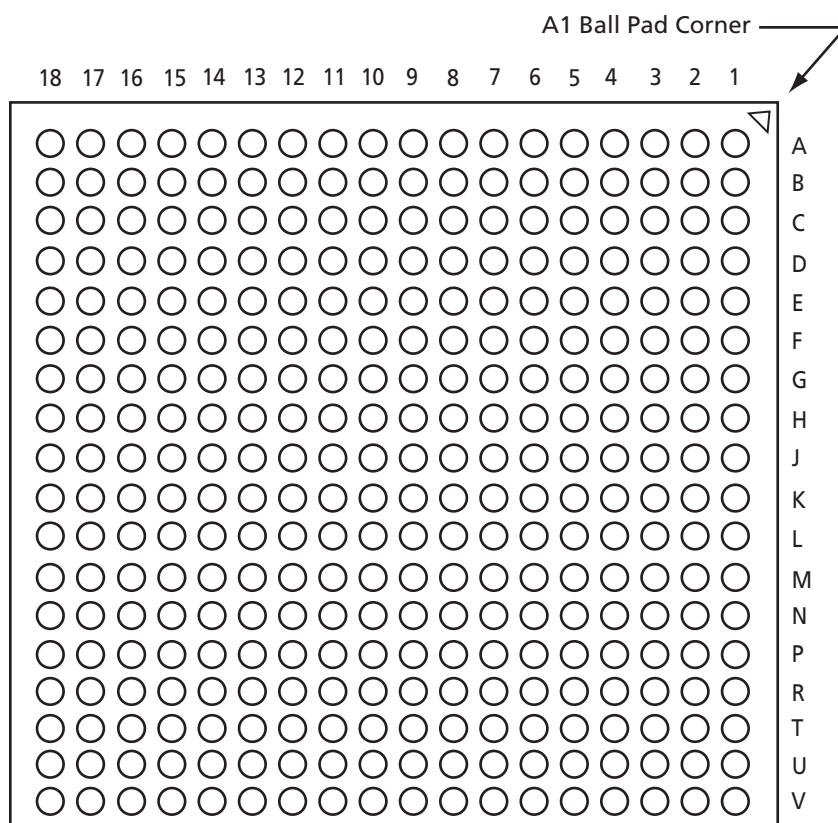
256-Pin FBGA		256-Pin FBGA		256-Pin FBGA	
Pin Number	A3P1000L Function	Pin Number	A3P1000L Function	Pin Number	A3P1000L Function
A1	GND	C5	GAC0/IO04RSB0	E9	IO47RSB0
A2	GAA0/IO00RSB0	C6	GAC1/IO05RSB0	E10	V _{CCI} B0
A3	GAA1/IO01RSB0	C7	IO25RSB0	E11	V _{CCI} B0
A4	GAB0/IO02RSB0	C8	IO36RSB0	E12	VMV1
A5	IO16RSB0	C9	IO42RSB0	E13	GBC2/IO80PDB1
A6	IO22RSB0	C10	IO49RSB0	E14	IO83PPB1
A7	IO28RSB0	C11	IO56RSB0	E15	IO86PPB1
A8	IO35RSB0	C12	GBC0/IO72RSB0	E16	IO87PDB1
A9	IO45RSB0	C13	IO62RSB0	F1	IO217NDB3
A10	IO50RSB0	C14	VMV0	F2	IO218NDB3
A11	IO55RSB0	C15	IO78NDB1	F3	IO216PDB3
A12	IO61RSB0	C16	IO81NDB1	F4	IO216NDB3
A13	GBB1/IO75RSB0	D1	IO222NDB3	F5	V _{CCI} B3
A14	GBA0/IO76RSB0	D2	IO222PDB3	F6	GND
A15	GBA1/IO77RSB0	D3	GAC2/IO223PDB3	F7	V _{CC}
A16	GND	D4	IO223NDB3	F8	V _{CC}
B1	GAB2/IO224PDB3	D5	GNDQ	F9	V _{CC}
B2	GAA2/IO225PDB3	D6	IO23RSB0	F10	V _{CC}
B3	GNDQ	D7	IO29RSB0	F11	GND
B4	GAB1/IO03RSB0	D8	IO33RSB0	F12	V _{CCI} B1
B5	IO17RSB0	D9	IO46RSB0	F13	IO83NPB1
B6	IO21RSB0	D10	IO52RSB0	F14	IO86NPB1
B7	IO27RSB0	D11	IO60RSB0	F15	IO90PPB1
B8	IO34RSB0	D12	GNDQ	F16	IO87NDB1
B9	IO44RSB0	D13	IO80NDB1	G1	IO210PSB3
B10	IO51RSB0	D14	GBB2/IO79PDB1	G2	IO213NDB3
B11	IO57RSB0	D15	IO79NDB1	G3	IO213PDB3
B12	GBC1/IO73RSB0	D16	IO82NSB1	G4	GFC1/IO209PPB3
B13	GBB0/IO74RSB0	E1	IO217PDB3	G5	V _{CCI} B3
B14	IO71RSB0	E2	IO218PDB3	G6	V _{CC}
B15	GBA2/IO78PDB1	E3	IO221NDB3	G7	GND
B16	IO81PDB1	E4	IO221PDB3	G8	GND
C1	IO224NDB3	E5	VMV0	G9	GND
C2	IO225NDB3	E6	V _{CCI} B0	G10	GND
C3	VMV3	E7	V _{CCI} B0	G11	V _{CC}
C4	IO11RSB0	E8	IO38RSB0	G12	V _{CCI} B1

256-Pin FBGA		256-Pin FBGA		256-Pin FBGA	
Pin Number	A3P1000L Function	Pin Number	A3P1000L Function	Pin Number	A3P1000L Function
G13	GCC1/IO91PPB1	K1	GFC2/IO204PDB3	M5	VMV3
G14	IO90NPB1	K2	IO204NDB3	M6	V _{CCI} B2
G15	IO88PDB1	K3	IO203NDB3	M7	V _{CCI} B2
G16	IO88NDB1	K4	IO203PDB3	M8	IO147RSB2
H1	GFB0/IO208NPB3	K5	V _{CCI} B3	M9	IO136RSB2
H2	GFA0/IO207NDB3	K6	V _{CC}	M10	V _{CCI} B2
H3	GFB1/IO208PPB3	K7	GND	M11	V _{CCI} B2
H4	V _{COMPLF}	K8	GND	M12	VMV2
H5	GFC0/IO209NPB3	K9	GND	M13	IO110NDB1
H6	V _{CC}	K10	GND	M14	GDB1/IO112PPB1
H7	GND	K11	V _{CC}	M15	GDC1/IO111PDB1
H8	GND	K12	V _{CCI} B1	M16	IO107NDB1
H9	GND	K13	IO95NPB1	N1	IO194PSB3
H10	GND	K14	IO100NPB1	N2	IO192PPB3
H11	V _{CC}	K15	IO102NDB1	N3	GEC1/IO190PPB3
H12	GCC0/IO91NPB1	K16	IO102PDB1	N4	IO192NPB3
H13	GCB1/IO92PPB1	L1	IO202NDB3	N5	GNDQ
H14	GCA0/IO93NPB1	L2	IO202PDB3	N6	GEA2/IO187RSB2
H15	IO96NPB1	L3	IO196PPB3	N7	IO161RSB2
H16	GCB0/IO92NPB1	L4	IO193PPB3	N8	IO155RSB2
J1	GFA2/IO206PSB3	L5	V _{CCI} B3	N9	IO141RSB2
J2	GFA1/IO207PDB3	L6	GND	N10	IO129RSB2
J3	V _{CCPLF}	L7	V _{CC}	N11	IO124RSB2
J4	IO205NDB3	L8	V _{CC}	N12	GNDQ
J5	GFB2/IO205PDB3	L9	V _{CC}	N13	IO110PDB1
J6	V _{CC}	L10	V _{CC}	N14	V _{JTAG}
J7	GND	L11	GND	N15	GDC0/IO111NDB1
J8	GND	L12	V _{CCI} B1	N16	GDA1/IO113PDB1
J9	GND	L13	GDB0/IO112NPB1	P1	GEB1/IO189PDB3
J10	GND	L14	IO106NDB1	P2	GEB0/IO189NDB3
J11	V _{CC}	L15	IO106PDB1	P3	VMV2
J12	GCB2/IO95PPB1	L16	IO107PDB1	P4	IO179RSB2
J13	GCA1/IO93PPB1	M1	IO197NSB3	P5	IO171RSB2
J14	GCC2/IO96PPB1	M2	IO196NPB3	P6	IO165RSB2
J15	IO100PPB1	M3	IO193NPB3	P7	IO159RSB2
J16	GCA2/IO94PSB1	M4	GEC0/IO190NPB3	P8	IO151RSB2

256-Pin FBGA	
Pin Number	A3P1000L Function
P9	IO137RSB2
P10	IO134RSB2
P11	IO128RSB2
P12	VMV1
P13	TCK
P14	V _{PUMP}
P15	TRST
P16	GDA0/IO113NDB1
R1	GEA1/IO188PDB3
R2	GEA0/IO188NDB3
R3	IO184RSB2
R4	GEC2/IO185RSB2
R5	IO168RSB2
R6	IO163RSB2
R7	IO157RSB2
R8	IO149RSB2
R9	IO143RSB2
R10	IO138RSB2
R11	IO131RSB2
R12	IO125RSB2
R13	GDB2/IO115RSB2
R14	TDI
R15	GNDQ
R16	TDO
T1	GND
T2	IO183RSB2
T3	FF/GEB2/IO186RSB2
T4	IO172RSB2
T5	IO170RSB2
T6	IO164RSB2
T7	IO158RSB2
T8	IO153RSB2
T9	IO142RSB2
T10	IO135RSB2
T11	IO130RSB2
T12	GDC2/IO116RSB2

256-Pin FBGA	
Pin Number	A3P1000L Function
T13	IO120RSB2
T14	GDA2/IO114RSB2
T15	TMS
T16	GND

324-Pin FBGA



Note: This is the bottom view of the package.

Figure 3-5 •

Note

For Package Manufacturing and Environmental information, visit the Resource Center at <http://www.actel.com/products/solutions/package/docs.aspx>.

324-Pin FBGA		324-Pin FBGA		324-Pin FBGA	
Pin Number	A3PE3000L Function	Pin Number	A3PE3000L Function	Pin Number	A3PE3000L Function
A1	GND	C1	IO305NDB7V3	E1	IO303NDB7V3
A2	IO08NDB0V0	C2	IO308NDB7V4	E2	GNDQ
A3	IO08PDB0V0	C3	GAA2/IO309PPB7V4	E2	GNDQ
A4	IO10NDB0V1	C4	GAA1/IO00PPB0V0	E3	VMV7
A5	IO10PDB0V1	C5	VMV0	E3	VMV7
A6	IO12PDB0V1	C6	IO14NDB0V1	E4	IO307NPB7V4
A7	GND	C7	IO18PDB0V2	E5	V _{CCPLA}
A8	IO32NDB0V3	C8	IO40NDB0V4	E6	GAB0/IO01NPB0V0
A9	IO32PDB0V3	C9	IO40PDB0V4	E7	V _{CCIB0}
A10	IO42PPB1V0	C10	IO44PDB1V0	E8	GND
A11	IO52NPB1V1	C11	IO56NDB1V1	E9	IO28NDB0V3
A12	GND	C12	IO64NDB1V2	E10	IO48PDB1V0
A13	IO66NDB1V3	C13	IO64PDB1V2	E11	GND
A14	IO72NDB1V3	C14	VMV1	E12	V _{CCIB1}
A15	IO72PDB1V3	C15	GBC0/IO79NDB1V4	E13	IO60NPB1V2
A16	IO74NDB1V4	C16	GBC1/IO79PDB1V4	E14	V _{CCPLB}
A17	IO74PDB1V4	C17	GBB2/IO83PPB2V0	E15	IO82NDB2V0
A18	GND	C18	IO88NDB2V0	E16	VMV2
B1	IO305PDB7V3	D1	IO303PDB7V3	E16	VMV2
B2	GAB2/IO308PDB7V4	D2	V _{CCIB7}	E17	GNDQ
B3	GAA0/IO00NPB0V0	D3	GAC2/IO307PPB7V4	E17	GNDQ
B4	V _{CCIB0}	D4	IO309NPB7V4	E18	IO90NDB2V1
B5	GNDQ	D5	GAB1/IO01PPB0V0	F1	IO299NDB7V3
B6	IO12NDB0V1	D6	IO14PDB0V1	F2	IO299PDB7V3
B7	IO18NDB0V2	D7	IO24NDB0V2	F3	IO295PDB7V2
B8	V _{CCIB0}	D8	IO24PDB0V2	F4	IO295NDB7V2
B9	IO42NPB1V0	D9	IO28PDB0V3	F5	V _{COMPLA}
B10	IO44NDB1V0	D10	IO48NDB1V0	F6	IO291PPB7V2
B11	V _{CCIB1}	D11	IO56PDB1V1	F7	GAC0/IO02NDB0V0
B12	IO52PPB1V1	D12	IO60PPB1V2	F8	GAC1/IO02PDB0V0
B13	IO66PDB1V3	D13	GBB0/IO80NDB1V4	F9	IO26PDB0V3
B14	GNDQ	D14	GBB1/IO80PDB1V4	F10	IO34PDB0V4
B15	V _{CCIB1}	D15	GBA2/IO82PDB2V0	F11	IO58NDB1V2
B16	GBA0/IO81NDB1V4	D16	IO83NPB2V0	F12	IO58PDB1V2
B17	GBA1/IO81PDB1V4	D17	V _{CCIB2}	F13	IO94PPB2V1
B18	IO88PDB2V0	D18	IO90PDB2V1	F14	V _{COMPLB}

324-Pin FBGA		324-Pin FBGA		324-Pin FBGA	
Pin Number	A3PE3000L Function	Pin Number	A3PE3000L Function	Pin Number	A3PE3000L Function
F15	GBC2/IO84PDB2V0	H15	GCB1/IO113PDB2V3	K15	GCC2/IO117PDB3V0
F16	IO84NDB2V0	H16	GCC1/IO112PPB2V3	K16	V _{CC} PLC
F17	IO92NDB2V1	H17	V _{CC} B2	K17	IO124NPB3V1
F18	IO92PDB2V1	H18	IO108PDB2V3	K18	IO120PPB3V0
G1	GND	J1	IO267NDB6V4	L1	IO263NDB6V3
G2	IO287PDB7V1	J2	GFA0/IO273NDB6V4	L2	V _{CC} B6
G3	IO287NDB7V1	J3	V _{COM} PLF	L3	IO259PDB6V3
G4	IO283PPB7V1	J4	GFA2/IO272PDB6V4	L4	IO259NDB6V3
G5	V _{CC} B7	J5	GFB0/IO274NPB7V0	L5	GND
G6	IO279PDB7V0	J6	GFC0/IO275NDB7V0	L6	IO270NPB6V4
G7	IO291NPB7V2	J7	GFC1/IO275PDB7V0	L7	V _{CC}
G8	V _{CC}	J8	GND	L8	V _{CC}
G9	IO26NDB0V3	J9	GND	L9	GND
G10	IO34NDB0V4	J10	GND	L10	GND
G11	V _{CC}	J11	GND	L11	V _{CC}
G12	IO94NPB2V1	J12	GCA2/IO115PDB3V0	L12	V _{CC}
G13	IO98PDB2V2	J13	GCA1/IO114PDB3V0	L13	IO132PDB3V2
G14	V _{CC} B2	J14	GCA0/IO114NDB3V0	L14	GND
G15	GCC0/IO112NPB2V3	J15	GCB0/IO113NDB2V3	L15	IO117NDB3V0
G16	IO104PDB2V2	J16	V _{COM} PLC	L16	IO128NPB3V1
G17	IO104NDB2V2	J17	IO120NPB3V0	L17	V _{CC} B3
G18	GND	J18	IO108NDB2V3	L18	IO124PPB3V1
H1	IO267PDB6V4	K1	IO263PDB6V3	M1	GND
H2	V _{CC} B7	K2	GFA1/IO273PDB6V4	M2	IO255PDB6V2
H3	IO283NPB7V1	K3	V _{CC} PLF	M3	IO255NDB6V2
H4	GFB1/IO274PPB7V0	K4	IO272NDB6V4	M4	IO251PPB6V2
H5	GND	K5	GFC2/IO270PPB6V4	M5	V _{CC} B6
H6	IO279NDB7V0	K6	GFB2/IO271PDB6V4	M6	GEB0/IO235NDB6V0
H7	V _{CC}	K7	IO271NDB6V4	M7	GEB1/IO235PDB6V0
H8	V _{CC}	K8	GND	M8	V _{CC}
H9	GND	K9	GND	M9	IO192PPB4V4
H10	GND	K10	GND	M10	IO154NPB4V0
H11	V _{CC}	K11	GND	M11	V _{CC}
H12	V _{CC}	K12	IO115NDB3V0	M12	GDA0/IO153NPB3V4
H13	IO98NDB2V2	K13	GCB2/IO116PDB3V0	M13	IO132NDB3V2
H14	GND	K14	IO116NDB3V0	M14	V _{CC} B3

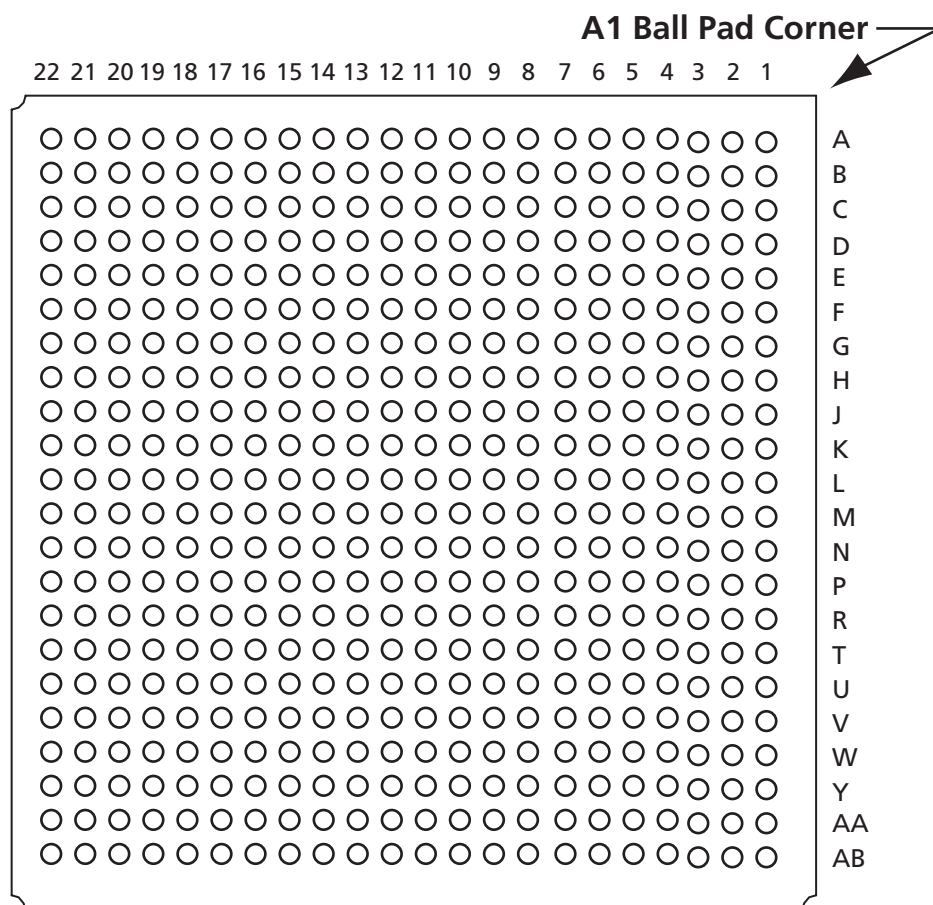
324-Pin FBGA	
Pin Number	A3PE3000L Function
M15	IO134NDB3V2
M16	IO134PDB3V2
M17	IO128PPB3V1
M18	GND
N1	IO247NDB6V1
N2	IO247PDB6V1
N3	IO251NPB6V2
N4	GEC0/IO236NDB6V0
N5	V _{COMPLE}
N6	IO212NDB5V2
N7	IO212PDB5V2
N8	IO192NPB4V4
N9	IO174PDB4V2
N10	IO170PDB4V2
N11	GDA2/IO154PPB4V0
N12	GDB2/IO155PPB4V0
N13	GDA1/IO153PPB3V4
N14	V _{COMPLD}
N15	GDB0/IO152NDB3V4
N16	GDB1/IO152PDB3V4
N17	IO138NDB3V3
N18	IO138PDB3V3
P1	IO245PDB6V1
P2	GNDQ
P2	GNDQ
P3	VMV6
P3	VMV6
P4	GEC1/IO236PDB6V0
P5	V _{CCPLE}
P6	IO214PDB5V2
P7	V _{CCIB5}
P8	GND
P9	IO174NDB4V2
P10	IO170NDB4V2
P11	GND
P12	V _{CCIB4}

324-Pin FBGA	
Pin Number	A3PE3000L Function
P13	IO155NPB4V0
P14	V _{CCPLD}
P15	V _{JTAG}
P16	GDC0/IO151NDB3V4
P17	GDC1/IO151PDB3V4
P18	IO142PDB3V3
R1	IO245NDB6V1
R2	V _{CCIB6}
R3	GEA1/IO234PPB6V0
R4	IO232NDB5V4
R5	FF/GEA2/IO232PDB5V4
R6	IO214NDB5V2
R7	IO202PDB5V1
R8	IO194PDB5V0
R9	IO186PDB4V4
R10	IO178PDB4V3
R11	IO168NSB4V1
R12	IO164PDB4V1
R13	GDC2/IO156PDB4V0
R14	TCK
R15	V _{PUMP}
R16	TRST
R17	V _{CCIB3}
R18	IO142NDB3V3
T1	IO241PDB6V0
T2	GEA0/IO234NPB6V0
T3	IO233NPB5V4
T4	IO231NPB5V4
T5	VMV5
T6	IO208NDB5V1
T7	IO202NDB5V1
T8	IO194NDB5V0
T9	IO186NDB4V4
T10	IO178NDB4V3
T11	IO166NPB4V1

324-Pin FBGA	
Pin Number	A3PE3000L Function
T12	IO164NDB4V1
T13	IO156NDB4V0
T14	VMV4
T15	TDI
T16	GNDQ
T16	GNDQ
T17	TDO
T18	IO146PDB3V4
U1	IO241NDB6V0
U2	GEA2/IO233PPB5V4
U3	GEC2/IO231PPB5V4
U4	V _{CCIB5}
U5	GNDQ
U6	IO208PDB5V1
U7	IO198PPB5V0
U8	V _{CCIB5}
U9	IO182NPB4V3
U10	IO180NPB4V3
U11	V _{CCIB4}
U12	IO166PPB4V1
U13	IO162PDB4V1
U14	GNDQ
U15	V _{CCIB4}
U16	TMS
U17	VMV3
U17	VMV3
U18	IO146NDB3V4
V1	GND
V2	IO218NDB5V3
V3	IO218PDB5V3
V4	IO206NDB5V1
V5	IO206PDB5V1
V6	IO198NPB5V0
V7	GND
V8	IO190NDB4V4
V9	IO190PDB4V4

324-Pin FBGA	
Pin Number	A3PE3000L Function
V10	IO182PPB4V3
V11	IO180PPB4V3
V12	GND
V13	IO162NDB4V1
V14	IO160NDB4V0
V15	IO160PDB4V0
V16	IO158NDB4V0
V17	IO158PDB4V0
V18	GND

484-Pin FBGA



Note: This is the bottom view of the package.

Figure 3-6 •

Note

For Package Manufacturing and Environmental information, visit the Resource Center at <http://www.actel.com/products/solutions/package/docs.aspx>.

484-Pin FBGA		484-Pin FBGA		484-Pin FBGA	
Pin Number	A3P600L Function	Pin Number	A3P600L Function	Pin Number	A3P600L Function
A1	GND	AA15	NC	B7	IO12RSB0
A2	GND	AA16	IO101RSB2	B8	NC
A3	V _{CCI} B0	AA17	NC	B9	NC
A4	NC	AA18	NC	B10	IO17RSB0
A5	NC	AA19	NC	B11	NC
A6	IO09RSB0	AA20	NC	B12	NC
A7	IO15RSB0	AA21	V _{CCI} B1	B13	IO36RSB0
A8	NC	AA22	GND	B14	NC
A9	NC	AB1	GND	B15	NC
A10	IO22RSB0	AB2	GND	B16	IO47RSB0
A11	IO23RSB0	AB3	V _{CCI} B2	B17	IO49RSB0
A12	IO29RSB0	AB4	NC	B18	NC
A13	IO35RSB0	AB5	NC	B19	NC
A14	NC	AB6	IO130RSB2	B20	NC
A15	NC	AB7	IO128RSB2	B21	V _{CCI} B1
A16	IO46RSB0	AB8	IO122RSB2	B22	GND
A17	IO48RSB0	AB9	IO116RSB2	C1	V _{CCI} B3
A18	NC	AB10	NC	C2	NC
A19	NC	AB11	NC	C3	NC
A20	V _{CCI} B0	AB12	IO113RSB2	C4	NC
A21	GND	AB13	IO112RSB2	C5	GND
A22	GND	AB14	NC	C6	NC
AA1	GND	AB15	NC	C7	NC
AA2	V _{CCI} B3	AB16	IO100RSB2	C8	V _{CC}
AA3	NC	AB17	IO95RSB2	C9	V _{CC}
AA4	NC	AB18	NC	C10	NC
AA5	NC	AB19	NC	C11	NC
AA6	IO135RSB2	AB20	V _{CCI} B2	C12	NC
AA7	IO133RSB2	AB21	GND	C13	NC
AA8	NC	AB22	GND	C14	V _{CC}
AA9	NC	B1	GND	C15	V _{CC}
AA10	NC	B2	V _{CCI} B3	C16	NC
AA11	NC	B3	NC	C17	NC
AA12	NC	B4	NC	C18	GND
AA13	NC	B5	NC	C19	NC
AA14	NC	B6	IO08RSB0	C20	NC

484-Pin FBGA		484-Pin FBGA		484-Pin FBGA	
Pin Number	A3P600L Function	Pin Number	A3P600L Function	Pin Number	A3P600L Function
C21	NC	E13	IO38RSB0	G5	IO171PDB3
C22	V _{CCI} B1	E14	IO42RSB0	G6	GAC2/IO172PDB3
D1	NC	E15	GBC1/IO55RSB0	G7	IO06RSB0
D2	NC	E16	GBB0/IO56RSB0	G8	GNDQ
D3	NC	E17	IO52RSB0	G9	IO10RSB0
D4	GND	E18	GBA2/IO60PDB1	G10	IO19RSB0
D5	GAA0/IO00RSB0	E19	IO60NDB1	G11	IO26RSB0
D6	GAA1/IO01RSB0	E20	GND	G12	IO30RSB0
D7	GAB0/IO02RSB0	E21	NC	G13	IO40RSB0
D8	IO11RSB0	E22	NC	G14	IO45RSB0
D9	IO16RSB0	F1	NC	G15	GNDQ
D10	IO18RSB0	F2	NC	G16	IO50RSB0
D11	IO28RSB0	F3	NC	G17	GBB2/IO61PPB1
D12	IO34RSB0	F4	IO173NDB3	G18	IO53RSB0
D13	IO37RSB0	F5	IO174NDB3	G19	IO63NDB1
D14	IO41RSB0	F6	VMV3	G20	NC
D15	IO43RSB0	F7	IO07RSB0	G21	NC
D16	GBB1/IO57RSB0	F8	GAC0/IO04RSB0	G22	NC
D17	GBA0/IO58RSB0	F9	GAC1/IO05RSB0	H1	NC
D18	GBA1/IO59RSB0	F10	IO20RSB0	H2	NC
D19	GND	F11	IO24RSB0	H3	V _{CC}
D20	NC	F12	IO33RSB0	H4	IO166PDB3
D21	NC	F13	IO39RSB0	H5	IO167NPB3
D22	NC	F14	IO44RSB0	H6	IO172NDB3
E1	NC	F15	GBC0/IO54RSB0	H7	IO169NDB3
E2	NC	F16	IO51RSB0	H8	VMV0
E3	GND	F17	VMV0	H9	V _{CCI} B0
E4	GAB2/IO173PDB3	F18	IO61NPB1	H10	V _{CCI} B0
E5	GAA2/IO174PDB3	F19	IO63PDB1	H11	IO25RSB0
E6	GNDQ	F20	NC	H12	IO31RSB0
E7	GAB1/IO03RSB0	F21	NC	H13	V _{CCI} B0
E8	IO13RSB0	F22	NC	H14	V _{CCI} B0
E9	IO14RSB0	G1	IO170NDB3	H15	VMV1
E10	IO21RSB0	G2	IO170PDB3	H16	GBC2/IO62PDB1
E11	IO27RSB0	G3	NC	H17	IO67PPB1
E12	IO32RSB0	G4	IO171NDB3	H18	IO64PPB1

484-Pin FBGA		484-Pin FBGA		484-Pin FBGA	
Pin Number	A3P600L Function	Pin Number	A3P600L Function	Pin Number	A3P600L Function
H19	IO66PDB1	K11	GND	M3	IO158NPB3
H20	V _{CC}	K12	GND	M4	GFA2/IO161PPB3
H21	NC	K13	GND	M5	GFA1/IO162PDB3
H22	NC	K14	V _{CC}	M6	V _{CCPLF}
J1	NC	K15	VvB1	M7	IO160NDB3
J2	NC	K16	GCC1/IO69PPB1	M8	GFB2/IO160PDB3
J3	NC	K17	IO65NPB1	M9	V _{CC}
J4	IO166NDB3	K18	IO75PDB1	M10	GND
J5	IO168NPB3	K19	IO75NDB1	M11	GND
J6	IO167PPB3	K20	NC	M12	GND
J7	IO169PDB3	K21	IO76NDB1	M13	GND
J8	V _{CCIB3}	K22	IO76PDB1	M14	V _{CC}
J9	GND	L1	NC	M15	GCB2/IO73PPB1
J10	V _{CC}	L2	IO155PDB3	M16	GCA1/IO71PPB1
J11	V _{CC}	L3	NC	M17	GCC2/IO74PPB1
J12	V _{CC}	L4	GFB0/IO163NPB3	M18	IO80PPB1
J13	V _{CC}	L5	GFA0/IO162NDB3	M19	GCA2/IO72PDB1
J14	GND	L6	GFB1/IO163PPB3	M20	IO79PPB1
J15	V _{CCIB1}	L7	V _{COMPLF}	M21	IO78PPB1
J16	IO62NDB1	L8	GFC0/IO164NPB3	M22	NC
J17	IO64NPB1	L9	V _{CC}	N1	IO154NDB3
J18	IO65PPB1	L10	GND	N2	IO154PDB3
J19	IO66NDB1	L11	GND	N3	NC
J20	NC	L12	GND	N4	GFC2/IO159PDB3
J21	IO68PDB1	L13	GND	N5	IO161NPB3
J22	IO68NDB1	L14	V _{CC}	N6	IO156PPB3
K1	IO157PDB3	L15	GCC0/IO69NPB1	N7	IO129RSB2
K2	IO157NDB3	L16	GCB1/IO70PPB1	N8	V _{CCIB3}
K3	NC	L17	GCA0/IO71NPB1	N9	V _{CC}
K4	IO165NDB3	L18	IO67NPB1	N10	GND
K5	IO165PDB3	L19	GCB0/IO70NPB1	N11	GND
K6	IO168PPB3	L20	IO77PDB1	N12	GND
K7	GFC1/IO164PPB3	L21	IO77NDB1	N13	GND
K8	V _{CCIB3}	L22	IO78NPB1	N14	V _{CC}
K9	V _{CC}	M1	NC	N15	V _{CCIB1}
K10	GND	M2	IO155NDB3	N16	IO73NPB1

484-Pin FBGA	
Pin Number	A3P600L Function
N17	IO80NPB1
N18	IO74NPB1
N19	IO72NDB1
N20	NC
N21	IO79NPB1
N22	NC
P1	NC
P2	IO153PDB3
P3	IO153NDB3
P4	IO159NDB3
P5	IO156NPB3
P6	IO151PPB3
P7	IO158PPB3
P8	V _{CC} B3
P9	GND
P10	V _{CC}
P11	V _{CC}
P12	V _{CC}
P13	V _{CC}
P14	GND
P15	V _{CC} B1
P16	GDB0/IO87NPB1
P17	IO85NDB1
P18	IO85PDB1
P19	IO84PDB1
P20	NC
P21	IO81PDB1
P22	NC
R1	NC
R2	NC
R3	V _{CC}
R4	IO150PDB3
R5	IO151NPB3
R6	IO147NPB3
R7	GEC0/IO146NPB3
R8	VMV3

484-Pin FBGA	
Pin Number	A3P600L Function
R9	V _{CC} B2
R10	V _{CC} B2
R11	IO117RSB2
R12	IO110RSB2
R13	V _{CC} B2
R14	V _{CC} B2
R15	VMV2
R16	IO94RSB2
R17	GDB1/IO87PPB1
R18	GDC1/IO86PDB1
R19	IO84NDB1
R20	V _{CC}
R21	IO81NDB1
R22	IO82PDB1
T1	IO152PDB3
T2	IO152NDB3
T3	NC
T4	IO150NDB3
T5	IO147PPB3
T6	GEC1/IO146PPB3
T7	IO140RSB2
T8	GNDQ
T9	GEA2/IO143RSB2
T10	IO126RSB2
T11	IO120RSB2
T12	IO108RSB2
T13	IO103RSB2
T14	IO99RSB2
T15	GNDQ
T16	IO92RSB2
T17	V _{JTAG}
T18	GDC0/IO86NDB1
T19	GDA1/IO88PDB1
T20	NC
T21	IO83PDB1
T22	IO82NDB1

484-Pin FBGA	
Pin Number	A3P600L Function
U1	IO149PDB3
U2	IO149NDB3
U3	NC
U4	GEB1/IO145PDB3
U5	GEB0/IO145NDB3
U6	VMV2
U7	IO138RSB2
U8	IO136RSB2
U9	IO131RSB2
U10	IO124RSB2
U11	IO119RSB2
U12	IO107RSB2
U13	IO104RSB2
U14	IO97RSB2
U15	VMV1
U16	TCK
U17	V _{PUMP}
U18	TRST
U19	GDA0/IO88NDB1
U20	NC
U21	IO83NDB1
U22	NC
V1	NC
V2	NC
V3	GND
V4	GEA1/IO144PDB3
V5	GEA0/IO144NDB3
V6	IO139RSB2
V7	GEC2/IO141RSB2
V8	IO132RSB2
V9	IO127RSB2
V10	IO121RSB2
V11	IO114RSB2
V12	IO109RSB2
V13	IO105RSB2
V14	IO98RSB2

484-Pin FBGA		484-Pin FBGA	
Pin Number	A3P600L Function	Pin Number	A3P600L Function
V15	IO96RSB2	Y7	NC
V16	GDB2/IO90RSB2	Y8	V _{CC}
V17	TDI	Y9	V _{CC}
V18	GNDQ	Y10	NC
V19	TDO	Y11	NC
V20	GND	Y12	NC
V21	NC	Y13	NC
V22	NC	Y14	V _{CC}
W1	NC	Y15	V _{CC}
W2	IO148PDB3	Y16	NC
W3	NC	Y17	NC
W4	GND	Y18	GND
W5	IO137RSB2	Y19	NC
W6	FF/GEB2/IO142RSB2	Y20	NC
W7	IO134RSB2	Y21	NC
W8	IO125RSB2	Y22	V _{CC} B1
W9	IO123RSB2		
W10	IO118RSB2		
W11	IO115RSB2		
W12	IO111RSB2		
W13	IO106RSB2		
W14	IO102RSB2		
W15	GDC2/IO91RSB2		
W16	IO93RSB2		
W17	GDA2/IO89RSB2		
W18	TMS		
W19	GND		
W20	NC		
W21	NC		
W22	NC		
Y1	V _{CC} B3		
Y2	IO148NDB3		
Y3	NC		
Y4	NC		
Y5	GND		
Y6	NC		

484-Pin FBGA		484-Pin FBGA		484-Pin FBGA	
Pin Number	A3P1000L Function	Pin Number	A3P1000L Function	Pin Number	A3P1000L Function
A1	GND	AA15	NC	B7	IO15RSB0
A2	GND	AA16	IO122RSB2	B8	IO19RSB0
A3	V _{CC} I B0	AA17	IO119RSB2	B9	IO24RSB0
A4	IO07RSB0	AA18	IO117RSB2	B10	IO31RSB0
A5	IO09RSB0	AA19	NC	B11	IO39RSB0
A6	IO13RSB0	AA20	NC	B12	IO48RSB0
A7	IO18RSB0	AA21	V _{CC} I B1	B13	IO54RSB0
A8	IO20RSB0	AA22	GND	B14	IO58RSB0
A9	IO26RSB0	AB1	GND	B15	IO63RSB0
A10	IO32RSB0	AB2	GND	B16	IO66RSB0
A11	IO40RSB0	AB3	V _{CC} I B2	B17	IO68RSB0
A12	IO41RSB0	AB4	IO180RSB2	B18	IO70RSB0
A13	IO53RSB0	AB5	IO176RSB2	B19	NC
A14	IO59RSB0	AB6	IO173RSB2	B20	NC
A15	IO64RSB0	AB7	IO167RSB2	B21	V _{CC} I B1
A16	IO65RSB0	AB8	IO162RSB2	B22	GND
A17	IO67RSB0	AB9	IO156RSB2	C1	V _{CC} I B3
A18	IO69RSB0	AB10	IO150RSB2	C2	IO220PDB3
A19	NC	AB11	IO145RSB2	C3	NC
A20	V _{CC} I B0	AB12	IO144RSB2	C4	NC
A21	GND	AB13	IO132RSB2	C5	GND
A22	GND	AB14	IO127RSB2	C6	IO10RSB0
AA1	GND	AB15	IO126RSB2	C7	IO14RSB0
AA2	V _{CC} I B3	AB16	IO123RSB2	C8	V _{CC}
AA3	NC	AB17	IO121RSB2	C9	V _{CC}
AA4	IO181RSB2	AB18	IO118RSB2	C10	IO30RSB0
AA5	IO178RSB2	AB19	NC	C11	IO37RSB0
AA6	IO175RSB2	AB20	V _{CC} I B2	C12	IO43RSB0
AA7	IO169RSB2	AB21	GND	C13	NC
AA8	IO166RSB2	AB22	GND	C14	V _{CC}
AA9	IO160RSB2	B1	GND	C15	V _{CC}
AA10	IO152RSB2	B2	V _{CC} I B3	C16	NC
AA11	IO146RSB2	B3	NC	C17	NC
AA12	IO139RSB2	B4	IO06RSB0	C18	GND
AA13	IO133RSB2	B5	IO08RSB0	C19	NC
AA14	NC	B6	IO12RSB0	C20	NC

484-Pin FBGA		484-Pin FBGA		484-Pin FBGA	
Pin Number	A3P1000L Function	Pin Number	A3P1000L Function	Pin Number	A3P1000L Function
C21	NC	E13	IO51RSB0	G5	IO222PDB3
C22	V _{CC} I B1	E14	IO57RSB0	G6	GAC2/IO223PDB3
D1	IO219PDB3	E15	GBC1/IO73RSB0	G7	IO223NDB3
D2	IO220NDB3	E16	GGB0/IO74RSB0	G8	GNDQ
D3	NC	E17	IO71RSB0	G9	IO23RSB0
D4	GND	E18	GBA2/IO78PDB1	G10	IO29RSB0
D5	GAA0/IO00RSB0	E19	IO81PDB1	G11	IO33RSB0
D6	GAA1/IO01RSB0	E20	GND	G12	IO46RSB0
D7	GAB0/IO02RSB0	E21	NC	G13	IO52RSB0
D8	IO16RSB0	E22	IO84PDB1	G14	IO60RSB0
D9	IO22RSB0	F1	NC	G15	GNDQ
D10	IO28RSB0	F2	IO215PDB3	G16	IO80NDB1
D11	IO35RSB0	F3	IO215NDB3	G17	GGB2/IO79PDB1
D12	IO45RSB0	F4	IO224NDB3	G18	IO79NDB1
D13	IO50RSB0	F5	IO225NDB3	G19	IO82NPB1
D14	IO55RSB0	F6	VMV3	G20	IO85PDB1
D15	IO61RSB0	F7	IO11RSB0	G21	IO85NDB1
D16	GGB1/IO75RSB0	F8	GAC0/IO04RSB0	G22	NC
D17	GBA0/IO76RSB0	F9	GAC1/IO05RSB0	H1	NC
D18	GBA1/IO77RSB0	F10	IO25RSB0	H2	NC
D19	GND	F11	IO36RSB0	H3	V _{CC}
D20	NC	F12	IO42RSB0	H4	IO217PDB3
D21	NC	F13	IO49RSB0	H5	IO218PDB3
D22	NC	F14	IO56RSB0	H6	IO221NDB3
E1	IO219NDB3	F15	GBC0/IO72RSB0	H7	IO221PDB3
E2	NC	F16	IO62RSB0	H8	VMV0
E3	GND	F17	VMV0	H9	V _{CC} I B0
E4	GAB2/IO224PDB3	F18	IO78NDB1	H10	V _{CC} I B0
E5	GAA2/IO225PDB3	F19	IO81NDB1	H11	IO38RSB0
E6	GNDQ	F20	IO82PPB1	H12	IO47RSB0
E7	GAB1/IO03RSB0	F21	NC	H13	V _{CC} I B0
E8	IO17RSB0	F22	IO84NDB1	H14	V _{CC} I B0
E9	IO21RSB0	G1	IO214NDB3	H15	VMV1
E10	IO27RSB0	G2	IO214PDB3	H16	GBC2/IO80PDB1
E11	IO34RSB0	G3	NC	H17	IO83PPB1
E12	IO44RSB0	G4	IO222NDB3	H18	IO86PPB1

484-Pin FBGA		484-Pin FBGA		484-Pin FBGA	
Pin Number	A3P1000L Function	Pin Number	A3P1000L Function	Pin Number	A3P1000L Function
H19	IO87PDB1	K11	GND	M3	IO206NDB3
H20	V _{CC}	K12	GND	M4	GFA2/IO206PDB3
H21	NC	K13	GND	M5	GFA1/IO207PDB3
H22	NC	K14	V _{CC}	M6	V _{CC} PLF
J1	IO212NDB3	K15	V _{CC} B1	M7	IO205NDB3
J2	IO212PDB3	K16	GCC1/IO91PPB1	M8	GFB2/IO205PDB3
J3	NC	K17	IO90NPB1	M9	V _{CC}
J4	IO217NDB3	K18	IO88PDB1	M10	GND
J5	IO218NDB3	K19	IO88NDB1	M11	GND
J6	IO216PDB3	K20	IO94NPB1	M12	GND
J7	IO216NDB3	K21	IO98NDB1	M13	GND
J8	V _{CC} B3	K22	IO98PDB1	M14	V _{CC}
J9	GND	L1	NC	M15	GCB2/IO95PPB1
J10	V _{CC}	L2	IO200PDB3	M16	GCA1/IO93PPB1
J11	V _{CC}	L3	IO210NPB3	M17	GCC2/IO96PPB1
J12	V _{CC}	L4	GFB0/IO208NPB3	M18	IO100PPB1
J13	V _{CC}	L5	GFA0/IO207NDB3	M19	GCA2/IO94PPB1
J14	GND	L6	GFB1/IO208PPB3	M20	IO101PPB1
J15	V _{CC} B1	L7	V _{CC} OMPLF	M21	IO99PPB1
J16	IO83NPB1	L8	GFC0/IO209NPB3	M22	NC
J17	IO86NPB1	L9	V _{CC}	N1	IO201NDB3
J18	IO90PPB1	L10	GND	N2	IO201PDB3
J19	IO87NDB1	L11	GND	N3	NC
J20	NC	L12	GND	N4	GFC2/IO204PDB3
J21	IO89PDB1	L13	GND	N5	IO204NDB3
J22	IO89NDB1	L14	V _{CC}	N6	IO203NDB3
K1	IO211PDB3	L15	GCC0/IO91NPB1	N7	IO203PDB3
K2	IO211NDB3	L16	GCB1/IO92PPB1	N8	V _{CC} B3
K3	NC	L17	GCA0/IO93NPB1	N9	V _{CC}
K4	IO210PPB3	L18	IO96NPB1	N10	GND
K5	IO213NDB3	L19	GCB0/IO92NPB1	N11	GND
K6	IO213PDB3	L20	IO97PDB1	N12	GND
K7	GFC1/IO209PPB3	L21	IO97NDB1	N13	GND
K8	V _{CC} B3	L22	IO99NPB1	N14	V _{CC}
K9	V _{CC}	M1	NC	N15	V _{CC} B1
K10	GND	M2	IO200NDB3	N16	IO95NPB1

484-Pin FBGA		484-Pin FBGA		484-Pin FBGA	
Pin Number	A3P1000L Function	Pin Number	A3P1000L Function	Pin Number	A3P1000L Function
N17	IO100NPB1	R9	V _{CC} B2	U1	IO195PDB3
N18	IO102NDB1	R10	V _{CC} B2	U2	IO195NDB3
N19	IO102PDB1	R11	IO147RSB2	U3	IO194NPB3
N20	NC	R12	IO136RSB2	U4	GEB1/IO189PDB3
N21	IO101NPB1	R13	V _{CC} B2	U5	GEB0/IO189NDB3
N22	IO103PDB1	R14	V _{CC} B2	U6	VMV2
P1	NC	R15	VMV2	U7	IO179RSB2
P2	IO199PDB3	R16	IO110NDB1	U8	IO171RSB2
P3	IO199NDB3	R17	GDB1/IO112PPB1	U9	IO165RSB2
P4	IO202NDB3	R18	GDC1/IO111PDB1	U10	IO159RSB2
P5	IO202PDB3	R19	IO107NDB1	U11	IO151RSB2
P6	IO196PPB3	R20	V _{CC}	U12	IO137RSB2
P7	IO193PPB3	R21	IO104NDB1	U13	IO134RSB2
P8	V _{CC} B3	R22	IO105PDB1	U14	IO128RSB2
P9	GND	T1	IO198PDB3	U15	VMV1
P10	V _{CC}	T2	IO198NDB3	U16	TCK
P11	V _{CC}	T3	NC	U17	V _{PUMP}
P12	V _{CC}	T4	IO194PPB3	U18	TRST
P13	V _{CC}	T5	IO192PPB3	U19	GDA0/IO113NDB1
P14	GND	T6	GEC1/IO190PPB3	U20	NC
P15	V _{CC} B1	T7	IO192NPB3	U21	IO108NDB1
P16	GDB0/IO112NPB1	T8	GNDQ	U22	IO109PDB1
P17	IO106NDB1	T9	GEA2/IO187RSB2	V1	NC
P18	IO106PDB1	T10	IO161RSB2	V2	NC
P19	IO107PDB1	T11	IO155RSB2	V3	GND
P20	NC	T12	IO141RSB2	V4	GEA1/IO188PDB3
P21	IO104PDB1	T13	IO129RSB2	V5	GEA0/IO188NDB3
P22	IO103NDB1	T14	IO124RSB2	V6	IO184RSB2
R1	NC	T15	GNDQ	V7	GEC2/IO185RSB2
R2	IO197PPB3	T16	IO110PDB1	V8	IO168RSB2
R3	V _{CC}	T17	V _{JTAG}	V9	IO163RSB2
R4	IO197NPB3	T18	GDC0/IO111NDB1	V10	IO157RSB2
R5	IO196NPB3	T19	GDA1/IO113PDB1	V11	IO149RSB2
R6	IO193NPB3	T20	NC	V12	IO143RSB2
R7	GEC0/IO190NPB3	T21	IO108PDB1	V13	IO138RSB2
R8	VMV3	T22	IO105NDB1	V14	IO131RSB2

484-Pin FBGA	
Pin Number	A3P1000L Function
V15	IO125RSB2
V16	GDB2/IO115RSB2
V17	TDI
V18	GNDQ
V19	TDO
V20	GND
V21	NC
V22	IO109NDB1
W1	NC
W2	IO191PDB3
W3	NC
W4	GND
W5	IO183RSB2
W6	FF/GEB2/IO186RSB2
W7	IO172RSB2
W8	IO170RSB2
W9	IO164RSB2
W10	IO158RSB2
W11	IO153RSB2
W12	IO142RSB2
W13	IO135RSB2
W14	IO130RSB2
W15	GDC2/IO116RSB2
W16	IO120RSB2
W17	GDA2/IO114RSB2
W18	TMS
W19	GND
W20	NC
W21	NC
W22	NC
Y1	V _{CC} I B3
Y2	IO191NDB3
Y3	NC
Y4	IO182RSB2
Y5	GND
Y6	IO177RSB2

484-Pin FBGA	
Pin Number	A3P1000L Function
Y7	IO174RSB2
Y8	V _{CC}
Y9	V _{CC}
Y10	IO154RSB2
Y11	IO148RSB2
Y12	IO140RSB2
Y13	NC
Y14	V _{CC}
Y15	V _{CC}
Y16	NC
Y17	NC
Y18	GND
Y19	NC
Y20	NC
Y21	NC
Y22	V _{CC} I B1

484-Pin FBGA		484-Pin FBGA		484-Pin FBGA	
Pin Number	A3PE3000L Function	Pin Number	A3PE3000L Function	Pin Number	A3PE3000L Function
A1	GND	AA15	IO170PDB4V2	B7	IO14PDB0V1
A2	GND	AA16	IO166NDB4V1	B8	IO18NDB0V2
A3	V _{CC} B0	AA17	IO166PDB4V1	B9	IO24NDB0V2
A4	IO10NDB0V1	AA18	IO160NDB4V0	B10	IO34PDB0V4
A5	IO10PDB0V1	AA19	IO160PDB4V0	B11	IO40PDB0V4
A6	IO16NDB0V1	AA20	IO158NPB4V0	B12	IO46NDB1V0
A7	IO16PDB0V1	AA21	V _{CC} B3	B13	IO54NDB1V1
A8	IO18PDB0V2	AA22	GND	B14	IO62NDB1V2
A9	IO24PDB0V2	AB1	GND	B15	IO62PDB1V2
A10	IO28NDB0V3	AB2	GND	B16	IO68NDB1V3
A11	IO28PDB0V3	AB3	V _{CC} B5	B17	IO68PDB1V3
A12	IO46PDB1V0	AB4	IO216NDB5V2	B18	IO72PDB1V3
A13	IO54PDB1V1	AB5	IO216PDB5V2	B19	IO74PDB1V4
A14	IO56NDB1V1	AB6	IO210NDB5V2	B20	IO76NPB1V4
A15	IO56PDB1V1	AB7	IO210PDB5V2	B21	V _{CC} B2
A16	IO64NDB1V2	AB8	IO208NDB5V1	B22	GND
A17	IO64PDB1V2	AB9	IO208PDB5V1	C1	V _{CC} B7
A18	IO72NDB1V3	AB10	IO197NDB5V0	C2	IO303PDB7V3
A19	IO74NDB1V4	AB11	IO197PDB5V0	C3	IO305PDB7V3
A20	V _{CC} B1	AB12	IO174NDB4V2	C4	IO06NPB0V0
A21	GND	AB13	IO174PDB4V2	C5	GND
A22	GND	AB14	IO172NDB4V2	C6	IO12NDB0V1
AA1	GND	AB15	IO172PDB4V2	C7	IO12PDB0V1
AA2	V _{CC} B6	AB16	IO168NDB4V1	C8	V _{CC}
AA3	IO228PDB5V4	AB17	IO168PDB4V1	C9	V _{CC}
AA4	IO224PDB5V3	AB18	IO162NDB4V1	C10	IO34NDB0V4
AA5	IO218NDB5V3	AB19	IO162PDB4V1	C11	IO40NDB0V4
AA6	IO218PDB5V3	AB20	V _{CC} B4	C12	IO48NDB1V0
AA7	IO212NDB5V2	AB21	GND	C13	IO48PDB1V0
AA8	IO212PDB5V2	AB22	GND	C14	V _{CC}
AA9	IO198PDB5V0	B1	GND	C15	V _{CC}
AA10	IO198NDB5V0	B2	V _{CC} B7	C16	IO70NDB1V3
AA11	IO188PPB4V4	B3	IO06PPB0V0	C17	IO70PDB1V3
AA12	IO180NDB4V3	B4	IO08NDB0V0	C18	GND
AA13	IO180PDB4V3	B5	IO08PDB0V0	C19	IO76PPB1V4
AA14	IO170NDB4V2	B6	IO14NDB0V1	C20	IO88NDB2V0

484-Pin FBGA		484-Pin FBGA		484-Pin FBGA	
Pin Number	A3PE3000L Function	Pin Number	A3PE3000L Function	Pin Number	A3PE3000L Function
C21	IO94PPB2V1	E13	IO58NDB1V2	G5	IO297PDB7V2
C22	V _{CCI} B2	E14	IO58PDB1V2	G6	GAC2/IO307PDB7V4
D1	IO293PDB7V2	E15	GBC1/IO79PDB1V4	G7	V _{COMPLA}
D2	IO303NDB7V3	E16	GBB0/IO80NDB1V4	G8	GNDQ
D3	IO305NDB7V3	E17	GNDQ	G9	IO26NDB0V3
D4	GND	E18	GBA2/IO82PDB2V0	G10	IO26PDB0V3
D5	GAA0/IO00NDB0V0	E19	IO86NDB2V0	G11	IO36PDB0V4
D6	GAA1/IO00PDB0V0	E20	GND	G12	IO42PDB1V0
D7	GAB0/IO01NDB0V0	E21	IO90NDB2V1	G13	IO50PDB1V1
D8	IO20PDB0V2	E22	IO98PDB2V2	G14	IO60NDB1V2
D9	IO22PDB0V2	F1	IO299NPB7V3	G15	GNDQ
D10	IO30PDB0V3	F2	IO301NDB7V3	G16	V _{COMPLB}
D11	IO38NDB0V4	F3	IO301PDB7V3	G17	GBB2/IO83PDB2V0
D12	IO52NDB1V1	F4	IO308NDB7V4	G18	IO92PDB2V1
D13	IO52PDB1V1	F5	IO309NDB7V4	G19	IO92NDB2V1
D14	IO66NDB1V3	F6	VMV7	G20	IO102PDB2V2
D15	IO66PDB1V3	F7	V _{CCPLA}	G21	IO102NDB2V2
D16	GBB1/IO80PDB1V4	F8	GAC0/IO02NDB0V0	G22	IO105NDB2V2
D17	GBA0/IO81NDB1V4	F9	GAC1/IO02PDB0V0	H1	IO286PSB7V1
D18	GBA1/IO81PDB1V4	F10	IO32NDB0V3	H2	IO291NPB7V2
D19	GND	F11	IO32PDB0V3	H3	V _{CC}
D20	IO88PDB2V0	F12	IO44PDB1V0	H4	IO295NDB7V2
D21	IO90PDB2V1	F13	IO50NDB1V1	H5	IO297NDB7V2
D22	IO94NPB2V1	F14	IO60PDB1V2	H6	IO307NDB7V4
E1	IO293NDB7V2	F15	GBC0/IO79NDB1V4	H7	IO287PDB7V1
E2	IO299PPB7V3	F16	V _{CCPLB}	H8	VMV0
E3	GND	F17	VMV2	H9	V _{CCI} B0
E4	GAB2/IO308PDB7V4	F18	IO82NDB2V0	H10	V _{CCI} B0
E5	GAA2/IO309PDB7V4	F19	IO86PDB2V0	H11	IO36NDB0V4
E6	GNDQ	F20	IO96PDB2V1	H12	IO42NDB1V0
E7	GAB1/IO01PDB0V0	F21	IO96NDB2V1	H13	V _{CCI} B1
E8	IO20NDB0V2	F22	IO98NDB2V2	H14	V _{CCI} B1
E9	IO22NDB0V2	G1	IO289NDB7V1	H15	VMV1
E10	IO30NDB0V3	G2	IO289PDB7V1	H16	GBC2/IO84PDB2V0
E11	IO38PDB0V4	G3	IO291PPB7V2	H17	IO83NDB2V0
E12	IO44NDB1V0	G4	IO295PDB7V2	H18	IO100NDB2V2

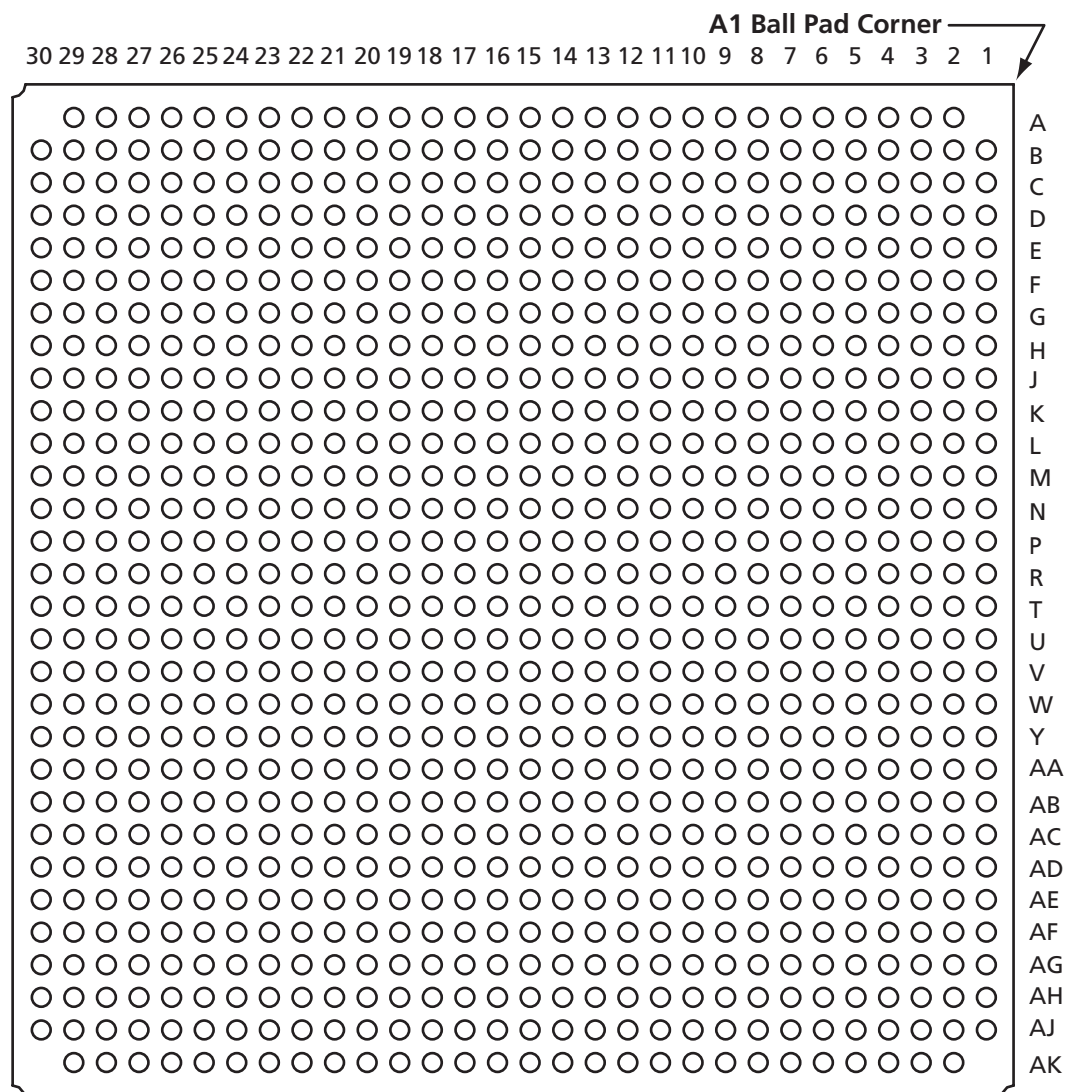
484-Pin FBGA		484-Pin FBGA		484-Pin FBGA	
Pin Number	A3PE3000L Function	Pin Number	A3PE3000L Function	Pin Number	A3PE3000L Function
H19	IO100PDB2V2	K11	GND	M3	IO272NDB6V4
H20	V _{CC}	K12	GND	M4	GFA2/IO272PDB6V4
H21	VMV2	K13	GND	M5	GFA1/IO273PDB6V4
H22	IO105PDB2V2	K14	V _{CC}	M6	V _{CCPLF}
J1	IO285NDB7V1	K15	V _{CC} B2	M7	IO271NDB6V4
J2	IO285PDB7V1	K16	GCC1/IO112PPB2V3	M8	GFB2/IO271PDB6V4
J3	VMV7	K17	IO108NDB2V3	M9	V _{CC}
J4	IO279PDB7V0	K18	IO108PDB2V3	M10	GND
J5	IO283PDB7V1	K19	IO110NPB2V3	M11	GND
J6	IO281PDB7V0	K20	IO106NPB2V3	M12	GND
J7	IO287NDB7V1	K21	IO109NDB2V3	M13	GND
J8	V _{CC} B7	K22	IO107NDB2V3	M14	V _{CC}
J9	GND	L1	IO257PSB6V2	M15	GCB2/IO116PPB3V0
J10	V _{CC}	L2	IO276PDB7V0	M16	GCA1/IO114PPB3V0
J11	V _{CC}	L3	IO276NDB7V0	M17	GCC2/IO117PPB3V0
J12	V _{CC}	L4	GFB0/IO274NPB7V0	M18	V _{CCPLC}
J13	V _{CC}	L5	GFA0/IO273NDB6V4	M19	GCA2/IO115PDB3V0
J14	GND	L6	GFB1/IO274PPB7V0	M20	IO115NDB3V0
J15	V _{CC} B2	L7	V _{COMPLF}	M21	IO126PDB3V1
J16	IO84NDB2V0	L8	GFC0/IO275NPB7V0	M22	IO124PSB3V1
J17	IO104NDB2V2	L9	V _{CC}	N1	IO255PPB6V2
J18	IO104PDB2V2	L10	GND	N2	IO253NDB6V2
J19	IO106PPB2V3	L11	GND	N3	VMV6
J20	GNDQ	L12	GND	N4	GFC2/IO270PPB6V4
J21	IO109PDB2V3	L13	GND	N5	IO261PPB6V3
J22	IO107PDB2V3	L14	V _{CC}	N6	IO263PDB6V3
K1	IO277NDB7V0	L15	GCC0/IO112NPB2V3	N7	IO263NDB6V3
K2	IO277PDB7V0	L16	GCB1/IO113PPB2V3	N8	V _{CC} B6
K3	GNDQ	L17	GCA0/IO114NPB3V0	N9	V _{CC}
K4	IO279NDB7V0	L18	V _{COMPLC}	N10	GND
K5	IO283NDB7V1	L19	GCB0/IO113NPB2V3	N11	GND
K6	IO281NDB7V0	L20	IO110PPB2V3	N12	GND
K7	GFC1/IO275PPB7V0	L21	IO111NDB2V3	N13	GND
K8	V _{CC} B7	L22	IO111PDB2V3	N14	V _{CC}
K9	V _{CC}	M1	GNDQ	N15	V _{CC} B3
K10	GND	M2	IO255NPB6V2	N16	IO116NPB3V0

484-Pin FBGA		484-Pin FBGA		484-Pin FBGA	
Pin Number	A3PE3000L Function	Pin Number	A3PE3000L Function	Pin Number	A3PE3000L Function
N17	IO132NPB3V2	R9	V _{CC} B5	U1	IO240PPB6V0
N18	IO117NPB3V0	R10	V _{CC} B5	U2	IO238PDB6V0
N19	IO132PPB3V2	R11	IO196NDB5V0	U3	IO238NDB6V0
N20	GNDQ	R12	IO196PDB5V0	U4	GEB1/IO235PDB6V0
N21	IO126NDB3V1	R13	V _{CC} B4	U5	GEB0/IO235NDB6V0
N22	IO128PDB3V1	R14	V _{CC} B4	U6	VMV6
P1	IO247PDB6V1	R15	VMV3	U7	V _{CC} PLE
P2	IO253PDB6V2	R16	V _{CC} PLD	U8	IO233NPB5V4
P3	IO270NPB6V4	R17	GDB1/IO152PPB3V4	U9	IO222PPB5V3
P4	IO261NPB6V3	R18	GDC1/IO151PDB3V4	U10	IO206PDB5V1
P5	IO249PPB6V1	R19	IO138NDB3V3	U11	IO202PDB5V1
P6	IO259PDB6V3	R20	V _{CC}	U12	IO194PDB5V0
P7	IO259NDB6V3	R21	IO130NDB3V2	U13	IO176NDB4V2
P8	V _{CC} B6	R22	IO134PDB3V2	U14	IO176PDB4V2
P9	GND	T1	IO243PPB6V1	U15	VMV4
P10	V _{CC}	T2	IO245NDB6V1	U16	TCK
P11	V _{CC}	T3	IO243NPB6V1	U17	V _{PUMP}
P12	V _{CC}	T4	IO241PDB6V0	U18	TRST
P13	V _{CC}	T5	IO241NDB6V0	U19	GDA0/IO153NDB3V4
P14	GND	T6	GEC1/IO236PPB6V0	U20	IO144NDB3V3
P15	V _{CC} B3	T7	V _{COMPLE}	U21	IO140NDB3V3
P16	GDB0/IO152NPB3V4	T8	GNDQ	U22	IO142PDB3V3
P17	IO136NDB3V2	T9	GEA2/IO233PPB5V4	V1	IO239PDB6V0
P18	IO136PDB3V2	T10	IO206NDB5V1	V2	IO240NPB6V0
P19	IO138PDB3V3	T11	IO202NDB5V1	V3	GND
P20	VMV3	T12	IO194NDB5V0	V4	GEA1/IO234PDB6V0
P21	IO130PDB3V2	T13	IO186NDB4V4	V5	GEA0/IO234NDB6V0
P22	IO128NDB3V1	T14	IO186PDB4V4	V6	GNDQ
R1	IO247NDB6V1	T15	GNDQ	V7	GEC2/IO231PDB5V4
R2	IO245PDB6V1	T16	V _{COMPLD}	V8	IO222NPB5V3
R3	V _{CC}	T17	V _{JTAG}	V9	IO204NDB5V1
R4	IO249NPB6V1	T18	GDC0/IO151NDB3V4	V10	IO204PDB5V1
R5	IO251NDB6V2	T19	GDA1/IO153PDB3V4	V11	IO195NDB5V0
R6	IO251PDB6V2	T20	IO144PDB3V3	V12	IO195PDB5V0
R7	GEC0/IO236NPB6V0	T21	IO140PDB3V3	V13	IO178NDB4V3
R8	VMV5	T22	IO134NDB3V2	V14	IO178PDB4V3

484-Pin FBGA	
Pin Number	A3PE3000L Function
V15	IO155NDB4V0
V16	GDB2/IO155PDB4V0
V17	TDI
V18	GNDQ
V19	TDO
V20	GND
V21	IO146PDB3V4
V22	IO142NDB3V3
W1	IO239NDB6V0
W2	IO237PDB6V0
W3	IO230PSB5V4
W4	GND
W5	IO232NDB5V4
W6	FF/GEB2/IO232PDB5V4
W7	IO231NDB5V4
W8	IO214NDB5V2
W9	IO214PDB5V2
W10	IO200NDB5V0
W11	IO192NDB4V4
W12	IO184NDB4V3
W13	IO184PDB4V3
W14	IO156NDB4V0
W15	GDC2/IO156PDB4V0
W16	IO154NDB4V0
W17	GDA2/IO154PDB4V0
W18	TMS
W19	GND
W20	IO150NDB3V4
W21	IO146NDB3V4
W22	IO148PPB3V4
Y1	V _{CCI} B6
Y2	IO237NDB6V0
Y3	IO228NDB5V4
Y4	IO224NDB5V3
Y5	GND

484-Pin FBGA	
Pin Number	A3PE3000L Function
Y6	IO220NDB5V3
Y7	IO220PDB5V3
Y8	V _{CC}
Y9	V _{CC}
Y10	IO200PDB5V0
Y11	IO192PDB4V4
Y12	IO188NPB4V4
Y13	IO187PSB4V4
Y14	V _{CC}
Y15	V _{CC}
Y16	IO164NDB4V1
Y17	IO164PDB4V1
Y18	GND
Y19	IO158PPB4V0
Y20	IO150PDB3V4
Y21	IO148NPB3V4
Y22	V _{CCI} B3

896-Pin FBGA



Note: This is the bottom view.

Figure 4 •

Note

For Package Manufacturing and Environmental information, visit the Resource Center at <http://www.actel.com/products/solutions/package/docs.aspx>.

896-Pin FBGA		896-Pin FBGA		896-Pin FBGA	
Pin Number	A3PE3000L Function	Pin Number	A3PE3000L Function	Pin Number	A3PE3000L Function
A2	GND	AA9	GEB1/IO235PPB6V0	AB15	IO198PDB5V0
A3	GND	AA10	V _{CC}	AB16	IO192NDB4V4
A4	IO14NPB0V1	AA11	IO226PPB5V4	AB17	IO192PDB4V4
A5	GND	AA12	V _{CC} B5	AB18	IO178NDB4V3
A6	IO07NPB0V0	AA13	V _{CC} B5	AB19	IO178PDB4V3
A7	GND	AA14	V _{CC} B5	AB20	IO174NDB4V2
A8	IO09NDB0V1	AA15	V _{CC} B5	AB21	IO162NPB4V1
A9	IO17NDB0V2	AA16	V _{CC} B4	AB22	V _{CC}
A10	IO17PDB0V2	AA17	V _{CC} B4	AB23	V _{CC} PLD
A11	IO21NDB0V2	AA18	V _{CC} B4	AB24	V _{CC} B3
A12	IO21PDB0V2	AA19	V _{CC} B4	AB25	IO150PDB3V4
A13	IO33NDB0V4	AA20	IO174PDB4V2	AB26	IO148PDB3V4
A14	IO33PDB0V4	AA21	V _{CC}	AB27	IO147NDB3V4
A15	IO35NDB0V4	AA22	IO142NPB3V3	AB28	IO145PDB3V3
A16	IO35PDB0V4	AA23	IO144NDB3V3	AB29	IO143PDB3V3
A17	IO41NDB1V0	AA24	IO144PDB3V3	AB30	IO137PDB3V2
A18	IO43NDB1V0	AA25	IO146NDB3V4	AC1	IO254PDB6V2
A19	IO43PDB1V0	AA26	IO146PDB3V4	AC2	IO254NDB6V2
A20	IO45NDB1V0	AA27	IO147PDB3V4	AC3	IO240PDB6V0
A21	IO45PDB1V0	AA28	IO139NDB3V3	AC4	GEC1/IO236PDB6V0
A22	IO57NDB1V2	AA29	IO139PDB3V3	AC5	IO237PDB6V0
A23	IO57PDB1V2	AA30	IO133NDB3V2	AC6	IO237NDB6V0
A24	GND	AB1	IO256NDB6V2	AC7	V _{COMPLE}
A25	IO69PPB1V3	AB2	IO244PDB6V1	AC8	GND
A26	GND	AB3	IO244NDB6V1	AC9	IO226NPB5V4
A27	GBC1/IO79PPB1V4	AB4	IO241PDB6V0	AC10	IO222NDB5V3
A28	GND	AB5	IO241NDB6V0	AC11	IO216NPB5V2
A29	GND	AB6	IO243NPB6V1	AC12	IO210NPB5V2
AA1	IO256PDB6V2	AB7	V _{CC} B6	AC13	IO204NDB5V1
AA2	IO248PDB6V1	AB8	V _{CC} PLE	AC14	IO204PDB5V1
AA3	IO248NDB6V1	AB9	V _{CC}	AC15	IO194NDB5V0
AA4	IO246NDB6V1	AB10	IO222PDB5V3	AC16	IO188NDB4V4
AA5	GEA1/IO234PDB6V0	AB11	IO218PPB5V3	AC17	IO188PDB4V4
AA6	GEA0/IO234NDB6V0	AB12	IO206NDB5V1	AC18	IO182PPB4V3
AA7	IO243PPB6V1	AB13	IO206PDB5V1	AC19	IO170NPB4V2
AA8	IO245NDB6V1	AB14	IO198NDB5V0	AC20	IO164NDB4V1

896-Pin FBGA		896-Pin FBGA		896-Pin FBGA	
Pin Number	A3PE3000L Function	Pin Number	A3PE3000L Function	Pin Number	A3PE3000L Function
AC21	IO164PDB4V1	AD26	V _{CCI} B3	AE30	IO149PDB3V4
AC22	IO162PPB4V1	AD27	GDA0/IO153NDB3V4	AF1	GND
AC23	GND	AD28	GDC0/IO151NDB3V4	AF2	IO238PPB6V0
AC24	V _{COMPLD}	AD29	GDC1/IO151PDB3V4	AF3	V _{CCI} B6
AC25	IO150NDB3V4	AD30	GND	AF4	IO220NPB5V3
AC26	IO148NDB3V4	AE1	IO242PPB6V1	AF5	V _{CC}
AC27	GDA1/IO153PDB3V4	AE2	V _{CC}	AF6	IO228NDB5V4
AC28	IO145NDB3V3	AE3	IO239PDB6V0	AF7	V _{CCI} B5
AC29	IO143NDB3V3	AE4	IO239NDB6V0	AF8	IO230PDB5V4
AC30	IO137NDB3V2	AE5	VMV6	AF9	IO229NDB5V4
AD1	GND	AE5	VMV6	AF10	IO229PDB5V4
AD2	IO242NPB6V1	AE6	GND	AF11	IO214PPB5V2
AD3	IO240NDB6V0	AE7	GNDQ	AF12	IO208NDB5V1
AD4	GEC0/IO236NDB6V0	AE8	IO230NDB5V4	AF13	IO208PDB5V1
AD5	V _{CCI} B6	AE9	IO224NPB5V3	AF14	IO200PDB5V0
AD6	GNDQ	AE10	IO214NPB5V2	AF15	IO196NDB5V0
AD6	GNDQ	AE11	IO212NDB5V2	AF16	IO186NDB4V4
AD7	V _{CC}	AE12	IO212PDB5V2	AF17	IO186PDB4V4
AD8	VMV5	AE13	IO202NPB5V1	AF18	IO180NDB4V3
AD9	V _{CCI} B5	AE14	IO200NDB5V0	AF19	IO180PDB4V3
AD10	IO224PPB5V3	AE15	IO196PDB5V0	AF20	IO168NDB4V1
AD11	IO218NPB5V3	AE16	IO190NDB4V4	AF21	IO168PDB4V1
AD12	IO216PPB5V2	AE17	IO184PDB4V3	AF22	IO160NDB4V0
AD13	IO210PPB5V2	AE18	IO184NDB4V3	AF23	IO158NPB4V0
AD14	IO202PPB5V1	AE19	IO172PDB4V2	AF24	V _{CCI} B4
AD15	IO194PDB5V0	AE20	IO172NDB4V2	AF25	IO154NPB4V0
AD16	IO190PDB4V4	AE21	IO166NDB4V1	AF26	V _{CC}
AD17	IO182NPB4V3	AE22	IO160PDB4V0	AF27	TDO
AD18	IO176NDB4V2	AE23	GNDQ	AF28	V _{CCI} B3
AD19	IO176PDB4V2	AE24	VMV4	AF29	GNDQ
AD20	IO170PPB4V2	AE25	GND	AF29	GNDQ
AD21	IO166PDB4V1	AE26	GDB0/IO152NDB3V4	AF30	GND
AD22	V _{CCI} B4	AE27	GDB1/IO152PDB3V4	AG1	IO238NPB6V0
AD23	TCK	AE28	VMV3	AG2	V _{CC}
AD24	V _{CC}	AE28	VMV3	AG3	IO232NPB5V4
AD25	TRST	AE29	V _{CC}	AG4	GND

896-Pin FBGA		896-Pin FBGA		896-Pin FBGA	
Pin Number	A3PE3000L Function	Pin Number	A3PE3000L Function	Pin Number	A3PE3000L Function
AG5	IO220PPB5V3	AH10	IO225PPB5V3	AJ16	IO183NDB4V3
AG6	IO228PDB5V4	AH11	IO223PPB5V3	AJ17	IO183PDB4V3
AG7	IO231NDB5V4	AH12	IO211NDB5V2	AJ18	IO179NPB4V3
AG8	GEC2/IO231PDB5V4	AH13	IO211PDB5V2	AJ19	IO177PDB4V2
AG9	IO225NPB5V3	AH14	IO205PPB5V1	AJ20	IO173NDB4V2
AG10	IO223NPB5V3	AH15	IO195NDB5V0	AJ21	IO173PDB4V2
AG11	IO221PDB5V3	AH16	IO185NDB4V3	AJ22	IO163NDB4V1
AG12	IO221NDB5V3	AH17	IO185PDB4V3	AJ23	IO163PDB4V1
AG13	IO205NPB5V1	AH18	IO181PDB4V3	AJ24	IO167NPB4V1
AG14	IO199NDB5V0	AH19	IO177NDB4V2	AJ25	V _{CC}
AG15	IO199PDB5V0	AH20	IO171NPB4V2	AJ26	IO156NPB4V0
AG16	IO187NDB4V4	AH21	IO165PPB4V1	AJ27	V _{CC}
AG17	IO187PDB4V4	AH22	IO161PPB4V0	AJ28	TMS
AG18	IO181NDB4V3	AH23	IO157NDB4V0	AJ29	GND
AG19	IO171PPB4V2	AH24	IO157PDB4V0	AJ30	GND
AG20	IO165NPB4V1	AH25	IO155NDB4V0	AK2	GND
AG21	IO161NPB4V0	AH26	V _{CC} B4	AK3	GND
AG22	IO159NDB4V0	AH27	TDI	AK4	IO217PPB5V2
AG23	IO159PDB4V0	AH28	V _{CC}	AK5	GND
AG24	IO158PPB4V0	AH29	V _{PUMP}	AK6	IO215PPB5V2
AG25	GDB2/IO155PDB4V0	AH30	GND	AK7	GND
AG26	GDA2/IO154PPB4V0	AJ1	GND	AK8	IO207NDB5V1
AG27	GND	AJ2	GND	AK9	IO207PDB5V1
AG28	V _{JTAG}	AJ3	GEA2/IO233PPB5V4	AK10	IO201NDB5V0
AG29	V _{CC}	AJ4	V _{CC}	AK11	IO201PDB5V0
AG30	IO149NDB3V4	AJ5	IO217NPB5V2	AK12	IO193NDB4V4
AH1	GND	AJ6	V _{CC}	AK13	IO193PDB4V4
AH2	IO233NPB5V4	AJ7	IO215NPB5V2	AK14	IO197PDB5V0
AH3	V _{CC}	AJ8	IO213NDB5V2	AK15	IO191NDB4V4
AH4	FF/GEB2/IO232PPB5V4	AJ9	IO213PDB5V2	AK16	IO191PDB4V4
AH5	V _{CC} B5	AJ10	IO209NDB5V1	AK17	IO189NDB4V4
AH6	IO219NDB5V3	AJ11	IO209PDB5V1	AK18	IO189PDB4V4
AH7	IO219PDB5V3	AJ12	IO203NDB5V1	AK19	IO179PPB4V3
AH8	IO227NDB5V4	AJ13	IO203PDB5V1	AK20	IO175NDB4V2
AH9	IO227PDB5V4	AJ14	IO197NDB5V0	AK21	IO175PDB4V2
		AJ15	IO195PDB5V0	AK22	IO169NDB4V1

896-Pin FBGA	
Pin Number	A3PE3000L Function
AK23	IO169PDB4V1
AK24	GND
AK25	IO167PPB4V1
AK26	GND
AK27	GDC2/IO156PPB4V0
AK28	GND
AK29	GND
B1	GND
B2	GND
B3	GAA2/IO309PPB7V4
B4	V _{CC}
B5	IO14PPB0V1
B6	V _{CC}
B7	IO07PPB0V0
B8	IO09PDB0V1
B9	IO15PPB0V1
B10	IO19NDB0V2
B11	IO19PDB0V2
B12	IO29NDB0V3
B13	IO29PDB0V3
B14	IO31PPB0V3
B15	IO37NDB0V4
B16	IO37PDB0V4
B17	IO41PDB1V0
B18	IO51NDB1V1
B19	IO59PDB1V2
B20	IO53PDB1V1
B21	IO53NDB1V1
B22	IO61NDB1V2
B23	IO61PDB1V2
B24	IO69NPB1V3
B25	V _{CC}
B26	GBC0/IO79NPB1V4
B27	V _{CC}
B28	IO64NPB1V2
B29	GND

896-Pin FBGA	
Pin Number	A3PE3000L Function
B30	GND
C1	GND
C2	IO309NPB7V4
C3	V _{CC}
C4	GAA0/IO00NPB0V0
C5	V _{CC} B0
C6	IO03PDB0V0
C7	IO03NDB0V0
C8	GAB1/IO01PDB0V0
C9	IO05PDB0V0
C10	IO15NPB0V1
C11	IO25NDB0V3
C12	IO25PDB0V3
C13	IO31NPB0V3
C14	IO27NDB0V3
C15	IO39NDB0V4
C16	IO39PDB0V4
C17	IO55PPB1V1
C18	IO51PDB1V1
C19	IO59NDB1V2
C20	IO63NDB1V2
C21	IO63PDB1V2
C22	IO67NDB1V3
C23	IO67PDB1V3
C24	IO75NDB1V4
C25	IO75PDB1V4
C26	V _{CC} B1
C27	IO64PPB1V2
C28	V _{CC}
C29	GBA1/IO81PPB1V4
C30	GND
D1	IO303PPB7V3
D2	V _{CC}
D3	IO305NPB7V3
D4	GND
D5	GAA1/IO00PPB0V0

896-Pin FBGA	
Pin Number	A3PE3000L Function
D6	GAC1/IO02PDB0V0
D7	IO06NPB0V0
D8	GAB0/IO01NDB0V0
D9	IO05NDB0V0
D10	IO11NDB0V1
D11	IO11PDB0V1
D12	IO23NDB0V2
D13	IO23PDB0V2
D14	IO27PDB0V3
D15	IO40PDB0V4
D16	IO47NDB1V0
D17	IO47PDB1V0
D18	IO55NPB1V1
D19	IO65NDB1V3
D20	IO65PDB1V3
D21	IO71NDB1V3
D22	IO71PDB1V3
D23	IO73NDB1V4
D24	IO73PDB1V4
D25	IO74NDB1V4
D26	GBB0/IO80NPB1V4
D27	GND
D28	GBA0/IO81NPB1V4
D29	V _{CC}
D30	GBA2/IO82PPB2V0
E1	GND
E2	IO303NPB7V3
E3	V _{CC} B7
E4	IO305PPB7V3
E5	V _{CC}
E6	GAC0/IO02NDB0V0
E7	V _{CC} B0
E8	IO06PPB0V0
E9	IO24NDB0V2
E10	IO24PDB0V2
E11	IO13NDB0V1

896-Pin FBGA		896-Pin FBGA		896-Pin FBGA	
Pin Number	A3PE3000L Function	Pin Number	A3PE3000L Function	Pin Number	A3PE3000L Function
E12	IO13PDB0V1	F17	IO48PDB1V0	G21	IO66PDB1V3
E13	IO34NDB0V4	F18	IO50NDB1V1	G22	V _{CC} B1
E14	IO34PDB0V4	F19	IO58NDB1V2	G23	VMV1
E15	IO40NDB0V4	F20	IO60PDB1V2	G24	V _{CC}
E16	IO49NDB1V1	F21	IO77NDB1V4	G25	GNDQ
E17	IO49PDB1V1	F22	IO72NDB1V3	G25	GNDQ
E18	IO50PDB1V1	F23	IO72PDB1V3	G26	V _{CC} B2
E19	IO58PDB1V2	F24	GNDQ	G27	IO86NDB2V0
E20	IO60NDB1V2	F25	GND	G28	IO92NDB2V1
E21	IO77PDB1V4	F26	VMV2	G29	IO100PPB2V2
E22	IO68NDB1V3	F26	VMV2	G30	GND
E23	IO68PDB1V3	F27	IO86PDB2V0	H1	IO294PDB7V2
E24	V _{CC} B1	F28	IO92PDB2V1	H2	IO294NDB7V2
E25	IO74PDB1V4	F29	V _{CC}	H3	IO300NDB7V3
E26	V _{CC}	F30	IO100NPB2V2	H4	IO300PDB7V3
E27	GBB1/IO80PPB1V4	G1	GND	H5	IO295PDB7V2
E28	V _{CC} B2	G2	IO296NPB7V2	H6	IO299PDB7V3
E29	IO82NPB2V0	G3	IO306NDB7V4	H7	V _{COMPLA}
E30	GND	G4	IO297NDB7V2	H8	GND
F1	IO296PPB7V2	G5	V _{CC} B7	H9	IO08NDB0V0
F2	V _{CC}	G6	GNDQ	H10	IO08PDB0V0
F3	IO306PDB7V4	G6	GNDQ	H11	IO18PDB0V2
F4	IO297PDB7V2	G7	V _{CC}	H12	IO26NPB0V3
F5	VMV7	G8	VMV0	H13	IO28NDB0V3
F5	VMV7	G9	V _{CC} B0	H14	IO28PDB0V3
F6	GND	G10	IO10NDB0V1	H15	IO38PPB0V4
F7	GNDQ	G11	IO16NDB0V1	H16	IO42NDB1V0
F8	IO12NDB0V1	G12	IO22PDB0V2	H17	IO52NDB1V1
F9	IO12PDB0V1	G13	IO26PPB0V3	H18	IO52PDB1V1
F10	IO10PDB0V1	G14	IO38NPB0V4	H19	IO62NDB1V2
F11	IO16PDB0V1	G15	IO36NDB0V4	H20	IO62PDB1V2
F12	IO22NDB0V2	G16	IO46NDB1V0	H21	IO70NDB1V3
F13	IO30NDB0V3	G17	IO46PDB1V0	H22	IO70PDB1V3
F14	IO30PDB0V3	G18	IO56NDB1V1	H23	GND
F15	IO36PDB0V4	G19	IO56PDB1V1	H24	V _{COMPLB}
F16	IO48NDB1V0	G20	IO66NDB1V3	H25	GBC2/IO84PDB2V0

896-Pin FBGA		896-Pin FBGA		896-Pin FBGA	
Pin Number	A3PE3000L Function	Pin Number	A3PE3000L Function	Pin Number	A3PE3000L Function
H26	IO84NDB2V0	K2	IO288PDB7V1	L8	IO293PDB7V2
H27	IO96PDB2V1	K3	IO304NDB7V3	L9	IO293NDB7V2
H28	IO96NDB2V1	K4	IO304PDB7V3	L10	IO307NPB7V4
H29	IO89PDB2V0	K5	GAB2/IO308PDB7V4	L11	V _{CC}
H30	IO89NDB2V0	K6	IO308NDB7V4	L12	V _{CC}
J1	IO290NDB7V2	K7	IO301PDB7V3	L13	V _{CC}
J2	IO290PDB7V2	K8	IO301NDB7V3	L14	V _{CC}
J3	IO302NDB7V3	K9	GAC2/IO307PPB7V4	L15	V _{CC}
J4	IO302PDB7V3	K10	V _{CC}	L16	V _{CC}
J5	IO295NDB7V2	K11	IO04PPB0V0	L17	V _{CC}
J6	IO299NDB7V3	K12	V _{CC} B0	L18	V _{CC}
J7	V _{CC} B7	K13	V _{CC} B0	L19	V _{CC}
J8	V _{CC} PLA	K14	V _{CC} B0	L20	V _{CC}
J9	V _{CC}	K15	V _{CC} B0	L21	IO78NPB1V4
J10	IO04NPB0V0	K16	V _{CC} B1	L22	IO104NPB2V2
J11	IO18NDB0V2	K17	V _{CC} B1	L23	IO98NDB2V2
J12	IO20NDB0V2	K18	V _{CC} B1	L24	IO98PDB2V2
J13	IO20PDB0V2	K19	V _{CC} B1	L25	IO87PDB2V0
J14	IO32NDB0V3	K20	IO76PPB1V4	L26	IO87NDB2V0
J15	IO32PDB0V3	K21	V _{CC}	L27	IO97PDB2V1
J16	IO42PDB1V0	K22	IO78PPB1V4	L28	IO101PDB2V2
J17	IO44NDB1V0	K23	IO88NDB2V0	L29	IO103PDB2V2
J18	IO44PDB1V0	K24	IO88PDB2V0	L30	IO119NDB3V0
J19	IO54NDB1V1	K25	IO94PDB2V1	M1	IO282NDB7V1
J20	IO54PDB1V1	K26	IO94NDB2V1	M2	IO282PDB7V1
J21	IO76NPB1V4	K27	IO85PDB2V0	M3	IO292NDB7V2
J22	V _{CC}	K28	IO85NDB2V0	M4	IO292PDB7V2
J23	V _{CC} PLB	K29	IO93PDB2V1	M5	IO283NDB7V1
J24	V _{CC} B2	K30	IO93NDB2V1	M6	IO285PDB7V1
J25	IO90PDB2V1	L1	IO286NDB7V1	M7	IO287PDB7V1
J26	IO90NDB2V1	L2	IO286PDB7V1	M8	IO289PDB7V1
J27	GBB2/IO83PDB2V0	L3	IO298NDB7V3	M9	IO289NDB7V1
J28	IO83NDB2V0	L4	IO298PDB7V3	M10	V _{CC} B7
J29	IO91PDB2V1	L5	IO283PDB7V1	M11	V _{CC}
J30	IO91NDB2V1	L6	IO291NDB7V2	M12	GND
K1	IO288NDB7V1	L7	IO291PDB7V2	M13	GND

896-Pin FBGA		896-Pin FBGA		896-Pin FBGA	
Pin Number	A3PE3000L Function	Pin Number	A3PE3000L Function	Pin Number	A3PE3000L Function
M14	GND	N20	V _{CC}	P26	IO111NPB2V3
M15	GND	N21	V _{CC} B2	P27	IO105PDB2V2
M16	GND	N22	IO106NDB2V3	P28	IO105NDB2V2
M17	GND	N23	IO106PDB2V3	P29	GCC2/IO117PDB3V0
M18	GND	N24	IO108PDB2V3	P30	IO117NDB3V0
M19	GND	N25	IO108NDB2V3	R1	GFC2/IO270PDB6V4
M20	V _{CC}	N26	IO95NDB2V1	R2	GFB1/IO274PPB7V0
M21	V _{CC} B2	N27	IO99NDB2V2	R3	V _{COMPLF}
M22	NC	N28	IO99PDB2V2	R4	GFA0/IO273NDB6V4
M23	IO104PPB2V2	N29	IO107PDB2V3	R5	GFB0/IO274NPB7V0
M24	IO102PDB2V2	N30	IO107NDB2V3	R6	IO271NDB6V4
M25	IO102NDB2V2	P1	IO276NDB7V0	R7	GFB2/IO271PDB6V4
M26	IO95PDB2V1	P2	IO278NDB7V0	R8	IO269PDB6V4
M27	IO97NDB2V1	P3	IO280NDB7V0	R9	IO269NDB6V4
M28	IO101NDB2V2	P4	IO284NDB7V1	R10	V _{CC} B7
M29	IO103NDB2V2	P5	IO279NDB7V0	R11	V _{CC}
M30	IO119PDB3V0	P6	GFC1/IO275PDB7V0	R12	GND
N1	IO276PDB7V0	P7	GFC0/IO275NDB7V0	R13	GND
N2	IO278PDB7V0	P8	IO277PDB7V0	R14	GND
N3	IO280PDB7V0	P9	IO277NDB7V0	R15	GND
N4	IO284PDB7V1	P10	V _{CC} B7	R16	GND
N5	IO279PDB7V0	P11	V _{CC}	R17	GND
N6	IO285NDB7V1	P12	GND	R18	GND
N7	IO287NDB7V1	P13	GND	R19	GND
N8	IO281NDB7V0	P14	GND	R20	V _{CC}
N9	IO281PDB7V0	P15	GND	R21	V _{CC} B2
N10	V _{CC} B7	P16	GND	R22	GCC0/IO112NDB2V3
N11	V _{CC}	P17	GND	R23	GCB2/IO116PDB3V0
N12	GND	P18	GND	R24	IO118PDB3V0
N13	GND	P19	GND	R25	IO111PPB2V3
N14	GND	P20	V _{CC}	R26	IO122PPB3V1
N15	GND	P21	V _{CC} B2	R27	GCA0/IO114NPB3V0
N16	GND	P22	GCC1/IO112PDB2V3	R28	V _{COMPLC}
N17	GND	P23	IO110PDB2V3	R29	GCB1/IO113PPB2V3
N18	GND	P24	IO110NDB2V3	R30	IO115NPB3V0
N19	GND	P25	IO109PPB2V3	T1	IO270NDB6V4

896-Pin FBGA		896-Pin FBGA		896-Pin FBGA	
Pin Number	A3PE3000L Function	Pin Number	A3PE3000L Function	Pin Number	A3PE3000L Function
T2	V _{CCPLF}	U8	IO265NDB6V3	V14	GND
T3	GFA2/IO272PPB6V4	U9	IO263NDB6V3	V15	GND
T4	GFA1/IO273PDB6V4	U10	V _{CCIB6}	V16	GND
T5	IO272NPB6V4	U11	V _{CC}	V17	GND
T6	IO267NDB6V4	U12	GND	V18	GND
T7	IO267PDB6V4	U13	GND	V19	GND
T8	IO265PDB6V3	U14	GND	V20	V _{CC}
T9	IO263PDB6V3	U15	GND	V21	V _{CCIB3}
T10	V _{CCIB6}	U16	GND	V22	IO120NDB3V0
T11	V _{CC}	U17	GND	V23	IO128NDB3V1
T12	GND	U18	GND	V24	IO132PDB3V2
T13	GND	U19	GND	V25	IO130PPB3V2
T14	GND	U20	V _{CC}	V26	IO126NDB3V1
T15	GND	U21	V _{CCIB3}	V27	IO129NDB3V1
T16	GND	U22	IO120PDB3V0	V28	IO127NDB3V1
T17	GND	U23	IO128PDB3V1	V29	IO125NDB3V1
T18	GND	U24	IO124PDB3V1	V30	IO123PDB3V1
T19	GND	U25	IO124NDB3V1	W1	IO266NDB6V4
T20	V _{CC}	U26	IO126PDB3V1	W2	IO262NDB6V3
T21	V _{CCIB3}	U27	IO129PDB3V1	W3	IO260NDB6V3
T22	IO109NPB2V3	U28	IO127PDB3V1	W4	IO252NDB6V2
T23	IO116NDB3V0	U29	IO125PDB3V1	W5	IO251NDB6V2
T24	IO118NDB3V0	U30	IO121NDB3V0	W6	IO251PDB6V2
T25	IO122NPB3V1	V1	IO268NDB6V4	W7	IO255NDB6V2
T26	GCA1/IO114PPB3V0	V2	IO262PDB6V3	W8	IO249PPB6V1
T27	GCB0/IO113NPB2V3	V3	IO260PDB6V3	W9	IO253PDB6V2
T28	GCA2/IO115PPB3V0	V4	IO252PDB6V2	W10	V _{CCIB6}
T29	V _{CCPLC}	V5	IO257NPB6V2	W11	V _{CC}
T30	IO121PDB3V0	V6	IO261NPB6V3	W12	GND
U1	IO268PDB6V4	V7	IO255PDB6V2	W13	GND
U2	IO264NDB6V3	V8	IO259PDB6V3	W14	GND
U3	IO264PDB6V3	V9	IO259NDB6V3	W15	GND
U4	IO258PDB6V3	V10	V _{CCIB6}	W16	GND
U5	IO258NDB6V3	V11	V _{CC}	W17	GND
U6	IO257PPB6V2	V12	GND	W18	GND
U7	IO261PPB6V3	V13	GND	W19	GND

896-Pin FBGA	
Pin Number	A3PE3000L Function
W20	V _{CC}
W21	V _{CC} I _{B3}
W22	IO134PDB3V2
W23	IO138PDB3V3
W24	IO132NDB3V2
W25	IO136NPB3V2
W26	IO130NPB3V2
W27	IO141PDB3V3
W28	IO135PDB3V2
W29	IO131PDB3V2
W30	IO123NDB3V1
Y1	IO266PDB6V4
Y2	IO250PDB6V2
Y3	IO250NDB6V2
Y4	IO246PDB6V1
Y5	IO247NDB6V1
Y6	IO247PDB6V1
Y7	IO249NPB6V1
Y8	IO245PDB6V1
Y9	IO253NDB6V2
Y10	GEB0/IO235NPB6V0
Y11	V _{CC}
Y12	V _{CC}
Y13	V _{CC}
Y14	V _{CC}
Y15	V _{CC}
Y16	V _{CC}
Y17	V _{CC}
Y18	V _{CC}
Y19	V _{CC}
Y20	V _{CC}
Y21	IO142PPB3V3
Y22	IO134NDB3V2
Y23	IO138NDB3V3
Y24	IO140NDB3V3
Y25	IO140PDB3V3

896-Pin FBGA	
Pin Number	A3PE3000L Function
Y26	IO136PPB3V2
Y27	IO141NDB3V3
Y28	IO135NDB3V2
Y29	IO131NDB3V2
Y30	IO133PDB3V2

Part Number and Revision Date

Part Number 51700100-003-1

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List of Changes

The following table lists critical changes that were made in the current version of the chapter.

Previous Version	Changes in Current Version (v1.1)	Page
v1.0 (January 2008)	The " 324-Pin FBGA " package diagram was replaced.	3-29

Datasheet Categories

Categories

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Unmarked (production)

This version contains information that is considered to be final.

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Actel Corporation

2061 Stierlin Court
Mountain View, CA
94043-4655 USA

Phone 650.318.4200

Fax 650.318.4600

Actel Europe Ltd.

River Court, Meadows Business Park
Station Approach, Blackwater
Camberley Surrey GU17 9AB
United Kingdom

Phone +44 (0) 1276 609 300

Fax +44 (0) 1276 607 540

Actel Japan

EXOS Ebisu Building 4F
1-24-14 Ebisu Shibuya-ku
Tokyo 150 Japan

Phone +81.03.3445.7671

Fax +81.03.3445.7668

<http://jp.actel.com>

Actel Hong Kong

Room 2107, China Resources Building
26 Harbour Road
Wanchai, Hong Kong

Phone +852 2185 6460

Fax +852 2185 6488

www.actel.com.cn